

Panel PC 800

User's Manual

Version: **1.00 (Mai 2010)**

Model number: **MAPPC800-ENG**

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Chapter 1 • General information

Information:

B&R does its best to keep the printed versions of its user's manuals as current as possible. However, any newer versions of the User's Manual can always be downloaded in electronic form (pdf) from the B&R homepage www.br-automation.com.

1. Manual history

Version	Date	Change
0.10 Preliminary	2009-11-10	- First version

Table 1: Manual history

Version	Date	Change
1.00	2010-05-06	- Dimension diagrams for the PPC800 system units corrected. - Section 1 "Temperature sensor locations", on page 353 expanded. - Additional point added to section 8 "Known problems / issues", on page 163. - Section 2.2 "Firmware upgrade", on page 238 updated. - Section 2.1 "Temperature specifications", on page 37 updated. - Section 2.2 "Humidity specifications", on page 41 updated. - Section 2.3 "Power management", on page 42 updated. - Section 2.4 "Block diagram", on page 45 updated. - Section 7 "Panel PC 800 with Automation Runtime", on page 256 updated. - Section 2.5 "Serial number sticker", on page 46 updated. - Section 3.10 "Fan kits", on page 124 updated. - Section 2.1 "Temperature monitoring - Fan control", on page 355 updated. - Section 8 "Automation Device Interface (ADI) - Control Center", on page 257 updated. - Section 5 "Touch screen calibration", on page 151 updated. - Section 6 "Connection of USB peripheral devices", on page 152 updated. - Section 1.2.4 "Spacing for air circulation.", on page 132 updated. - Section 1.2 "Mounting orientation", on page 129 updated. - Section 6 "Panel PC 800 with Windows Embedded Standard 2009", on page 253 updated. - Section 4 "Connection examples", on page 135 updated. - Chapter 5 "Standards and certifications", on page 271 updated. - The dongle 1A4300.LZ1U was updated, see section 11 "B&R Automation Studio 3.0USBdongle", on page 323. - Technical data updated for the system units 5PC820.1505-00 and 5PC820.1906-00. - Technical data revised for the sections 13.2 "SDL cable 5CASDL.0xxx-00", 13.3 "SDL cable with 45° plug 5CASDL.0xxx-01", 13.4 "SDL flex cable 5CASDL.0xxx-03" and 13.5 "SDL flex cable with extender 5CASDL.0x00-13". - Warning regarding replacement of batteries updated in section 2 "Replacement CMOS batteries", on page 294 and 1 "Changing the battery", on page 351. - Figures updated for expansions, options and bus units. - CPU boards 5PC800.B945-05, 5PC800.B945-10, 5PC800.B945-11, 5PC800.B945-12, 5PC800.B945-13 and 5PC800.B945-14 were updated. - Description of +24 VDC supply voltage changed on page 48. - USB port caps (attached) 5AC900.1200-01, 5AC900.1200-02 and 5AC900.1200-03 updated in Chapter 6 "Accessories". - The PCI SATA RAID controller 5ACPCI.RAIC-03 and the replacement PCI SATA RAID HDD 5ACPCI.RAIC-04 were updated. - Section 7 "Configuration of a SATA RAID array", on page 155 updated.

Table 1: Manual history

2. Safety notices

2.1 Intended use

Programmable logic controllers (PLCs), operating and monitoring devices (industrial PCs, Power Panels, Mobile Panels, etc.), and B&R uninterruptible power supplies have been designed, developed, and manufactured for conventional use in industry. They were not designed, developed, and manufactured for any use involving serious risks or hazards that could lead to death, injury, serious physical damage, or loss of any kind without the implementation of exceptionally stringent safety precautions. In particular, such risks and hazards include the use of these devices to monitor nuclear reactions in nuclear power plants, as well as flight control systems, flight safety, the control of mass transit systems, medical life support systems and the control of weapons systems.

2.2 Protection against electrostatic discharges

Electrical components that are vulnerable to electrostatic discharge (ESD) must be handled accordingly.

2.2.1 Packaging

- Electrical components with housing
... do not require special ESD packaging, but must be handled properly (see "Electrical components with housing").
- Electrical components without housing
... must be protected by ESD-suitable packaging.

2.2.2 Guidelines for proper ESD handling

Electrical components with housing

- Do not touch the connector contacts on connected cables.
- Do not touch the contact tips on the circuit boards.

Electrical components without housing

In addition to "Electrical components with housing", the following also applies:

- Any persons handling electrical components or devices that will be installed in the electrical components must be grounded.
- Components can only be touched on the small sides or on the front plate.
- Components should always be stored in a suitable medium (ESD packaging, conductive foam, etc.).
Metallic surfaces are not suitable storage surfaces!

- Electrostatic discharges should be avoided on the components (e.g. through charged plastics).
- A minimum distance of 10 cm must be kept from monitors and TV sets.
- Measurement devices and equipment must be grounded.
- Measurement probes on potential-free measurement devices must be discharged on sufficiently grounded surfaces before taking measurements.

Individual components

- ESD protective measures for individual components are thoroughly integrated at B&R (conductive floors, footwear, arm bands, etc.).

The increased ESD protective measures for individual components are not necessary for our customers for handling B&R products.

2.3 Policy and procedures

Electronic devices are generally not failsafe. In the event of a failure on the programmable control system operating or monitoring device, or uninterruptible power supply, the user is responsible for ensuring that other devices that may be connected, e.g. motors, are in a secure state.

Both when using programmable logic controllers and when using operating and monitoring devices as control systems in conjunction with a soft PLC (e.g. B&R Automation Runtime or comparable products) or a slot PLC (e.g. B&R LS251 or comparable products), the safety precautions applying to industrial control systems (e.g. the provision of safety devices such as emergency stop circuits, etc.) must be observed in accordance with applicable national and international regulations. The same applies for all other devices connected to the system, such as drives.

All tasks such as installation, commissioning, and maintenance are only permitted to be carried out by qualified personnel. Qualified personnel are persons familiar with transport, mounting, installation, commissioning, and operation of the product who also have the respective qualifications (e.g. IEC 60364). National accident prevention guidelines must be followed.

The safety guidelines, connection descriptions (type plate and documentation), and limit values listed in the technical data are to be read carefully before installation and commissioning and must be observed.

2.4 Transport and storage

During transport and storage, devices must be protected from excessive stress (mechanical load, temperature, humidity, aggressive atmospheres, etc.).

2.5 Installation

- Installation must take place according to the documentation, using suitable equipment and tools.
- Devices must be installed without voltage applied and by qualified personnel.
- General safety regulations and nationally applicable accident prevention guidelines must be observed.
- Electrical installation must be carried out according to the relevant guidelines (e.g. line cross section, fuse, protective ground connection).

2.6 Operation

2.6.1 Protection against touching electrical parts

To operate programmable logic controllers, operating and monitoring devices or uninterruptible power supplies, certain components must carry dangerous voltage levels of over 42 VDC. A life-threatening electrical shock could occur if you come into contact with these parts. This could result in death, severe injury or material damage.

Before turning on the programmable logic controller, the operating and monitoring devices and the uninterruptible power supply, ensure that the housing is properly grounded (PE rail). The ground connection must be established when testing the operating and monitoring devices or the uninterruptible power supply, even when operating them for only a short time.

Before turning the device on, make sure that all parts with voltage applied are securely covered. During operation, all covers must remain closed.

2.6.2 Environmental conditions - dust, humidity, aggressive gases

Use of operating and monitoring devices (e.g. industrial PCs, power panels, mobile panels, etc.) and uninterruptible power supplies in very dusty environments should be avoided. Dust collection on the devices influences their function and, especially in systems with active cooling (fans), sufficient cooling cannot be guaranteed.

The presence of aggressive gases in the environment can also lead to malfunctions. When combined with high temperature and humidity, aggressive gases - e.g. with sulfur, nitrogen and chlorine components - start chemical processes that can damage electronic components very quickly. Signs of the presence of aggressive gases are blackened copper surfaces and cable ends on existing installations.

For operation in dusty or humid conditions, correctly installed (cutout installation) operating and monitoring devices like Automation Panel or Power Panel are protected on the front side. The rear side of all devices must be protected from dust and humidity and must be cleaned at suitable intervals.

2.6.3 Programs, viruses, and dangerous programs

The system is subject to potential danger each time data is exchanged or software is installed from a data medium (e.g. diskette, CD-ROM, USB flash drive, etc.), a network connection, or the Internet. The user is responsible for assessing these dangers, implementing preventative measures such as virus protection programs, firewalls, etc. and obtaining software from reliable sources.

2.7 Environmentally-friendly disposal

All B&R programmable controllers, operating and monitoring devices, and uninterruptible power supplies are designed to inflict as little harm on the environment as possible.

2.7.1 Separation of materials

It is necessary to separate different materials so the device can undergo an environmentally-friendly recycling process.

Component	Disposal
Programmable logic controllers Operating and monitoring devices Uninterruptible power supply Cables	Electronics recycling
Cardboard box / paper packaging	Paper / cardboard recycling
Plastic packaging	Plastic recycling

Table 2: Environmentally-friendly separation of materials

Disposal must comply with the respective legal regulations.

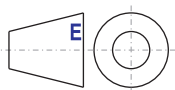
3. Organization of safety notices

The safety notices in this manual are organized as follows:

Safety notice	Description
Danger!	Disregarding the safety regulations and guidelines can be life-threatening.
Caution!	Disregarding the safety regulations and guidelines can result in severe injury or major damage to material.
Warning!	Disregarding the safety regulations and guidelines can result in injury or damage to material.
Information:	Important information for preventing errors.

Table 3: Organization of safety notices

4. Directives



European dimension standards apply to all dimensions (e.g. dimension diagrams, etc.).

5. Model numbers

5.1 System units

Model number	Short description	Note
5PC820.1505-00	PPC820 TFT C XGA 15in T Panel PC 820 15" TFT display with touch screen (resistive); connections for 1x RS232, 5x USB 2.0, Smart Display Link/DVI/monitor, 2x Ethernet 10/100/1000, HDA sound, add-on UPS slot, expandable with 1 or 2 PCI / PCI Express slots, optional PCI Express compact and slide-in compact slot; IP65 protection (front side); 24 VDC. Plug for power supply must be ordered separately (screw clamps: 0TB103.9; cage clamps: 0TB103.91).	See page 66
5PC820.1906-00	PPC820 TFT C SXGA 19in T Panel PC 820 19" SXGA color TFT display with touch screen (resistive); connections for 1x RS232, 5x USB 2.0, Smart Display Link/DVI/monitor, 2x Ethernet 10/100/1000, HDA sound, add-on UPS slot, expandable with 1 or 2 PCI / PCI Express slots, optional PCI Express compact and slide-in compact slot; IP65 protection (front side); 24 VDC. Plug for power supply must be ordered separately (screw clamps: 0TB103.9; cage clamps: 0TB103.91).	See page 72

Table 4: Model numbers - system units

5.2 CPU boards 945GME COM Express

Model number	Short description	Note
5PC800.B945-00	CPU board Intel® Core™ Duo L2400, 1.66 GHz 667 MHz FSB, 2 MB L2 cache; 945GME chipset; 2 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-10	CPU board Intel® Core™ Duo L2400, 1.66 GHz /2 667 MHz FSB, 2 MB L2 cache; 945GME chipset; 2 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-01	CPU board Intel® Core™2 Duo L7400, 1.5 GHz 667 MHz FSB, 2 MB L2 cache; 945GME chipset; 4 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-11	CPU board Intel® Core™2 Duo L7400, 1.5 /2 667 MHz FSB, 2 MB L2 cache; 945GME chipset; 4 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-02	CPU board Intel® Core™2 Duo U7500, 1.06 GHz 533 MHz FSB, 2 MB L2 cache; 945GME chipset; 2 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-12	CPU board Intel® Core™2 Duo U7500, 1.06 GHz /2 533 MHz FSB, 2 MB L2 cache; 945GME chipset; 2 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-03	CPU board Intel® Celeron® M 423, 1.06 GHz 533 MHz FSB, 2 MB L2 cache; 945GME chipset; 1 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-13	CPU board Intel® Celeron® M 423, 1.06 GHz /2 533 MHz FSB, 2 MB L2 cache; 945GME chipset; 1 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-04	CPU board Intel® Core™2 Duo T7400, 2.16 GHz 667 MHz FSB, 2 MB L2 cache; 945GME chipset; 4 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-14	CPU board Intel® Core™2 Duo T7400, 2.16 GHz /2 667 MHz FSB, 2 MB L2 cache; 945GME chipset; 4 sockets for SO-DIMM DDR2 module	See page 78
5PC800.B945-05	CPU board Intel® Atom™ N270, 1.6 GHz 533 MHz FSB, 512 kB L2 Cache; Chipset 945GME; 2 sockets for SO-DIMM DDR2 module	See page 78

Table 5: Model numbers - CPU boards 945GME

5.3 Heat sink

Model number	Short description	Note
5AC803.HS00-00	Panel PC 800 heat sink PPC800 heat sink for CPU boards with Dual Core processors L2400, L7400, U7500 and Celeron M 423.	See page 79
5AC803.HS00-01	Panel PC 800 heat sink T7400 PPC800 heat sink for CPU board with Dual Core processor T7400.	See page 79
5AC803.HS00-02	Panel PC 800 heat sink 945GME N270 PPC800 heat sink for CPU boards with Atom N270 processor and Chipset 945GME.	See page 79

Table 6: Model numbers - Heat sinks

5.4 Main memory

Model number	Short description	Note
5MMDDR.0512-01	SO-DIMM DDR2 512MB PC2-5300	See page 80
5MMDDR.1024-01	SO-DIMM DDR2 1024MB PC2-5300	See page 80
5MMDDR.2048-01	SO-DIMM DDR2 2048MB PC2-5300	See page 80

Table 7: Model numbers - Main memory

5.5 Expansion

Model number	Short description	Note
5AC803.SX01-00	PPC800 Expansion 1CS 1SI PPC800 expansion 1 PCI/PCI Express and 1 slide-in (bus 5AC803.BX01-00 or 5AC803.BX01-01 required).	See page 81
5AC803.SX02-00	PPC800 Expansion 2CS 1SI PPC800 expansion 2 PCI/PCI Express and 1 slide-in (bus 5AC803.BX02-00 or 5AC803.BX02-01 required).	See page 81

Table 8: Model numbers - Expansion

5.6 Bus units

Model number	Short description	Note
5AC803.BX01-00	PPC800 bus 1PCI 1SI PPC800 bus 1 PCI, 1 slide-in slot.	See page 86
5AC803.BX01-01	PPC800 bus 1PCle.x1 1SI PPC800 bus 1 PCI Express, 1 slide-in slot.	See page 86
5AC803.BX02-00	PPC800 bus 2PCI 1SI PPC800 bus 2 PCI, 1 slide-in slot.	See page 86
5AC803.BX02-01	PPC800 bus 1PCI 1PCle.x1 1SI PPC800 bus 1 PCI, 1 PCI Express, 1 slide-in slot.	See page 86

Table 9: Model numbers - bus units

5.7 Option

Model number	Short description	Note
5AC803.BC01-00	PPC800 option PCI Express compact PPC800 option for expanding a PCle card in the system unit.	See page 88
5AC803.BC02-00	PPC800 option slide-in compact PPC800 option for expanding a slide-in compact drive in the system unit.	See page 88

Table 10: Model numbers - Option

5.8 Plug-in cards

Model number	Short description	Note
5ACPC.C.ETH0-00	PCle Ethernet card 10/100/1000 PCle Ethernet plug-in card, 1 Ethernet interface 10/100/1000	See page 90
5ACPC.C.MPL0-00	PCle POWERLINK MN 2-port PCle POWERLINK plug-in card, 2 POWERLINK interfaces	See page 92

Table 11: Model numbers - Drives

5.9 Drives

Model number	Short description	Note
5AC801.ADAS-00	APC810 slide-in compact adapter Adapter for operating compact slide-in drives in a slide-in slot drive slot.	See page 105
5AC801.HDDI-00	APC810 slide-in compact HDD 40GB 40 GB SATA hard disk (slide-in compact), 24/7 hard disk with extended temperature range.	See page 95
5AC801.HDDI-02	APC810 slide-in compact HDD 160GB 24x7 ET 160 GB SATA hard disk (slide-in compact), 24/7 hard disk with extended temperature range.	See page 98
5AC801.HDDS-00	APC810 slide-in HDD 40GB 40 GB SATA hard disk (slide-in), 24/7 hard disk with extended temperature range.	See page 106
5AC801.SSDI-00	APC810 slide-in compact HDD 32GB (SLC) 32 GB SSD drive (slide-in)	See page 101
5AC801.DVDS-00	APC810 slide-in DVD-ROM DVD-ROM drive (slide-in)	See page 109
5AC801.DVRS-00	APC810 slide-in DVD-R/RW DVD-R/RW, DVD+R/RW drive (slide-in)	See page 112
5ACPCI.RAIC-03	PCI SATA RAID System 2x160 GB PCI RAID controller + 2 x 160 GB SATA hard disks; requires a free PCI slot.	See page 116
5ACPCI.RAIC-04	Replacement SATA-HDD 160GB Hard disk 160 GB SATA, replacement part for 5ACPCI.RAIC-03	See page 121

Table 12: Model numbers - Drives

5.10 Fan kits

Model number	Short description	Note
5AC803.FA01-00	PPC800 fan kit 1CS APC800 fan kit for system units without an expansion.	See page 124
5AC803.FA02-00	PPC800 fan kit 2CS APC800 fan kit for system units with expansion 5AC803.SX01-00.	See page 125
5AC803.FA03-00	PPC800 fan kit 3CS APC800 fan kit for system units with expansion 5AC803.SX02-00.	See page 126

Table 13: Model numbers - Fan kits

5.11 Accessories

5.11.1 Batteries

Model number	Short description	Note
0AC201.91	Lithium batteries, 4 pcs. Lithium batteries, 4 pcs., 3 V / 950 mAh, button cell	See page 294
4A0006.00-000	Lithium battery, 1 pc. Lithium battery, 1 pc., 3 V / 950 mAh, button cell	See page 294

Table 14: Model numbers - Batteries

5.11.2 Supply voltage connectors

Model number	Short description	Note
0TB103.9	Plug 24V 5.08 3-pin screw clamps 24 VDC 3-pin connector, female. Screw clamp, 3.31 mm ² , protected against vibration by the screw flange.	See page 296
0TB103.91	Plug 24V 5.08 3-pin cage clamps 24 VDC 3-pin connector, female. Cage clamps, 3.31 mm ² , protected against vibration by the screw flange.	See page 296

Table 15: Model numbers - Supply voltage connectors

5.11.3 UPS module + accessories

Model number	Short description	Note
5AC600.UPSI-00	Add-on UPS module UPS module for APC620 / APC810 / PPC800 system units. Order cable (5CAUPS.0005-00 or 5CAUPS.0030-00) and battery unit (5AC600.UPSB-00) separately.	See page 300
5AC600.UPSB-00	Battery unit 5 Ah UPS battery unit for the add-on UPS module	See page 300
5CAUPS.0005-00	0.5 m APC620 UPS cable Connection cable between add-on UPS module and UPS battery unit, length 0.5 meters	See page 300
5CAUPS.0030-00	3 m APC620 UPS cable Connection cable between add-on UPS module and UPS battery unit, length 3 meters	See page 300

Table 16: Model numbers - UPS module + accessories

5.11.4 External UPS

Model number	Short description	Note
9A0100.11	UPS 24 VDC 24 VDC input, 24 VDC output, serial interface	See page 309
9A0100.14	UPS battery unit type B 24 V; 2.2 Ah; including battery cage	See page 309
9A0100.15	UPS battery unit type B (replacement part) 2 x 12 V; 2.2 Ah; for battery unit 9A0100.14	See page 309
9A0017.01	RS232 Null Modem Cable, 0.6 m To connect UPS and load system (9-pin DSUB socket - 9-pin DSUB socket)	See page 309
9A0017.02	RS232 Null Modem Cable, 1.8 m To connect UPS and load system (9-pin DSUB socket - 9-pin DSUB socket)	See page 309

Table 17: Model numbers - External UPS

5.11.5 CompactFlash cards

Model number	Short description	Note
5CFCRD.0512-04	CompactFlash 512 MB B&R CompactFlash card with 512 MB SLC NAND flash and IDE/ATA interface	See page 311
5CFCRD.1024-04	CompactFlash 1024 MB B&R CompactFlash card with 1024 MB SLC NAND flash and IDE/ATA interface	See page 311
5CFCRD.2048-04	CompactFlash 2048 MB B&R CompactFlash card with 2048 MB SLC NAND flash and IDE/ATA interface	See page 311
5CFCRD.4096-04	CompactFlash 4096 MB B&R CompactFlash card with 4096 MB SLC NAND flash and IDE/ATA interface	See page 311
5CFCRD.8192-04	CompactFlash 8192 MB B&R CompactFlash card with 8192 MB SLC NAND flash and IDE/ATA interface	See page 311
5CFCRD.016G-04	16 GB B&R CompactFlash card CompactFlash card with 16 GB SLC NAND flash and IDE/ATA interface	See page 311
5CFCRD.0064-03	CompactFlash 64 MB SSI CompactFlash card with 64 MB SLC NAND flash and IDE/ATA interface	See page 316
5CFCRD.0128-03	CompactFlash 128 MB SSI CompactFlash card with 128 MB SLC NAND flash and IDE/ATA interface	See page 316
5CFCRD.0256-03	CompactFlash 256 MB SSI CompactFlash card with 256 MB SLC NAND flash and IDE/ATA interface	See page 316
5CFCRD.0512-03	CompactFlash 512 MB SSI CompactFlash card with 512 MB SLC NAND flash and IDE/ATA interface	See page 316
5CFCRD.1024-03	CompactFlash 1024 MB SSI CompactFlash card with 1024 MB SLC NAND flash and IDE/ATA interface	See page 316
5CFCRD.2048-03	CompactFlash 2048 MB SSI CompactFlash card with 2048 MB SLC NAND flash and IDE/ATA interface	See page 316
5CFCRD.4096-03	CompactFlash 4096 MB SSI CompactFlash card with 4096 MB SLC NAND flash and IDE/ATA interface	See page 316
5CFCRD.8192-03	CompactFlash 8192 MB SSI CompactFlash card with 8192 MB SLC NAND flash and IDE/ATA interface	See page 316

Table 18: Model numbers - CompactFlash cards

5.11.6 USB flash drives

Model number	Short description	Note
5MMUSB.2048-00	USB flash drive 2 GB SanDisk USB 2.0 flash drive 2 GB	See page 320

Table 19: Model numbers - USB flash drives

5.11.7 Cables

Model number	Short description	Note
5CADVI.0018-00	DVI-D cable 1.8 m Single cable, DVI-D/m; DVI-D/m; length: 1.8 m	See page 327
5CADVI.0050-00	DVI-D cable 5 m Single cable, DVI-D/m; DVI-D/m; length: 5 m	See page 327
5CADVI.0100-00	DVI-D cable 10 m Single cable, DVI-D/m; DVI-D/m; length: 10 m	See page 327
5CASDL.0018-00	SDL cable 1.8 m SDL cable for a fixed type of layout; length: 1.8 m	See page 330
5CASDL.0018-01	SDL cable 1.8 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 1.8 m	See page 333
5CASDL.0018-03	SDL flex cable 1.8 m SDL cable for fixed and flexible type of layout; length: 1.8 m	See page 336
5CASDL.0050-00	SDL cable 5 m SDL cable for a fixed type of layout; length: 5 m	See page 330
5CASDL.0050-01	SDL cable 5 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 5 m	See page 333
5CASDL.0050-03	5 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 5 m	See page 336
5CASDL.0100-00	SDL cable 10 m SDL cable for a fixed type of layout; length: 10 m	See page 330
5CASDL.0100-01	SDL cable 10 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 10 m	See page 333
5CASDL.0100-03	10 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 10 m	See page 336
5CASDL.0150-00	SDL cable 15 m SDL cable for a fixed type of layout; length: 15 m	See page 330
5CASDL.0150-01	SDL cable 15 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 15 m	See page 333
5CASDL.0150-03	15 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 15 m	See page 336
5CASDL.0200-00	SDL cable 20 m SDL cable for a fixed type of layout; length: 20 m	See page 330
5CASDL.0200-03	20 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 20 m	See page 336
5CASDL.0250-00	SDL cable 25 m SDL cable for a fixed type of layout; length: 25 m	See page 330

Table 20: Model numbers - Cables

General information • Model numbers

Model number	Short description	Note
5CASDL.0250-03	25 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 25 m	See page 336
5CASDL.0300-00	SDL cable 30 m SDL cable for a fixed type of layout; length: 30 m	See page 330
5CASDL.0300-03	30 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 30 m	See page 336
5CASDL.0300-13	30 m SDL flex cable with extender SDL cable with extender for fixed and flexible type of layout; length: 30 m	See page 341
5CASDL.0400-13	40 m SDL flex cable with extender SDL cable with extender for fixed and flexible type of layout; length: 40 m	See page 341
5CAUSB.0018-00	USB 2.0 cable, A/m:B/m 1.8 m USB 2.0 connection cable; plug type A - type B; length 1.8 m	See page 348
5CAUSB.0050-00	USB 2.0 cable, A/m:B/m 5 m USB 2.0 connection cable; plug type A - type B; length 5 m	See page 348
9A0014.02	RS232 cable DB9/f:DB9/m 1.8 m RS232 extension cable for remote operation of a display unit with touch screen; length 1.8 m.	See page 346
9A0014.05	RS232 cable DB9/f:DB9/m 5 m RS232 extension cable for remote operation of a display unit with touch screen; length 5 m.	See page 346
9A0014.10	RS232 cable DB9/f:DB9/m 10 m RS232 extension cable for remote operation of a display unit with touch screen; length 10 m.	See page 346

Table 20: Model numbers - Cables (cont.)

5.11.8 Miscellaneous

Model number	Short description	Note
5AC900.1000-00	Adapter DVI-A/m to CRT DB15HD/f Adapter DVI (plug) to CRT (socket), for connecting a standard monitor to a DVI-I interface.	See page 298
5AC900.1200-01	USB port cap IP65 M20 /2 Front-side USB port cap (attached) knurled, short, not slotted.	See page 299
5AC900.1200-02	USB port cap IP65 M20 /3 Front-side USB port cap (attached) knurled, tall, not slotted.	See page 299
5AC900.1200-03	USB port cap IP65 M20 /4 Front-side USB port cap (attached) knurled, tall, slotted.	See page 299
1A4300.LZ1U	B&R Automation Studio 3.0 USB dongle Dongle for using AR010.	See page 323

Table 21: Model numbers - Other items

5.12 Software

Model number	Short description	Note
5SWHMI.0000-00	HMI Drivers & Utilities DVD Contains drivers, utilities, software upgrades and user's manuals for B&R panel system products (see B&R homepage – Industrial PCs, Visualization and Operation).	See page
9S0000.01-010	OEM MS-DOS 6.22 German (disk) OEM MS-DOS 6.22 German disks Only delivered with a new industrial PC.	See page 247
9S0000.01-020	OEM MS-DOS 6.22 English (disk) OEM MS-DOS 6.22 English disks Only delivered with a new industrial PC.	See page 247
5SWWXP.0600-GER	WinXP Professional with SP3, GER Microsoft OEM Windows XP Professional Service Pack 3, CD, German. Only available with a new device.	See page 249
5SWWXP.0600-ENG	WinXP Professional with SP3, ENG Microsoft OEM Windows XP Professional Service Pack 3, CD, English. Only available with a new device.	See page 249
5SWWXP.0600-MUL	WinXP Professional with SP3, MUL Microsoft OEM Windows XP Professional Service Pack 3, CD, multi-language. Only available with a new device.	See page 249
5SWWXP.0500-GER	WinXP Professional with SP 2c, GER Microsoft OEM Windows XP Professional Service Pack 2c, CD, German. Only available with a new device.	See page 249
5SWWXP.0500-ENG	WinXP Professional with SP 2c, ENG Microsoft OEM Windows XP Professional Service Pack 2c, CD, English. Only available with a new device.	See page 249
5SWWXP.0500-MUL	WinXP Professional with SP 2c, MUL Microsoft OEM Windows XP Professional Service Pack 2c, CD, multi-language. Only available with a new device.	See page 249
5SWWXP.0427-ENG	WinXPe FP2007 PPC800 945GME Order Microsoft OEM Windows XP embedded Feature Pack 2007, English; for PPC800 with CPU boards 5PC800.B945-00, 5PC800.B945-01, 5PC800.B945-02, 5PC800.B945-03, 5PC800.B945-04; 5PC800.B945-05; CompactFlash separately (at least 512 MB).	See page 250
5SWWXP.0727-ENG	Windows Embedded Standard 2009 PPC800 945GME Order Microsoft OEM Windows Embedded Standard 2009, English; for PPC800 with CPU boards 5PC800.B945-00, 5PC800.B945-01, 5PC800.B945-02, 5PC800.B945-03, 5PC800.B945-04, 5PC800.B945-05; CompactFlash separately (at least 1 GB).	See page 253

Table 22: Model numbers - Software

Chapter 2 • Technical data

1. Introduction

The Panel PC 800 covers a wide performance range from efficient Intel Atom N270 processors to Core2 Duo processors for applications with the highest performance requirements. Brilliant 15" XGA and 19" SXGA touch screen displays provide a simple and intuitive user interface. The flexibility was raised to a new level when designing the PPC800. Therefore, many options can be implemented on the cost-optimized basic device. This includes up to two PCI and PCI Express slots, modular drives, additional interfaces and an integrated UPS. The chipset, processor and other components are connected directly to the heat sink using heat conductive materials. This makes it possible to operate Atom processors without a fan, and also select dual core processors.



1.1 Features

- 15" and 19" diagonals
- Latest processor technologies - Core Duo, Core 2 Duo, Celeron M and Atom N270
- Up to 3 GB main memory (Dual Channel Memory Support)
- 2 CompactFlash slots (type I)
- Expandable expansion with 1 or 2 slots for PCI / PCI Express (PCIe) cards and a slide-in drive slot
- 1 optional PCIe (PCI express compact) card slot (can be expanded with option)
- 1 optional slide-in compact slot (can be expanded with option)
- 5x USB 2.0
- 2x Ethernet 10/100/1000 MBit interfaces
- 1x RS232 interface, modem compatible
- 24 VDC supply voltage
- BIOS (AMI)
- Real-time clock, RTC (battery-buffered)
- Easy slide-in drive exchange (SATA hot plug capable)
- HDA Sound
- Add-on UPS slot

1.2 System components / Configuration

The PPC800 system can be assembled to meet individual requirements and operating conditions.

The following components are absolutely essential for operation:

- System unit
- CPU board
- Heat sink (CPU board dependent)
- Main memory
- Drive (mass memory such as CompactFlash card or hard disk) for the operating system
- Software

1.2.1 Configuration - Basic system

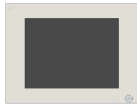
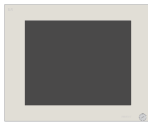
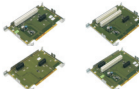
Configuration - Base system			
System unit	Select 1		
	 5PC820.1505-00	 5PC820.1906-00	
CPU board - Heat sink - Main memory			
CPU board	Select 1		
	5PC800.B945-00 / -10 5PC800.B945-01 / -11 5PC800.B945-02 / -12 5PC800.B945-03 / -13	5PC800.B945-04 / -14	5PC800.B945-05
Heat sink	Select 1		
	5AC803.HS00-00	5AC803.HS00-01	5AC803.HS00-02
Main memory	1 or 2 can be selected (max. 3 GB can be used)		
	5MMDR.0512-01 - 512 MB 5MMDR.1024-01 - 1 GB 5MMDR.2048-01 - 2 GB		

Figure 1: Configuration - Basic system

1.2.2 Configuration - Optional components

Configuration - Optional components			
Configuration of a system unit with option			
Option ¹⁾	Select 1 or both		
	5AC803.BC01-00 ↓	5AC803.BC02-00 ↓	
	PCle plug-in cards, select 1	Slide-in compact drives, select 1	
	5ACPCC.ETH0-00 (PCle Ethernet Card 10/100/1000) 5ACPCC.MPL0-00 (PCle POWERLINK MN 2-port)	5AC801.HDDI-00 (40 GB) 5AC801.HDDI-02 (160 GB) 5AC801.SSDI-00 (32 GB)	
Configuration of a system unit with expansion			
Expansion	No expansion	1 PCI/PCle slot + 1 slide-in slot	2 PCI/PCle slots + 1 slide-in slot
		5AC803.SX01-00	5AC803.SX02-00
Bus units		Select 1	Select 1
		5AC803.BX01-00 5AC803.BX01-01	5AC803.BX02-00 5AC803.BX02-01
Fan kit ²⁾	Select 1	Select 1	Select 1
	5AC803.FA01-00	5AC803.FA02-00	5AC803.FA03-00
Slide-in drives		Select 1	
		5AC801.HDDS-00 (40 GB) 5AC801.DVDS-00 (DVD drive) 5AC801.DVRS-00 (DVD burner) 5AC801.ADAS-00 (adapter)	
CompactFlash	Select 1 or 2		
	5CFCRD.0512-04, 5CFCRD.1024-04, 5CFCRD.2048-04, 5CFCRD.4096-04, 5CFCRD.8192-04, 5CFCRD.016G-04		5CFCRD.0064-03, 5CFCRD.0128-03, 5CFCRD.0256-03, 5CFCRD.0512-03, 5CFCRD.1024-03, 5CFCRD.2048-03, 5CFCRD.4096-03, 5CFCRD.8192-03
UPS battery	Select 1		
	5AC600.UPSI-00 (add-on UPS module), 5AC600.UPSB-00 (UPS battery unit) APC connection cable -> Battery: 5CAUPS.0005-00 (0.5 meter) or 5CAUPS.0030-00 (3 meters)		
Supply voltage connector	Select 1		
	0TB103.9 (screw clamp) 0TB103.91 (cage clamp)		

1) If both options are used, then a PCle plug-in card and a slide-in compact drive can also be operated in a device.

2) A fan kit may be necessary for certain system configurations.

Figure 2: Configuration - Optional components

2. Entire device

2.1 Temperature specifications

It is possible to combine CPU boards with various other components, such as drives, main memory, additional insert cards, etc. depending on system unit and fan kit. The various configurations result in varying maximum possible ambient temperatures, which can be seen in the following graphics.

Information:

The maximum specified ambient temperatures for operation with and without a fan kit were determined under worst-case conditions. Experience has shown that higher ambient temperatures can be reached under typical conditions, e.g. using Microsoft Windows. The testing and evaluation is to be done on-site by the user (temperatures can be read in BIOS or using the B&R Control Center).

Information on the worst-case conditions

- Thermal Analysis Tool (TAT V3.8) from Intel for simulating 100% processor load
- BurnIn testing tool (BurnIn V4.0 Pro from Passmark Software) to simulate a 100% load on the interface via loop-back adapters (serial interfaces, slide-in drives, USB interfaces, audio outputs)
- Maximum system extension and power consumption

What must be considered when determining the maximum ambient temperature?

- Operating the entire device with or without fan kit

2.1.1 Maximum ambient temperature

Information:

Only specified mounting orientations are permitted. See chapter 3 "Commissioning", section 1.2 "Mounting orientation", on page 129.

Ambient temperature for CPU boards 5PC800.B945-0x

		Operation without fan kit						Operation with fan kit						Temperature limits	Location of sensor(s)		
		ETH1: up to 1 GBit operation ETH2: up to 1 GBit operation						ETH1: up to 1 GBit operation ETH2: up to 1 GBit operation									
		L2400	L7400	U7500	CM 423	T7400	N270	L2400	L7400	U7500	CM 423	T7400	N270				
		5PC800.B945-00	5PC800.B945-01	5PC800.B945-02	5PC800.B945-03	5PC800.B945-04	5PC800.B945-05	5PC800.B945-00	5PC800.B945-01	5PC800.B945-02	5PC800.B945-03	5PC800.B945-04	5PC800.B945-05				
All temperature values in degrees celsius (°C) at 500 meters above sea level.																	
Derating of the maximum ambient temperature generally 1°C per 1000 meters starting at 500 meters above sea level.																	
Maximum ambient temperature		30	30	35	35	—	55	45	45	50	50	35	60	Temperature limits			
What can also be operated at the max. ambient temperature, or are there limits?																	
																	
Slide-in Compact	On-board CompactFlash ¹⁾	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	Board power		
	5AC801.HDDI-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80			
	5AC801.HDDI-02	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80			
	5AC801.SSDI-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	70			
Slide-in option	5AC801.HDDS-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	Slide-in drive		
	5AC801.DVDS-00	✓	✓	✓	✓		50	✓	✓	✓	✓	✓	50	50			
	5AC801.DVRS-00	✓	✓	✓	✓		50	✓	✓	✓	✓	✓	50	50			
Main memory	5MMDDR.0512-01	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-			
	5MMDDR.1024-01	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-			
	5MMDDR.2048-01	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-			
System units	5PC820.1505-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	Power Supply		
	5PC820.1906-00	✓	✓	✓	✓		45	✓	✓	✓	✓	✓	50	80			
Additional insert cards PCIe card slot	5ACPCCE.ETH0-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	Additional insert cards		
	5ACPCCE.MPL0-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-			
	5ACPCI.RAIC-03 (24 hours / default)	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-			
	5ACPCI.RAIC-04 (24 hours / default)	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-			
	5ACPCI.RAIC-04 (24 hours / default)	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-			

1) Only possible with a CompactFlash card (5CFCRD.xxxx-04 or 5CFCRD.xxxx-03) from B&R.

1) Only possible with a CompactFlash card (5CFCRD.xxxx-04 or 5CFCRD.xxxx-03) from B&R.

Figure 3: Ambient temperatures with and without fan kit - CPU boards 5PC800.B945-0x

Ambient temperature for CPU boards 5PC800.B945-1x and 5PC800.B945-05

		Operation without fan kit						Operation with fan kit							
		ETH1: up to 1 Gbit operation ETH2: up to 1 Gbit operation						ETH1: up to 1 Gbit operation ETH2: up to 1 Gbit operation							
		L3400	L7400	U7500	CM 423	T7400	N270	L3400	L7400	U7500	CM 423	T7400	N270		
		5PC800.B945-10	5PC800.B945-11	5PC800.B945-12	5PC800.B945-13	5PC800.B945-14	5PC800.B945-05	5PC800.B945-10	5PC800.B945-11	5PC800.B945-12	5PC800.B945-13	5PC800.B945-14	5PC800.B945-05		
All temperature values in degrees celsius (°C) at 500 meters above sea level.															
Derating of the maximum ambient temperature, generally 1°C per 1000 meters starting at 500 meters above sea level.															
Maxim um ambient temperature		35	35	45	45	/	55	45	45	55	55	45 ¹⁾	60	Temperature limits	Location of sensor(s)
What can also be operated at the max. ambient temperature, or are there limits?															
															
Slide-in Compact	On-board CompactFlash ²⁾	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	Board power
	5AC801.HDDI-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	
	5AC801.HDDI-02	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	
	5AC801.SSDI-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	70	
Slide-in option	5AC801.HDDS-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	Slide-in drive
	5AC801.DVDS-00	✓	✓	✓	✓		50	✓	✓	50	50	✓	50	50	
	5AC801.DVRS-00	✓	✓	✓	✓		50	✓	✓	50	50	✓	50	50	
Main memory	5MMDDR.0512-01	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	
	5MMDDR.1024-01	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	
	5MMDDR.2048-01	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	
System units	5PC820.1505-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	80	Power Supply
	5PC820.1906-00	30	30	35	35		45	✓	✓	50	50	35	50	80	
Additional insert cards PCIe card slot	5ACPCC.ETH0-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	Additional insert cards
	5ACPCC.MPL0-00	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	
	5ACPCL.RAIC-03 (24 hours / default)	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	
	5ACPCL.RAIC-04 (24 hours / default)	✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	
		✓	✓	✓	✓		✓	✓	✓	✓	✓	✓	✓	-	

1) The specified temperature is only valid for the CPU board 5PC800.B945-14 with the heat sink 5AC803.HS00-01 Rev > A5.
If a heat sink with an earlier revision is used, then the maximum ambient temperature of the CPU board 5PC800.B954-00 must be referred to.

2) Only possible with a CompactFlash card (5CFCRD.xxxx-04 or 5CFCRD.xxxx-03) from B&R.

Figure 4: Ambient temperatures with and without fan kit - CPU boards 5PC800.B945-1x and 5PC800.B945-05

2.1.2 Minimum ambient temperature

For systems containing one of the following components, the minimum ambient temperature is +5°C: 5AC801.DVDS-00, 5AC801.DVRS-00. If none of these components are used, then the minimum ambient temperature is 0°C.

2.1.3 How do you determine the maximum ambient temperature?

- 1) Selection of the CPU board (use with or without fan kit).
- 2) The "maximum ambient temperature" line shows the maximum ambient temperature for the entire system when using the respective CPU board.

Information:

Maximum temperature data is for operation at 500 meters. Derating the maximum ambient temperature - typically 1°C per 1000 meters (from 500 meters above sea level).

- 3) Incorporating additional drives (slide-in), main memory, additional insert cards, etc. can change the temperature limits of an PPC800 system.

If there is a ✓ (checkmark) next to the component, it can be used at the maximum ambient temperature of the whole system without problems.

If there is a specific temperature, for example "50", next to the component, then the ambient temperature of the whole PPC800 system cannot exceed this temperature.

2.1.4 Temperature monitoring

Sensors monitor temperature values in various places (board I/O, board ETH2, board power, power supply, slide-in drive 1, IF slot) in the PPC800. The position of the temperature sensors can be found in the figure "Temperature sensor locations", on page 353. The value listed in the table represents the defined maximum temperature for this measurement point¹⁾. An alarm is not triggered when this temperature is exceeded. The temperatures¹⁾ can be read in BIOS (menu item "Advanced" - Baseboard/panel features - Baseboard monitor) or in Microsoft Windows XP/Embedded and Windows Embedded Standard 9000 using the B&R Control Center. Additionally, the hard disks for PPC800 systems available from B&R are equipped with S.M.A.R.T, or Self Monitoring, Analysis, and Reporting Technology. This makes it possible to read various parameters, for example the temperature, using software (e.g. HDD thermometer - freeware) in Microsoft Windows XP/Embedded and Windows Embedded Standard 2009.

¹⁾ The measured temperature is a guideline for the immediate ambient temperature, but can be influenced by neighboring components.

2.2 Humidity specifications

The following table displays the minimum and maximum humidity for the individual components that are relevant for the humidity limitations of the entire device. The lowest and highest common values are always used when establishing these limits.

Component		Operation	Storage / Transport
CPU boards 945GME COM Express		10 - 90%	5 - 95%
Main memory for CPU boards		10 - 90%	5 - 95%
Slide-in compact drives Slide-in drives	5AC801.HDDI-00	5 - 90%	5 - 95%
	5AC801.HDDI-02	8 - 80%	5 - 95%
	5AC801.SSDI-00	5 - 95%	5 - 95%
	5AC801.HDDS-00	5 - 90%	5 - 90%
	5AC801.DVDS-00	8 - 90%	5 - 95%
	5AC801.DVRS-00	8 - 90%	5 - 95%
Additional insert cards	5ACPCI.RAIC-03 (24 hours/default)	8 - 90%	5 - 95%
	5ACPCI.RAIC-04 (24 hours/default)	8 - 90%	5 - 95%
Accessories	CompactFlash cards 5CFCRD.xxxx-04	85%	85%
	CompactFlash cards - 5CFCRD.xxxx-03	8 - 95%	8 - 95%
	Flash drive 5MMUSB.2048-00	10 - 90%	5 - 90%
	USB Media Drive 5MD900.USB2-01	20 - 80%	5 - 90%

Table 23: Overview of humidity specifications for individual components

The listed specifications correspond to the humidity at an ambient temperature of 30°C. More detailed information about the specific temperature-dependent humidity values can be found in the technical data for the individual components.

2.3 Power management

2.3.1 Block diagram - supply voltage

The following block diagram shows the simplified structure of the PPC800 supply voltage.

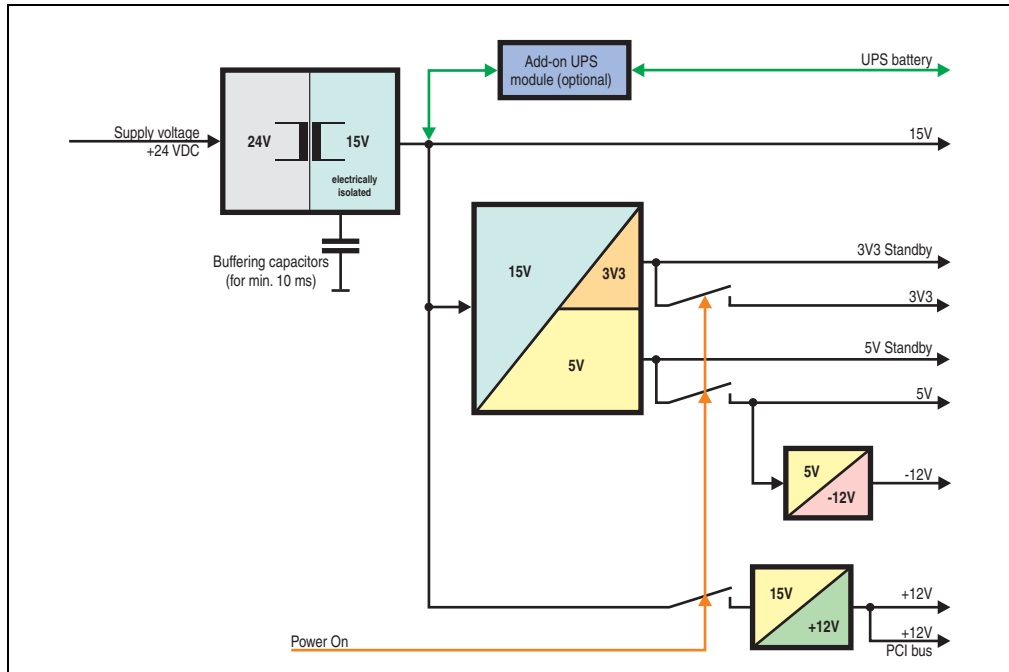


Figure 5: Block diagram - supply voltage

Description

The supply voltage is converted to 15 V with a DC/DC converter. These electrically isolated 15 V feed further DC/DC converters, which generate the remaining voltages.

After the system is turned on (e.g. using the power button), the voltages 3V3 and 5 V are placed on the bus. At the 5 V output, another DC/DC converter generates -12 V, and places these on the bus. An additional DC/DC converter generates +12 V.

The optional Add-on UPS (with battery unit) is supplied with 15 V and provides an uninterrupted power supply from the 15 V bus during power failures.

2.3.2 Power calculation with 5PC820.1505-00

Information:		CPU boards								This system	
		L2600	L7600	U7500	DM423	T7400	N270				Enter values in this column ↓
All values in watts The entries for the generator are maximum values. The entries for the device are determined maximum values, but not peak values.		5PC800.8945-00	5PC800.8945-10	5PC800.8945-11	5PC800.8945-12	5PC800.8945-13	5PC800.8945-14	5PC800.8945-15	5PC800.8945-16		
		7.5	7.5	7.5	7.5	7.5	7.5	7.5	7.5		
		14	14	14	14	14	14	14	14		
		Maximum possible at +12V								75	
Total power supply	+12V	CPU board, fixed device	26	30	18	14	43	11			
		512MB RAM max. 2 pcs., each 1.5 W									
		1024MB RAM max. 2 pcs., each 2.5 W									
		2048MB RAM max. 2 pcs., each 3 W									
		Fan kit, optional	2.4	2.4	2.4	2.4	2.4	2.4			
		Power required by PCIe card, optional (max. 4 W) ²⁾									
		Power required by PCI card, optional (max. 3 W without fan kit, max. 6 W with fan kit) ¹⁾									
		Power required by PCIe x1 card, optional (max. 3 W without fan kit, max. 20 W with fan kit) ¹⁾									
		Devices +12V ∑									
		Maximum possible at +5V									65
	+5V	System unit, fixed device	4	4	4	4	4	4			
		Hard disk (slide-in compact)	4	4	4	4	4	4			
		Slide-in drive (hard disk, DVD-ROM, etc.)	4	4	4	4	4	4			
		USB peripheral USB1 and USB3, each 2.5 W									
		USB peripheral USB2, USB4 and USB5, each 5 W									
		Power required by PCIe card, optional (max. 4 W) ²⁾									
		Power required by PCI card, optional (max. 3 W without fan kit, max. 20 W with fan kit) ¹⁾									
	-12V	Maximum possible at -12V									1.2
		Power required by PCI card, optional (max. 1.2 W with and without fan kit) ¹⁾									
		Devices -12V ∑									
	3V3	Devices 5V ∑									
		Maximum possible at 3V3									40
		System unit, fixed device	9	9	9	9	9	9			
		CompactFlash, each 1 W									
		Power required by PCIe card, optional (max. 4 W) ²⁾									
		Power required by PCI card, optional (max. 3 W without fan kit, max. 15 W with fan kit) ¹⁾									
		Power required by PCIe x1 card, optional (max. 3 W without fan kit, max. 10 W with fan kit) ¹⁾									
		Devices 3V3 ∑									
		Devices ∑									

1) The total performance of one PCI / PCIe card per PCI slot (= sum of power consumptions for each voltage area) may not exceed the limits stated for operation with or without a fan kit.

2) The total performance of one PCIe card per PCIe slot (= sum of power consumptions for each voltage area) may not exceed the limits stated for operation with or without a fan kit.

Figure 6: Power calculation for 5PC820.1505-00

Information:

The PCIe card must not consume more than a total of 4 W (12V/5V/3V3)!

2.3.3 Power calculation with 5PC820.1906-00

Information:		CPU boards							This system		
All values in watts		L3400	L7400	U7500	CM423	T7400	N270	Enter values in this column			
The entries for the generator are maximum values.		5PC800.B945-00	5PC800.B945-10	5PC800.B945-01	5PC800.B945-11	5PC800.B945-02	5PC800.B945-12	5PC800.B945-03	5PC800.B945-13		
The entries for the device are determined maximum values, but not peak values.		5PC800.B945-04	5PC800.B945-14	5PC800.B945-05	5PC800.B945-15	5PC800.B945-06	5PC800.B945-16	5PC800.B945-07	5PC800.B945-17		
Total power supply rating (maximum)										130	
Add-on UPS module, optional		7.5	7.5	7.5	7.5	7.5	7.5	7.5	7.5		
Backlight display 19"		32	32	32	32	32	32	32	32		
Maximum possible at +12V										75	
+12V	CPU board, fixed device	26	30	18	14	43	11				
	512MB RAM max. 2 pcs., each 1.5 W										
	1024MB RAM max. 2 pcs., each 2.5 W										
	2048MB RAM max. 2 pcs., each 3 W										
	Fan kit, optional	2.4	2.4	2.4	2.4	2.4	2.4				
	Power required by PCIe card, optional (max. 4 W) ²⁾										
	Power required by PCI card, optional (max. 3 W without fan kit, max. 6 W with fan kit) ¹⁾										
	Power required by PCIe x1 card, optional (max. 3 W without fan kit, max. 20 W with fan kit) ¹⁾										
	Devices +12V ∑										
	Maximum possible at +5V										65
+5V	System unit, fixed device	12	12	12	12	12	12				
	Hard disk (slide-in compact)	4	4	4	4	4	4				
	Slide-in drive (hard disk, DVD-ROM, etc.)	4	4	4	4	4	4				
	USB peripheral USB1 and USB3, each 2.5 W										
	USB peripheral USB2, USB4 and USB5, each 5 W										
	Power required by PCIe card, optional (max. 4 W) ²⁾										
	Power required by PCI card, optional (max. 3 W without fan kit, max. 20 W with fan kit) ¹⁾										
	Maximum possible at -12V										1.2
	-12V	Power required by PCI card, optional (max. 1.2 W with and without fan kit) ¹⁾									
	Devices -12V ∑										
Devices 5V ∑											
Maximum possible at 3V3										40	
3V3	System unit, fixed device	5	5	5	5	5	5				
	CompactFlash, each 1 W										
	Power required by PCIe card, optional (max. 4 W) ²⁾										
	Power required by PCI card, optional (max. 3 W without fan kit, max. 15 W with fan kit) ¹⁾										
	Power required by PCIe x1 card, optional (max. 3 W without fan kit, max. 10 W with fan kit) ¹⁾										
	Devices 3V3 ∑										
Devices ∑											

1) The total performance of one PCI / PCIe card per PCI slot (= sum of power consumptions for each voltage area) may not exceed the limits stated for operation with or without a fan kit.

2) The total performance of one PCIe card per PCIe slot (= sum of power consumptions for each voltage area) may not exceed the limits stated for operation with or without a fan kit.

Figure 7: Power calculation for 5PC820.1906-00

Information:

The PCIe card must not consume more than a total of 4 W (12V/5V/3V3)!

2.4 Block diagram

The following block diagram shows the simplified system unit structure with a 945GME CPU board.

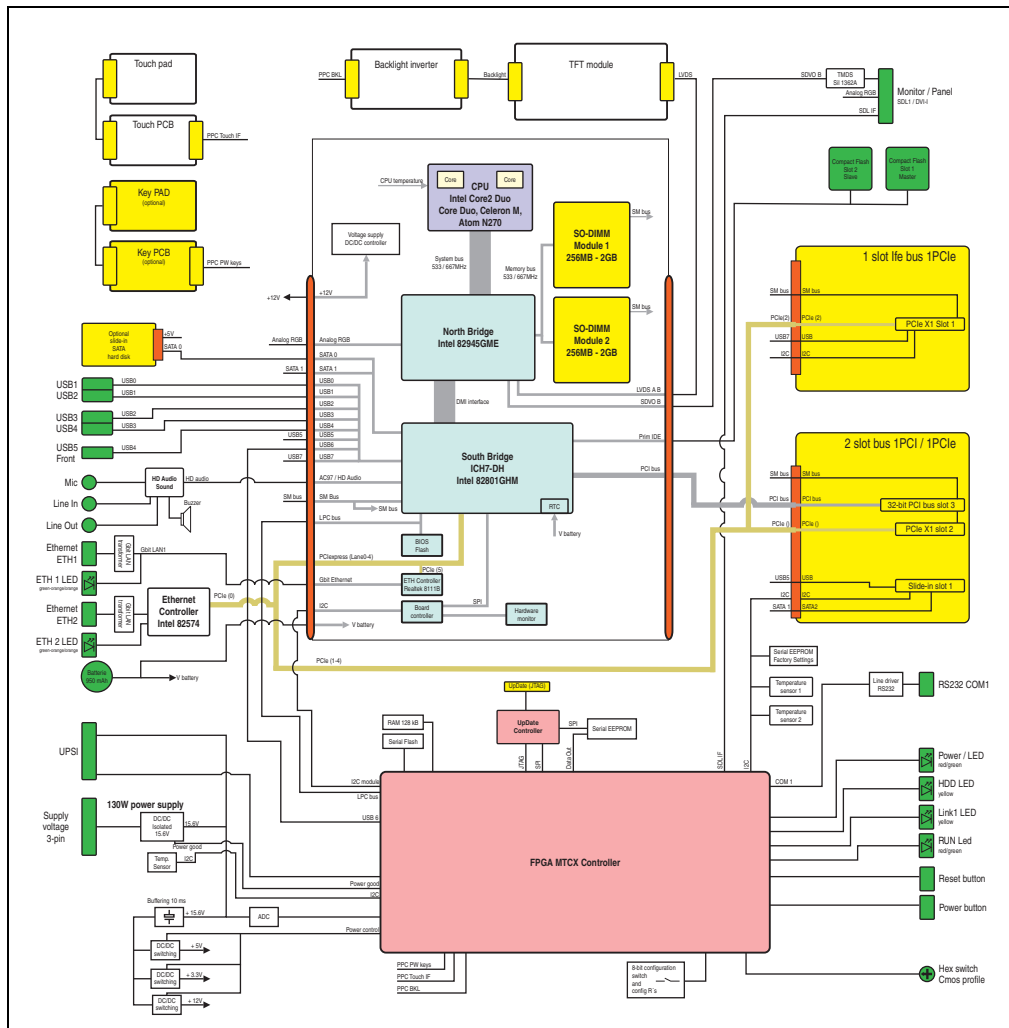


Figure 8: Block diagram

2.5 Serial number sticker

Each B&R device is assigned a unique serial number label with a bar code (type 128), which allows the device to be clearly identified. This serial number represents all of the components built into the system (model number, name, revision, serial number, delivery date and duration of warranty).



Figure 9: Serial number sticker (back)

This information can also be found on the B&R homepage. Enter the serial number of the entire device (found behind the front door) in the serial number search field on the start page www.br-automation.com. The search provides you with a detailed list of the individual components.

home | contact | language | login

Perfection in Automation
SERIAL NR. SEARCH

Company Industries **Products** Service Events News Career myPortal

Serial number: Model Number: SPC820.1505-00

Search

Enter serial number
e.g. AF210168454

Description:
Panel PC 820 15" XGA color TFT display
Panel PC 820 15" XGA color TFT display
with touch screen (resistive),
connections for 1x RS232, 5x USB 2.0,
Smart Display Link/DVI/Monitor, 2x
Ethernet 10/100/1000, HDA Sound, add-on
UPS slot, expandable with 1 or 2 PCI /
PCI express slots, optional PCI Express
compact and slide-in compact slot; IP65
protection (front side); 24 VDC. Plug
for power supply must be ordered
separately (screw clamp: OTB103.9); cage
clamp: OTB103.91).

GENERATE RECLAMATION...

Serial number	Model number	Rev	Delivery date	End of warranty
AF210168454	SPC820.1505-00	A2	0000-00-00	0000-00-00

This material is part of a configured material which was assembled as follows.

Serial number	Model number	Rev	Delivery date-0	End of warranty
B15B0168428	SPC820.1505-00	C0	0000-00-00	0000-00-00
AF210168475	SAC803.BC02-00	A5	0000-00-00	0000-00-00
AF210168456	SAC803.BC01-00	A5	0000-00-00	0000-00-00
AF210168454	SPC820.1505-00	A2	0000-00-00	0000-00-00
A3CA0168483	SPC800.B945-00	C0	0000-00-00	0000-00-00
A3E50168807	SMMDCR.0512-01	B0	0000-00-00	0000-00-00
AF270168430	SAC803.SX01-00	A0	0000-00-00	0000-00-00
AF250168515	SAC803.BX01-00	A5	0000-00-00	0000-00-00
AF300168465	SAC803.FA02-00	A0	0000-00-00	0000-00-00
AF230168467	SAC803.H500-00	A5	0000-00-00	0000-00-00

List of installed
components according
to serial number search

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Figure 10: Example of serial number search

2.6 Device interfaces

2.6.1 +24 VDC supply voltage

The 3-pin socket required for the supply voltage connection is not included in delivery. This can be ordered from B&R using the model number 0TB103.9 (screw clamp) or 0TB103.91 (cage clamp).

The pin assignments can be found either in the following table or printed on the PPC800 housing. The supply voltage is protected internally by a soldered fuse (15A, fast-acting), so that the device cannot be damaged if there is an overload (fuse replacement necessary) or if the voltage supply is connected incorrectly (reverse polarity protection - fuse replacement not necessary). The device must be returned to B&R for repairs if the fuse is blown because of an error.

Supply voltage	
Protected against reverse polarity	
Pin	Description
1	+
2	Functional ground
3	-
Accessories	
0TB103.9	Plug 24 V 5.08 3p screw clamps
0TB103.91	Plug 24 V 5.08 3p cage clamps

3-pin, male

Supply voltage + 24 VDC

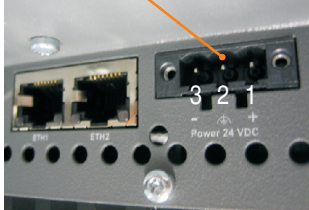


Table 24: Supply voltage connection + 24VDC

Ground

Caution!

The pin's connection to the functional ground (pin 2, e.g. switching cabinet) should be as short as possible. We recommend using the largest possible conductor cross section on the supply plug.

The grounding connection is located on the top right on the back of the PPC800 system.

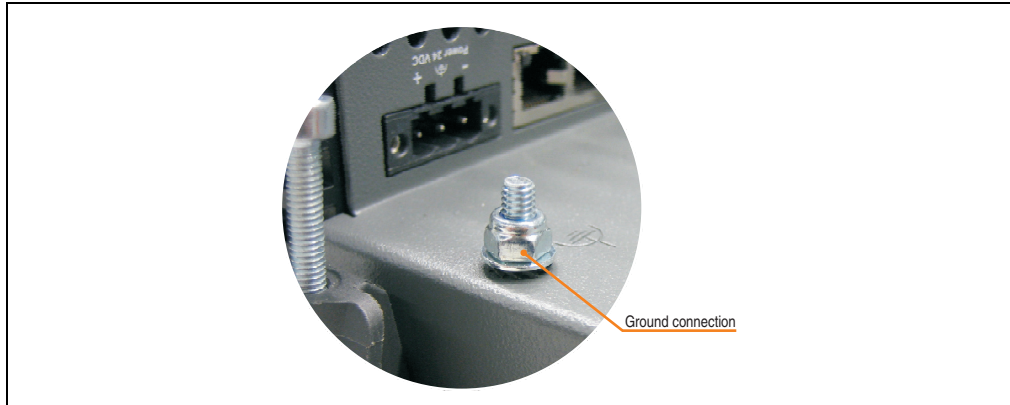


Figure 11: Ground connection

The M4 self-locking nut can be used, for example, to fasten a copper strip that is built into the PPC800 at a central grounding point in the switching cabinet or system. The largest possible conductor cross section should be used (at least 2.5 mm²).

2.6.2 Monitor / Panel connection - SDL (Smart Display Link / DVI)

Monitor / Panel connection - SDL (Smart Display Link / DVI)	
The following will provide an overview of the video signals available on the monitor/panel output. For details, see technical data for the CPU board being used.	
CPU board	Video signals with all system unit variations
5PC800.B945-00	RGB, DVI, SDL
5PC800.B945-01	RGB, DVI, SDL
5PC800.B945-02	RGB, DVI, SDL
5PC800.B945-03	RGB, DVI, SDL
5PC800.B945-04	RGB, DVI, SDL
5PC800.B945-05	RGB, DVI, SDL
5PC800.B945-10	RGB, DVI, SDL
5PC800.B945-11	RGB, DVI, SDL
5PC800.B945-12	RGB, DVI, SDL
5PC800.B945-13	RGB, DVI, SDL
5PC800.B945-14	RGB, DVI, SDL



Table 25: Monitor / Panel connection - RGB, DVI, SDL

2.6.3 Serial interface COM1

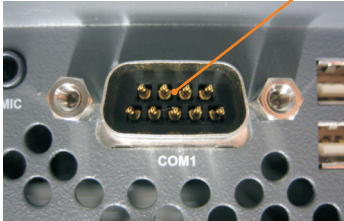
Serial interfaces COM1 ¹⁾		
Type	RS232, modem-capable, not electrically isolated	9-pin DSUB, male 
UART	16550-compatible, 16-byte FIFO	
Transfer rate	Max. 115 kBaud	
Cable length	Max. 15 meters	
Pin	Assignment	
1	DCD	
2	RXD	
3	TXD	
4	DTR	
5	GND	
6	DSR	
7	RTS	
8	CTS	
9	RI	

Table 26: Pin assignments - COM1

1) The interfaces, etc. available on the device or module were numbered accordingly for easy identification. This numbering can differ from the numbering used by the particular operating system.

2.6.4 Ethernet 1 (ETH1)

This Ethernet controller is integrated in the main board and is fed outwards via the system unit.

Ethernet 1 connection (ETH1 ¹⁾)		
Controller	Realtek RTL8111B/C ²⁾	
Cabling	S/STP (Cat5e)	
Transfer rate	10/100/1000 MBit/s ³⁾	
Cable length	max. 100 m (min. Cat5e)	
Speed LED	On	Off
Green	100 Mbit/s	10 Mbit/s ⁴⁾
Orange	1000 Mbit/s	-
Link LED	On	Off
Orange	Link (Ethernet network connection available)	Activity (blinking) (Data transfer in progress)

RJ45 twisted pair (10BaseT/100BaseT), female

Ethernet 1 (10/100/1000)
(ETH1)

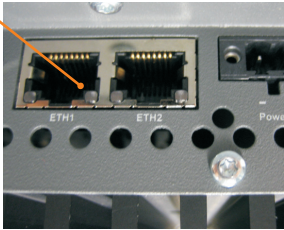


Table 27: Ethernet connection (ETH1)

- 1) The interfaces, etc. available on the device or module were numbered accordingly for easy identification. This numbering can differ from the numbering used by the particular operating system.
- 2) The Realtek RTL8111C is integrated in the CPU boards 5PC800.B945-05, 5PC800.B945-10, 5PC800.B945-11, 5PC800.B945-12, 5PC800.B945-13, 5PC800.B945-14.
- 3) Change-over takes place automatically.
- 4) The 10 MBit/s transfer speed / connection is only present if the Link LED is simultaneously active.

Driver support

A special driver is necessary for operating the Realtek Ethernet controllers RTL8111B/C. The necessary software can be downloaded from the download area on the B&R homepage (www.br-automation.com).

Information:

Required drivers can only be downloaded from the B&R homepage, not from manufacturers' pages.

2.6.5 Ethernet 2 (ETH2)

This Ethernet controller is integrated in the CPU board and is fed outwards via the system unit.

Ethernet 2 connection (ETH2 ¹⁾)		
Controller	Intel 82574	
Cabling	S/STP (Cat5e)	
Transfer rate	10/100/1000 MBit/s ²⁾	
Cable length	max. 100 m (min. Cat5e)	
Speed LED	On	Off
Green	100 Mbit/s	10 Mbit/s ³⁾
Orange	1000 Mbit/s	-
Link LED	On	Off
Orange	Link (Ethernet network connection available)	Activity (blinking) (Data transfer in progress)

RJ45 twisted pair (10BaseT/100BaseT), female

Ethernet 2 (10/100/1000)
(ETH2)

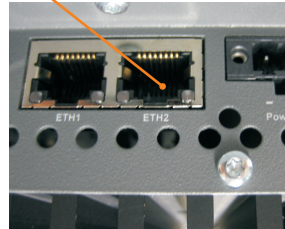


Table 28: Ethernet connection (ETH2)

1) The interfaces, etc. available on the device or module were numbered accordingly for easy identification. This numbering can differ from the numbering used by the particular operating system.

2) Change-over takes place automatically.

3) The 10 MBit/s transfer speed / connection is only present if the Link LED is simultaneously active.

Driver support

A special driver is necessary for operating the Intel Ethernet controller 82574. The necessary software can be downloaded from the download area on the B&R homepage (www.br-automation.com).

Information:

Required drivers can only be downloaded from the B&R homepage, not from manufacturers' pages.

2.6.6 USB interfaces (USB1, 2, 3, 4)

The PPC800 devices have a USB 2.0 (Universal Serial Bus) host controller with multiple USB ports, two of which are on the outside for easy access.

Warning!

Peripheral USB devices can be connected to the USB interfaces. Due to the vast number of USB devices available on the market, B&R cannot guarantee their performance. B&R does ensure the performance of all USB devices that they provide.

Caution!

Because of general PC specifications, this interface should be handled with extreme care with regard to EMC, location of cables, etc.

USB1,2,3,4

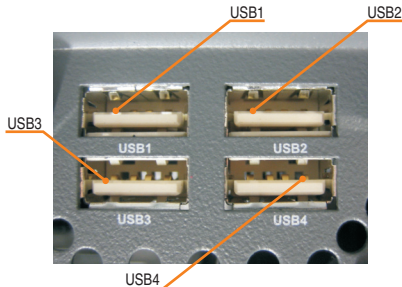
Universal Serial Bus (USB1, USB2, USB3, USB4) ¹⁾		
Transfer rate	Low speed (1.5 MBit/s), Full speed (12 MBit/s) up to High speed (480 MBit/s)	4 x USB type A, female 
Power supply ²⁾ USB1, USB3 USB2, USB4	Max. 500 mA Max. 1 A	
Maximum Cable length	5 m (without hub)	

Table 29: USB1, USB2, USB3, USB4 connection

1) The interfaces, etc. available on the device or module were numbered accordingly for easy identification. This numbering can differ from the numbering used by the particular operating system.

2) For safety, every USB port is equipped with a maintenance free "USB current-limiting circuit breaker" (max. 500 mA or 1 A).

USB5

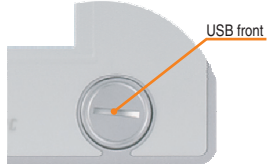
Universal Serial Bus (USB5) ¹⁾		
Transfer rate	Low speed (1.5 MBit/s), full speed (12 MBit/s), to high speed (480 MBit/s)	1 x USB type A, female 
Power supply ²⁾ USB5	Max. 1 A	
Maximum Cable length	5 m (without hub)	

Table 30: USB5 connection

1) The interfaces, etc. available on the device or module were numbered accordingly for easy identification. This numbering can differ from the numbering used by the particular operating system.

2) For safety, the USB port is equipped with a maintenance free "USB current-limiting circuit breaker" (max. 1 A)

2.6.7 MIC, Line IN, Line OUT

All PPC800 systems include an HDA compatible sound chip with access to the channels MIC, Line IN and Line OUT from the outside.

MIC, Line IN, Line OUT		
Controller	Realtek ALC 662	3.5 mm jack, female 
MIC	Connection of a mono microphone with a 3.5 mm stereo (headphone) jack.	
Line IN	Stereo Line IN signal supplied via 3.5 mm jack.	
Line OUT	Connection of a stereo sound device (e.g. amplifier) via a 3.5 mm jack.	

Table 31: MIC, Line IN, Line OUT

Driver support

A special driver is necessary for operating the audio controller. The necessary software can be downloaded from the download area on the B&R homepage (www.br-automation.com).

Information:

Required drivers can only be downloaded from the B&R homepage, not from manufacturers' pages.

2.6.8 Add-on UPS slot

An optional Automation PC add-on UPS module can be installed here.

Add-on UPS slot	
Add-on UPS + accessories	
5AC600.UPSI-00	Add-on UPS module
5AC600.UPSB-00	Battery unit 5 Ah
5CAUPS.0005-00	UPS cable 0.5 m
5CAUPS.0030-00	UPS cable 3 m
Pin assignments with mounted add-on UPS module	
1	+
2	+
3	-
4	-
5	NTC (for battery temperature measurement)
6	NTC (for battery temperature measurement)

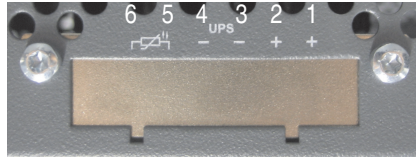


Table 32: Add-on UPS slot (with and without mounted UPS)

For more on the UPS module, see chapter 6 "Accessories", section 6 "Uninterruptible power supply", on page 300.

2.6.9 Status LEDs

The status LEDs are on the back of the system unit.

Status LEDs			
LED	Color		Meaning
Power	Green	On	Supply voltage OK
	Red	On	The system is in standby mode (S5: soft-off mode or S4: Hibernate mode -Suspend-to-Disk)
	Orange ¹⁾	On	Supply voltage not OK; the system is operating on battery power.
	red / green	Blinking	MTCX upgrade service function: A red/green blinking power LED indicates a faulty or incomplete MTCX upgrade. The MTCX runs using the firmware version installed when delivered. This could be caused by a power failure during an MTCX upgrade. An MTCX upgrade must be performed again.
HDD	Yellow	On	Signals IDE drive access (CF, HDD, CD, etc.)
Link	Yellow	On	Indicates an active SDL connection on the monitor / panel plug.
		Blinking	An active SDL connection has been interrupted by a loss of power in the display unit.
Run	Green	On	Application running
		Off	Application is not running

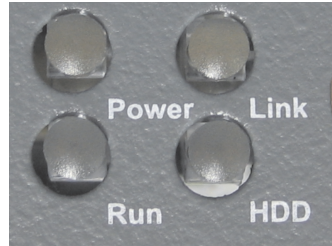


Table 33: Data - status LEDs

1) Only lit when add-on UPS module is installed.

2.6.10 CMOS profile switch

CMOS profile switch	
Different BIOS default value profiles can be defined using the 16-position CMOS profile switch.	
Switch position	Description
0	Profile 0: Default profile reserved.
1	Profile 1: Optimized for system units 5PC810.SX01-00 and 5PC810.SX02-00
2	Profile 2: Optimized for 5PC810.SX05-00 system unit
3	Profile 3: Optimized for the 5PC820.SX01-00 system unit
4	Profile 4: Reserved
5	Profile 5: Optimized for system units 5PC820.1505-00 and 5PC820.1906-00



Table 34: CMOS profile switch

Information:

The switch position that is set upon delivery represents the optimum BIOS default values for this system and should therefore not be changed.

The position of the CMOS profile switch is displayed in the BIOS setup pages and in the B&R ADI Control Center, among other places.

2.6.11 Power button

The power button has a variety of functions due to full ATX power supply support.

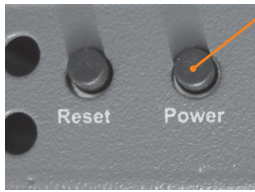
Power button	
The power button acts like the on/off switch on a normal desktop PC with ATX power supply: Press and release ... Switches on PPC800 or shuts down operating system and switches off the PPC800. Press and hold ... ATX power supply switches off without shutting down the PPC800 (data could be lost!). Pressing the power button does not reset the MTCX processor.	

Table 35: Power button

2.6.12 Reset button

Reset button	
Pushing the reset button results in a hardware-reset, PCI-reset. The PPC800 is restarted (cold restart). The MTCX processor is not reset when the reset button is pressed.	

Table 36: Reset button

Warning!

A system reset can cause data to be lost!

2.6.13 Battery

The lithium battery (3 V, 950 mAh) buffers the internal real-time clock (RTC) as well as the individually saved BIOS settings and is located behind the black cover. The buffer duration of the battery is at least 2½ years (at 50°C, 8.5 µA current requirements of the supplied components and a self discharge of 40%). The battery is subject to wear and should be replaced regularly (at least following the specified lifespan).

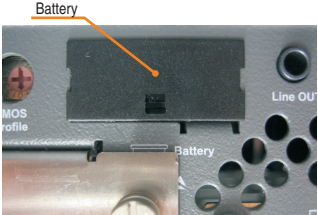
Battery		
Battery Type Removable Lifespan	Renata 950 mAh Yes, accessible from the outside 2½ years ¹⁾	
Accessories	Short description	
0AC201.91	Lithium batteries, 4 pcs. Lithium batteries, 4 pcs., 3 V / 950 mAh, button cell	
4A0006.00-000	Lithium battery, 1 pc. Lithium batteries, 1 pcs., 3 V / 950 mAh, button cell	

Table 37: Battery

1) At 50°C, 8.5 µA of the supplied components and a self discharge of 40%.

Battery status evaluation

The battery status is evaluated immediately following start-up of the device and is subsequently checked by the system every 24 hours. The battery is subjected to a brief load (1 second) during the measurement and then evaluated. The evaluated battery status is displayed in the BIOS Setup pages (under Advanced - Main board monitor) and in the B&R Control Center (ADI driver), but can also be read in a customer application via the ADI Library.

Battery status	Meaning
N/A	Hardware, i.e. firmware used is too old and does not support read.
Good	Data buffering is guaranteed
Bad	Data buffering is guaranteed for approx. another 500 hours from the point in time that the battery capacity is determined to be BAD (insufficient).

Table 38: Meaning of battery status

2.6.14 CompactFlash slot 1

This CompactFlash slot is a fixed part of an PPC800 system and is internally connected with the chipset via IDE PATA. Type I CompactFlash cards are supported.

CompactFlash slot (CF1)		
Connection	PATA Master	
CompactFlash Type	Type I	
Accessories	Short description	
5CFCRD.0512-04	512 MB B&R CompactFlash card	
5CFCRD.1024-04	1024 MB B&R CompactFlash card	
5CFCRD.2048-04	2048 MB B&R CompactFlash card	
5CFCRD.4096-04	4096 MB B&R CompactFlash card	
5CFCRD.8192-04	8192 MB B&R CompactFlash card	
5CFCRD.016G-04	16 GB B&R CompactFlash card	
5CFCRD.0064-03	CompactFlash 64 MB SSI	
5CFCRD.0128-03	CompactFlash 128 MB SSI	
5CFCRD.0256-03	CompactFlash 256 MB SSI	
5CFCRD.0512-03	CompactFlash 512 MB SSI	
5CFCRD.1024-03	CompactFlash 1024 MB SSI	
5CFCRD.2048-03	CompactFlash 2048 MB SSI	
5CFCRD.4096-03	CompactFlash 4096 MB SSI	
5CFCRD.8192-03	CompactFlash 8192 MB SSI	

Table 39: CompactFlash slot (CF1)

Warning!

Turn off power before inserting or removing the CompactFlash card!

2.6.15 CompactFlash slot 2

This CompactFlash slot is a fixed part of an PPC800 system and is internally connected with the chipset via IDE PATA. Type I CompactFlash cards are supported.

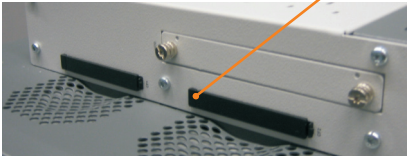
CompactFlash slot (CF2)		
Connection	PATA Slave	
CompactFlash Type	Type I	
Accessories	Short description	
5CFCRD.0512-04	512 MB B&R CompactFlash card	
5CFCRD.1024-04	1024 MB B&R CompactFlash card	
5CFCRD.2048-04	2048 MB B&R CompactFlash card	
5CFCRD.4096-04	4096 MB B&R CompactFlash card	
5CFCRD.8192-04	8192 MB B&R CompactFlash card	
5CFCRD.016G-04	16 GB B&R CompactFlash card	
5CFCRD.0064-03	CompactFlash 64 MB SSI	
5CFCRD.0128-03	CompactFlash 128 MB SSI	
5CFCRD.0256-03	CompactFlash 256 MB SSI	
5CFCRD.0512-03	CompactFlash 512 MB SSI	
5CFCRD.1024-03	CompactFlash 1024 MB SSI	
5CFCRD.2048-03	CompactFlash 2048 MB SSI	
5CFCRD.4096-03	CompactFlash 4096 MB SSI	
5CFCRD.8192-03	CompactFlash 8192 MB SSI	

Table 40: CompactFlash slot (CF2)

Warning!

Turn off power before inserting or removing the CompactFlash card!

2.6.16 Slide-in compact slot

The slide-in compact slot is internally connected with the chipset via SATA I.

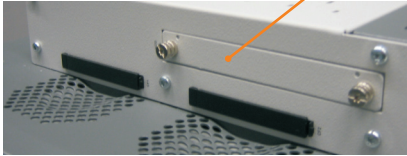
Slide-in compact slot		
Connection	SATA I	
Accessories	Short description	
5AC803.BC02-00	PPC800 option slide-in compact	
5AC801.HDDI-00	APC810 and PPC800 slide-in compact HDD 40GB EE25	
5AC801.HDDI-02	APC810 and PPC800 slide-in compact HDD 160GB EE25	
5AC801.SSDI-00	APC810 and PPC800 slide-in compact SSD 32GB (SLC)	

Table 41: Slide-in compact slot

Information:

The option 5AC803.BC02-00 is required for the use of slide-in compact drives.

Information:

The SATA I interface allows data carriers to be exchanged during operation (hot-plug). To utilize this capability, it must be supported by the operating system.

2.6.17 PClec slot (card slot)

Slide-in compact slot		
Accessories	Short description	
5AC803.BC01-00	PPC800 option PCI Express compact	
5ACPCC.ETH0-00	PClec Ethernet card 10/100/1000 PClec Ethernet plug-in card, 1 Ethernet interface 10/100/1000	
5ACPCC.MPL0-00	PClec POWERLINK MN 2-port PClec POWERLINK plug-in card, 2 POWERLINK interfaces	

Table 42: Slide-in compact slot

Information:

The option 5AC803.BC01-00 is required for the use of PClec plug-in cards.

Information:

Only B&R PClec cards that were specially designed for the Automation PC 820 and Panel PC 800 can be used.

More information can be found in section 3.8 "Plug-in cards", on page 89.

3. Individual components

3.1 System units

3.1.1 Panel PC 5PC820.1505-00

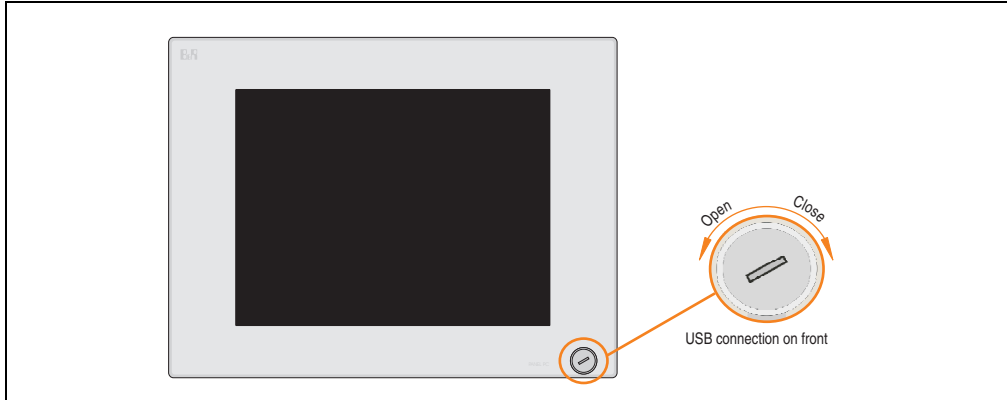


Figure 12: Front view - 5PC820.1505-00

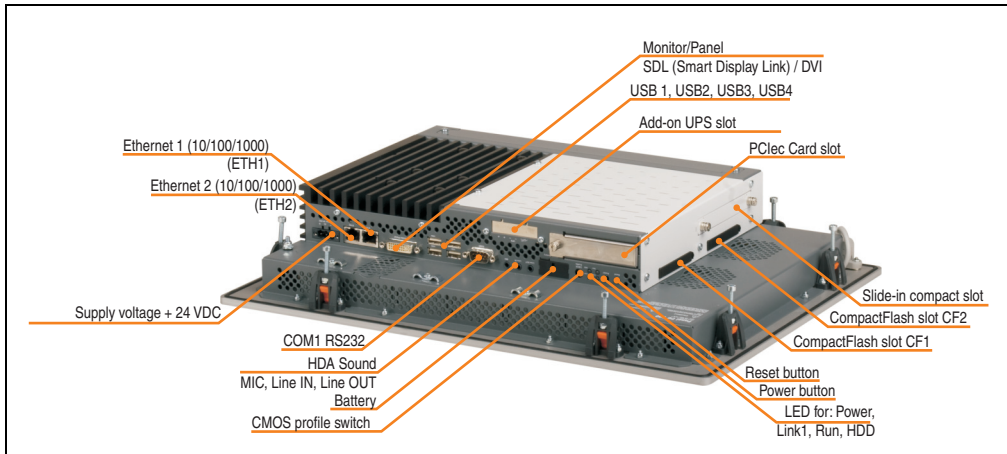


Figure 13: Rear view 5PC820.1505-00

Warning!

Do not remove the mounting screws from the heat sink, as it is connected to the processor and chipset by a thermal coupling. If this connection is broken, the PPC800 must be sent for repair. Removal of the mounting screws, which can be determined by a broken seal, voids all warranty.

During operation, surface temperatures of the heat sink may reach 70°C (warning "hot surface").

Technical data

General information	5PC820.1505-00
B&R ID code	\$AF21
Reset button	Yes
Power button	Yes
Buzzer	Yes
LED Amount	4 directed outwards via fiber optic lines
Controller	
Bootloader	BIOS
Processor Cooling Method	Component-dependent, see technical data for the 3.2 "CPU boards 945GME", on page 78 Passive via heat sink and supported with an active fan kit
Main memory	Max. 3 GB
Graphics Controller	Component-dependent, see technical data for the 3.2 "CPU boards 945GME", on page 78
Power failure logic Controller Buffer time	MTCX ¹⁾ 10 ms
Battery Type Removable Lifespan	Renata 950 mA Yes, accessible from the outside 2½ years
Interfaces	
Serial interfaces Type Amount UART Transfer rate Connection	RS232, modem-capable, not electrically isolated 1 16550-compatible, 16-byte FIFO Max. 115 kBaud 9-pin D-SUB

Table 43: Technical data - 5PC820.1505-00

Technical data • Individual components

Interfaces	5PC820.1505-00
Ethernet Amount Transfer rate Connection Controller	2 10/100/1000 MBit/s RJ45 twisted pair (10 Base T / 100 Base T) See page 52 and page 53
USB interfaces Type Amount Transfer rate Connection Current load	USB 2.0 5 Low speed (1.5 MBit/s), full speed (12 MBit/s), to high speed (480 MBit/s) Type A Max. 500 mA or 1 A per connection
Sound Inputs Outputs	HDA Sound Microphone, Line in Line out
CompactFlash slot Type Amount	Type I 2
Inserts	
PCI slots Amount	1 or 2 optional
PCIe slots Amount	1 or 2 optional
PCIec slots Amount	1, optional with 5AC803.BC01-00
Insert for slide-in compact drive Amount	1, optional with 5AC803.BC02-00
Insert for slide-in drive 1 Amount	Component-dependent (on the expansion and bus unit being used)
Fan insert for fan kit	Yes
Add-on UPS slot	Yes
Display	
Touch screen ²⁾ Touch screen type Technology Controller Degree of transmission	Accu Touch Analog, resistive Elo, serial, 12-bit 81±3%
Display Type Diagonal Colors Resolution Contrast Viewing angle (see page 361) Horizontal Vertical Background lighting Brightness Half-brightness time ³⁾	Color TFT 38.10 cm (381 mm) 16 million XGA, 1024 x 768 pixels 550, 1 Direction R = 60° / direction L = 60° Direction U = 45° / direction D = 55° 250 cd/m² 50,000 hours

Table 43: Technical data - 5PC820.1505-00 (cont.)

Display	5PC820.1505-00
Keys Function keys Soft keys Cursor keys Number block Other keys Key lifespan LED brightness	-
Electrical characteristics	
Power supply Rated voltage Rated current Starting current Power consumption Electrical isolation	24 VDC $\pm 25\%$ 6 A Typ. 10 A, max. 50 A for $<300\mu\text{s}$ Component-dependent, see "Power calculation with 5PC820.1505-00", on page 43 Yes
Mechanical characteristics	
Front Frame Design Membrane Light background Gasket	Naturally anodized aluminum Gray Polyester Similar to Pantone 427CV Flat gasket around display front
Housing	Metal
Outer dimensions Width Height Depth	See also "Dimensions", on page 70 435 mm 330 mm Component-dependent
Weight	Approx. 5.5 kg (component-dependent)
Environmental characteristics	
Ambient temperature Operation Storage Transport	See 2.1.1 "Maximum ambient temperature", on page 38 -20 to $+60^{\circ}\text{C}$ -20 to $+60^{\circ}\text{C}$
Relative humidity Operation Storage Transport	10 to 85%, non-condensing $\leq 40^{\circ}\text{C}$: 5 to 90% and $> 40^{\circ}\text{C}$: $< 90\%$, non-condensing $\leq 40^{\circ}\text{C}$: 5 to 90% and $> 40^{\circ}\text{C}$: $< 90\%$, non-condensing
Vibration Operation (continuous) Operation (occasional) Storage Transport	2 - 9 Hz: 1.75 mm, 9 - 150 Hz: 0.5 g 2 - 9 Hz: 3.5 mm, 9 - 150 Hz: 1 g 2 - 8 Hz: 7.5 mm, 8 - 200 Hz: 2 g, 200 - 500 Hz: 4 g 2 - 8 Hz: 7.5 mm, 8 - 200 Hz: 2 g, 200 - 500 Hz: 4 g
Shock Operation Storage Transport	15 g, 11 ms 30 g, 15 ms 30 g, 15 ms
Protection type	IP20 back side IP65 / NEMA 250 type 4X, dust and sprayed water protection (front side)
Altitude	-300 to 3000 m above sea level
Drop height	1 m

Table 43: Technical data - 5PC820.1505-00 (cont.)

- 1) Maintenance controller extended.
- 2) Touch screen drivers can be downloaded from the download area on the B&R homepage (www.br-automation.com).
- 3) At 25°C ambient temperature. Reducing the brightness by 50% can result in an approximate 50% increase of the half-brightness time.

Dimensions

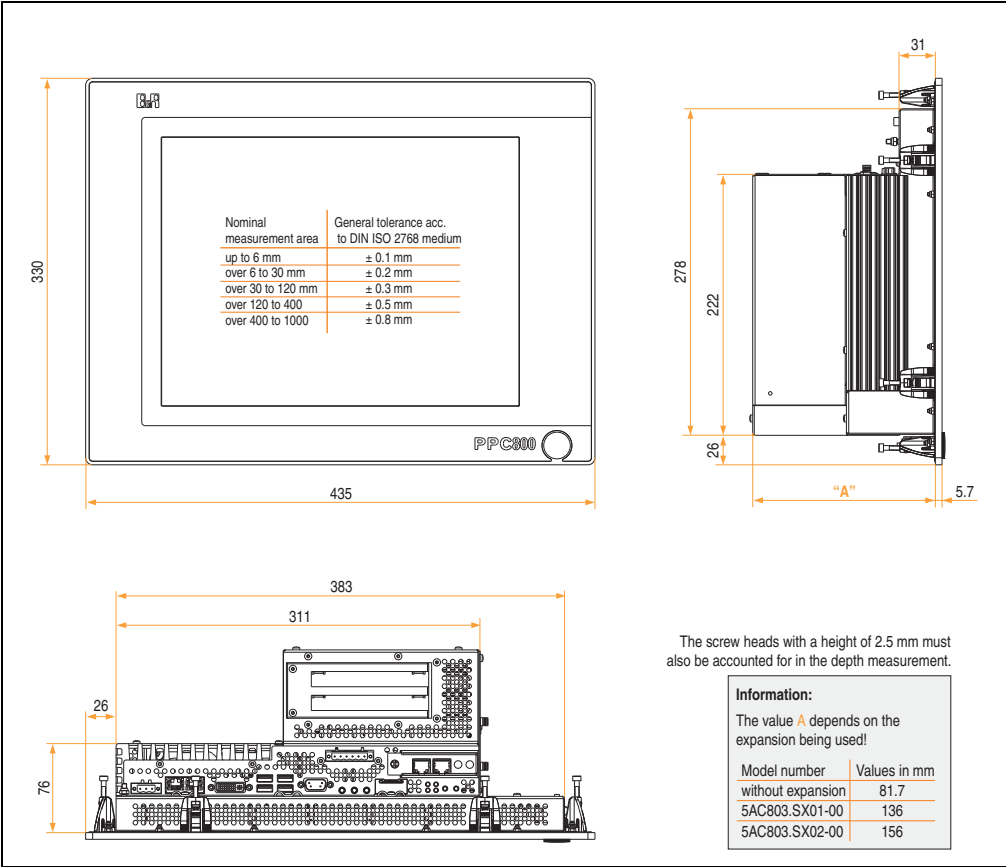


Figure 14: Dimensions - 5PC820.1505-00

Cutout installation

The Panel PC 800 with preassembled mounting blocks is installed e.g. in a housing cutout. A cutout that corresponds to the following drawing must be made.

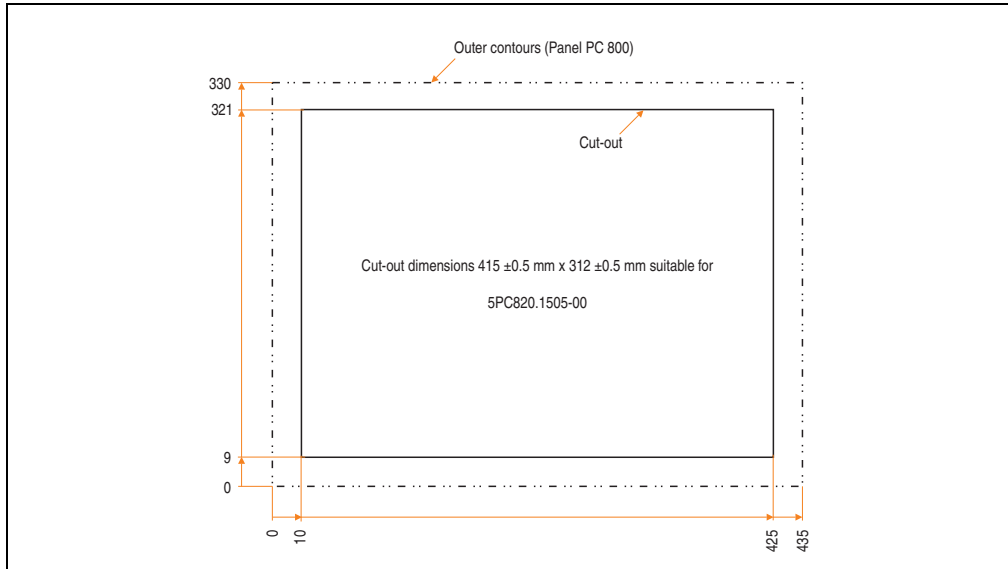


Figure 15: Cutout installation - 5PC820.1505-00

3.1.2 Panel PC 5PC820.1906-00

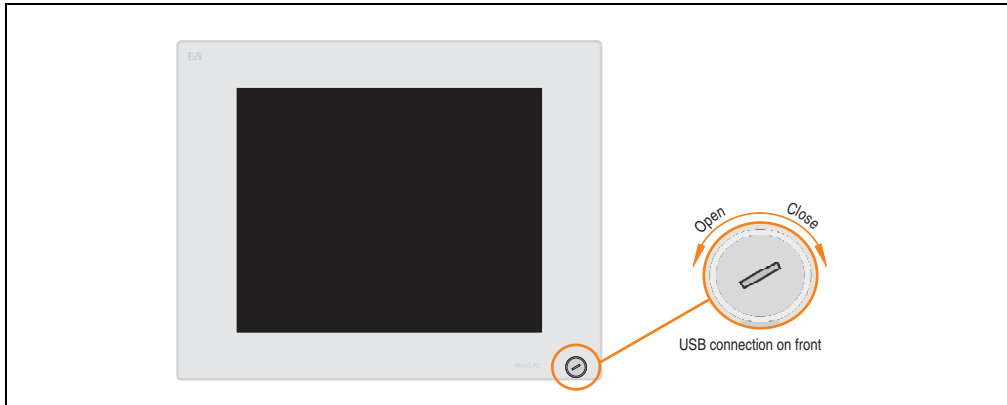


Figure 16: Front view - 5PC820.1906-00

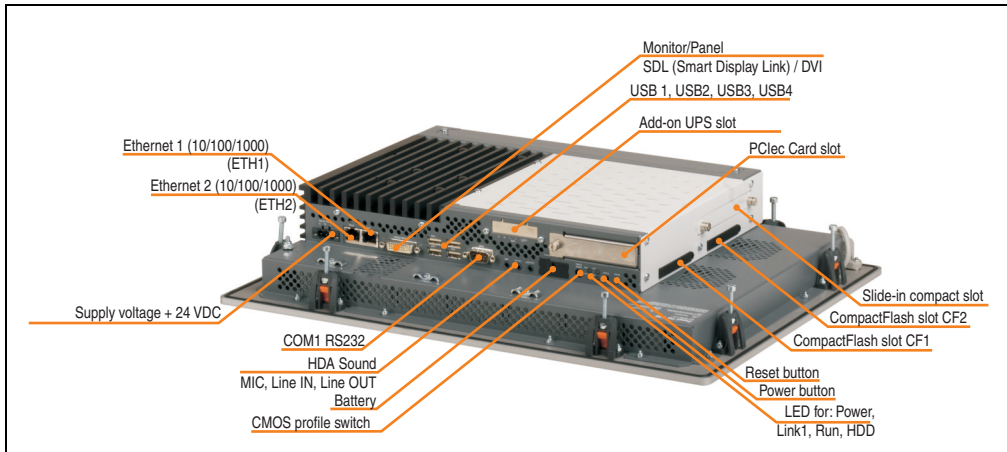


Figure 17: Rear view - 5PC820.1906-00

Warning!

Do not remove the mounting screws from the heat sink, as it is connected to the processor and chipset by a thermal coupling. If this connection is broken, the PPC800 must be sent for repair. Removal of the mounting screws, which can be determined by a broken seal, voids all warranty.

During operation, surface temperatures of the heat sink may reach 70°C (warning "hot surface").

Technical data

General information	5PC820.1906-00
B&R ID code	\$AF22
Reset button	Yes
Power button	Yes
Buzzer	Yes
LED Amount	4 directed outwards via fiber optic lines
Controller	
Bootloader	BIOS
Processor	Component-dependent, see technical data for the 3.2 "CPU boards 945GME", on page 78
Cooling Method	Passive via heat sink and supported with an active fan kit
Main memory	Max. 3 GB
Graphics Controller	Component-dependent, see technical data for the 3.2 "CPU boards 945GME", on page 78
Power failure logic Controller Buffer time	MTCX ¹⁾ 10 ms
Battery Type Removable Lifespan	Renata 950 mA Yes, accessible from the outside 2½ years
Interfaces	
Serial interfaces Type Amount UART Transfer rate Connection	RS232, modem-capable, not electrically isolated 1 16550-compatible, 16-byte FIFO Max. 115 kBaud 9-pin D-SUB
Ethernet Amount Transfer rate Connection Controller	2 10/100/1000 MBit/s RJ45 twisted pair (10 Base T / 100 Base T) See page 52 and page 53
USB interfaces Type Amount Transfer rate Connection Current load	USB 2.0 5 Low speed (1.5 MBit/s), full speed (12 MBit/s), to high speed (480 MBit/s) Type A Max. 500 mA or 1 A per connection
Sound Inputs Outputs	HDA Sound Microphone, Line in Line out
CompactFlash slot Type Amount	Type I 2

Table 44: Technical data - 5PC820.1906-00

Technical data • Individual components

Inserts	5PC820.1906-00
PCI slots Amount	1 or 2 optional
PCIe slots Amount	1 or 2 optional
PCIec slots Amount	1, optional with 5AC803.BC01-00
Insert for slide-in compact drive Amount	1, optional with 5AC803.BC02-00
Insert for slide-in drive 1 Amount	Component-dependent (on the expansion and bus unit being used)
Fan insert for fan kit	Yes
Add-on UPS slot	Yes
Display	
Touch screen ²⁾ Touch screen type Technology Controller Degree of transmission	Accu Touch Analog, resistive Elo, serial, 12-bit 81% ±3
Display Type Diagonal Colors Resolution Contrast Viewing angle (see page 361) Horizontal Vertical Background lighting Brightness Half-brightness time ³⁾	Color TFT 19 inch (480 mm) 16,777,216 colors SXGA, 1280 x 1024 pixels 900, 1 Direction R / direction L = 85° Direction U / direction D = 85° 300 cd/m² 50,000 hours
Keys Function keys Soft keys Cursor keys Number block Other keys Key lifespan LED brightness	-
Electrical characteristics	
Power supply Rated voltage Rated current Starting current Power consumption Electrical isolation	24 VDC ±25% 6 A Typ. 10 A, max. 50 A for <300µs Component-dependent, see "Power calculation with 5PC820.1906-00", on page 44 Yes

Table 44: Technical data - 5PC820.1906-00 (cont.)

Mechanical characteristics	5PC820.1906-00
Front Frame Design Membrane Light background Gasket	Naturally anodized aluminum Gray Polyester Similar to Pantone 427CV Flat gasket around display front
Housing	Metal
Outer dimensions Width Height Depth	See also "Dimensions", on page 76 527 mm 421 mm Component-dependent
Weight	Approx. 10 kg (component-dependent)
Environmental characteristics	
Ambient temperature Operation Storage Transport	See 2.1.1 "Maximum ambient temperature", on page 38 -20 to +60°C -20 to +60°C
Relative humidity Operation Storage Transport	≤ 50°C: 10 to 85% and > 50°C: max. 80%, non-condensing ≤ 40°C: 5 to 90% and > 40°C: < 90%, non-condensing ≤ 40°C: 5 to 90% and > 40°C: < 90%, non-condensing
Vibration Operation (continuous) Operation (occasional) Storage Transport	2 - 9 Hz: 1.75 mm, 9 - 150 Hz: 0.5 g 2 - 9 Hz: 3.5 mm, 9 - 150 Hz: 1 g 2 - 8 Hz: 7.5 mm, 8 - 200 Hz: 2 g, 200 - 500 Hz: 4 g 2 - 8 Hz: 7.5 mm, 8 - 200 Hz: 2 g, 200 - 500 Hz: 4 g
Shock Operation Storage Transport	15 g, 11 ms 30 g, 15 ms 30 g, 15 ms
Protection type	IP20 back side IP65 / NEMA 250 type 4X, dust and sprayed water protection (front side)
Altitude	-300 to 3000 m above sea level
Drop height	1 m

Table 44: Technical data - 5PC820.1906-00 (cont.)

- 1) Maintenance controller extended.
- 2) Touch screen drivers can be downloaded from the download area on the B&R homepage (www.br-automation.com).
- 3) At 25°C ambient temperature. Reducing the brightness by 50% can result in an approximate 50% increase of the half-brightness time.

Dimensions

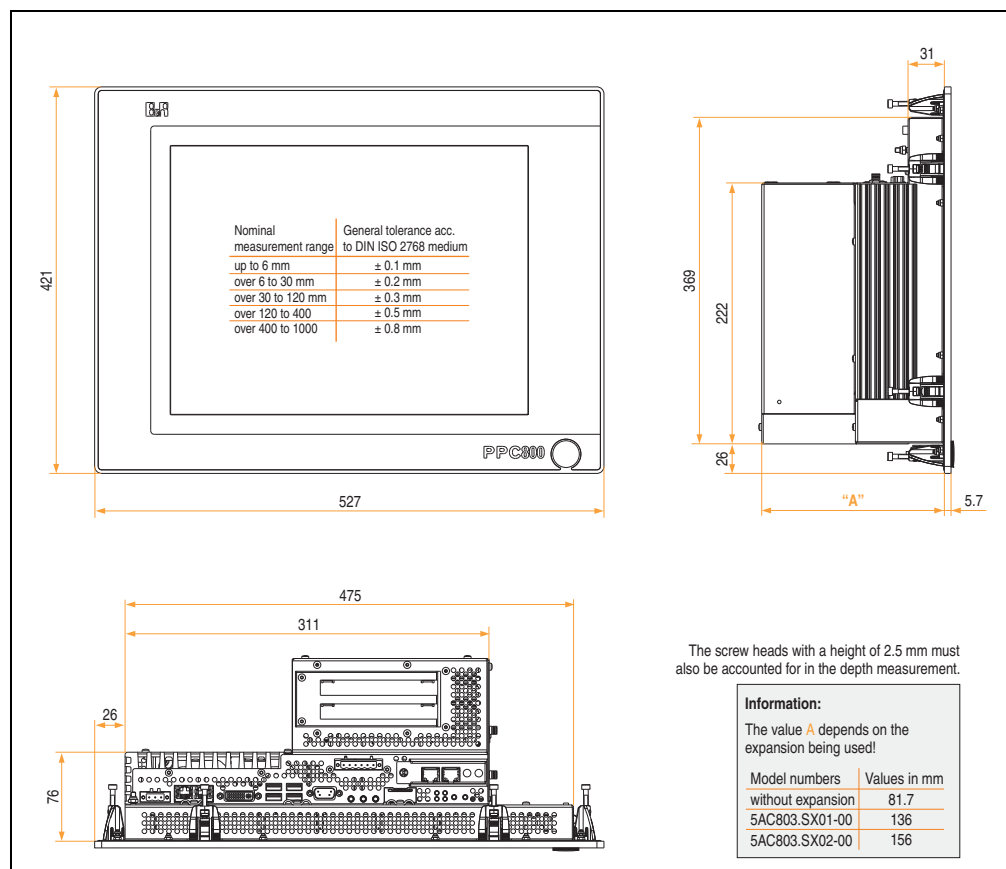


Figure 18: Dimensions - 5PC820.1906-00

Cutout installation

The Panel PC 800 with preassembled mounting blocks is installed e.g. in a housing cutout. A cutout that corresponds to the following drawing must be made.

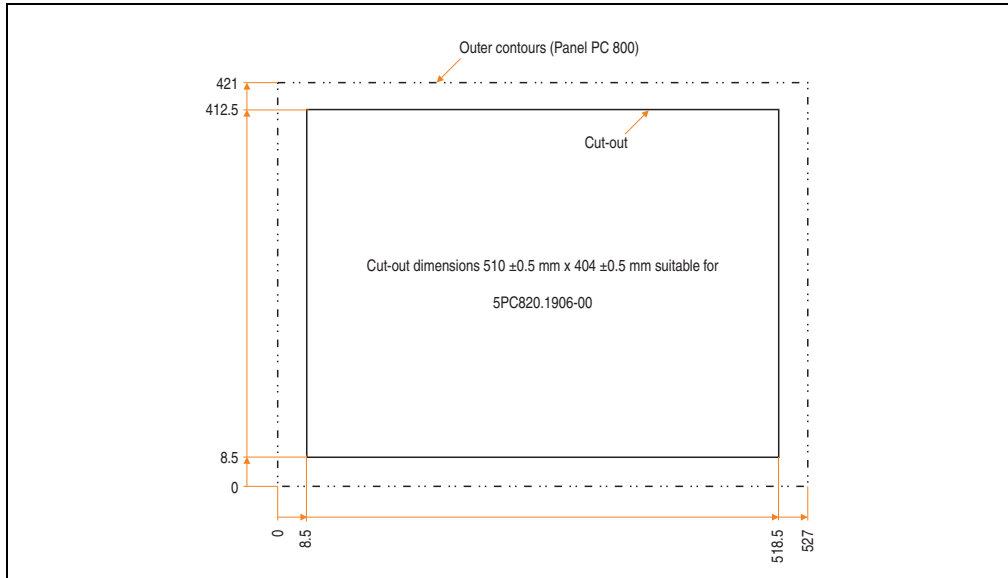


Figure 19: Cutout installation - 5PC820.1906-00

3.2 CPU boards 945GME

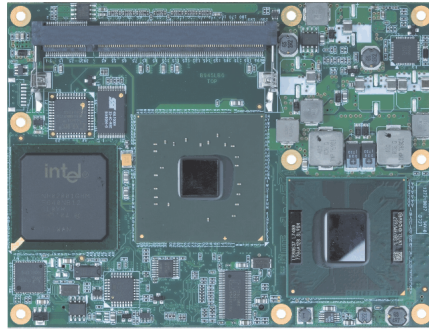


Figure 20: CPU board

3.2.1 Technical data

Features	5PC800.B945-00	5PC800.B945-01	5PC800.B945-02	5PC800.B945-03	5PC800.B945-04	5PC800.B945-05
	5PC800.B945-10	5PC800.B945-11	5PC800.B945-12	5PC800.B945-13	5PC800.B945-14	
Boot loader / Operating sys.	embedded AMI BIOS (for a description, see Chapter 4 "Software", section "BIOS options", on page 167)					
Processor Type	Intel® Core™ Duo	Intel® Core™2 Duo	Intel® Core™2 Duo	Intel® Celeron® M	Intel® Core™2 Duo	Intel® Atom™
Name	L2400	L7400	U7500	423	T7400	N270
Clock frequency	1.66 GHz	1.5 GHz	1.06 GHz	1.06 GHz	2.16 GHz	1.66 GHz
Architectures	65 nm	65 nm	65 nm	65 nm	65 nm	45 nm
L1 cache	32 KB	32 KB	32 KB	32 KB	32 KB	24 KB
L2 cache	2 MB	4 MB	2 MB	1 MB	4 MB	512 kB
Front side bus - FSB	667 MHz	667 MHz	533 MHz	533 MHz	667 MHz	533 MHz
Chipset	Intel® 945GME / Intel 82801 GMH (ICH7M-DH)					
Memory	SO-DIMM DDR2 667/PC5300, max. 3 GByte					
Graphics Controller	Intel® Graphics Media Accelerator 950					
Memory	Up to 224 MB (reserved from main memory)					
Color depth	Max. 32-bit					
Resolution	400 MHz RAMDAC, up to 2048 x 1536 @75 Hz (QXGA) including 1920 x 1080 @ 85 Hz (HDTV)					
RGB	2x Intel compliant SDVO port, 1920 x 1080					
DVI						
Real-time clock (RTC)	Yes					
Battery-buffered	At 25°C typ. 12 ppm (1 second) ¹⁾ per day					
Accuracy						
Mass memory management	2x SATA, 1x IDE					
Power management	ACPI 2.0, S3 Support (suspend to RAM)					

Table 45: Technical data - CPU boards

1) At max. specified ambient temperature: typ. 58 ppm (5 seconds) - worst-case 220 ppm (19 seconds).

3.3 Heat sink



Figure 21: Heat sink

3.3.1 Technical data

Mechanical characteristics	5AC803.HS00-00	5AC803.HS00-01	5AC803.HS00-02
Ideal for CPU boards	5PC800.B945-00 5PC800.B945-01 5PC800.B945-02 5PC800.B945-03 5PC800.B945-10 5PC800.B945-11 5PC800.B945-12 5PC800.B945-13	5PC800.B945-04 5PC800.B945-14	5PC800.B945-05
Item	Aluminum, black-coated with copper heat pipes		
Outer dimensions			
Width	143 mm		
Height	183.5 mm		
Depth	60 mm		
Weight	Approx. 1.2 kg		

Table 46: Technical data - Heat sink

3.4 Main memory

The CPU boards offer room for two main memory modules. Dual-Channel memory technology is supported when two modules of the same size (e.g. 1 GB) are plugged in. This technology is not supported when two modules of different sizes (e.g. 1 GB and 2 GB) are plugged in.

When two 2 GB modules are plugged in, only 3 GB of main memory can be used.

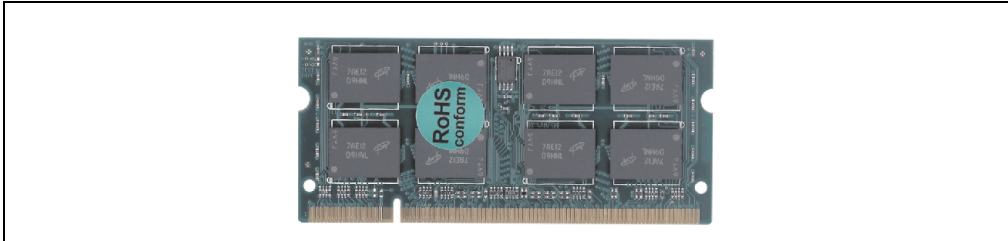


Figure 22: Main memory

3.4.1 Technical data

Features	5MMDDR.0512-01	5MMDDR.1024-01	5MMDDR.2048-01
Quantity	512 MB	1 GB	2 GB
Type	DDR2 SDRAM / PC2-5300		
Construction	200 Pin SO-DIMM		
Organization	64M x 64-bit	128M x 64-bit	256M x 64-bit

Table 47: Technical data - Main memory

Information:

A main memory module can only be replaced at the B&R plant.

3.5 Expansion

The PPC800 expansion is an expandable extension for mounting up to 2 PCI / PCIe cards and a slide-in drive.

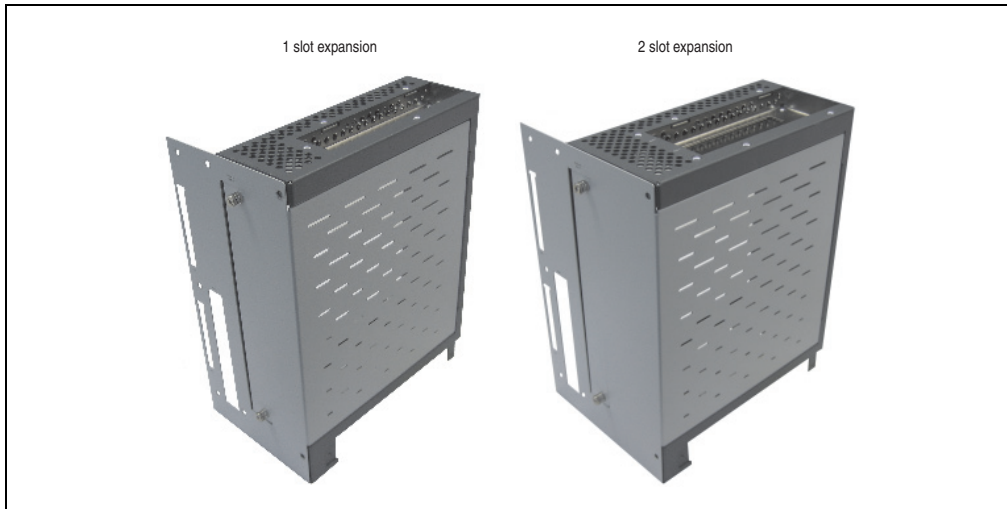


Figure 23: 1 slot and 2 slot expansion

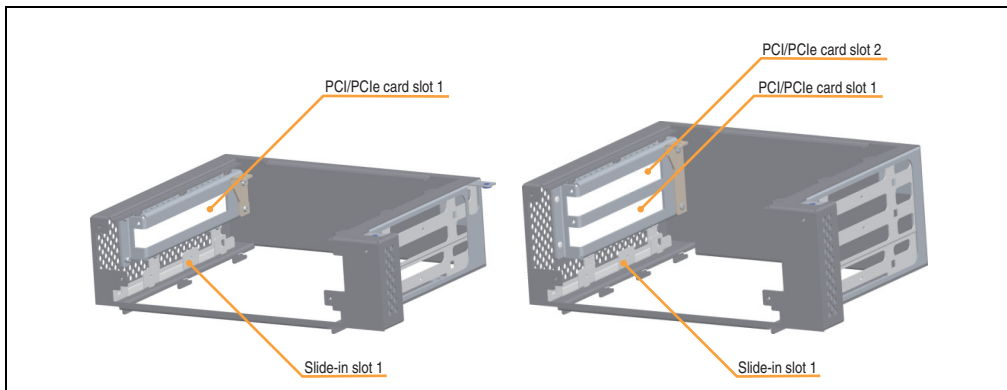


Figure 24: Expansion description

3.5.1 Technical data

Inserts	5AC803.SX01-00	5AC803.SX02-00
PCI/PCIe slots Amount	1	2
Slide-in drive Amount	1	1
Mechanical characteristics		
Dimensions Width Height Depth	167mm 222 mm 60 mm	167mm 222 mm 80 mm
Weight	Approx. 1 kg	Approx. 1kg

Table 48: Technical data - Expansion

3.5.2 Dimensions - 5PC803.SX01-00

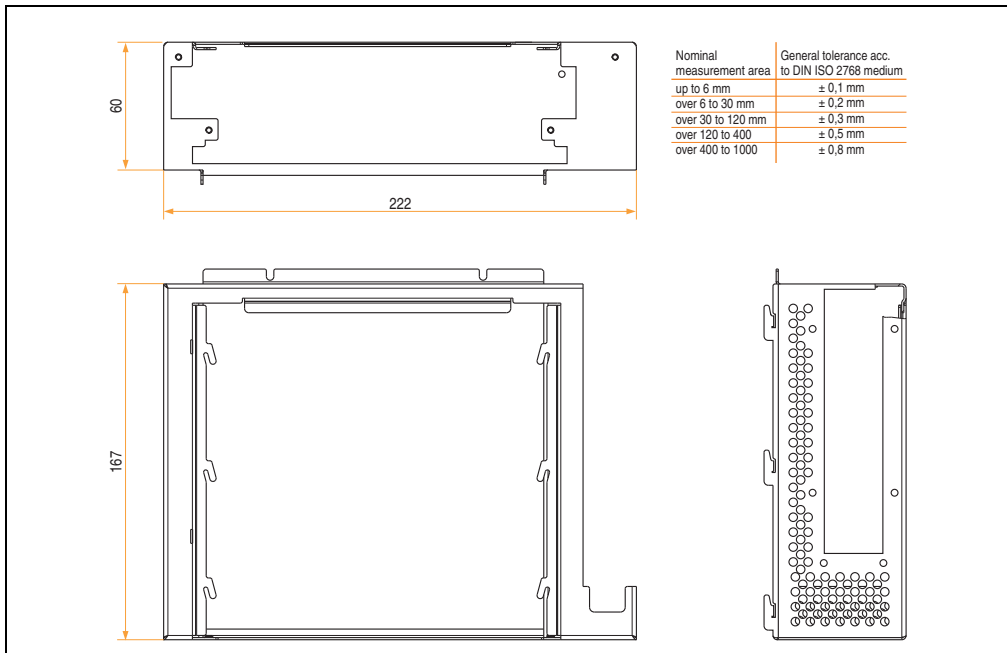


Figure 25: Dimensions - Expansion 5PC803.SX01-00

3.5.3 Dimensions - 5PC803.SX02-00

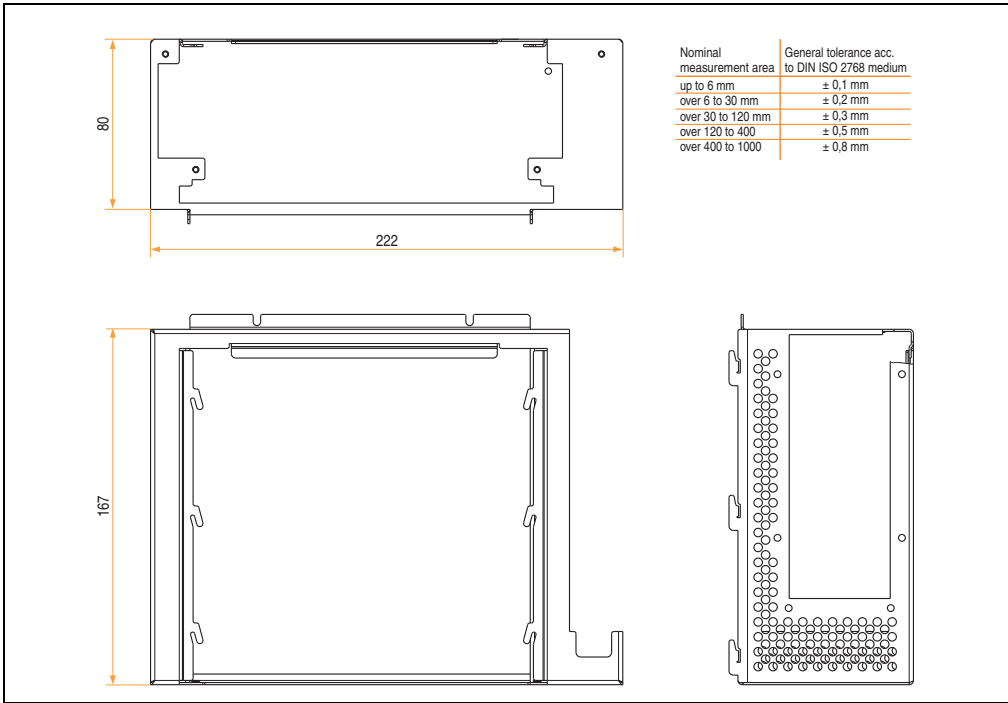


Figure 26: Dimensions - Expansion 5PC803.SX02-00

3.5.4 Slot for bus units

Card slot (PCI / PCIe)

Standard PCI 2.2 half-size cards or PCI Express (PCIe) half-size cards can be plugged in depending on the type of bus unit. They cannot exceed the following dimensions.

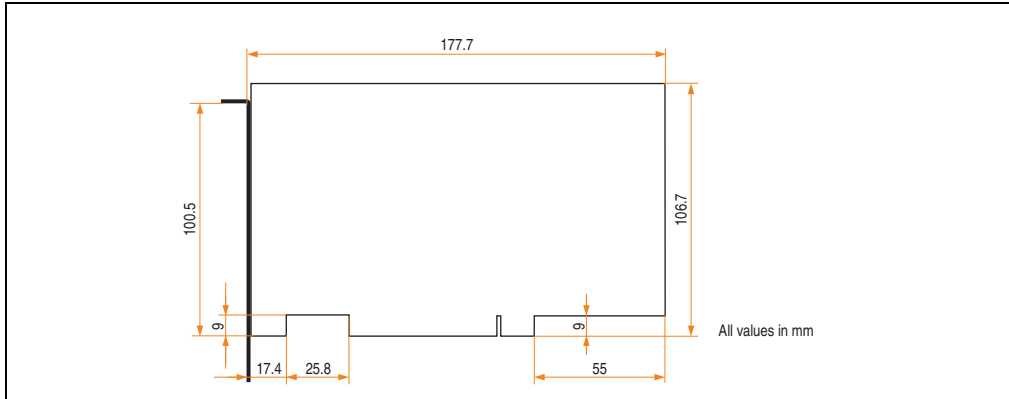


Figure 27: Dimensions - Standard half-size PCI card

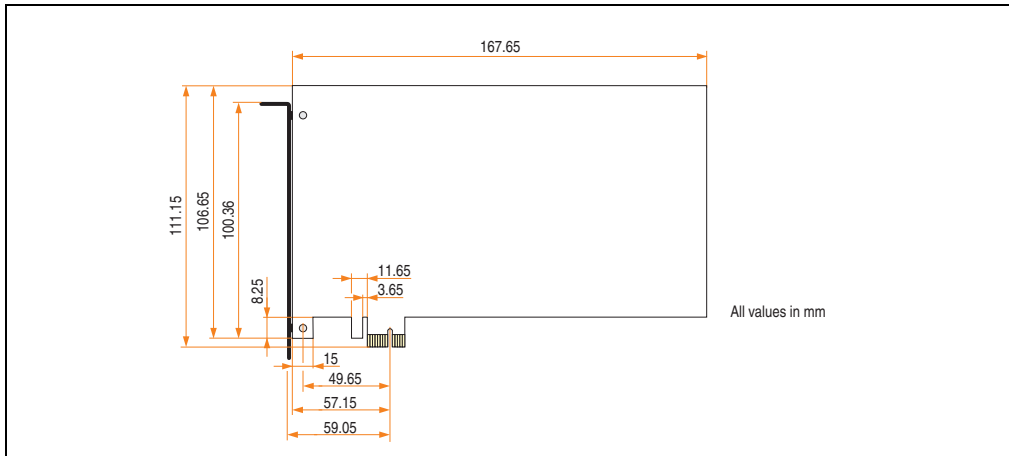


Figure 28: Dimensions - Standard half-size PCIe card

3.5.5 Slide-in slot 1

The slide-in slot 1 is internally connected with the chipset via SATA I and USB.

Slide-in slot 1		
Connection	SATA I and USB	
Accessories	Short description	
5AC801.ADAS-00	APC810 and PPC800 slide-in compact adapter	
5AC801.HDDS-00	APC810 and PPC800 slide-in HDD EE25	
5AC801.DVRS-00	APC810 and PPC800 slide-in DVD-R/RW	
5AC801.DVDS-00	APC810 and PPC800 slide-in DVD ROM	

Table 49: Slide-in slot 1

Information:

The SATA I interface allows data carriers to be exchanged during operation (hot-plug). To utilize this capability, it must be supported by the operating system.

3.6 Bus units

The bus units are compatible with the expansions in 1 or 2 PCI slot sizes, available with PCI and/or PCI Express support.

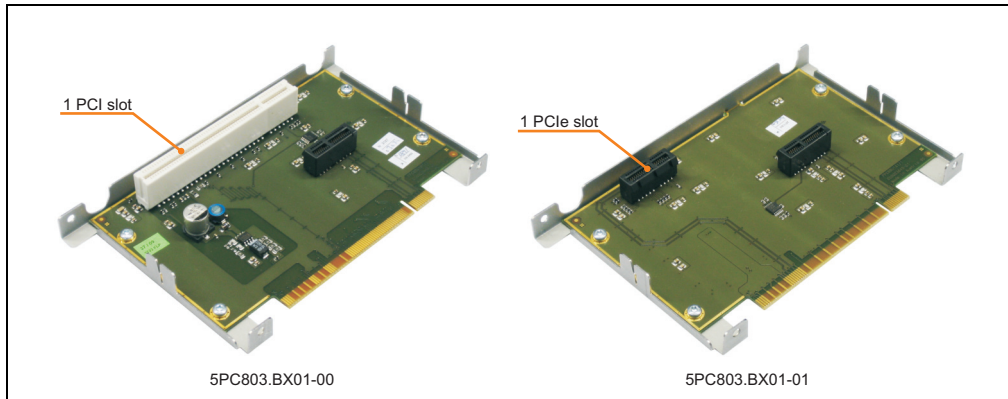


Figure 29: 1 slot bus units

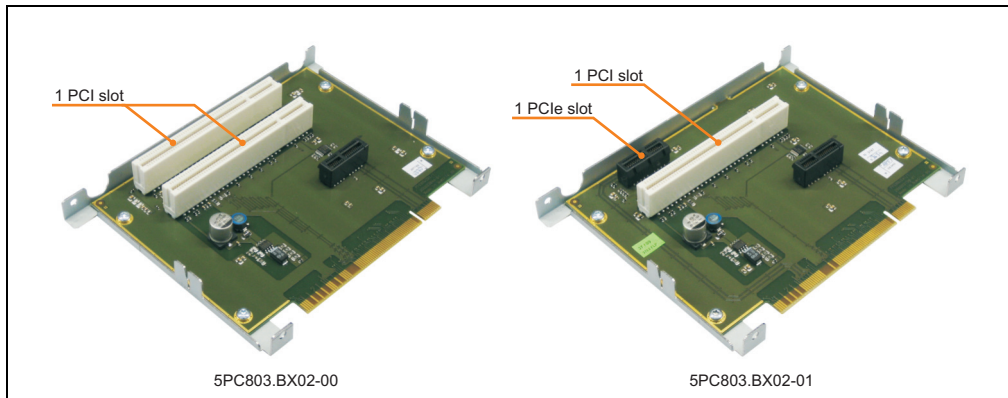


Figure 30: 2 slot bus units

3.6.1 Technical data

Inserts	5AC803.BX01-00	5AC803.BX01-01	5AC803.BX02-00	5AC803.BX02-01
PCI slot				
Amount	1		2	1
Default	2.2	-	2.2	2.2
PCI bus type	32-bit		32-bit	32-bit
Bus speed	33 MHz		33 MHz	33 MHz
PCI Express				
Amount		1		1
Default	-	1.0a	-	1.0a
Bus speed		x1 (250 MB/s)		x1 (250 MB/s)

Table 50: Technical data - Bus units

3.7 Option

The option 5AC803.BC01-00 enables a PCIe plug-in card to be connected to the system unit. If the option 5AC803.BC02-00 is selected, then a slide-in compact drive can be operated in the system unit. It is also possible to select both options so that a PCIe plug-in card and a slide-in compact drive can be operated in the PC 800.

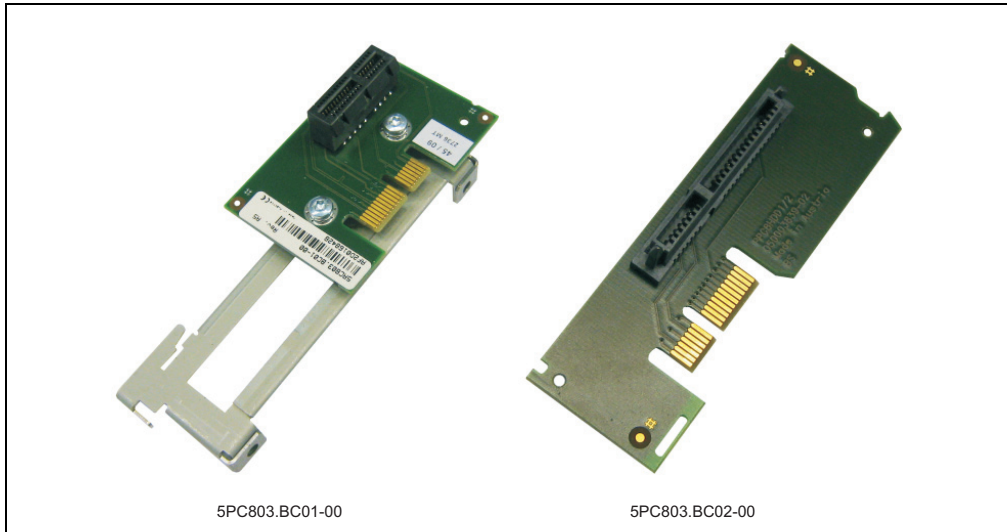


Figure 31: Options

Information:

Options are only available factory-installed.

3.8 Plug-in cards

The PClec plug-in cards are equipped with a sensor that monitors the card's temperature. This value is read out in the BIOS (menu item: Advanced - Baseboard/Panel Features - Baseboard Monitor on page 207) and in the ADI.

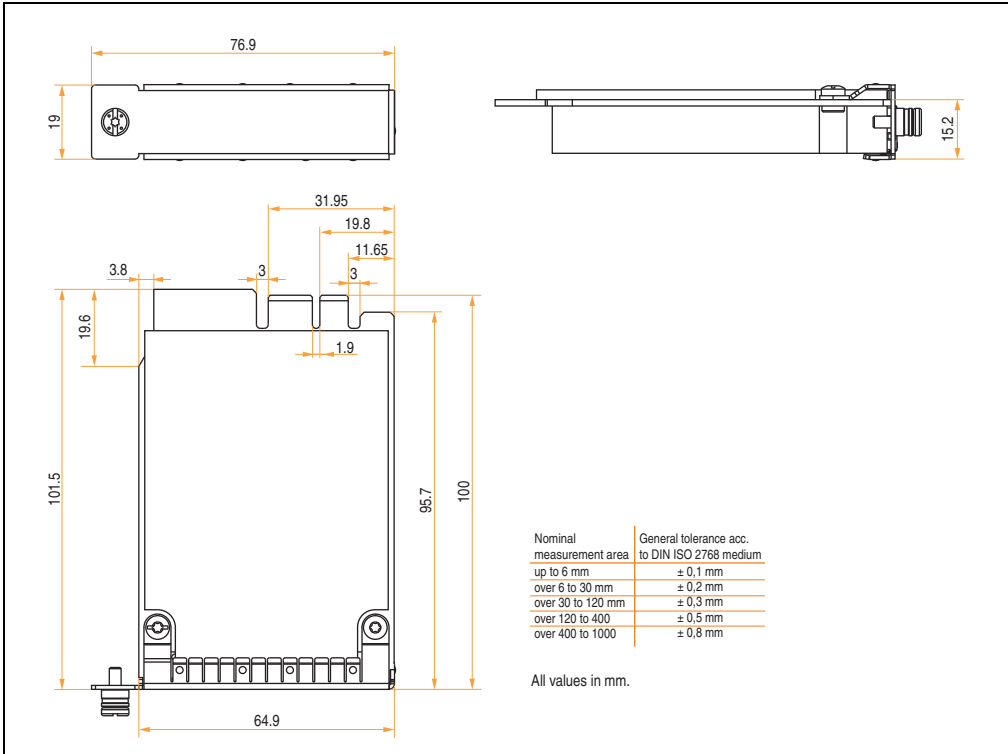


Figure 32: Dimensions - PClec cards

Information:

Only B&R PClec cards that were specially designed for the Automation PC 820 and Panel PC 800 can be used.

Information:

The option 5AC803.BC01-00 is required for the use of PClec plug-in cards.

3.8.1 Ethernet Card 10/100/1000 - 5ACPCC.ETH0-00



Figure 33: Ethernet card 10/100/1000 - 5ACPCC.ETH0-00

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Ethernet card 1 connection		
Controller	Intel 82574	
Cabling	S/STP (Cat5e)	
Transfer rate	10/100/1000 MBit/s ¹⁾	
Cable length	max. 100 m (min. Cat5e)	
Speed LED	On	Off
Green	100 Mbit/s	10 Mbit/s ²⁾
Orange	1000 Mbit/s	-
Link LED	On	Off
Orange	Link (Ethernet network connection available)	Activity (blinking) (data being transferred)

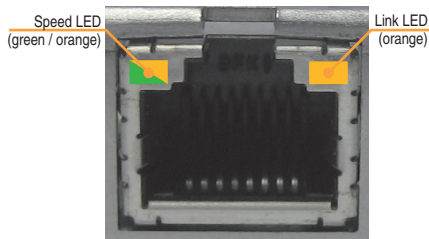


Table 51: Technical data - Ethernet card 10/100/1000 - 5ACPCC.ETH0-00

1) Change-over takes place automatically.

2) The 10 MBit/s transfer speed / connection is only present if the IF slot Link LED is simultaneously active.

Driver support

A special driver is necessary for operating the Intel Ethernet controller 82574. The necessary drivers can be downloaded from the download area on the B&R homepage (www.br-automation.com).

Information:

Required drivers can only be downloaded from the B&R homepage, not from manufacturers' pages.

3.8.2 POWERLINK card 2-port - 5ACPCC.MPL0-00

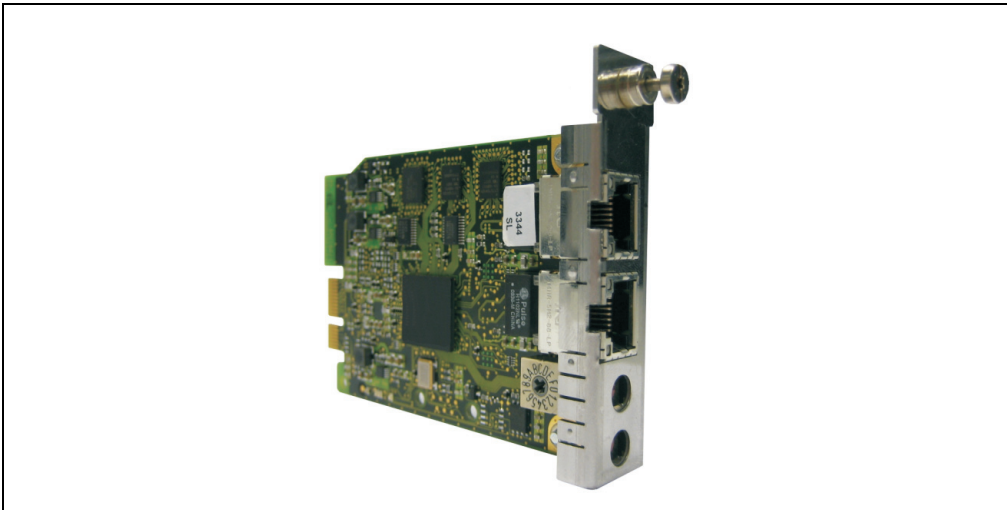


Figure 34: POWERLINK card 2-port - 5ACPCC.MPL0-00

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

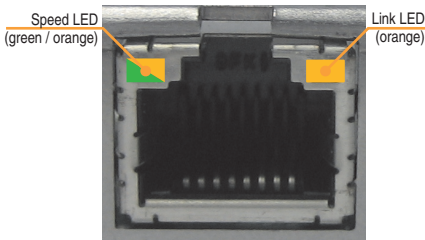
POWERLINK card 2 connections			
Cabling	S/STP (Cat5e)		The LEDs are identical for both connections. 
Cable length	max. 100 m (min. Cat5e)		
Speed LED	On	Off	
Green / red	see Status / Error LED		
Link LED	On	Blinking	
Yellow	Link (POWERLINK network connection available)	Activity (blinking) (Data transfer in progress)	

Table 52: POWERLINK card 2-port connection

Status / Error LED

The status/error LED is a green/red LED.

Red - error	Description
On	The POWERLINK interface has encountered an error (failed Ethernet frames, increased number of collisions on the network, etc.).

Table 53: Status / Error LED as error LED - POWERLINK card 2-port operating mode

Green - status	Description
Off NOT_ACTIVE	Managing Node (MN) The bus is monitored for POWERLINK frames. If a frame is not received within the configured time window (timeout), the interface goes directly into PRE_OPERATIONAL_1 status (single flash). If, however, POWERLINK communication is detected before this time passes, the interface goes directly into the BASIC_ETHERNET status (flickering). Controlled Node (CN) The bus is monitored for POWERLINK frames. If a frame is not received within the configured time window (timeout), the interface goes directly into BASIC_ETHERNET status (flickering). If, however, POWERLINK communication is detected during this time, the interface goes directly into the PRE_OPERATIONAL_1 status (single flash).
Green flickering (approx. 10 Hz) BASIC_ETHERNET	The interface is in BASIC_ETHERNET status, and is operated purely as an Ethernet TCP/IP interface. Managing Node (MN) This status can only be changed by resetting the interface. Controlled Node (CN) If POWERLINK communication is detected while in this status, the interface goes into the PRE_OPERATIONAL_1 state (single flash).
Single flash (approx. 1 Hz) PRE_OPERATIONAL_1	The interface status is PRE_OPERATIONAL_1. Managing Node (MN) The MN starts the operation of the "reduced cycle". Collisions are allowed on the bus. There is not yet any cyclic communication. Controlled Node (CN) The CN waits until it receives an SoC frame and then switches to PRE_OPERATIONAL_2 status (double flash).
Double flash (approx. 1 Hz) PRE_OPERATIONAL_2	The interface status is PRE_OPERATIONAL_2. Managing Node (MN) The MN begins with the cyclic communication (cyclic input data is not yet evaluated). The CNs are configured in this status. Controlled Node (CN) In this status, the interface is normally configured by the manager. After this, a command changes the status to PRE_OPERATIONAL_3 (triple flash).
Triple flash (approx. 1 Hz) READY_TO_OPERATE	The interface status is READY_TO_OPERATE. Managing Node (MN) Normal cyclic and asynchronous communication. Received PDO data is ignored. Controlled Node (CN) The configuration of the interface is complete. Normal cyclic and asynchronous communication. The PDO data sent corresponds to the PDO mapping used. However, cyclic data is not yet evaluated.
On OPERATIONAL	The interface status is OPERATIONAL.
Blinking (approx. 2.5 Hz) STOPPED	The interface status is STOPPED. Managing Node (MN) This status is not possible for the MN. Controlled Node (CN) No output data is produced and no input data is received. Only the appropriate command from the manager can enter or leave this state.

Table 54: Status / Error LED as status LED - POWERLINK card 2-port operating mode

POWERLINK station number

POWERLINK station number (x1, x16)		
Both of these hex switches (x16, x1) are used to configure the station number for the POWERLINK. Station numbers are permitted between #00 and #FD.		
Switch position		
x1	x16	Description
0	0	Operation as managing node
1 ... D	0 ... F	station number Operation as controlled node
E	F	Reserved
F	F	Reserved

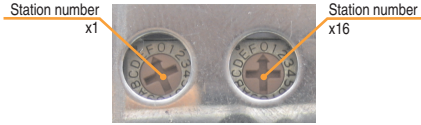


Table 55: POWERLINK card 2-port station number (x1, x16)

Card number switch

The one-digit card number (\$1 – \$F) is configured using the card number switch. This number is used to identify the module.

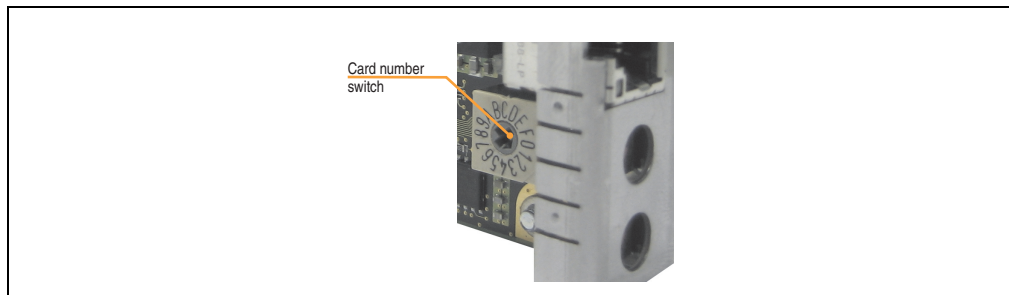


Figure 35: POWERLINK card 2-port node number switch

3.9 Drives

3.9.1 Slide-in compact HDD 40GB EE25 - 5AC801.HDDI-00

This hard disk is specified for 24-hour operation and also provides an extended temperature specification.

Information:

The option 5AC803.BC02-00 is required for the use of slide-in compact drives.



Figure 36: Slide-in compact HDD 40GB EE25 - 5AC801.HDDI-00

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Features	5AC801.HDDI-00
Manufacturer's product ID	Seagate ST940817SM
Formatted capacity	40 GB
Number of heads	1
Number of sectors (user)	78,140,160

Table 56: Technical data - Add-on hard disk - 5AC801.HDDI-00

Technical data • Individual components

Features	5AC801.HDDI-00
Bytes per sector	512
Revolution speed	5400 rpm
Access time (average)	12.5 ms
Positioning time (seek, typical values)	
Minimum (track to track)	1 ms
Average (read access)	12.5 ms
Maximum (read access)	23 ms
Starting time (0 rpm to read access)	3 seconds (typically)
Interface	SATA
Data transfer rate	
Internal	Max. 450 MBit/s
To/from host	Max. 150 MB/s (Ultra-DMA Mode 5)
Cache	8 MB
S.M.A.R.T. Support	Yes
MTBF	750,000 Power On Hours ¹⁾
Mechanical characteristics	
Slide-in compact mounting	Fixed
Outer dimensions	
Height	98 mm
Width	13 mm
Depth	105 mm
Weight	134 g
Environmental characteristics	
Ambient temperature ²⁾	
Operation - Standard / 24-hour	-30 to +85°C
Bearings	-40 to +95°C
Transport	-40 to +95°C
Relative humidity ³⁾	
Operation	5 to 90%, non-condensing
Bearings	5 to 95%, non-condensing
Transport	5 to 95%, non-condensing
Vibration	
Operation	2 g at 5 - 500 Hz, no non-recovered errors
Bearings	5 g at 5 - 500 Hz, no non-recovered errors
Shock (pulse with a sine half-wave)	
Operation	300 g and 2 ms duration, no non-recovered errors
Bearings	150 g and 11 ms duration, no non-recovered errors
	800 g and 2 ms duration, no non-recovered errors
	400 g and 0.5 ms duration, no non-recovered errors
Altitude	
Operation	- 300 to 5000 m
Bearings	- 300 to 12,192 m

Table 56: Technical data - Add-on hard disk - 5AC801.HDDI-00 (cont.)

1) With 8760 POH (Power On Hours) per year and 70°C surface temperature.

2) Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 20°C per hour.

3) Humidity gradient: Maximum 15% per hour.

Temperature humidity diagram - Operation and storage

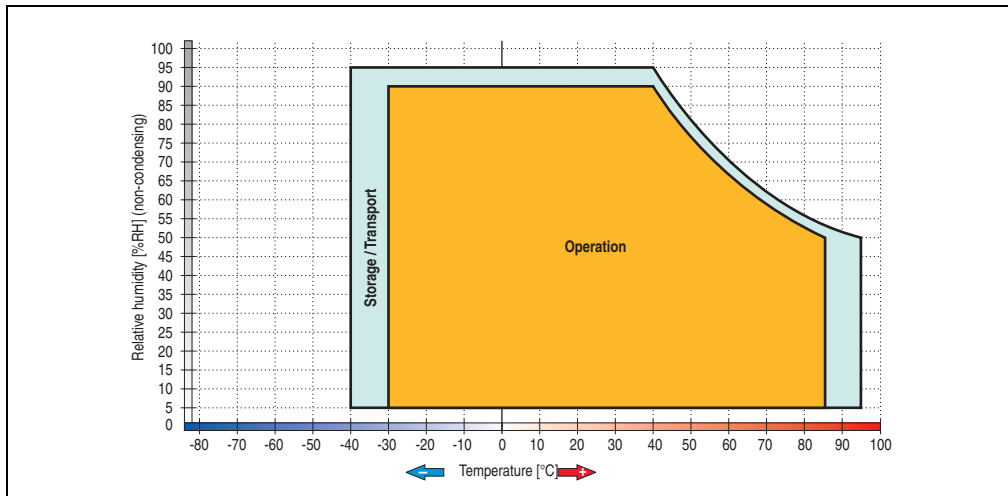


Figure 37: Temperature humidity diagram - 5AC801.HDDI-00

Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 20°C per hour.

3.9.2 Slide-in compact HDD 160 GB 24x7 ET - 5AC801.HDDI-02

This hard disk is specified for 24-hour operation (24x7) and also provides an extended temperature specification (ET).

Information:

The option 5AC803.BC02-00 is required for the use of slide-in compact drives.



Figure 38: Slide-in compact HDD 160 GB - 5AC801.HDDI-02

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Features	5AC801.HDDI-02
Manufacturer's product ID	Fujitsu MHY2160BH-ESW
Formatted capacity	160 GB
Number of heads	3
Number of sectors (user)	312,581,808
Bytes per sector	512
Revolution speed	5400 rpm

Table 57: Technical data - Slide-in compact HDD - 5AC801.HDDI-02

Features	5AC801.HDDI-02
Access time (average)	12 ms
Positioning time (seek, typical values)	
Minimum (track to track)	1.5 ms
Average (read access)	12 ms
Maximum (read access)	22 ms
Starting time (0 rpm to read access)	4 seconds (typically)
Interface	SATA
Data transfer rate	
Internal	Max. 84.6 MBit/s
To/from host	Max. 150 MB/s (Ultra-DMA Mode 5)
Cache	8 MB
S.M.A.R.T. Support	Yes
MTBF	300,000 Power On Hours ¹⁾
Mechanical characteristics	
Slide-in compact mounting	Fixed
Outer dimensions	
Height	98 mm
Width	13 mm
Depth	105 mm
Weight	135 g
Environmental characteristics	
Ambient temperature ²⁾	
Operation - Standard / 24-hour	-15 to +80°C
Bearings	-40 to +95°C
Transport	-40 to +95°C
Relative humidity ³⁾	
Operation	8 to 90% non-condensing (maximum humidity at +29°C)
Bearings	5 to 95% non-condensing (maximum humidity at +40°C)
Transport	5 to 95% non-condensing (maximum humidity at +40°C)
Vibration	
Operation	5 - 500 Hz: 1 g, no unrecoverable errors
Bearings	5 - 500 Hz: 5 g, no damage
Shock (pulse with a sine half-wave)	
Operation	325 g, 2 ms, no unrecoverable errors
Bearings	900 g, 1 ms, no damage 120 g, 11 ms, no damage
Altitude	
Operation	- 300 to 3000 m
Bearings	- 300 to 12,192 m

Table 57: Technical data - Slide-in compact HDD - 5AC801.HDDI-02 (cont.)

1) With 8760 POH (Power On Hours) per year and 70°C surface temperature.

2) Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 20°C per hour.

3) Humidity gradient: Maximum 15% per hour.

Temperature humidity diagram - Operation and storage

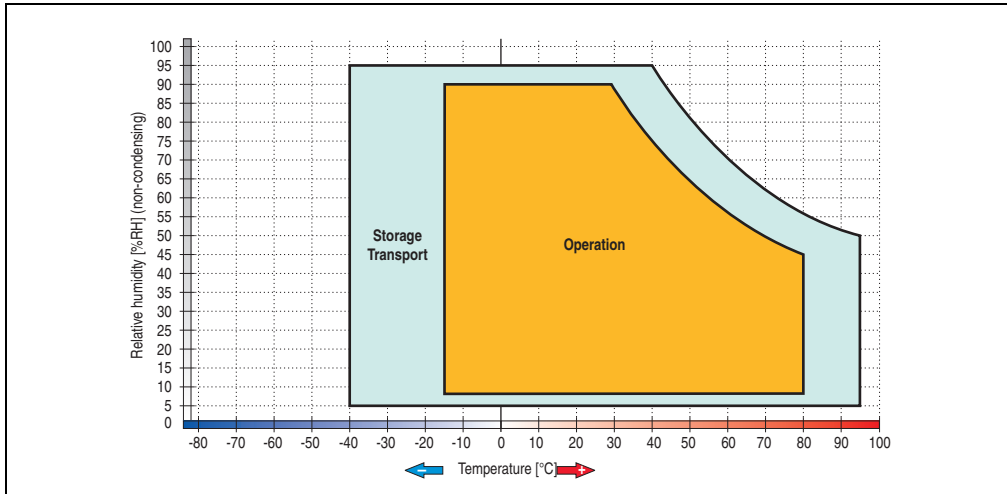


Figure 39: Temperature humidity diagram - 5AC801.HDDI-02

Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 20°C per hour.

3.9.3 Slide-in compact SSD - 5AC801.SSDI-00

Information:

The option 5AC803.BC02-00 is required for the use of slide-in compact drives.



Figure 40: Slide-in compact SSD 5AC801.SSDI-00

Technical data

Caution!

A sudden loss of power can cause data to be lost! In very rare cases, the mass memory may also become damaged.

To prevent damage and loss of data, it is recommended to use a UPS device.

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Technical data • Individual components

Features	5AC801.SSDI-00
Manufacturer's product ID	Intel SSDSA2SH032G1
Formatted capacity	32 GB
Interface	SATA
Continuous reading	Max. 250 MB/s
Continuous writing	Max. 170 MB/s
IOPS ¹⁾ 4k write 4k read	3,300 35,000
S.M.A.R.T. support	Yes
MTBF	2,000,000 hours
Maintenance	None
Data reliability	< 1 unrecoverable error in 10 ¹⁵ bit read accesses
Power on/off cycles	50,000
Endurance	
Guaranteed amount of data Results for 5 years	700 TB 350 GB/day
SLC-Flash	Yes
Wear leveling	Static
Error Correction Coding (ECC)	Yes
Compatibility	SATA revision 2.6 compliant, compatible with SATA 1.5 Gbit/s and 3 Gbit/s interface rates ATA/ATAPI-7 SSD Enhanced SMART ATA feature set Native Command Queuing (NCQ) command
Mechanical characteristics	
Slide-in compact mounting	Fixed
Outer dimensions Height Width Depth	98 mm 13 mm 105 mm
Weight	118 g
Environmental characteristics	
Ambient temperature Operation Bearings Transport	0 to +70°C -55 to +95°C -55 to +95°C
Relative humidity Operation Bearings Transport	5 to 95% 5 to 95% 5 to 95%
Vibration Operation Bearings Transport	2.17 g at 7 - 800 Hz 3.13 g at 10 - 500 Hz 3.13 g at 10 - 500 Hz

Table 58: Technical data - Slide-in compact SSD - 5AC801.SSDI-00

Environmental characteristics	5AC801.SSDI-00
Shock	
Operation	1000 g / 0.5 ms
Bearings	1000 g / 0.5 ms
Transport	1000 g / 0.5 ms
Altitude	
Operation	-300 to 12,192 m
Bearings	-300 to 12,192 m
Transport	-300 to 12,192 m

Table 58: Technical data - Slide-in compact SSD - 5AC801.SSDI-00 (cont.)

1) IOPS: Random read and write input/output operations per second

Temperature humidity diagram - Operation and storage

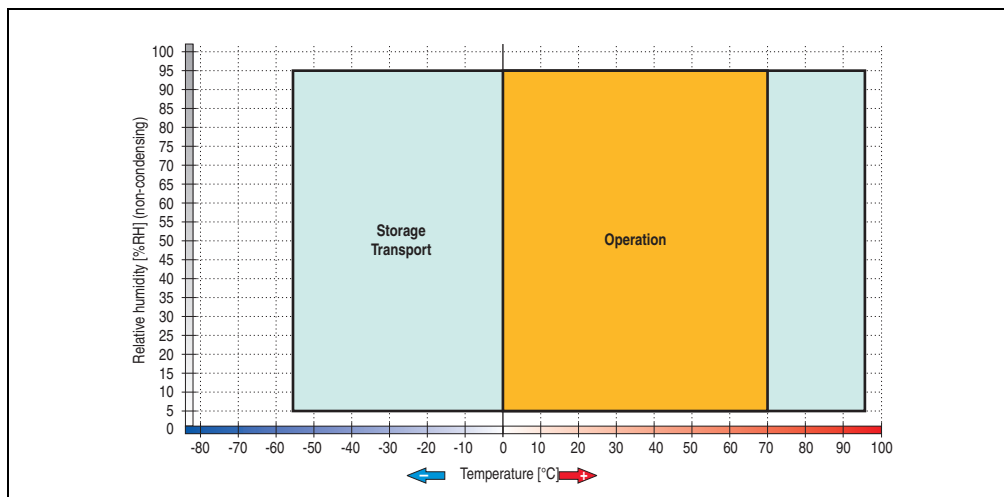


Figure 41: Temperature humidity diagram - 5AC801.SSDI-00

Benchmark

The following two benchmarks show a comparison of the Intel Solid State Drive (5AC801.SSDI-00) and the Seagate Hard Disk (5AC801.HDDI-00) for cyclic reading and writing.

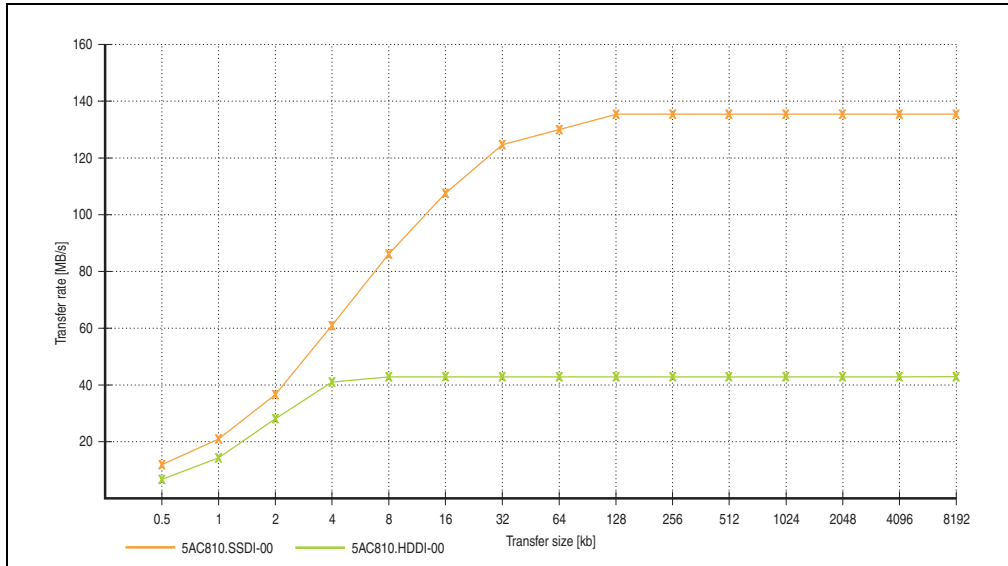


Figure 42: ATTO disk benchmark v2.34 - cyclic read

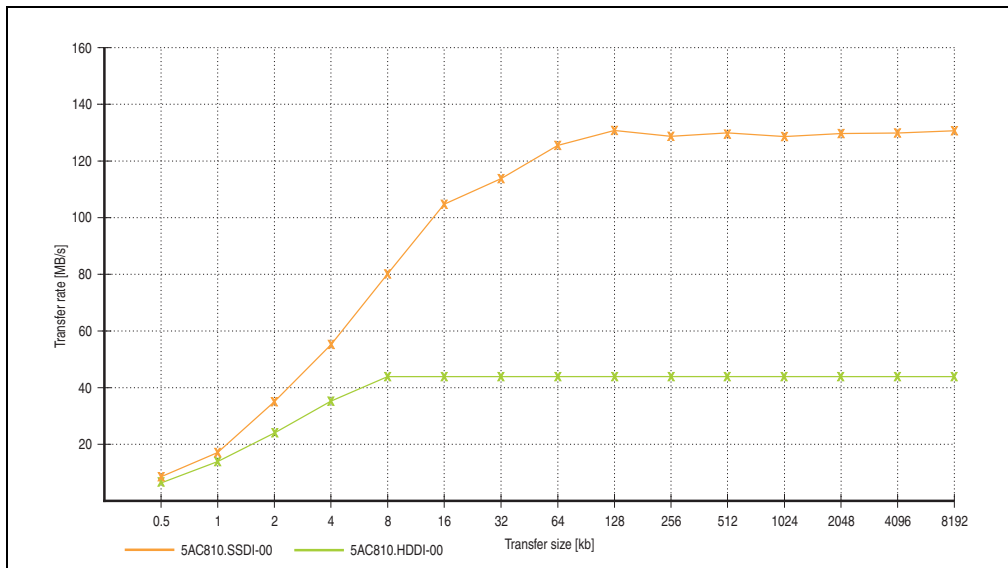


Figure 43: ATTO disk benchmark v2.34 - cyclic write

3.9.4 Hard disk adapter (slide-in compact) - 5AC801.ADAS-00

Information:

The expansion 5AC803.SX01-00 or 5AC803.SX02-00 is required in order to use slide-in drives.

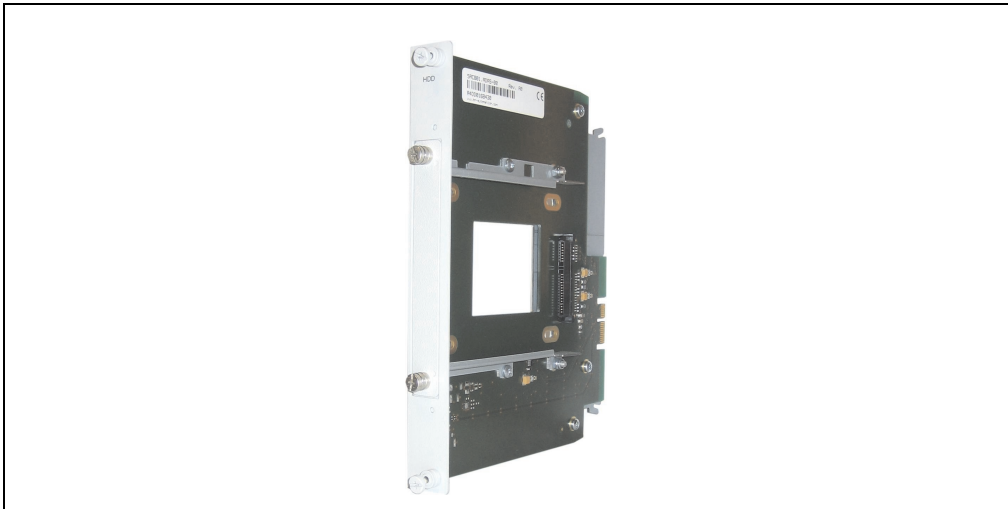


Figure 44: Hard disk adapter (slide-in compact) 5AC801.ADAS-00

Technical data

Mechanical characteristics	5AC801.ADAS-00
Outer dimensions	
Height	172.5 mm
Width	22 mm
Depth	150 mm
Weight	328 g

Table 59: Technical data - Slide-in HDD adapter - 5AC801.ADAS-00

3.9.5 Slide-in HDD EE25 - 5AC801.HDDS-00

Information:

The expansion 5AC803.SX01-00 or 5AC803.SX02-00 is required in order to use slide-in drives.



Figure 45: Slide-in HDD EE25 5AC801.HDDS-00

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Features	5AC801.HDDS-00
Manufacturer's product ID	Seagate ST940817SM
Formatted capacity	40 GB
Number of heads	1
Number of sectors (user)	78,140,160
Bytes per sector	512

Table 60: Technical data - Slide-in HDD EE25 - 5AC801.HDDS-00

Features	5AC801.HDDS-00
Revolution speed	5400 rpm
Access time (average)	12.5 ms
Positioning time (seek, typical values)	
Minimum (track to track)	1 ms
Average (read access)	12.5 ms
Maximum (read access)	23 ms
Starting time (0 rpm to read access)	3 seconds (typically)
Interface	SATA
Data transfer rate	
Internal	Max. 450 MBit/s
To/from host	Max. 150 MB/s (Ultra-DMA Mode 5)
Cache	8 MB
S.M.A.R.T. Support	Yes
MTBF	750,000 Power On Hours ¹⁾
Mechanical characteristics	
Slide-in compact mounting	Fixed
Outer dimensions	
Height	172.5 mm
Width	22 mm
Depth	150 mm
Weight	387 g
Environmental characteristics	
Ambient temperature ²⁾	
Operation - Standard / 24-hour	-30 to +85°C
Bearings	-40 to +95°C
Transport	-40 to +95°C
Relative humidity ³⁾	
Operation	5 to 90%, non-condensing
Bearings	5 to 95%, non-condensing
Transport	5 to 95%, non-condensing
Vibration	
Operation	2 g at 5 - 500 Hz, no non-recovered errors
Bearings	5 g at 5 - 500 Hz, no non-recovered errors
Shock (pulse with a sine half-wave)	
Operation	300 g and 2 ms duration, no non-recovered errors
	150 g and 11 ms duration, no non-recovered errors
Bearings	800 g and 2 ms duration, no non-recovered errors
	400 g and 0.5 ms duration, no non-recovered errors
Altitude	
Operation	- 300 to 5000 m
Bearings	- 300 to 12,192 m

Table 60: Technical data - Slide-in HDD EE25 - 5AC801.HDDS-00 (cont.)

1) With 8760 POH (Power On Hours) per year and 70°C surface temperature.

2) Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 20°C per hour.

3) Humidity gradient: Maximum 15% per hour.

Temperature humidity diagram - Operation and storage

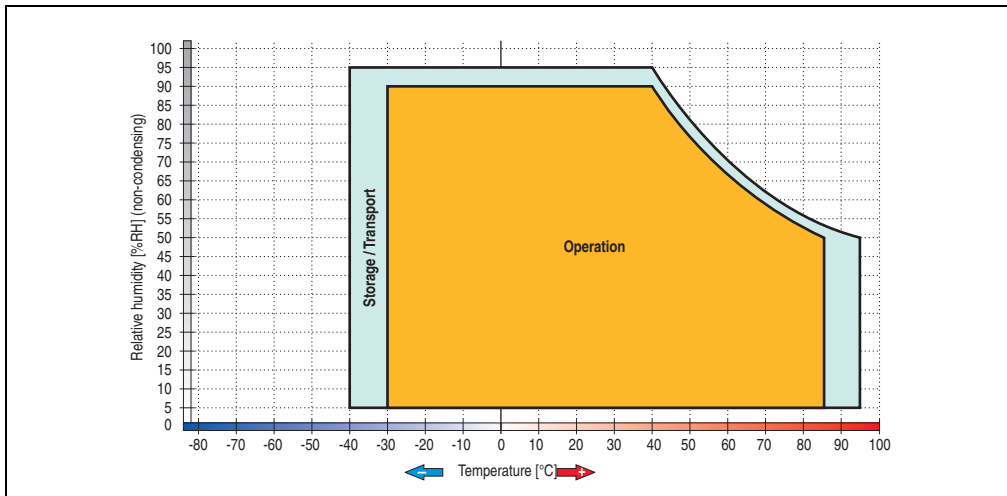


Figure 46: Temperature humidity diagram - 5AC801.HDDS-00

Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 20°C per hour.

3.9.6 Slide-in DVD-ROM - 5AC801.DVDS-00

Information:

The expansion 5AC803.SX01-00 or 5AC803.SX02-00 is required in order to use slide-in drives.



Figure 47: Slide-in DVD-ROM 5AC801.DVDS-00

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Features	5AC801.DVDS-00
Reading rate CD DVD	24x 8x
Data transfer rate	max. 1.5 Gbit/s
Access time (average) CD DVD	130 ms 140 ms

Table 61: Technical data - 5AC801.DVDS-00

Technical data • Individual components

Features	5AC801.DVDS-00
Revolution speed	Max. 5090 rpm $\pm 1\%$
Starting time (0 rpm to read access)	19 seconds (maximum)
Host interface	SATA
Readable media CD DVD	CD-ROM (12 cm, 8 cm), CD-A CD-R, CD-RW DVD-ROM, DVD-R, DVD-R DL, DVD-RW, DVD+R DVD+R DL, DVD+RW, DVD-RAM
Compatible formats	CD-DA, CD-ROM mode 1/mode 2 CD-ROM XA mode 2 (form 1, form 2) Photo CD (single/multi-session) Enhanced CD, CD text DVD-ROM, DVD-Video (Double Layer), DVD-R (Single/Multi-border), DVD-R DL (Single/Multi-border), DVD-RW (Single/Multi-border), DVD+R (Single/Multi session), DVD+R DL (Single/Multi session), DVD+RW (Single/Multi session), DVD-RAM (4.7 GB, 2.6 GB)
Laser class	Class 1 laser
Noise level (complete read access)	Approx. 45 dBA in a distance of 50 cm
Lifespan Opening/closing the drawer	60,000 POH (Power-On Hours) > 10,000 times
Mechanical characteristics	
Outer dimensions Height Width Depth	172.5 mm 22 mm 150 mm
Weight	455 g
Environmental characteristics	
Ambient temperature ¹⁾ Operation Bearings Transport	+5 to +55°C ²⁾ -20 to +60°C -40 to +65°C
Relative humidity Operation Bearings Transport	8 to 80%, non-condensing 5 to 95%, non-condensing 5 to 95%, non-condensing
Vibration Operation Bearings Transport	0.2 g at 5 - 500 Hz 2 g at 5 - 500 Hz 2 g at 5 - 500 Hz
Shock Operation Bearings Transport	5 g and 11 ms duration 60 g and 11 ms duration 200 g and 2 ms duration 60 g and 11 ms duration 200 g and 2 ms duration

Table 61: Technical data - 5AC801.DVDS-00 (cont.)

1) Temperature data is for operation at 500 meters. Derating the max. ambient temperature - typically 1°C per 1000 meters (from 500 meters above sea level).

2) Drive surface temperature

Temperature humidity diagram - Operation and storage

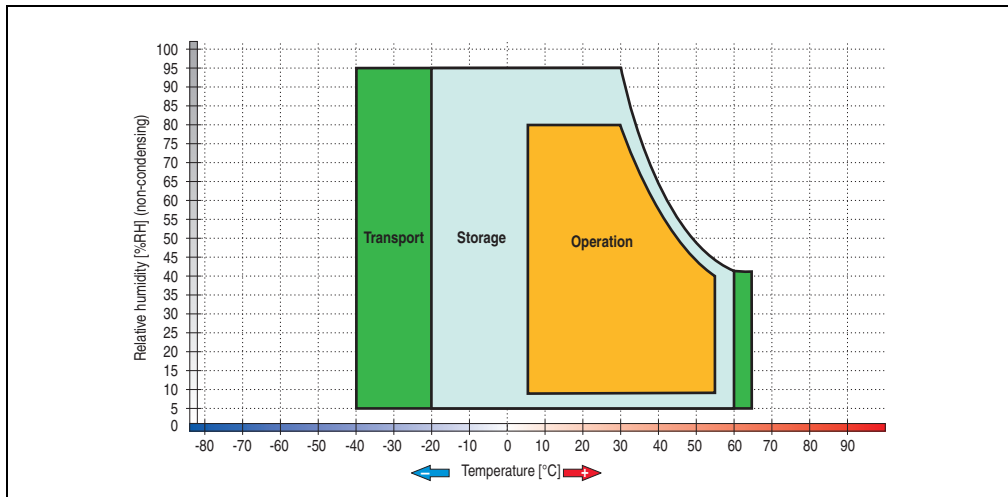


Figure 48: Temperature humidity diagram - Slide-in DVD-ROM/CD-RW - 5AC801.DVDS-00

Temperature data is for operation at 500 meters. Derating the max. ambient temperature - typically 1°C per 1000 meters (from 500 meters above sea level).

Hot plug capable

Hardware revision B0 of the slide-in DVD-ROM - 5AC801.DVDS-00 does not offer SATA hot plug capability. Other hardware revisions are hot plug capable.

3.9.7 Slide-in DVD-R/RW - 5AC801.DVRS-00

Information:

The expansion 5AC803.SX01-00 or 5AC803.SX02-00 is required in order to use slide-in drives.



Figure 49: Slide-in DVD-R/RW - 5AC801.DVRS-00

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Features	5AC801.DVRS-00
Write speed CD-R CD-RW DVD-R DVD-R (Double Layer) DVD-RW DVD-RAM ¹⁾ DVD+R DVD+R (double layer) DVD+RW	24x, 16x, 10x and 4x 24x, 16x, 10x and 4x 8x, 4x and 2x 6x, 4x and 2x 6x, 4x and 2x 5x, 3x and 2x 8x, 4x and 2, 4x 6x, 4x and 2, 4x 4x and 2x
Reading rate CD DVD	max. 24x max. 8x
Data transfer rate	Max. 33.3 MB/s
Access time (average) CD DVD	140 ms (24x) 150 ms (8x)
Revolution speed	Max. 5160 rpm ±1%
Starting time (0 rpm to read access) CD DVD	14 seconds (maximum) 15 seconds (maximum)
Host interface	SATA
Readable media CD DVD	CD/CD-ROM (12 cm, 8 cm), CD-R, CD-RW DVD-ROM, DVD-R, DVD-R (double layer), DVD-RW, DVD-RAM, DVD+R, DVD+R (double layer), DVD+RW, DVD-RAM
Non-write protected media CD DVD	CD-R, CD-RW DVD-R/RW, DVD-R (double layer), DVD-RAM (4.7 GB), DVD+R/RW, DVD+R (double layer)
Compatible formats	CD-DA, CD-ROM mode 1/mode 2 CD-ROM XA mode 2 (form 1, form 2) Photo CD (single/multi-session), Enhanced CD, CD text DVD-ROM, DVD-R, DVD-R (double layer), DVD-RW, DVD-Video DVD-RAM (4.7 GB, 2.6 GB) DVD+R, DVD+R (double layer), DVD+RW
Write-methods CD DVD	Disk at once, session at once, packet write, track at once Disk at once, incremental, over-write, sequential, multi-session
Laser class	Class 1 laser

Table 62: Technical data - Slide-in DVD-R/RW, DVD+R/RW - 5AC801.DVRS-00

Technical data • Individual components

Features	5AC801.DVRS-00
Data buffer capacity	2 MB
Noise level (complete read access)	Approx. 45 dBA at 50 cm
Lifespan Opening/closing the drawer	60,000 POH (Power-On Hours) > 10,000 times
Mechanical characteristics	
Outer dimensions	
Height	172.5 mm
Width	22 mm
Depth	150 mm
Weight	400 g
Environmental characteristics	
Ambient temperature ²⁾	
Operation	+5 to +55°C ³⁾
Bearings	-20 to +60°C
Transport	-40 to +65°C
Relative humidity	
Operation	8 to 80%, non-condensing
Bearings	5 to 95%, non-condensing
Transport	5 to 95%, non-condensing
Vibration	
Operation	At max. 5 - 500 Hz and 0.2 g
Bearings	At max. 5 - 500 Hz and 2 g
Transport	At max. 5 - 500 Hz and 2 g
Shock (pulse with a sine half-wave)	
Operation	At max. 5 g for 11 ms
Bearings	At max. 60 g for 11 ms
Transport	At max. 200 g for 2 ms
	At max. 60 g for 11 ms
	At max. 200 g for 2 ms

Table 62: Technical data - Slide-in DVD-R/RW, DVD+R/RW - 5AC801.DVRS-00

1) RAM drivers are not provided by the manufacturer. Support of RAM function by the burning software "Nero" (model number 5SWUTL.0000-00) or other burning software packages and drivers from third party providers.

2) Temperature data is for operation at 500 meters. Derating the max. ambient temperature - typically 1°C per 1000 meters (from 500 meters above sea level).

3) Drive surface temperature

Temperature humidity diagram - Operation and storage

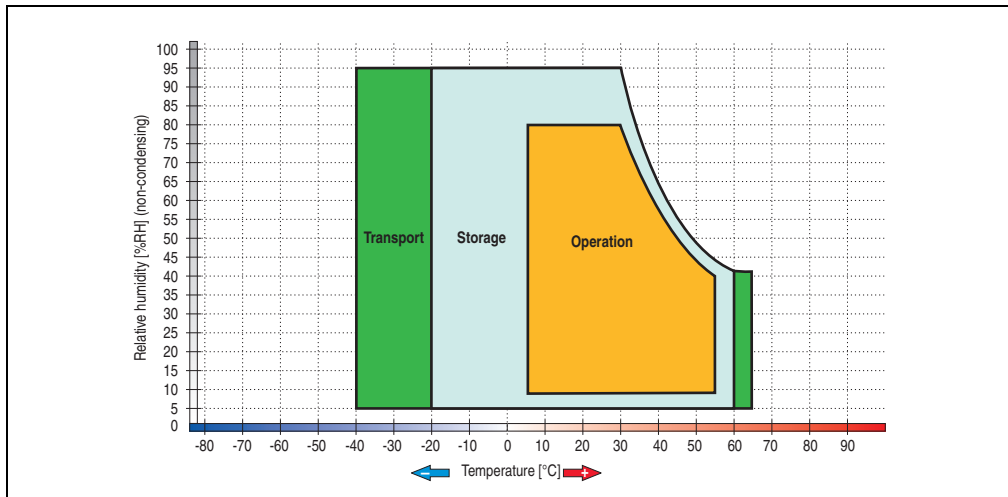


Figure 50: Temperature humidity diagram - Slide-in DVD-R/RW, DVD+R/RW - 5AC801.DVRS-00

Temperature data is for operation at 500 meters. Derating the max. ambient temperature - typically 1°C per 1000 meters (from 500 meters above sea level).

3.9.8 PCI SATA RAID 2 x 160 GB 24x7 ET - 5ACPCI.RAIC-03

The hard disks being used are specified for 24-hour operation (24x7) and also provides an extended temperature specification (ET).

Features

- SATA RAID controller
- RAID Level 0 (striped) and 1 (mirrored)
- 2 SATA hard disk drives (suitable for 24 hour operation)
- Only requires 1 PCI slot
- Transfer rates up to 150 MB/s

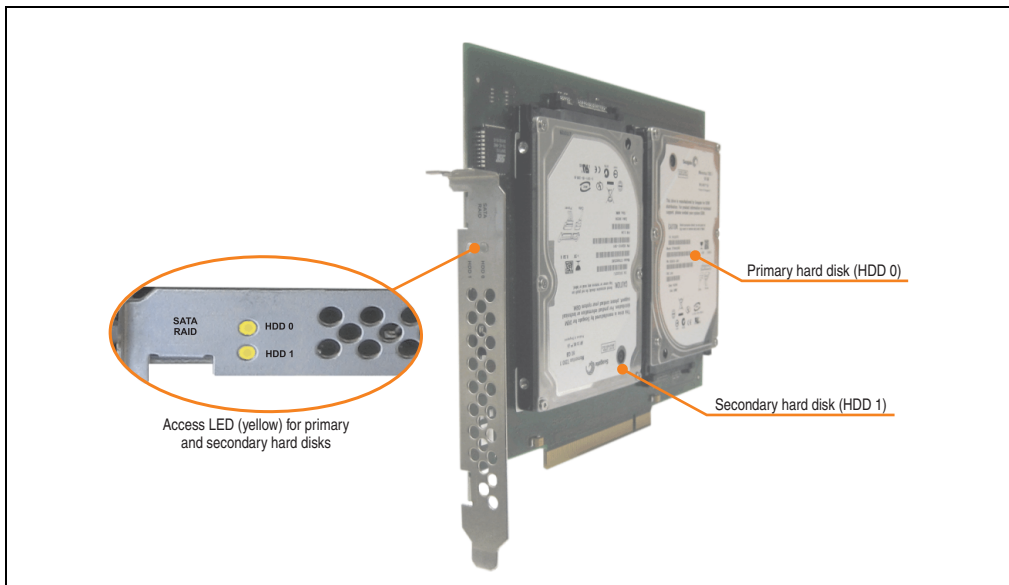


Figure 51: PCI SATA RAID controller - 5ACPCI.RAIC-03

Information:

The PCI SATA RAID controller can not be used in place of a Universal Power Supply (UPS). If the operating system is shut down improperly, the next time it is started it is detected as an error by the RAID 1, and a complete rebuild is executed. This generally takes at least 120 minutes (configurable) to complete.

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Features	5ACPCI.RAIC-03
SATA RAID controller Type Specifications Data transfer rate RAID level BIOS Extension ROM - requirements	Sil 3512 SATA link Serial ATA 1.0 Max. 1.5 GB/s (150 MB/s) Supports RAID 0, 1 Approx. 32 KB
Hard disks Amount	Fujitsu M120-ESW MHY2160BH-ESW 2
Formatted capacity (512 bytes/sector)	160 GB
Number of heads	3
Number of sectors (user)	312,581,808
Bytes per sector	512
Revolution speed	5400 rpm $\pm 1\%$
Access time (average)	5.56 ms
Positioning time (seek, typical values) Minimum (track to track) Average (read access) Maximum (read access)	1.5 ms 12 ms 22 ms
Starting time (0 rpm to read access)	4 seconds (typically)
Supported transfer mode	SATA 1.0, PIO mode 0-4, multiword DMA mode 0-2, UDMA 0-5
Data transfer rate On the medium To/from host	Max. 84.6 MBit/s Max. 150 MB/s
Cache	8 MB
S.M.A.R.T. Support	Yes
Lifespan	5 years
Electrical characteristics	
Power consumption	0.3 A at 3.3 V (PCI bus) 1 A at 5 V (PCI bus)
Mechanical characteristics	
Mounted on PCI insert	Fixed
Weight	350 g

Table 63: Technical data - RAID hard disk - 5ACPCI.RAIC-03

Environmental characteristics	5ACPCI.RAIC-03
Ambient temperature ¹⁾ Operation - Standard / 24-hour ²⁾ Bearings Transport	-15 to +80°C -40 to +95°C -40 to +95°C
Relative humidity Operation Bearings Transport	8 to 90% non-condensing (maximum humidity at +29°C) 5 to 95% non-condensing (maximum humidity at +40°C) 5 to 95% non-condensing (maximum humidity at +40°C)
Vibration ³⁾ Operation (continuous) Operation (occasional) Bearings Transport	5 - 500 Hz: max. 0.125 g; duration 1 octave per minute; no unrecoverable errors 5 - 500 Hz: max. 0.25 g; duration 1 octave per minute; no unrecoverable errors 5 - 500 Hz: max. 5 g; duration 0.5 octaves per minute; no damage 5 - 500 Hz: max. 5 g; duration 0.5 octaves per minute; no damage
Shock ⁴⁾ (pulse with a sine half-wave) Operation Bearings	Max. 125 g, 2 ms; no unrecoverable errors Max. 400 g, 2 ms; no damage Max. 450 g, 1 ms; no damage Max. 200 g, 0.5 ms; no damage
Altitude Operation Bearings	- 300 to 3048 m - 300 to 12,192 m

Table 63: Technical data - RAID hard disk - 5ACPCI.RAIC-03 (cont.)

- 1) Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 3°C per minute.
- 2) 24-hour operation means 732 POH (power-on hours) per month.
- 3) Operation in areas prone to vibration and shock can affect performance negatively (reduction of transfer rate).
- 4) Operation in areas prone to vibration and shock can affect performance negatively (reduction of transfer rate).

Temperature humidity diagram - Operation and storage

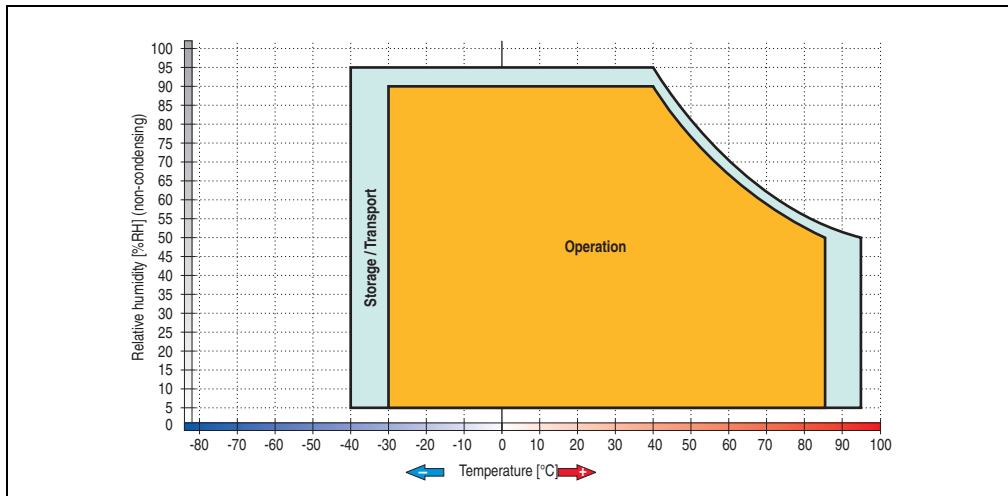


Figure 52: Temperature humidity diagram - SATA RAID hard disk 5ACPCI.RAIC-03

Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 3°C per minute.

Driver support

Special drivers are necessary for operating the PCI SATA RAID controller. Drivers for Windows XP Professional and Windows XP Embedded are available for download on the B&R Homepage in the download area (www.br-automation.com).

The .NET-based SATARaid™ serial ATA RAID management software can also be found on the B&R homepage.

Information:

Required drivers can only be downloaded from the B&R homepage, not from manufacturers' pages.

Configuration

For configuration of a SATA RAID network, see Chapter 3 "Commissioning", section 7 "Configuration of a SATA RAID array", on page 155.

Exchanging a HDD

A hard drive can be easily exchanged in the event of an error when using the RAID1 (mirroring) configuration without having to re-install the system. The replacement SATA HDD 160GB 5ACPCI.RAIC-04 is available as a replacement part for a HDD.

3.9.9 Replacement PCI SATA RAID HDD 160 GB - 5ACPCI.RAIC-04

The hard disk can be used as a replacement part for 5ACPCI.RAIC-03.



Figure 53: Replacement SATA HDD 160 GB - 5ACPCI.RAIC-04

Technical data

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device. For the entire device in which this individual component is used, refer to the data given specifically for the entire device.

Features	5ACPCI.RAIC-04
Hard disks Amount	Fujitsu M120-ESW MHY2160BH-ESW 1
Formatted capacity (512 bytes/sector)	160 GB
Number of heads	3
Number of sectors (user)	312,581,808
Bytes per sector	512
Revolution speed	5400 rpm $\pm 1\%$
Access time (average)	5.56 ms
Positioning time (seek, typical values) Minimum (track to track) Average (read access) Maximum (read access)	1.5 ms 12 ms 22 ms
Starting time (0 rpm to read access)	4 seconds (typically)
Supported transfer mode	SATA 1.0, PIO mode 0-4, multiword DMA mode 0-2, UDMA 0-5
Data transfer rate On the medium To/from host	Max. 84.6 MBit/s Max. 150 MB/s

Table 64: Technical data - RAID hard disk - 5ACPCI.RAIC-04

Technical data • Individual components

Features	5ACPCI.RAIC-04
Cache	8 MB
S.M.A.R.T. Support	Yes
Lifespan	5 years
Environmental characteristics	
Ambient temperature ¹⁾ Operation - Standard / 24-hour ²⁾ Bearings Transport	-15 to +80°C -40 to +95°C -40 to +95°C
Relative humidity Operation Bearings Transport	8 to 90% non-condensing (maximum humidity at +29°C) 5 to 95% non-condensing (maximum humidity at +40°C) 5 to 95% non-condensing (maximum humidity at +40°C)
Vibration ³⁾ Operation (continuous) Operation (occasional) Bearings Transport	5 - 500 Hz: max. 0.125 g; duration 1 octave per minute; no unrecoverable errors 5 - 500 Hz: max. 0.25 g; duration 1 octave per minute; no unrecoverable errors 5 - 500 Hz: max. 5 g; duration 0.5 octaves per minute; no damage 5 - 500 Hz: max. 5 g; duration 0.5 octaves per minute; no damage
Shock ⁴⁾ (pulse with a sine half-wave) Operation Bearings	Max. 125 g, 2 ms; no unrecoverable errors Max. 400 g, 2 ms; no damage Max. 450 g, 1 ms; no damage Max. 200 g, 0.5 ms; no damage
Altitude Operation Bearings	- 300 to 3048 m - 300 to 12,192 m

Table 64: Technical data - RAID hard disk - 5ACPCI.RAIC-04 (cont.)

- 1) Temperature values for 305 meter altitude. The temperature specification must be reduced linearly by 1°C every 305 meters. The temperature increase and decrease can be a maximum of 3°C per minute.
- 2) 24-hour operation means 732 POH (power-on hours) per month.
- 3) Operation in areas prone to vibration and shock can affect performance negatively (reduction of transfer rate).
- 4) Operation in areas prone to vibration and shock can affect performance negatively (reduction of transfer rate).

Temperature humidity diagram - Operation and storage

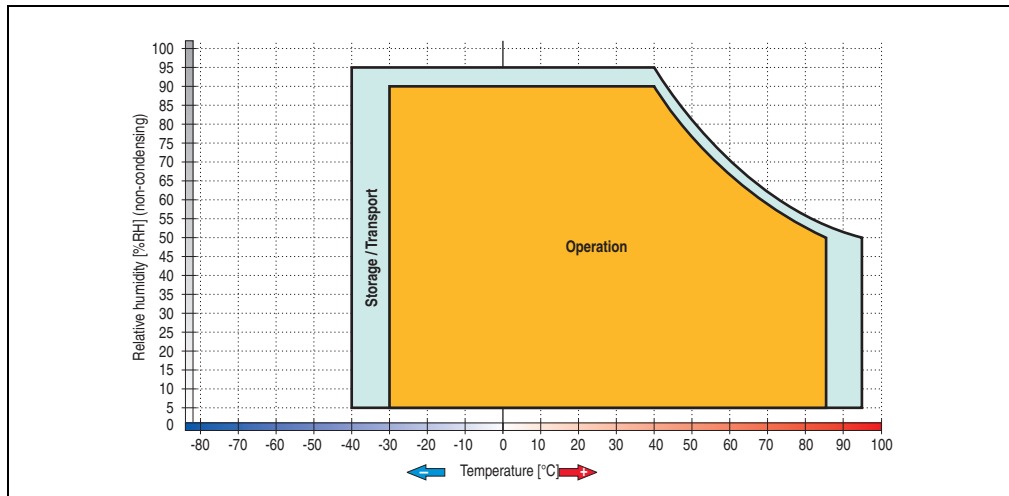


Figure 54: Temperature humidity diagram - SATA RAID hard disk 5ACPCI.RAIC-04

3.10 Fan kits

Information:

Fans are necessary when using components which must work within certain temperature limits, e.g. DVD combos, PCI cards, etc.

The fan and dust filter are subject to wear and must be checked with appropriate frequency and cleaned or replaced when not functioning properly (e.g. due to dirt and grime).

3.10.1 Fan kit 1 card slot - 5AC803.FA01-00

This fan kit is an optional addition for system units without expansion.

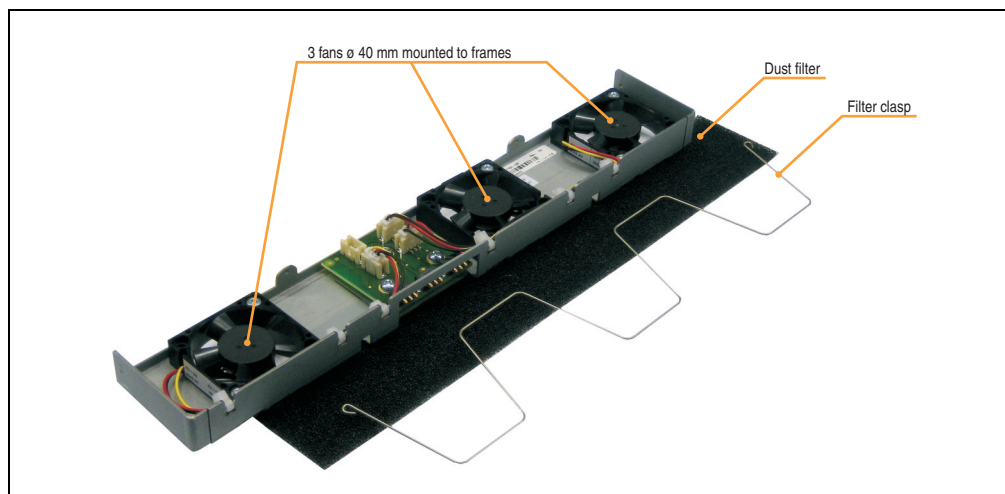


Figure 55: Fan kit - 5AC803.FA01-00

Technical data

Features	5AC803.FA01-00
Fan type	
Width	40 mm
Length	40 mm
Height	10 mm
Revolution speed	6100 rpm
Noise level	21 dB
Lifespan	95,000 at 20°C 29,000 at 70°C

Table 65: Technical data - 5AC803.FA01-00

Features	5AC803.FA01-00
Maintenance interval	The fans are subject to wear. Depending on the work environment, the dust filter should be checked with appropriate frequency to determine whether the air flow provides sufficient cooling. An exchange or cleaning of the filter kit is appropriate at that time.

Table 65: Technical data - 5AC803.FA01-00

3.10.2 Fan kit 2 card slot - 5AC803.FA02-00

This fan kit is an optional addition for system units with the expansion 5AC803.SX01.

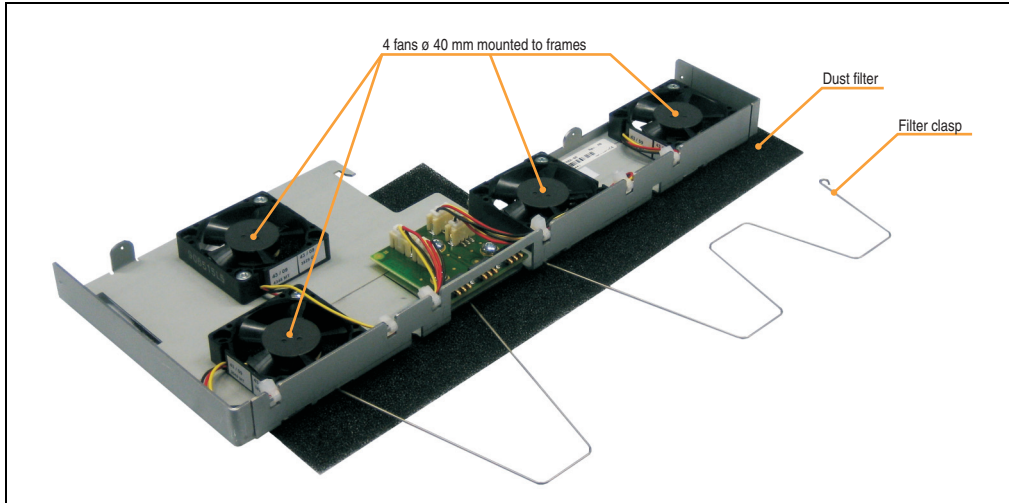


Figure 56: Fan kit - 5AC803.FA02-00

Technical data

Features	5AC803.FA02-00
Fan type	
Width	40 mm
Length	40 mm
Height	10 mm
Revolution speed	6100 rpm
Noise level	21 dB
Lifespan	95,000 at 20°C 29,000 at 70°C
Maintenance interval	The fans are subject to wear. Depending on the work environment, the dust filter should be checked with appropriate frequency to determine whether the air flow provides sufficient cooling. An exchange or cleaning of the filter kit is appropriate at that time.

Table 66: Technical data - 5AC803.FA02-00

3.10.3 Fan kit 3 card slot - 5AC803.FA03-00

This fan kit is an optional addition for system units with the expansion 5AC803.SX02-00.

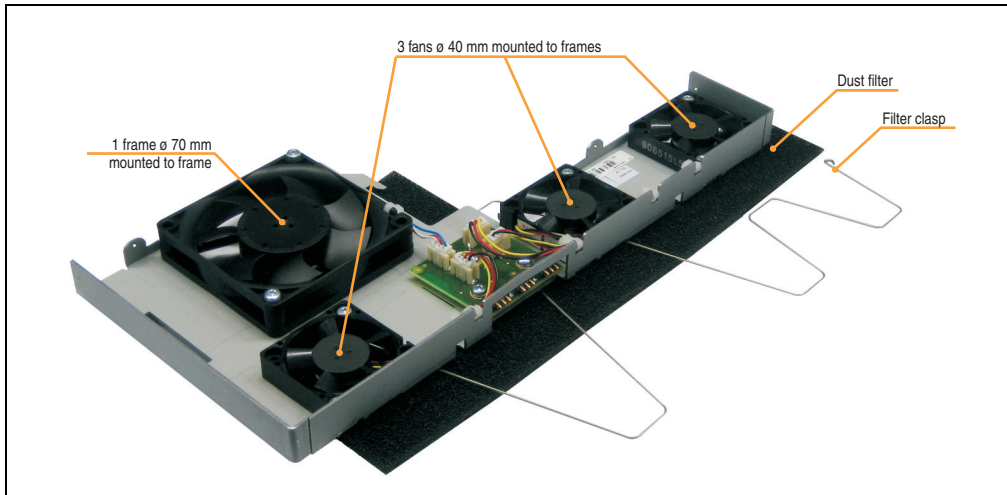


Figure 57: Fan kit - 5AC803.FA03-00

Technical data

Features	5AC803.FA03-00	
Fan type		
Width	40 mm	70 mm
Length	40 mm	70 mm
Height	10 mm	15 mm
Revolution speed	6100 rpm	4300 rpm $\pm$ 10
Noise level	21 dB	5 dB
Lifespan	95,000 at 20°C 29,000 at 70°C	$\pm$ 60,000 at 40°C
Maintenance interval	The fans are subject to wear. Depending on the work environment, the dust filter should be checked with appropriate frequency to determine whether the air flow provides sufficient cooling. An exchange or cleaning of the filter kit is appropriate at that time.	

Table 67: Technical data - 5AC803.FA03-00

Chapter 3 • Commissioning

1. Installation

Panel PC 800 devices are best mounted in a housing cutout using the clamps found on the housing (different designs possible).

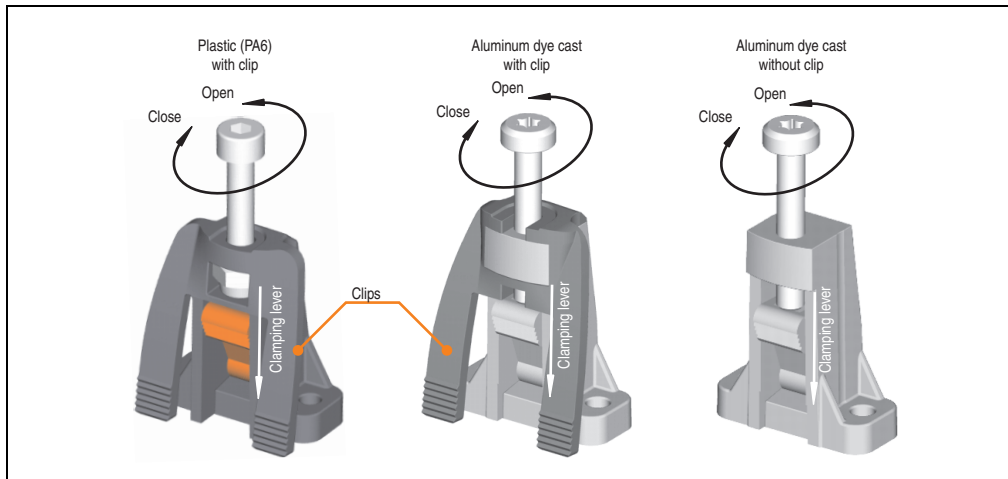


Figure 58: Terminal block

The terminal blocks are designed for a maximum thickness of 10 mm for the material where the device is being clamped.

In order to tighten or loosen the screws, a hex key (size 3) is required for the plastic clamps and a Torx screwdriver (size 20) or a large flat-head screwdriver for the aluminum die casting.

The maximum torque when tightening the clamp is 0.5 Nm. A Panel PC 800 unit must be mounted to a flat surface. Uneven areas can cause damage to the display when the screws are tightened.

1.1 Important mounting information

- The environmental conditions must be taken into consideration.
- The PPC800 must be mounted to a planar surface.
- The PPC800 is only for operation in closed rooms.
- The PPC800 cannot be situated in direct sunlight.
- The vent holes may not be covered.
- When mounting the device, be sure to adhere to the allowable mounting orientations.
- Be sure the wall or switching cabinet can withstand four times the total weight of the the PPC800.
- When connecting certain cable types (DVI, SDL, USB, etc.), keep the flex radius in mind.

1.2 Mounting orientation

The PPC800 system must be mounted as described in the following sections.

1.2.1 Standard mounting

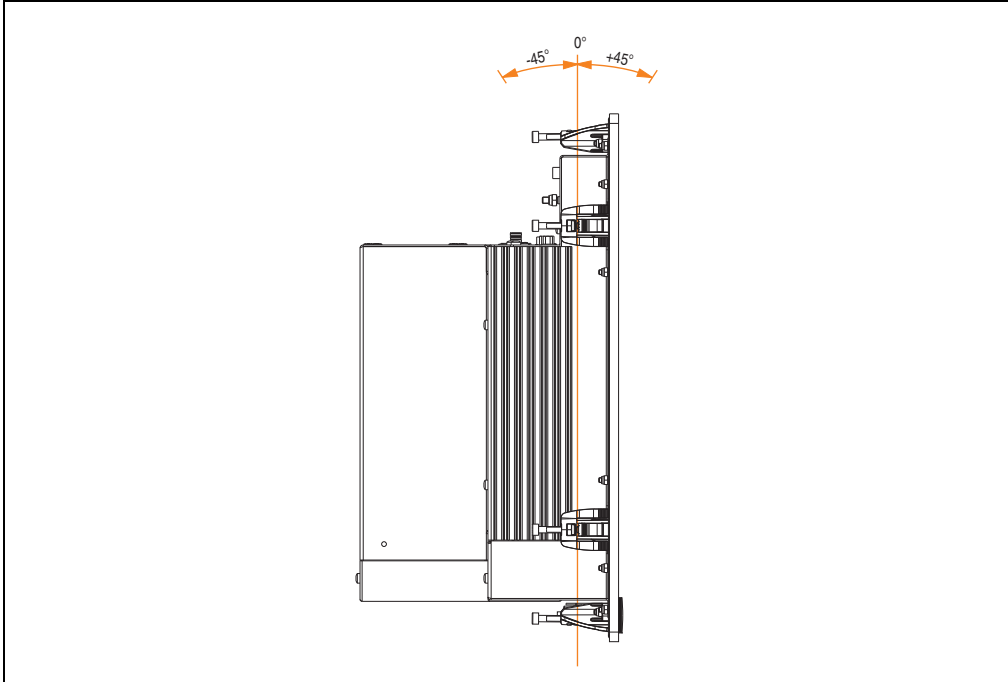


Figure 59: Mounting orientation - Standard mounting

In order to guarantee natural air circulation, mount the system so that the spacing on the top, bottom, and sides is as indicated in section 1.2.4 "Spacing for air circulation".

1.2.2 Standard mounting with 5AC801.DVRS-00

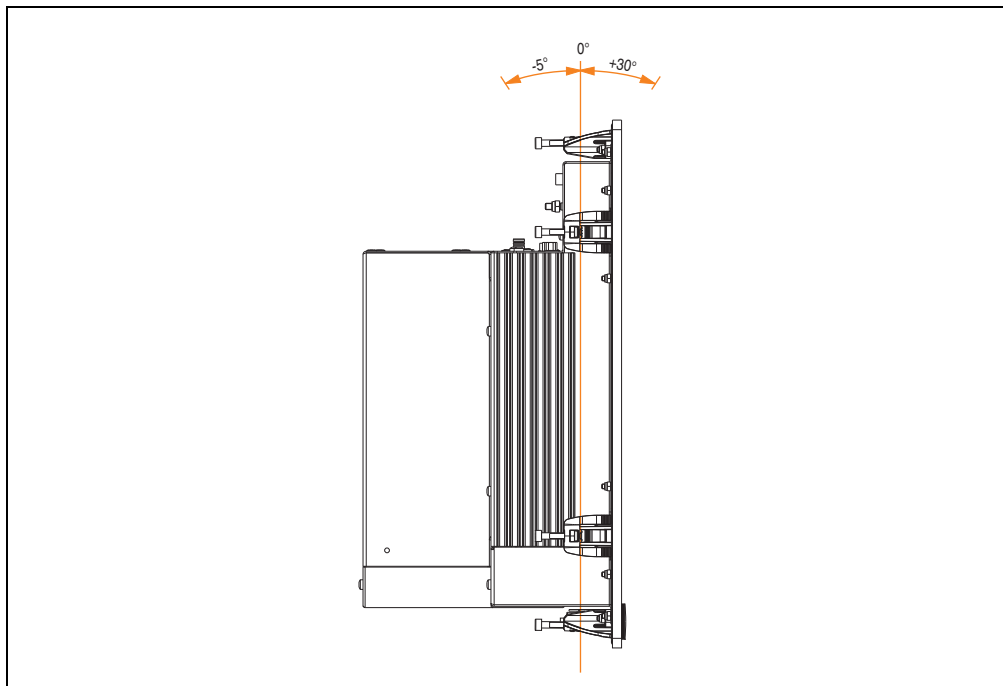


Figure 60: Mounting orientation - Standard mounting

In order to guarantee natural air circulation, mount the system so that the spacing on the top, bottom, and sides is as indicated in section 1.2.4 "Spacing for air circulation".

1.2.3 Standard mounting with 5AC801.DVDS-00

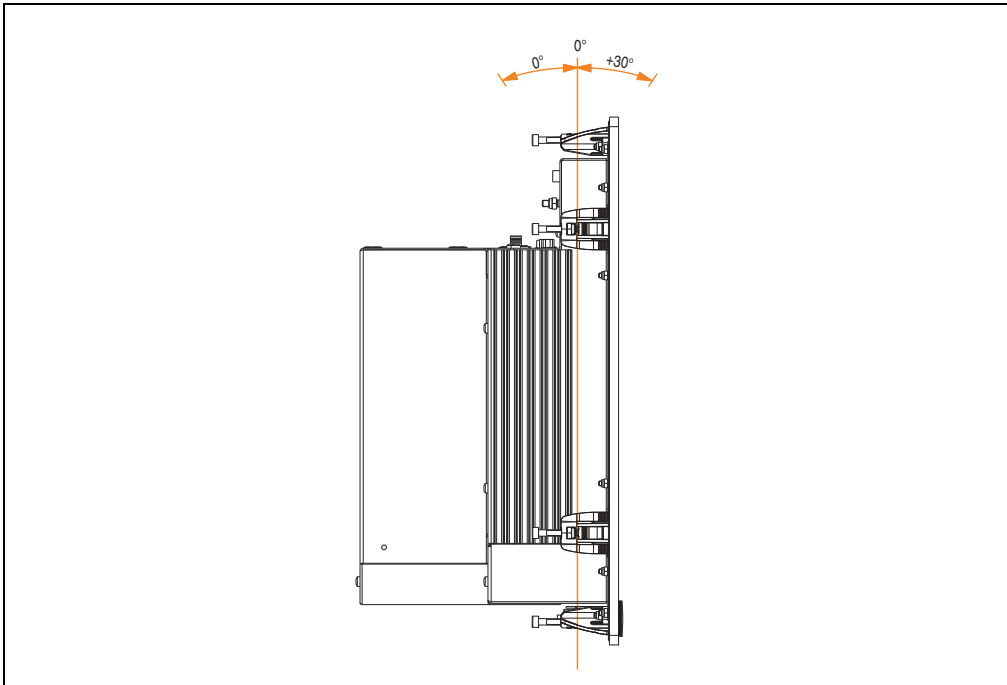


Figure 61: Mounting orientation - Standard mounting

In order to guarantee natural air circulation, mount the system so that the spacing on the top, bottom, and sides is as indicated in section 1.2.4 "Spacing for air circulation.".

1.2.4 Spacing for air circulation.

In order to guarantee proper air circulation, allow the specified amount of space above, below, to the side and behind the Panel PC 800. The minimum specified free space can be found in the diagram below.

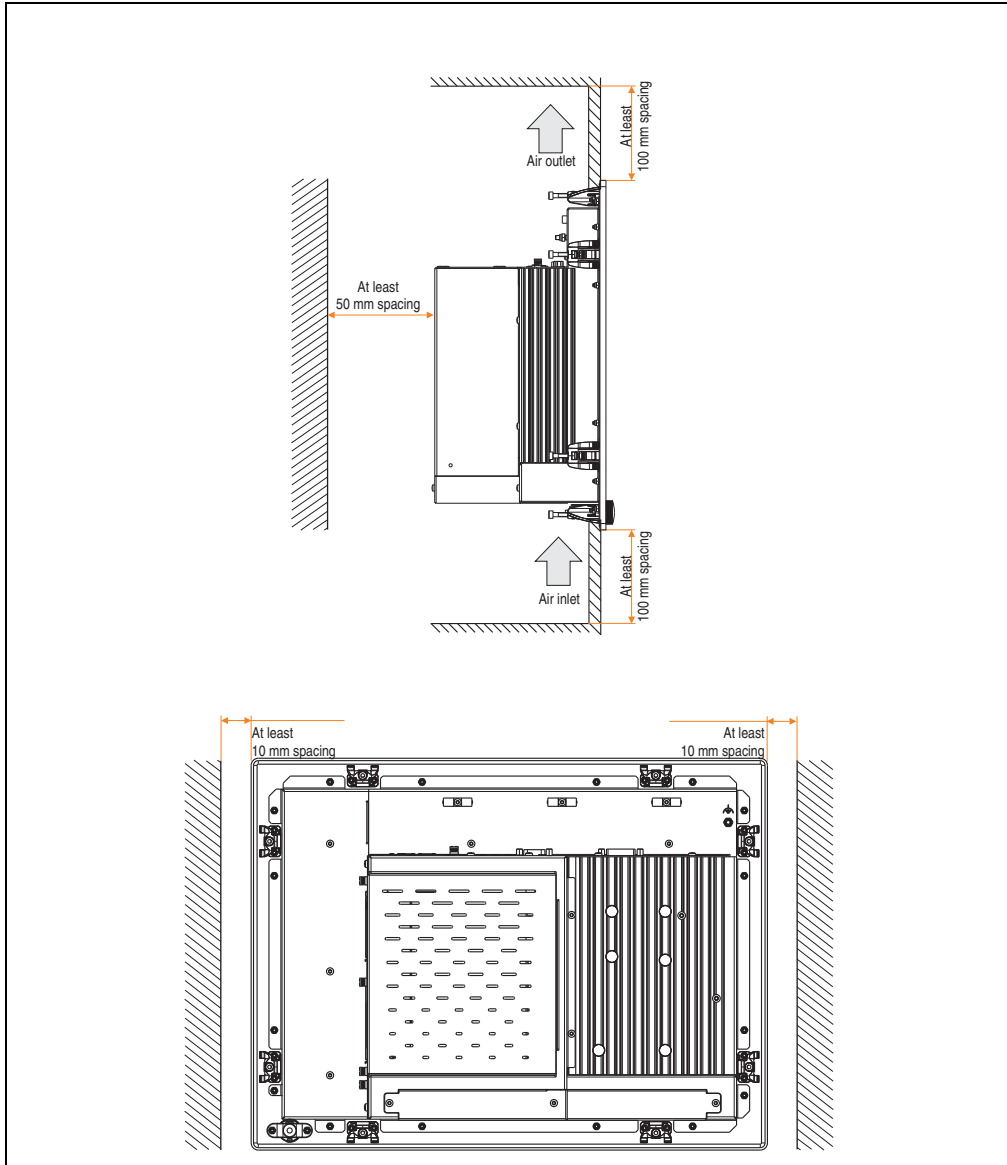


Figure 62: Distances for air circulation

2. Cable connections

When making cable connections and installing cables, it is not permitted to have a flex radius smaller than the minimum value specified.

Information:

The value specified for the minimum flex radius can be found in the technical data for the cable that is being used.

3. Grounding concept

The functional ground is a current path with low impedance between isolated circuits and ground, which is not a protective measure, but rather provides e.g. increased immunity to disturbances. It serves only as disturbance dissipation and not as contact protection for persons.

The PPC800 functional ground has 2 connections:

- Supply voltage
- Ground connection

To guarantee secure dissipation of electric disturbances, the following points should be observed:

- The device should be connected to the ground using the shortest route possible.
- Use cable with a minimum cross section of 2.5 mm^2 per connection.

Note the line shielding concept. All data cables connected to the device must use shielded lines.

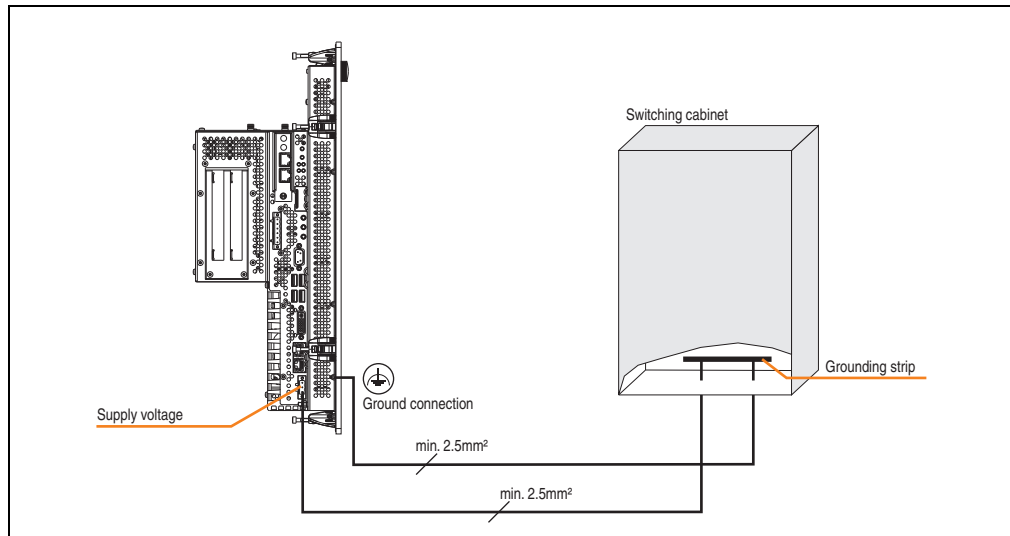


Figure 63: Grounding concept

4. Connection examples

The following examples provide an overview of the configuration options for connecting Automation Panel 800 and Automation Panel 900 and/or Automation Panel 800 devices with the PPC800. The following questions will be answered:

- How are Automation Panel 900 devices connected to the monitor / panel output of the PPC800, and what needs to be considered?
- How are Automation Panel 800 devices connected to the monitor / panel output of the PPC800, and what needs to be considered?
- What are "Display Clone" and "Extended Desktop" modes?
- How many Automation Panel 900 devices can be connected per line?
- How many Automation Panel 900 devices can be connected to an Automation Panel 800 device per line?
- How are the connected devices internally numbered?
- Are there limitations to the segment length and if so, what are they?
- What cables and link modules are needed?
- Do BIOS settings have to be changed for a specific configuration?

4.1 Selecting the display units

If an Automation Panel 800 and an Automation Panel 900 should be connected on the same line, the devices must have the same display type. The following table lists the AP900 devices that can be connected on the same line with an AP800 device.

Automation Panel 800	Automation Panel 900
5AP820.1505-00	5AP920.1505-01 5AP951.1505-01 5AP980.1505-01 5AP981.1505-01
5AP880.1505-00	5AP920.1505-01 5AP951.1505-01 5AP980.1505-01 5AP981.1505-01

Table 68: Selecting the display units

4.2 One Automation Panel 900 via DVI

An Automation Panel 900 with max. SXGA resolution is connected to the integrated DVI interface. As an alternative, an office TFT with DVI interface or an analog monitor (using adapter with model no. 5AC900.1000-00) can also be operated. A separate cable is used for touch screen and USB. If USB devices are to be operated on the Automation Panel 900, the maximum distance is 5 meters. USB devices can only be connected directly to the Automation Panel 900 (without a hub).

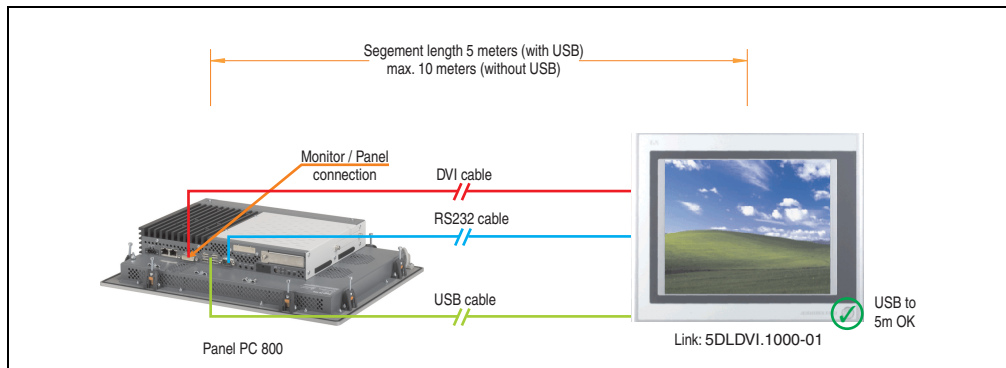


Figure 64: Configuration - One Automation Panel 900 via DVI

4.2.1 Basic system requirements

The following table displays the possible combinations for the PPC800 system unit with CPU board to implement the configuration shown in the figure above. If the maximum resolution is limited when making the combination then it is also shown in the following table (e.g. for connecting a non-B&R Automation Panel 900 device).

CPU board	with system unit		Limitation Resolution
	5PC820.1505-00	5PC820.1906-00	
5PC800.B945-00 5PC800.B945-10	✓	✓	Max. SXGA
5PC800.B945-01 5PC800.B945-11	✓	✓	Max. SXGA
5PC800.B945-02 5PC800.B945-12	✓	✓	Max. SXGA
5PC800.B945-03 5PC800.B945-13	✓	✓	Max. SXGA
5PC800.B945-04 5PC800.B945-14	✓	✓	Max. SXGA
5PC800.B945-05	✓	✓	Max. SXGA

Table 69: Possible combinations of system unit and CPU board

4.2.2 Link modules

Model number	Description	Note
5DL DVI.1000-01	Automation Panel Link DVI receiver connections for DVI-D, RS232 and USB 2.0 (Type B); 24VDC (screw clamp 0TB103.9 or cage clamp 0TB103.91 sold separately).	For Automation Panel 900

Table 70: Link module for the configuration - One Automation Panel 900 via DVI

4.2.3 Cables

Select one Automation Panel 900 cable each from the 3 required types.

Model number	Type	Length
5CADVI.0018-00	DVI cable	1.8 m
5CADVI.0050-00	DVI cable	5 m
5CADVI.0100-00	DVI cable	10 m ¹⁾
9A0014.02	Touch screen cable - serial	1.8 m
9A0014.05	Touch screen cable - serial	5 m
9A0014.10	Touch screen cable - serial	10 m ¹⁾
5CAUSB.0018-00	USB cable	1.8 m
5CAUSB.0050-00	USB cable	5 m

Table 71: Cables for DVI configurations

1) USB support is not possible on the Automation Panel 900 because USB is limited to 5 m.

Information:

Detailed technical data about the cables can be found in the Automation Panel 900 User's Manual. This can be downloaded as a .pdf file from the B&R homepage www.br-automation.com.

4.2.4 Possible Automation Panel units, resolutions und segment lengths

The following Automation Panel 900 units can be used. In rare cases, the segment length is limited according to the resolution.

Model number	Diagonal	Resolution	Touch screen	Keys	Max. segment length
5AP920.1043-01	10.4"	VGA	✓	-	5 m / 10 m ¹⁾
5AP920.1214-01	12.1"	SVGA	✓	-	5 m / 10 m ¹⁾
5AP920.1505-01	15.0"	XGA	✓	-	5 m / 10 m ¹⁾
5AP920.1706-01	17.0"	SXGA	✓	-	5 m / 10 m ¹⁾
5AP920.1906-01	19.0"	SXGA	✓	-	5 m / 10 m ¹⁾

Table 72: Possible Automation Panel units, resolutions und segment lengths

1) USB support is not possible on the Automation Panel 900 because USB is limited to 5 m.

Information:

The DVI transfer mode does not allow reading statistical values on Automation Panel 900 units.

4.2.5 BIOS settings

No special BIOS settings are necessary for operation.

4.3 One Automation Panel 900 via SDL

One Automation Panel 900 is connected to the integrated SDL interface via an SDL cable. USB devices can only be connected directly to the Automation Panel (without a hub).

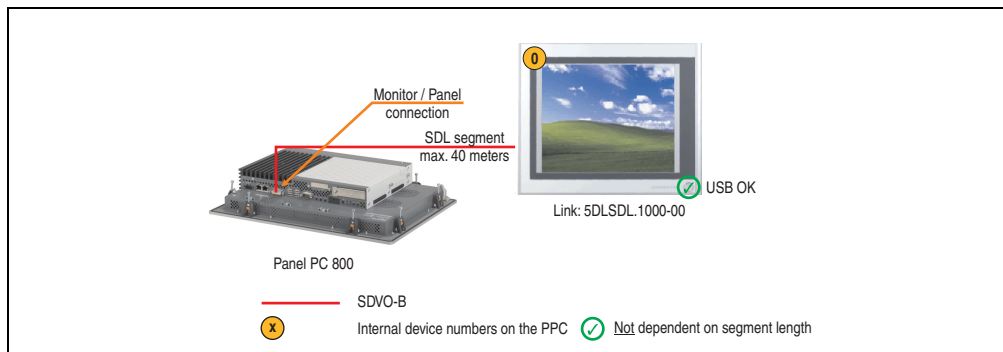


Figure 65: Configuration - One Automation Panel 900 via SDL

4.3.1 Basic system requirements

The following table displays the possible combinations for the PPC800 system unit with CPU board to implement the configuration shown in the figure above. If the maximum resolution is limited when making the combination then it is also shown in the following table (e.g. for connecting a non-B&R Automation Panel 900 device).

CPU board	with system unit		Limitation Resolution
	5PC820.1505-00	5PC820.1906-00	
5PC800.B945-00 5PC800.B945-10	✓	✓	Max. UXGA
5PC800.B945-01 5PC800.B945-11	✓	✓	Max. UXGA
5PC800.B945-02 5PC800.B945-12	✓	✓	Max. UXGA
5PC800.B945-03 5PC800.B945-13	✓	✓	Max. UXGA
5PC800.B945-04 5PC800.B945-14	✓	✓	Max. UXGA
5PC800.B945-05	✓	✓	Max. UXGA

Table 73: Possible combinations of system unit and CPU board

4.3.2 Link modules

Model number	Description	Note
5DLSDL.1000-00	Automation Panel Link SDL receiver Connection for SDL in, transfer of display data, touch screen, USB 1.1, matrix keys, and service data, 24 VDC (screw clamp 0TB103.9 or cage clamp 0TB103.91 sold separately).	For Automation Panel 900

Table 74: Link module for the configuration - One Automation Panel 900 via SDL

4.3.3 Cables

Select an Automation Panel 900 cable from the following table.

Model number	Type	Length
5CASDL.0018-00	SDL cable for a fixed type of layout	1.8 m
5CASDL.0018-01	SDL cable with 45° plug for fixed type of layout	1.8 m
5CASDL.0018-03	SDL cable for fixed and flexible type of layout	1.8 m
5CASDL.0050-00	SDL cable for a fixed type of layout	5 m
5CASDL.0050-01	SDL cable with 45° plug for fixed type of layout	5 m
5CASDL.0050-03	SDL cable for fixed and flexible type of layout	5 m
5CASDL.0100-00	SDL cable for a fixed type of layout	10 m
5CASDL.0100-01	SDL cable with 45° plug for fixed type of layout	10 m
5CASDL.0100-03	SDL cable for fixed and flexible type of layout	10 m
5CASDL.0150-00	SDL cable for a fixed type of layout	15 m
5CASDL.0150-01	SDL cable with 45° plug for fixed type of layout	15 m
5CASDL.0150-03	SDL cable for fixed and flexible type of layout	15 m
5CASDL.0200-00	SDL cable for a fixed type of layout	20 m
5CASDL.0200-03	SDL cable for fixed and flexible type of layout	20 m
5CASDL.0250-00	SDL cable for a fixed type of layout	25 m
5CASDL.0250-30	SDL cable for fixed and flexible type of layout	25 m
5CASDL.0300-00	SDL cable for a fixed type of layout	30 m
5CASDL.0300-03	SDL cable for fixed and flexible type of layout	30 m
5CASDL.0300-10	SDL cable with extender for a fixed type of layout	30 m
5CASDL.0300-13	SDL cable with extender for fixed and flexible type of layout	30 m
5CASDL.0400-10	SDL cable with extender for a fixed type of layout	40 m
5CASDL.0400-13	SDL cable with extender for fixed and flexible type of layout	40 m

Table 75: Cables for SDL configurations

Information:

Detailed technical data about the cables can be found in the Automation Panel 900 User's Manual. This can be downloaded as a .pdf file from the B&R homepage www.br-automation.com.

Cable lengths and resolutions for SDL transfer

The following table shows the relationship between segment lengths and the maximum resolution according to the SDL cable used:

Cables Segment length [m]	Resolution				
	VGA 640 x 480	SVGA 800 x 600	XGA 1024 x 768	SXGA 1280 x 1024	UXGA 1600 x 1200
1.8	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03
5	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03
10	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03
15	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	- - -
20	5CASDL.0200-00 5CASDL.0200-03	5CASDL.0200-00 5CASDL.0200-03	5CASDL.0200-00 5CASDL.0200-03	5CASDL.0200-00 5CASDL.0200-03	- -
25	5CASDL.0250-00 5CASDL.0250-03	5CASDL.0250-00 5CASDL.0250-03	5CASDL.0250-00 5CASDL.0250-03	- -	- -
30	5CASDL.0300-00 5CASDL.0300-03	5CASDL.0300-00 5CASDL.0300-03	5CASDL.0300-10 5CASDL.0300-13	5CASDL.0300-10 5CASDL.0300-13	- -
40	5CASDL.0400-10 5CASDL.0400-13	5CASDL.0400-10 5CASDL.0400-13	5CASDL.0400-10 5CASDL.0400-13	5CASDL.0400-10 5CASDL.0400-13	- -

Table 76: Segment lengths, resolutions and SDL cables

4.3.4 BIOS settings

No special BIOS settings are necessary for operation.

Touch screen functionality

The COM C must be enabled in BIOS in order to operate the connected panel touch screen on the monitor / panel connection (found in the BIOS menu under "Advanced - Main board / Panel Features - Legacy Devices").

4.4 One Automation Panel 800 via SDL

One Automation Panel 800 is connected to the integrated SDL interface via an SDL cable. USB devices can only be connected directly to the extension keyboard (without a hub).

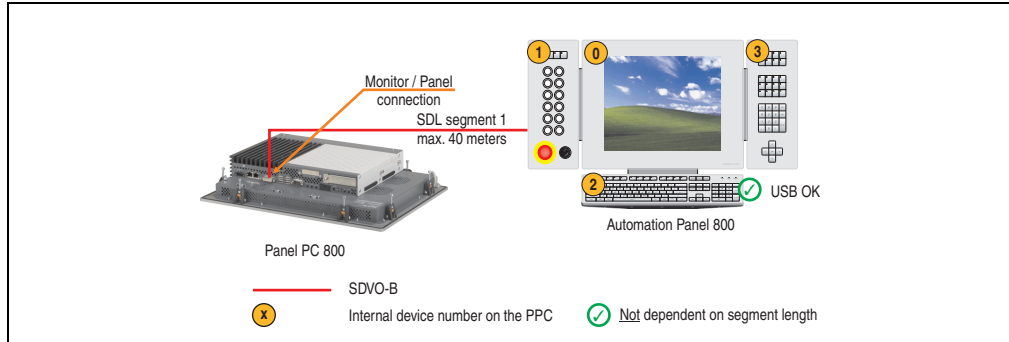


Figure 66: Configuration - One Automation Panel 800 via SDL

4.4.1 Basic system requirements

The following table displays the possible combinations for the PPC800 system unit with CPU board to implement the configuration shown in the figure above. If the maximum resolution is limited when making the combination then it is also shown in the following table (e.g. for connecting a non-B&R Automation Panel 900 device).

CPU board	with system unit		Limitation Resolution
	5PC820.1505-00	5PC820.1906-00	
5PC800.B945-00 5PC800.B945-10	✓	✓	Max. UXGA
5PC800.B945-01 5PC800.B945-11	✓	✓	Max. UXGA
5PC800.B945-02 5PC800.B945-12	✓	✓	Max. UXGA
5PC800.B945-03 5PC800.B945-13	✓	✓	Max. UXGA
5PC800.B945-04 5PC800.B945-14	✓	✓	Max. UXGA
5PC800.B945-05	✓	✓	Max. UXGA

Table 77: Possible combinations of system unit and CPU board

4.4.2 Cables

Select an Automation Panel 800 SDL cable from the following table.

Model number	Type	Length
5CASDL.0018-20	SDL cable for fixed and flexible type of layout	1.8 m
5CASDL.0050-20	SDL cable for fixed and flexible type of layout	5 m
5CASDL.0100-20	SDL cable for fixed and flexible type of layout	10 m
5CASDL.0150-20	SDL cable for fixed and flexible type of layout	15 m
5CASDL.0200-20	SDL cable for fixed and flexible type of layout	20 m
5CASDL.0250-20	SDL cable for fixed and flexible type of layout	25 m
5CASDL.0300-30	SDL cable with extender for fixed and flexible type of layout	30 m
5CASDL.0400-30	SDL cable with extender for fixed and flexible type of layout	40 m

Table 78: Cables for SDL configurations

Information:

Detailed technical data about the cables can be found in the Automation Panel 800 User's Manual. This can be downloaded as a .pdf file from the B&R homepage www.br-automation.com.

Cable lengths and resolutions for SDL transfer

The following table shows the relationship between segment lengths and the maximum resolution according to the SDL cable used:

Cables Segment length [m]	Resolution
	XGA 1024 x 768
1.8	5CASDL.0018-20
5	5CASDL.0050-20
10	5CASDL.0100-20
15	5CASDL.0150-20
20	5CASDL.0200-20
25	5CASDL.0250-20
30	5CASDL.0300-30
40	5CASDL.0400-30

Table 79: Segment lengths, resolutions and SDL cables

4.4.3 BIOS settings

No special BIOS settings are necessary for operation.

Touch screen functionality

The COM C must be enabled in BIOS in order to operate the connected panel touch screen on the monitor / panel connection (found in the BIOS menu under "Advanced - Main board / Panel Features - Legacy Devices").

4.5 One AP900 and one AP800 via SDL

One Automation Panel 900 and one Automation Panel 800 are connected to the integrated SDL interface via SDL.

USB is supported up to a maximum distance (segment 1 + segment 2) of 30 m on the two displays. Starting at a distance of 30 m, USB is only available on the first display (front and back) up to a maximum of 40 m. USB devices can only be connected directly to the Automation Panel 900 or extension keyboard (without a hub).

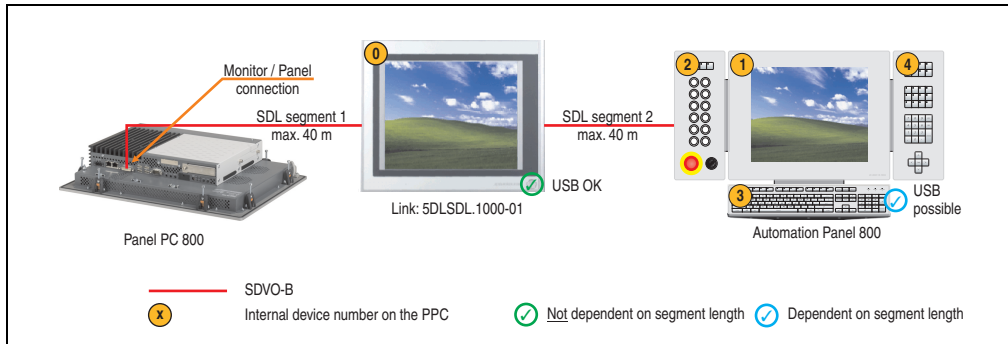


Figure 67: Configuration - One AP900 and one AP800 via SDL

4.5.1 Basic system requirements

The following table displays the possible combinations for the PPC800 system unit with CPU board to implement the configuration shown in the figure above. If the maximum resolution is limited when making the combination then it is also shown in the following table (e.g. for connecting a non-B&R Automation Panel 900 device).

CPU board	with system unit		Limitation Resolution
	5PC820.1505-00	5PC820.1906-00	
5PC800.B945-00 5PC800.B945-10	✓	✓	Max. UXGA
5PC800.B945-01 5PC800.B945-11	✓	✓	Max. UXGA
5PC800.B945-02 5PC800.B945-12	✓	✓	Max. UXGA
5PC800.B945-03 5PC800.B945-13	✓	✓	Max. UXGA
5PC800.B945-04 5PC800.B945-14	✓	✓	Max. UXGA
5PC800.B945-05	✓	✓	Max. UXGA

Table 80: Possible combinations of system unit and CPU board

4.5.2 Link modules

Model number	Description	Note
5DLSDL.1000-01	Automation Panel Link SDL transceiver Connections for SDL in, transfer of display data, touch screen, USB 1.1, matrix keys, and service data, 24 VDC (screw clamp 0TB103.9 or cage clamp 0TB103.91 sold separately).	For Automation Panel 900 1 pieces required

Table 81: Link modules for configuration - One AP900 and one AP800 via SDL

4.5.3 Cables

How to select an SDL cable for connecting the PPC800 display to the AP900 display4.3 "One Automation Panel 900 via SDL".

How to select an SDL cable for connecting the AP800 display to the AP900 display4.4 "One Automation Panel 800 via SDL".

Information:

Detailed technical data about the cables can be found in the Automation Panel 800 or Automation Panel 900 User's Manual. These can be downloaded as .pdf files from the B&R homepage www.br-automation.com.

4.5.4 BIOS settings

No special BIOS settings are necessary for operation.

Touch screen functionality

The COM C must be enabled in BIOS in order to operate the connected panel touch screen on the monitor / panel connection (found in the BIOS menu under "Advanced - Main board / Panel Features - Legacy Devices").

4.6 Four Automation Panel 900 units via SDL

One Automation Panel 900 is connected to the integrated SDL interface via an SDL cable. Up to three other Automation Panels of the same type are connected to this Automation Panel and operated via SDL. All four panels show the same content (Display Clone).

USB is supported up to a maximum distance (SDL segment 1 + SDL segment 2) of 30 m on the first two panels (front and back side). From a distance of 30 m and longer, USB is only available for the first panel (front and back side). USB devices can only be connected directly to the Automation Panel (without a hub).

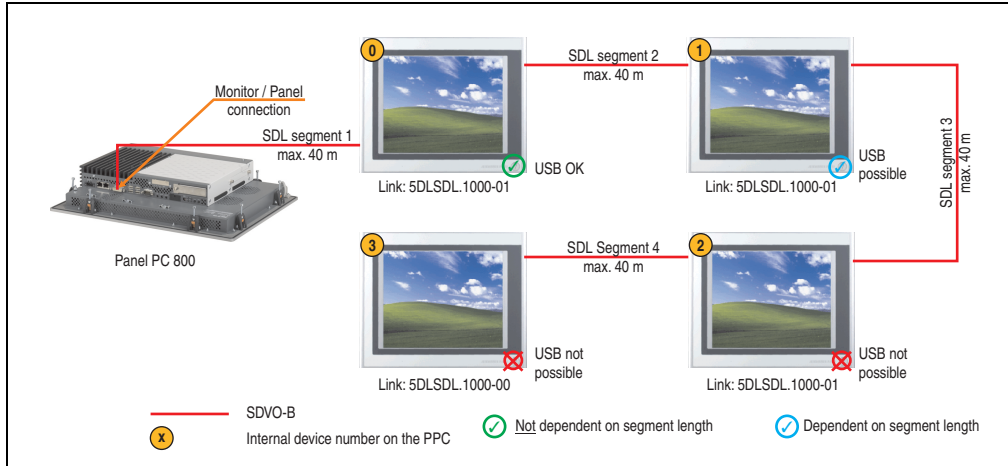


Figure 68: Configuration - Four Automation Panel 900 units via SDL

4.6.1 Basic system requirements

The following table displays the possible combinations for the PPC800 system unit with CPU board to implement the configuration shown in the figure above. If the maximum resolution is limited when making the combination then it is also shown in the following table (e.g. for connecting a non-B&R Automation Panel 900 device).

CPU board	with system unit		Limitation Resolution
	5PC820.1505-00	5PC820.1906-00	
5PC800.B945-00 5PC800.B945-10	✓	✓	Max. UXGA
5PC800.B945-01 5PC800.B945-11	✓	✓	Max. UXGA
5PC800.B945-02 5PC800.B945-12	✓	✓	Max. UXGA
5PC800.B945-03 5PC800.B945-13	✓	✓	Max. UXGA

Table 82: Possible combinations of system unit and CPU board

Commissioning • Connection examples

CPU board	with system unit		Limitation Resolution
	5PC820.1505-00	5PC820.1906-00	
5PC800.B945-04 5PC800.B945-14	✓	✓	Max. UXGA
5PC800.B945-05	✓	✓	Max. UXGA

Table 82: Possible combinations of system unit and CPU board

4.6.2 Link modules

Model number	Description	Note
5DLSDL.1000-00	Automation Panel Link SDL receiver Connection for SDL in, transfer of display data, touch screen, USB 1.1, matrix keys, and service data, 24 VDC (screw clamp 0TB103.9 or cage clamp 0TB103.91 sold separately).	For Automation Panel 900
5DLSDL.1000-01	Automation Panel Link SDL transceiver Connections for SDL in, transfer of display data, touch screen, USB 1.1, matrix keys, and service data, 24 VDC (screw clamp 0TB103.9 or cage clamp 0TB103.91 sold separately).	For Automation Panel 900 3 pieces required

Table 83: Link modules for the configuration: 4 Automation Panel 900 via SDL on 1 line

4.6.3 Cables

Select an Automation Panel 900 cable from the following table.

Model number	Type	Length
5CASDL.0018-00	SDL cable for a fixed type of layout	1.8 m
5CASDL.0018-01	SDL cable with 45° plug for fixed type of layout	1.8 m
5CASDL.0018-03	SDL cable for fixed and flexible type of layout	1.8 m
5CASDL.0050-00	SDL cable for a fixed type of layout	5 m
5CASDL.0050-01	SDL cable with 45° plug for fixed type of layout	5 m
5CASDL.0050-03	SDL cable for fixed and flexible type of layout	5 m
5CASDL.0100-00	SDL cable for a fixed type of layout	10 m
5CASDL.0100-01	SDL cable with 45° plug for fixed type of layout	10 m
5CASDL.0100-03	SDL cable for fixed and flexible type of layout	10 m
5CASDL.0150-00	SDL cable for a fixed type of layout	15 m
5CASDL.0150-01	SDL cable with 45° plug for fixed type of layout	15 m
5CASDL.0150-03	SDL cable for fixed and flexible type of layout	15 m
5CASDL.0200-00	SDL cable for a fixed type of layout	20 m
5CASDL.0200-03	SDL cable for fixed and flexible type of layout	20 m
5CASDL.0250-00	SDL cable for a fixed type of layout	25 m
5CASDL.0250-30	SDL cable for fixed and flexible type of layout	25 m
5CASDL.0300-00	SDL cable for a fixed type of layout	30 m
5CASDL.0300-03	SDL cable for fixed and flexible type of layout	30 m
5CASDL.0300-10	SDL cable with extender for a fixed type of layout	30 m

Table 84: Cables for SDL configurations

Model number	Type	Length
5CASDL.0300-13	SDL cable with extender for fixed and flexible type of layout	30 m
5CASDL.0400-10	SDL cable with extender for a fixed type of layout	40 m
5CASDL.0400-13	SDL cable with extender for fixed and flexible type of layout	40 m

Table 84: Cables for SDL configurations

Information:

Detailed technical data about the cables can be found in the Automation Panel 900 User's Manual. This can be downloaded as a .pdf file from the B&R homepage www.br-automation.com.

Cable lengths and resolutions for SDL transfer

The following table shows the relationship between segment lengths and the maximum resolution according to the SDL cable used:

Cables Segment length [m]	Resolution				
	VGA 640 x 480	SVGA 800 x 600	XGA 1024 x 768	SXGA 1280 x 1024	UXGA 1600 x 1200
1.8	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03	5CASDL.0018-00 5CASDL.0018-01 5CASDL.0018-03
5	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03	5CASDL.0050-00 5CASDL.0050-01 5CASDL.0050-03
10	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03	5CASDL.0100-00 5CASDL.0100-01 5CASDL.0100-03
15	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	5CASDL.0150-00 5CASDL.0150-01 5CASDL.0150-03	- - -
20	5CASDL.0200-00 5CASDL.0200-03	5CASDL.0200-00 5CASDL.0200-03	5CASDL.0200-00 5CASDL.0200-03	5CASDL.0200-00 5CASDL.0200-03	- -
25	5CASDL.0250-00 5CASDL.0250-03	5CASDL.0250-00 5CASDL.0250-03	5CASDL.0250-00 5CASDL.0250-03	- -	- -
30	5CASDL.0300-00 5CASDL.0300-03	5CASDL.0300-00 5CASDL.0300-03	5CASDL.0300-10 5CASDL.0300-13	5CASDL.0300-10 5CASDL.0300-13	- -
40	5CASDL.0400-10 5CASDL.0400-13	5CASDL.0400-10 5CASDL.0400-13	5CASDL.0400-10 5CASDL.0400-13	5CASDL.0400-10 5CASDL.0400-13	- -

Table 85: Segment lengths, resolutions and SDL cables

4.6.4 BIOS settings

No special BIOS settings are necessary for operation.

Touch screen functionality

The COM C must be enabled in BIOS in order to operate the connected panel touch screen on the monitor / panel connection (found in the BIOS menu under "Advanced - Main board / Panel Features - Legacy Devices").

5. Touch screen calibration

B&R touch screen devices are equipped with a touch controller, which supports hardware calibration. This means that the devices are pre-calibrated from stock (pre-calibration). This feature proves advantageous in the case of a replacement part because a new calibration is no longer required when exchanging devices (identical model / type). Nevertheless, we recommend calibrating the device in order to achieve the best results and to better readjust the touch screen to the user's preferences.

Regardless of this, the touch screen driver requires calibration following installation.

5.1 Windows XP Professional

After installing Windows XP Professional, the touch screen driver must be installed in the device in order to operate the touch screen. The corresponding drivers can be downloaded from the download area on the B&R homepage (www.br-automation.com). The touch screen should be calibrated while installing the driver.

5.2 Windows CE

Windows CE starts the touch screen calibration sequence during its first boot in the default configuration / delivered state.

5.3 Windows XP Embedded

After first starting Windows XP Embedded (First Boot Agent), the touch screen driver must be installed in the device in order to operate the touch screen. The corresponding drivers can be downloaded from the download area on the B&R homepage (www.br-automation.com). The touch screen should be calibrated while installing the driver.

5.4 Windows Embedded Standard 2009

After first starting Windows Embedded Standard 2009 (First Boot Agent), the touch screen driver must be installed in the device in order to operate the touch screen. The corresponding drivers can be downloaded from the download area on the B&R homepage (www.br-automation.com). The touch screen should be calibrated while installing the driver.

5.5 Automation Runtime / Visual Components

The first time the touch screen is used, it must be calibrated once in the customer application for the existing device and project.

6. Connection of USB peripheral devices

Warning!

Peripheral USB devices can be connected to the USB interfaces. Due to the vast number of USB devices available on the market, B&R cannot guarantee their performance. B&R does ensure the performance of all USB devices that they provide.

6.1 Locally on the PPC800

Many different peripheral USB devices can be connected to the 2 or 5 USB interfaces on the Panel PC 800. These can each handle a maximum load of 1A. The maximum transfer rate is USB 2.0.

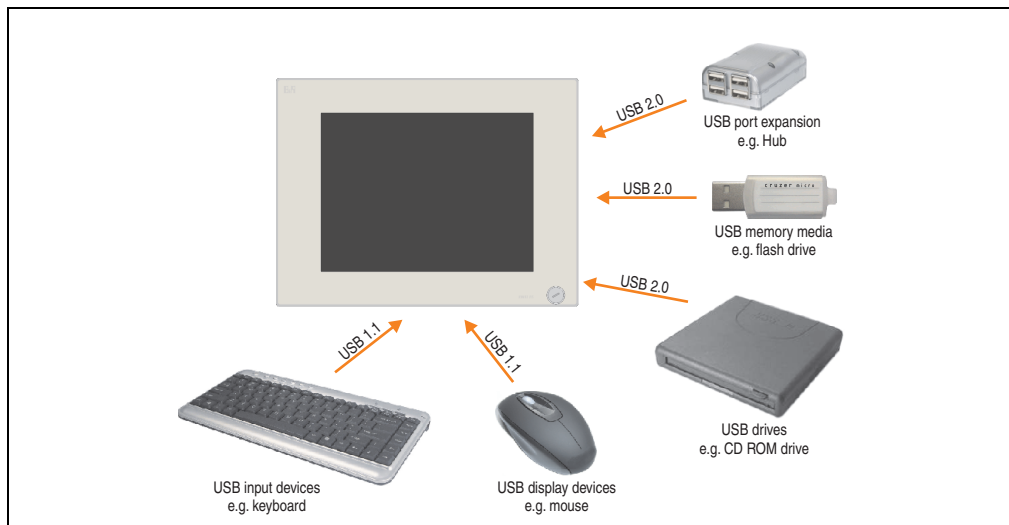


Figure 69: Local connection of USB peripheral devices on the PPC800

6.2 Remote connection to Automation Panel 900 via DVI

Many different peripheral USB devices can be connected to the 2 or 3 USB interfaces on the Automation Panel 900. These can each handle a load of 500 mA. The maximum transfer rate is USB 2.0.

Information:

Only end devices (no hubs) can be connected to the Automation Panel 900.

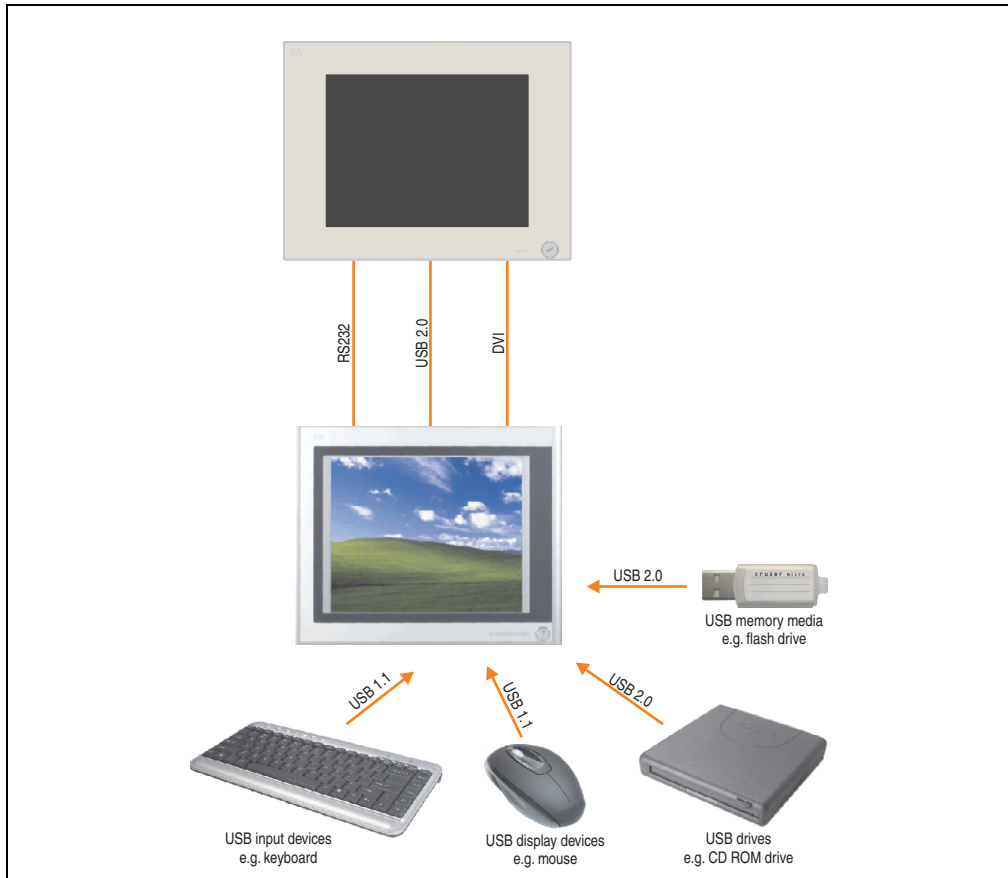


Figure 70: Remote connection of USB peripheral devices to the APC900 via DVI

6.3 Remote connection to Automation Panel 800/900 via SDL

Many different peripheral USB devices can be connected to the 2 or 3 USB interfaces on Automation Panel 900 and/or USB connections on the Automation Panel 800 devices. These can each handle a load of 500 mA. The maximum transfer rate is USB 1.1.

Information:

Only end devices (no hubs) can be connected to the Automation Panel 800/900.

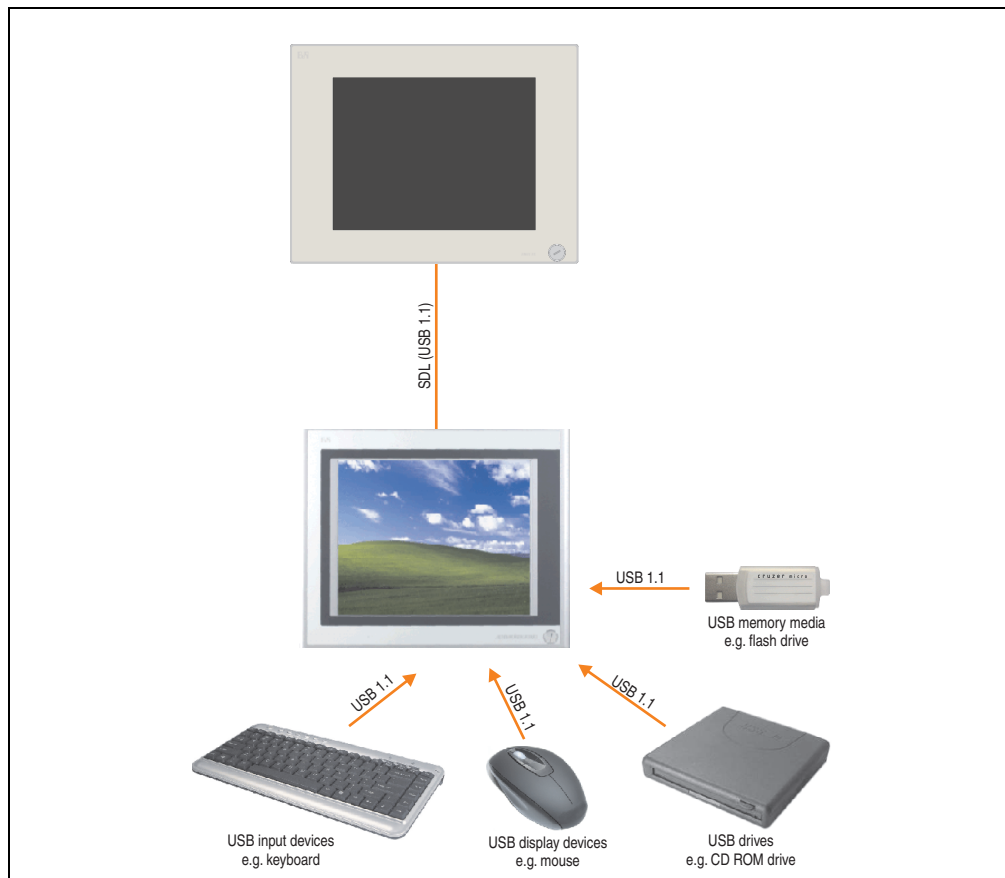


Figure 71: Remote connection of USB peripheral devices to the APC800/900 via SDL

7. Configuration of a SATA RAID array

Information:

The following software description is valid for PCI SATA controllers 5ACPCI.RAIC-01 and 5ACPCI.RAIC-03.

You must enter the BIOS "RAID Configuration Utility" in order to make the necessary settings. After the POST, enter <Ctrl+S> or <F4> to open RAID BIOS.

```
SiI 3512A SATAraid BIOS Verison 4.3.79
Copyright (C) 1997-2006 Silicon Image, Inc.

Press <Ctrl+S> or F4 to enter RAID utility
0   ST96023AS                      55 GB
1   ST96023AS                      55 GB
```

Figure 72: Open the RAID Configuration Utility

```
RAID Configuration Utility - Silicon Image Inc. Copyright (C) 2006

Create RAID set
Delete RAID set
Rebuild Mirrored set
Resolve Conflicts
Low Level Format

* 0 PM   ST96023AS                      55GB
  1 SM   ST96023AS                      55GB

Press " Enter" to create RAID set

↑↓   Select Menu
ESC   Previous Menu
Enter Select
Ctrl-E Exit

*     First HDD
```

Figure 73: RAID Configuration Utility - Menu

Commissioning • Configuration of a SATA RAID array

The following keys can be used after entering the BIOS setup:

Key	Function
Cursor ↑	Go to previous item.
Cursor ↓	Go to the next item.
Enter	Select an item or open a submenu.
ESC	Go back to previous menu.
Ctrl+E	Exit setup and save the changed settings.

Table 86: BIOS-relevant keys in the RAID Configuration Utility

7.1 Create RAID set

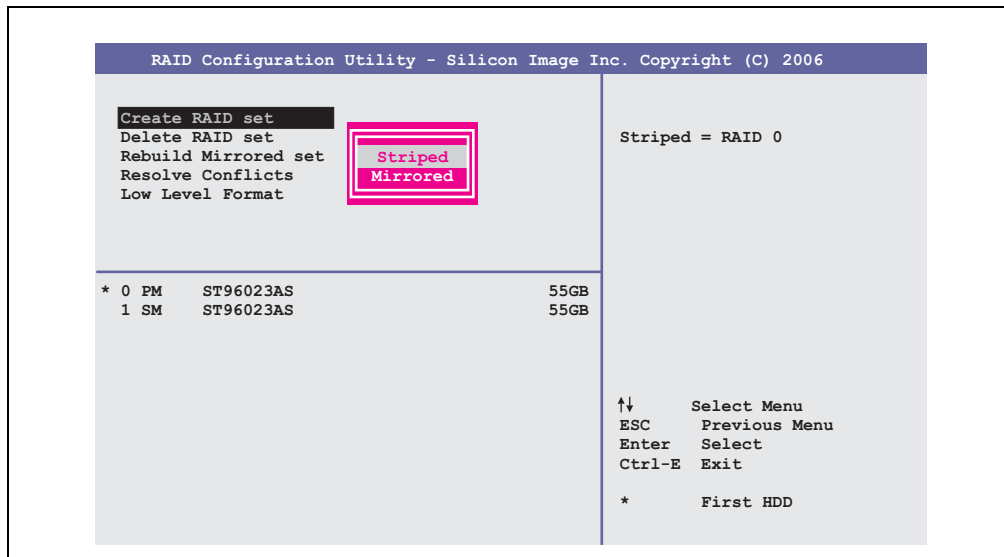


Figure 74: RAID Configuration Utility - Menu

The RAID system can be recreated as "Striped" = RAID0 or "Mirrored" = RAID1 using the menu "Create RAID set".

7.1.1 Create RAID set - Striped

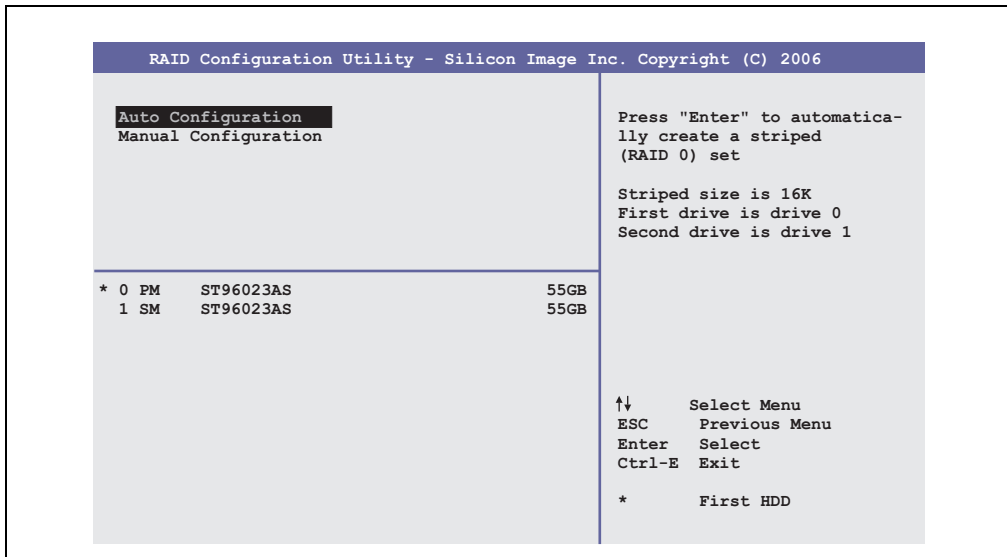


Figure 75: RAID Configuration Utility - Create RAID set - Striped

Auto configuration

Auto configuration optimizes all settings.

"Manual configuration"

It is possible to specify the first and second HDD as well as the "Chunk Size" (= block size, application-dependent).

7.1.2 Create RAID set - Mirrored

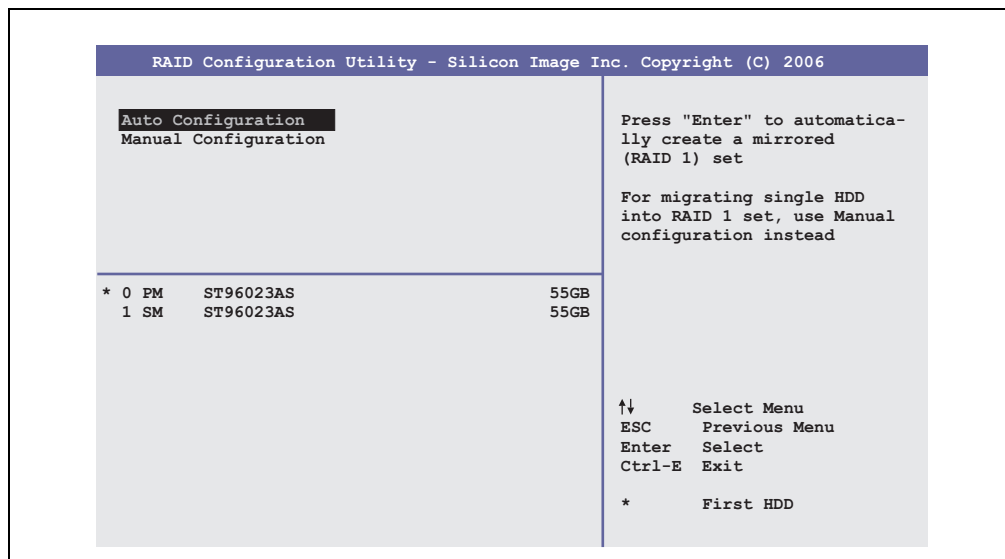


Figure 76: RAID Configuration Utility - Create RAID set - Mirrored

Auto configuration

Auto configuration optimizes all settings.

"Manual configuration"

It is possible to specify the "Source" and "Target" HDD, and also to specify whether a rebuild (mirror) should be performed immediately (approx. 50 minutes).

7.2 Delete RAID set

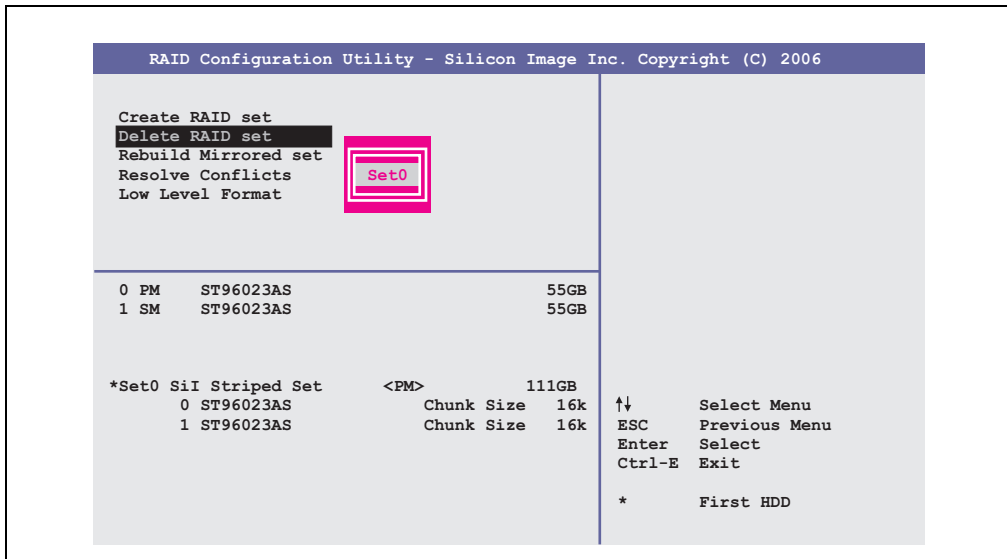


Figure 77: RAID Configuration Utility - Delete RAID set

An existing RAID set can be deleted using the menu "Delete RAID set".

7.3 Rebuild mirrored set

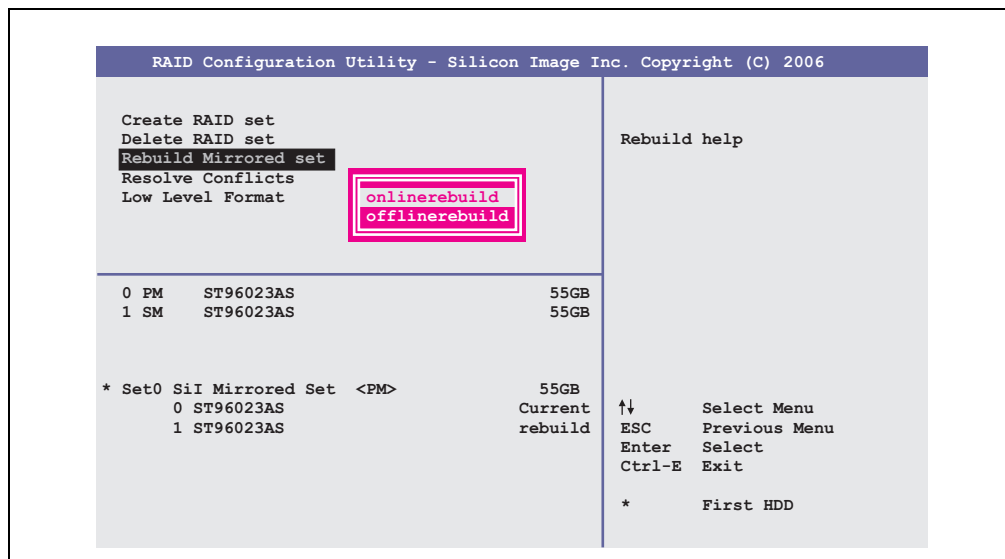


Figure 78: RAID Configuration Utility - Rebuild mirrored set

The "Rebuild mirrored set" menu can be used to restart a rebuild procedure in a RAID 1 network if an error occurs, after first interrupting the rebuild procedure or when exchanging a hard disk.

If "onlinerebuild" is selected, then the rebuild is executed during operation after the system is booted. E.g. an event pop-up is displayed by the installed SATA RAID configuration program: `SATAraid detected a new event and the rebuild is started`. The entire rebuild lasts approximately 50 minutes.

If "offlinerebuild" is selected, then a rebuild is performed immediately before starting the operating system (lasts approximately 30 minutes).

7.4 Resolve conflicts

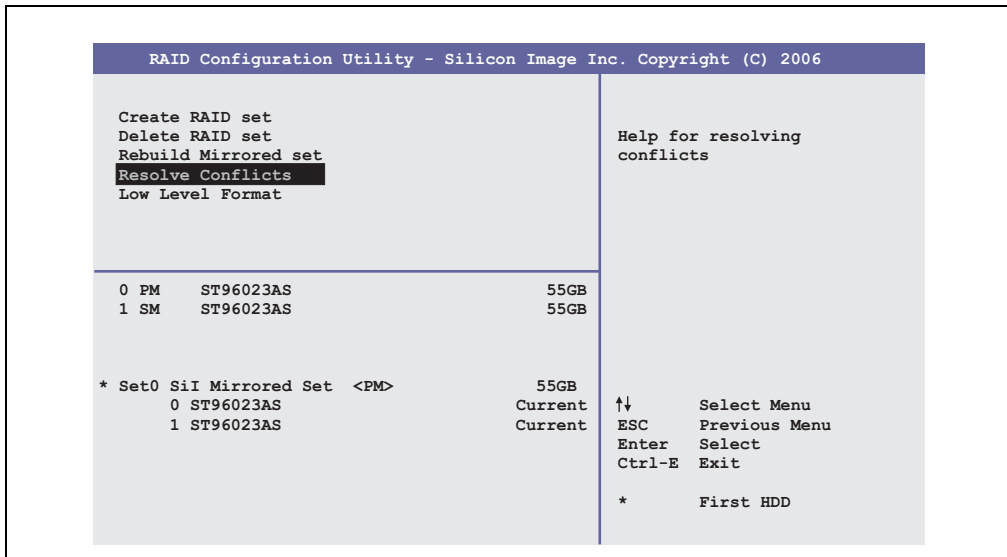


Figure 79: RAID Configuration Utility - Resolve conflicts

Conflicts in a RAID set can be resolved using the "Resolve conflicts" menu. This function is only available if the status of the hard disk is "conflict".

7.5 Low level format

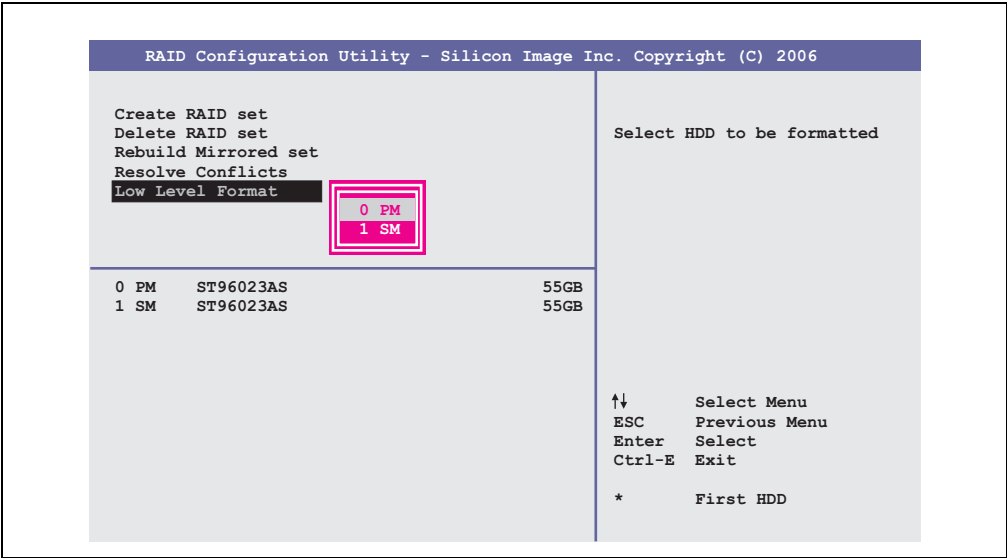


Figure 80: RAID Configuration Utility - Low level format

Individual hard disks can be configured using the "Low Level Format" menu. This can only be done if a RAID set is not configured. A low level format of a hard disk takes approx. 40 minutes.

8. Known problems / issues

The following issue for the PPC800 devices is known:

- Using two different types of CompactFlash cards can cause problems in Automation PCs and Panel PCs. This can result in one of the two cards not being detected during system startup. This is caused by varying startup speeds. CompactFlash cards with older technology require significantly more time during system startup than CompactFlash cards with newer technology. This behavior occurs near the limits of the time frame provided for startup. The problem described above can occur because the startup time for the CompactFlash cards fluctuates due to the variance of the components being used. Depending on the CompactFlash cards being used, this error might never, sometimes or always occur.
- During daisy chain operation of multiple AP800/AP900 devices via SDL, it's possible that the touch controller status shows a red "X" in the Control Center applet for the touch screen driver when the touch controller is detected. The functionality of the touch system is not affected by this. This can be avoided by setting a panel locking time of 50 ms. The panel locking time can be configured with the B&R Key Editor.

9. User tips for increasing the display lifespan

9.1 Backlight

The lifespan of the backlight is specified in "Half Brightness Time". An operating time of 50,000 hours would mean that the display brightness would still be 50% after this time.

9.1.1 How can the lifespan of backlights be extended?

- Set the display brightness to the lowest value that is still comfortable for the eyes
- Use dark images
- Reducing the brightness by 50% can result in an approximate 50% increase of the half-brightness time.

9.2 Image sticking

Image sticking is the "burning in" of a static image on a display after being displayed for a prolonged period of time. However, this does not only occur with static images. Image sticking is known in technical literature as the "burn-in effect", "image retention", "memory effect", "memory sticking" or "ghost image".

There are 2 types of this:

- Area type: This is seen with a dark gray image. The effect disappears if the display is switched off for a longer period of time.
- Line type: This can cause lasting damage.

9.2.1 What causes image sticking?

- Static images
- Screensaver not enabled
- Sharp contrast transitions (e.g. black / white)
- High ambient temperatures
- Operation outside of the specifications

9.2.2 How can image sticking be avoided?

- continual change between static and dynamic images
- avoiding excessive brightness contrast between foreground and background display
- use of colors with similar brightness
- use of complementary colors in subsequent images
- use of screensavers

Chapter 4 • Software

1. BIOS options

Information:

The following diagrams and BIOS menu items including descriptions refer to BIOS version 1.15. It is therefore possible that these diagrams and BIOS descriptions do not correspond with the installed BIOS version.

1.1 General information

BIOS stands for "Basic Input Output System". It is the most basic standardized communication between the user and the system (hardware). The BIOS system used in the Panel PC 800 systems is produced by American Megatrends Inc.

The BIOS Setup Utility lets you modify basic system configuration settings. These settings are stored in CMOS and in EEPROM (as a backup).

The CMOS data is buffered by a battery (if present), and remains in the PPC800 even when the power is turned off (no 24VDC supply).

1.2 BIOS setup and boot procedure

BIOS is immediately activated when switching on the power supply of the Panel PC 800 system or pressing the power button. The system checks if the setup data from the EEPROM is "OK". If the data is "OK", then it is transferred to the CMOS. If the data is "not OK", then the CMOS data is checked for validity. An error message is output if the CMOS data contains errors and the boot procedure can be continued by pressing the <F1> key. To prevent the error message from appearing at each restart, open the BIOS setup by pressing the key and re-save the settings.

BIOS reads the system configuration information in CMOS RAM, checks the system, and configures it using the Power On Self Test (POST).

When these "preliminaries" are finished, BIOS seeks an operating system in the data storage devices available (hard drive, floppy drive, etc.). BIOS launches the operating system and hands over control of system operations to it.

To enter BIOS Setup, the DEL key must be pressed after the USB controller has been initialized as soon as the following message appears on the monitor (during POST):

"Press DEL to run SETUP"

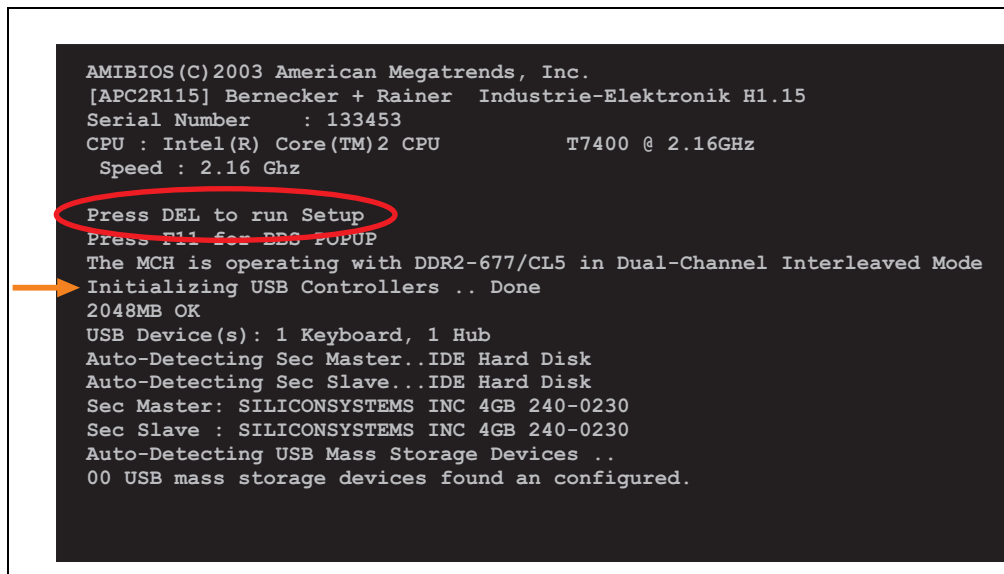


Figure 81: Boot screen

1.2.1 BIOS setup keys

The following keys are enabled during the POST:

Information:

The key signals from the USB keyboard are only registered after the USB controller has been initialized.

Key	Function
Del	Enters the BIOS setup menu.
F12	Using the F12 key, you can boot from the network.

Table 87: 945GME - Bios-relevant keys at POST

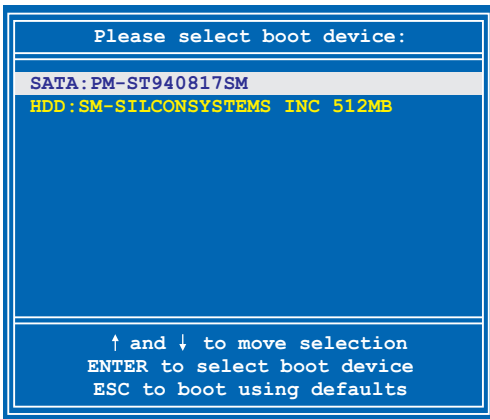
Key	Function
F11	Cues the boot menu. Lists all bootable devices that are connected to the system. With cursor ↑ and cursor ↓ and by pressing <ENTER>, select the device from which will be booted. 
<Pause>	Pressing the <pause> key stops the POST. Press any other key to resume the POST.

Table 87: 945GME - Bios-relevant keys at POST

The following keys can be used after entering the BIOS setup:

Key	Function
F1	General help.
Cursor ↑	Moves to the previous item.
Cursor ↓	Go to the next item.
Cursor ←	Moves to the previous item.
Cursor →	Go to the next item.
+ -	Changes the setting of the selected function.
Enter	Changes to the selected menu.
PageUp ↑	Change to the previous page.
PageDown ↓	Change to the previous page.
Pos 1	Jumps to the first BIOS menu item or object.
End	Jumps to the last BIOS menu item or object.
F2 / F3	The colors of the BIOS Setup are switched.
F7	Changes are reset.
F9	These settings are loaded for all BIOS configurations.
F10	Save and close.
Esc	Exits the submenu.

Table 88: 945GME - Bios-relevant keys in the BIOS menu

1.3 Main

Immediately after the DEL button is pressed during startup, the main BIOS setup menu appears.

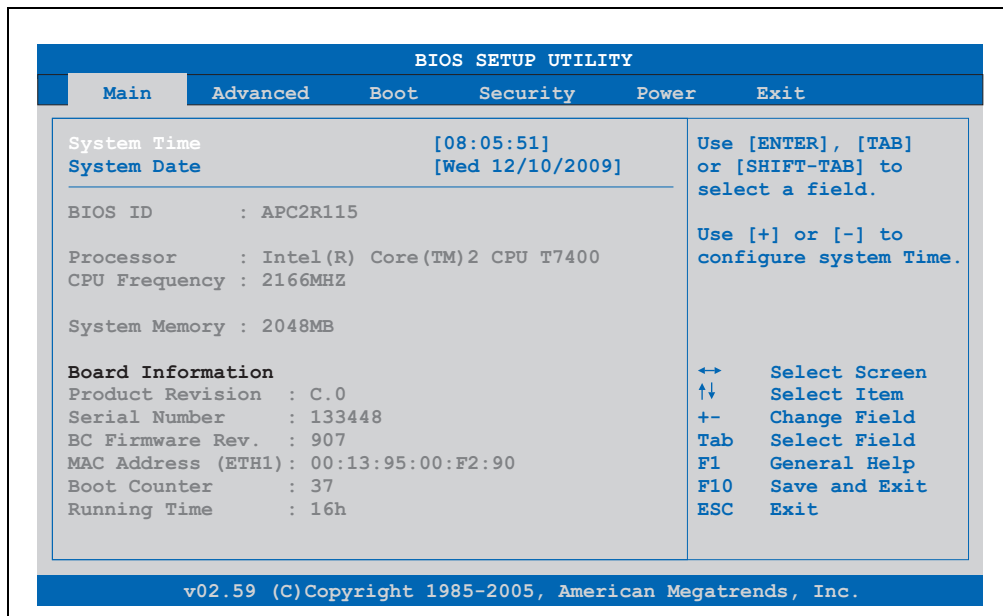


Figure 82: 945GME - BIOS Main Menu

BIOS setting	Meaning	Setting options	Effect
System Time	This is the current system time setting. The time is buffered by a battery (CMOS battery) after the system has been switched off.	Changes the system time	Set the system time in the format Hour:Minute:Second (hh:mm:ss).
System Date	This is the current system date setting. The time is buffered by a battery (CMOS battery) after the system has been switched off.	Changes the system date	Sets the system date in the format Month:Day:Year (mm:dd:yyyy).
BIOS ID	Displays the BIOS recognition.	None	-
Processor	Displays the processor type.	None	-
CPU Frequency	Displays the processor frequency.	None	-
System Memory	Displays the system memory size.	None	-
Product Revision	Displays the CPU board HW revision.	None	-
Serial Number	Displays the CPU board serial number.	None	-
BC Firmware Rev.	Displays the CPU board controller firmware revision.	None	-
MAC Address (ETH1)	Displays the MAC addresses assigned for the ETH1 interface.	None	-

Table 89: 945GME - Main Menu - Setting options

BIOS setting	Meaning	Setting options	Effect
Boot Counter	Displays the boot counter - each restart increments the counter by one (max. 16777215).	None	-
Running Time	Displays the runtime in whole hours. (max. 65535).	None	-

Table 89: 945GME - Main Menu - Setting options (cont.)

1.4 Advanced

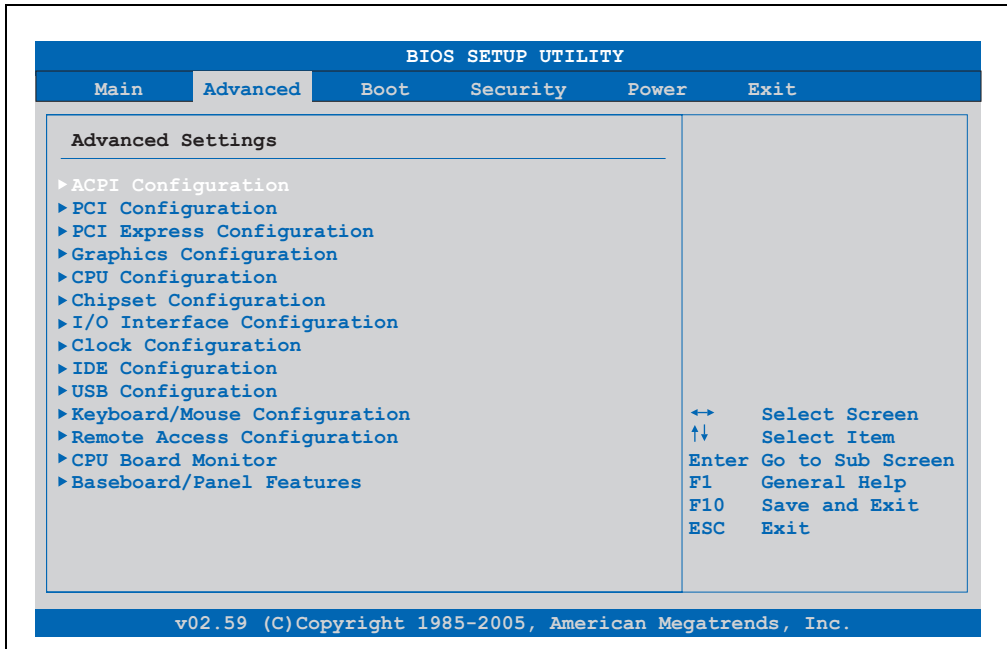


Figure 83: 945GME - Advanced Menu

BIOS setting	Meaning	Setting options	Effect
ACPI configuration	Configures the ACPI devices.	Enter	Opens the submenu See "ACPI configuration", on page 173.
PCI Configuration	Configures PCI devices.	Enter	Opens the submenu See "PCI Configuration", on page 175.
PCI express configuration	Configures the PCI Express.	Enter	Opens the submenu See "PCI express configuration", on page 179.
Graphics configuration	Configures the graphics settings.	Enter	Opens the submenu See "Graphics configuration", on page 181.
CPU configuration	Configures the CPU settings.	Enter	Opens the submenu See "CPU configuration", on page 185.

Table 90: 945GME - Advanced Menu - Setting options

BIOS setting	Meaning	Setting options	Effect
Chipset configuration	Configures the chipset functions.	Enter	Opens the submenu See "Chipset configuration", on page 186.
I/O interface configuration	Configures the I/O devices.	Enter	Opens the submenu See "I/O interface configuration", on page 188.
Clock Configuration	Configures the clock settings.	Enter	Opens the submenu See "Clock Configuration", on page 189.
IDE Configuration	Configures the IDE functions.	Enter	Opens the submenu See "IDE Configuration", on page 190.
USB configuration	Configures the USB settings.	Enter	Opens the submenu See "USB configuration", on page 198.
Keyboard/mouse configuration	Configures the keyboard/mouse options.	Enter	Opens the submenu See "Keyboard/mouse configuration", on page 200.
Remote access configuration	Configures the remote access settings.	Enter	Opens the submenu See "Remote access configuration", on page 201.
CPU board monitor	Displays the current voltages and temperature of the processor in use.	Enter	Opens the submenu See "CPU board monitor", on page 203.
Main Board/Panel Features	Displays device specific information and setup of device specific values.	Enter	Opens the submenu See "Main Board/Panel Features", on page 204.

Table 90: 945GME - Advanced Menu - Setting options (cont.)

1.4.1 ACPI configuration

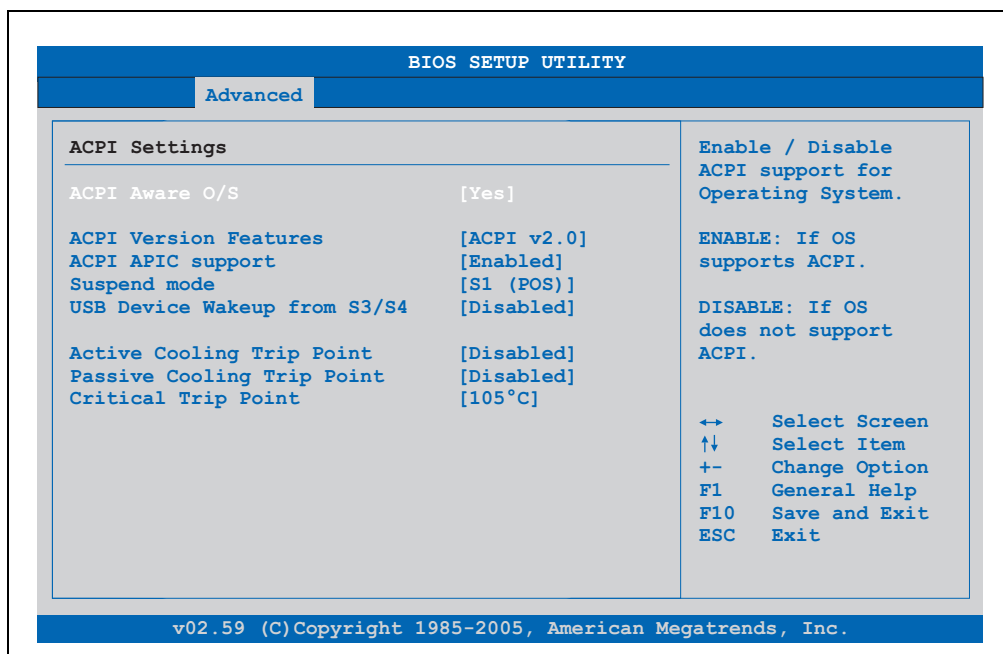


Figure 84: 945GME - Advanced ACPI configuration

BIOS setting	Meaning	Setting options	Effect
ACPI Aware O/S	This function determines if the operating system supports the ACPI function (Advanced Configuration and Power Interface).	Yes	The operating system supports ACPI.
		No	The operating system does not support ACPI.
ACPI Version Features	Option for setting the power option specifications to be supported. The ACPI functions must be supported by the drivers and operating systems being used.	ACPI v1.0	ACPI functions in accordance with v1.0
		ACPI v2.0	ACPI functions in accordance with v2.0
		ACPI v3.0	ACPI functions in accordance with v3.0
ACPI APIC support	This option controls the support of the advanced programmable interrupt controller in the processor.	Enabled	Enables this function.
		Disabled	Disables the function
Suspend mode	Selects the ACPI status to be used when Suspend Mode is enabled.	S1 (POS)	Sets S1 as Suspend mode. Only a few functions are disabled and are available again at the touch of a button
		S3 (STR)	Sets S3 as Suspend Mode. The current state of the operating system is written to the RAM, which is then supplied solely with power.
USB Device Wakeup from S3/S4	This options makes it possible for activity on a connected USB device to wake the system up from the S3/S4 standby mode.	Enabled	Enables this function.
		Disabled	Disables the function

Table 91: 945GME - Advanced ACPI configuration - Setting options

BIOS setting	Meaning	Setting options	Effect
Active Cooling Trip Point	With this function, an optional CPU fan above the operating system can be set to turn on when the CPU reaches the set temperature.	Disabled	Disables this function.
		50°C, 60°C, 70°C, 80°C, 90°C	Temperature setting for the active cooling trip point. Can be set in 10 degree increments.
Passive Cooling Trip Point	With this function, a temperature can be set at which the CPU automatically reduces its speed.	Disabled	Disables this function.
		50°C, 60°C, 70°C, 80°C, 90°C	Temperature setting for the passive cooling trip point. Can be set in 10 degree increments.
Critical Trip Point	With this function, a temperature can be set at which the operating system automatically shuts itself down.	80°C, 85°C, 90°C, 95°C, 100°C, 105°C, 110°C	Temperature setting for the critical trip point. Can be set in 5 degree increments.

Table 91: 945GME - Advanced ACPI configuration - Setting options (cont.)

1.4.2 PCI Configuration

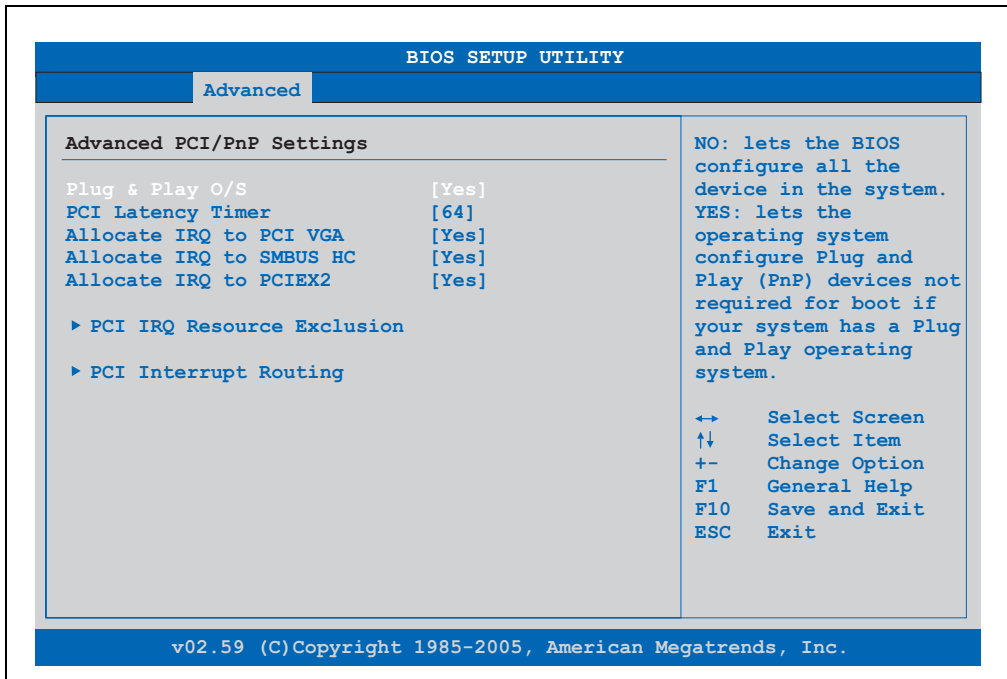


Figure 85: 945GME - Advanced PCI Configuration

BIOS setting	Meaning	Setting options	Effect
Plug & Play O/S	BIOS is informed if Plug & Play is capable on the operating system.	Yes	The operating system handles the distribution of resources.
		No	BIOS handles the distribution of resources.
PCI Latency Timer	This option controls how long (in PCI ticks) one PCI bus card can continue to use the master after another PCI card has requested access.	32, 64, 96, 128, 160, 192, 224, 248	Manually sets the value in PCI ticks.
Allocate IRQ to PCI VGA	This function is used to determine if an interrupt is assigned to the PCI VGA.	Yes	Automatic assignment of an interrupt.
		No	No assignment of an interrupt.
Allocate IRQ to SMBUS HC	Use this function to set whether or not the SM (System Management) bus controller is assigned a PCI interrupt.	Yes	Automatic assignment of a PCI interrupt.
		No	No assignment of an interrupt.
Allocate IRQ to PCIE X2	Use this function to set whether or not the PCIE X2 is assigned a PCI interrupt.	Yes	Automatic assignment of a PCI interrupt.
		No	No assignment of an interrupt.
PCI IRQ Resource Exclusion	Configures the PCI IRQ resource settings for ISA Legacy devices.	Enter	Opens the submenu See "PCI IRQ Resource Exclusion", on page 176
PCI Interrupt Routing	Configures PCI interrupt routing	Enter	Opens the submenu See "PCI Interrupt Routing", on page 177

Table 92: 945GME - Advanced PCI configuration - Setting options

PCI IRQ Resource Exclusion

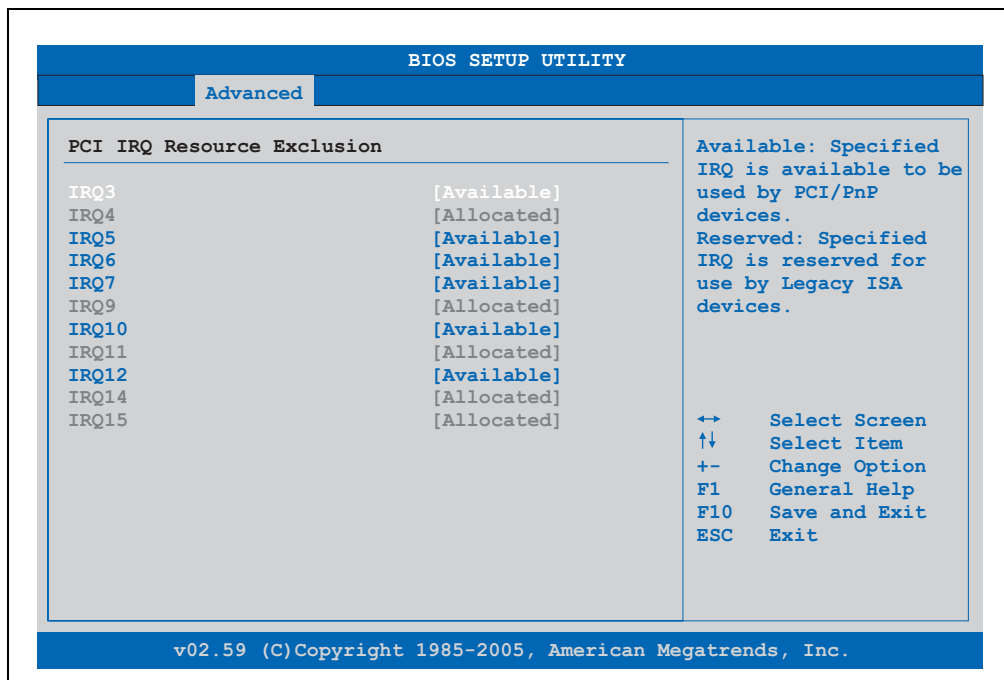


Figure 86: 945GME - Advanced PCI IRQ Resource Exclusion

BIOS setting	Meaning	Setting options	Effect
IRQx	IRQ interrupt routing for Legacy ISA devices.	Allocated	Allocated by the system - cannot be used.
		Available	Available - can be used.
		Reserved	Reserved - cannot be used.

Table 93: 945GME - Advanced PCI IRQ Resource Exclusion - Setting options

PCI Interrupt Routing

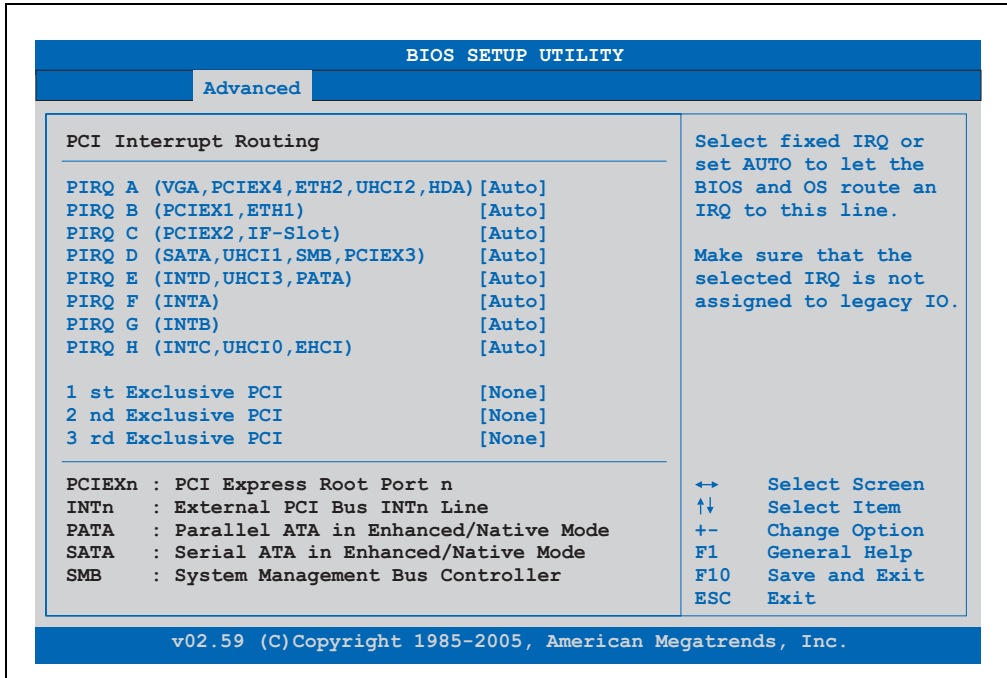


Figure 87: 945GME - Advanced PCI Interrupt Routing

BIOS setting	Meaning	Setting options	Effect
PIRQ A (VGA, PCIEX4, ETH2, UHCI2, HDA)	Option for setting the PIRQ A.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment
PIRQ B (PCIEX1, ETH1)	Option for setting the PIRQ B.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment.
PIRQ C (PCIEX2, IF slot)	Option for setting the PIRQ C.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment.
PIRQ D (SATA, UHCI1, SMB, PCIEX3)	Option for setting the PIRQ D.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment.
PIRQ E (INTD, UHCI3, PATA)	Option for setting the PIRQ E.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment.

Table 94: 945GME - Advanced PCI Interrupt Routing - Setting options

BIOS setting	Meaning	Setting options	Effect
PIRQ F (INTA)	Option for setting the PIRQ F.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment.
PIRQ G (INTB)	Option for setting the PIRQ G.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment.
PIRQ H (INTC,UHCI0,EHCI)	Option for setting the PIRQ H.	Auto	Automatic assignment by the BIOS and operating system.
		5,6,7,9,10,11,12	Manual assignment.
1st Exclusive PCI	With this option you can determine if the IRQ assigned to the PIRQ x is handled exclusively (no IRQ sharing). Information: Is only displayed if a PIRQ is manually set (e.g. 5).	None	No interrupt is assigned.
		x	Assigns the PIRQ as 1st exclusive PCI IRQ.
2nd Exclusive PCI	With this option you can determine if the IRQ assigned to the PIRQ x is handled exclusively (no IRQ sharing). Information: Only displayed when two PIRQs are set manually.	None	No interrupt is assigned.
		x	Assigns the PIRQ as 2nd exclusive PCI IRQ.
3rd Exclusive PCI	With this option you can determine if the IRQ assigned to the PIRQ x is handled exclusively (no IRQ sharing). Information: Only displayed when three PIRQs are set manually.	None	No interrupt is assigned.
		x	Assigns the PIRQ as 3rd exclusive PCI IRQ.

Table 94: 945GME - Advanced PCI Interrupt Routing - Setting options (cont.)

1.4.3 PCI express configuration

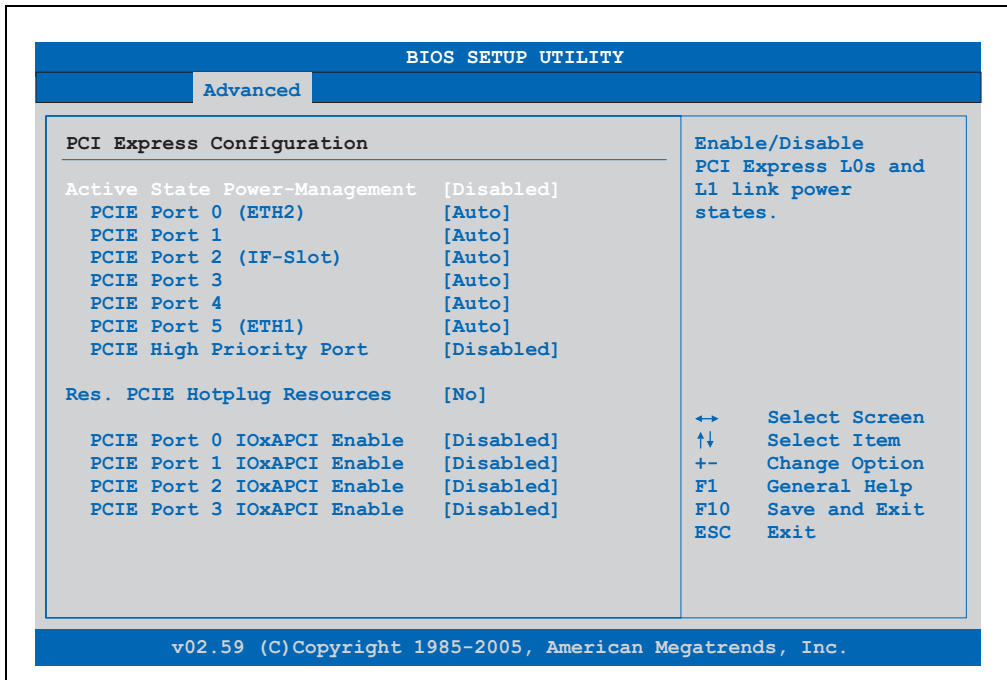


Figure 88: 945GME - Advanced PCI Express Configuration

BIOS setting	Meaning	Setting options	Effect
Active State Power-Management	Option for setting a power saving function (L0s/L1) for PCIE slots if they do not require full power.	Disabled	Disables this function.
		Enabled	Enables this function.
PCIE Port 0 (ETH2)	This option activates or deactivates the PCI Express connection function. Information: If you are not using any PCI Express devices, this option should be deactivated.	Auto	Automatic assignment by the BIOS and operating system.
		Enabled	Enables this function.
		Disabled	Disables this function.
PCIE Port 1	This option activates or deactivates the PCI Express connection function. Information: If you are not using any PCI Express devices, this option should be deactivated.	Auto	Automatic assignment by the BIOS and operating system.
		Enabled	Enables this function.
		Disabled	Disables this function.

Table 95: 945GME - Advanced PCI Express Configuration - Setting options

BIOS setting	Meaning	Setting options	Effect
PCIe Port 2 (IF slot)	This option activates or deactivates the PCI Express connection function. Information: If you are not using any PCI Express devices, this option should be deactivated.	Auto	Automatic assignment by the BIOS and operating system.
		Enabled	Enables this function.
		Disabled	Disables this function.
PCIe Port 3	This option activates or deactivates the PCI Express connection function. Information: If you are not using any PCI Express devices, this option should be deactivated.	Auto	Automatic assignment by the BIOS and operating system.
		Enabled	Enables this function.
		Disabled	Disables this function.
PCIe Port 4	This option activates or deactivates the PCI Express connection function. Information: If you are not using any PCI Express devices, this option should be deactivated.	Auto	Automatic assignment by the BIOS and operating system.
		Enabled	Enables this function.
		Disabled	Disables this function.
PCIe Port 5 (ETH1)	This option activates or deactivates the PCI Express connection function. Information: If you are not using any PCI Express devices, this option should be deactivated.	Auto	Automatic assignment by the BIOS and operating system.
		Enabled	Enables this function.
		Disabled	Disables this function.
PCIe High Priority Port	This option activates or deactivates the priority port for PCIe.	Disabled	Disables this function.
		Port 0	Activates Port 0 as priority port.
		Port 1	Activates Port 1 as priority port.
		Port 2	Activates Port 2 as priority port.
		Port 3	Activates Port 3 as priority port.
		ETH2	Activates ETH2 as priority port.
		ETH1	Activates ETH1 as priority port.
Res. PCIe Hotplug Resource	This option can be used to reserve an I/O and memory resource for a free PCIe port. A PCIe port must be set to enabled and resources must be reserved to support ExpressCard hot-plugging on a port.	No	Resource is not reserved.
		Yes	Resource is reserved.
PCIe Port 0 IOxAPIC Enable	This option is used to enable or disable the APIC (Advanced Programmable Interrupt Controller) on the PCIe port 0. The IRQ resources available to the system are expanded when the APIC mode is enabled.	Disabled	Disables this function.
		Enabled	Enables this function.

Table 95: 945GME - Advanced PCI Express Configuration - Setting options (cont.)

BIOS setting	Meaning	Setting options	Effect
PCIe Port 1 IOxAPIC Enable	This option is used to enable or disable the APIC (Advanced Programmable Interrupt Controller) on the PCIe port 1. The IRQ resources available to the system are expanded when the APIC mode is enabled.	Disabled	Disables this function.
		Enabled	Enables this function.
PCIe Port 2 IOxAPIC Enable	This option is used to enable or disable the APIC (Advanced Programmable Interrupt Controller) on the PCIe port 2. The IRQ resources available to the system are expanded when the APIC mode is enabled.	Disabled	Disables this function.
		Enabled	Enables this function.
PCIe Port 3 IOxAPIC Enable	This option is used to enable or disable the APIC (Advanced Programmable Interrupt Controller) on the PCIe port 3. The IRQ resources available to the system are expanded when the APIC mode is enabled.	Disabled	Disables this function.
		Enabled	Enables this function.

Table 95: 945GME - Advanced PCI Express Configuration - Setting options (cont.)

1.4.4 Graphics configuration

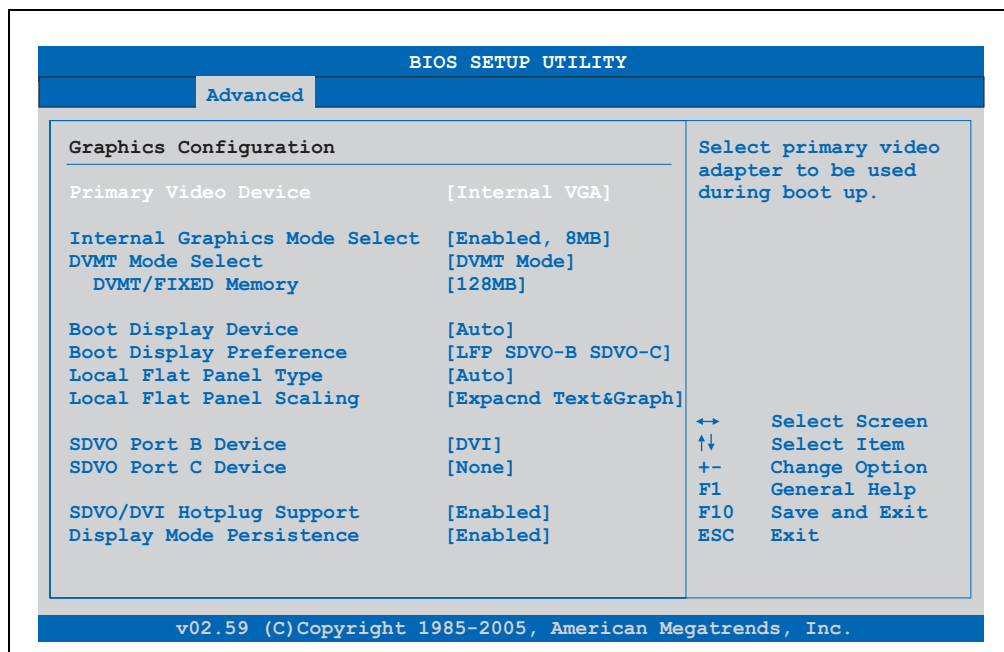


Figure 89: 945GME - Advanced Graphics Configuration

BIOS setting	Meaning	Setting options	Effect
Primary Video Device	Option for selecting the primary video device.	Internal VGA	The internal graphics chip on the CPU board is used as video device (monitor / panel connection).
		PCI / Int. VGA	The graphics chip of a connected graphics card is used as video device.
Internal Graphics Mode Select	Option for setting the memory size that can be used for the internal graphics controller.	Disabled	No reservation - Disables the graphics controller.
		Enabled, 1MB	1MB main memory provided.
		Enabled, 8MB	8MB main memory provided.
DVMT Mode Select	Option for determining the DVMT mode (Dynamic Video Memory Technology) of the DVMT graphics driver.	Fixed Mode	A fixed amount of memory is allocated to the graphics chip, which is no longer available to the PC.
		DVMT Mode	Memory consumption is controlled dynamically by the DVMT graphics driver. Only the amount of memory that is required is used.
		Combo Mode	The DVMT graphics driver reserves at least 64MB, but can use up to 224MB if necessary.
DVMT/FIXED Memory	Option for setting the amount of memory used for the DVMT mode.	64MB	64MB of main memory can be used.
		128MB	128MB of main memory can be used.
		Maximum DVMT	The remaining available main memory can be used.
Boot Display Device	Determines which video channel should be enabled for a video device during the boot procedure.	Auto	Automatic selection.
		CRT only	Only use the CRT (Cathode Ray Tube) channel.
		SDVO only	Only use the SDVO (Serial Digital Video Out) channel.
		CRT + SDVO	Use CRT and SDVO channel.
		LFP only	Only use the LFP (Local Flat Panel) channel.
		CRT + LFP	Use CRT + LFP channel.
Boot Display Preference	This option determines the order in which the devices on the connected channels LFP and SDVO should be checked and booted. Information: The setting is only needed when the Boot Display Device option is set to "Auto".	LFP SDVO-B SDVO-C	Local Flat Panel - Serial Digital Video B output - Serial Video C output.
		LFP SDVO-C SDVO-B	Local Flat Panel - Serial Digital Video C output - Serial Video B output.
		SDVO-B SDVO-C LFP	Serial Digital Video B output - Serial Digital Video C output - Local Flat Panel.
		SDVO-C SDVO-B LFP	Serial Digital Video C output - Serial Digital Video B output - Local Flat Panel.

Table 96: 945GME - Advanced Graphics Configuration - Setting options

BIOS setting	Meaning	Setting options	Effect
Local Flat Panel Type	This option can be used to set a pre-defined profile for the LVDS channel.	Auto	Automatic detection and setting using the EDID data.
		VGA 1x18 (002h)	640 x 480
		VGA 1x18 (013h)	640 x 480
		SVGA 1x18 (004h)	800 x 600
		XGA 1x18 (006h)	1024 x 768
		XGA 2x18 (007h)	1024 x 768
		XGA 1x24 (008h)	1024 x 768
		XGA 2x24 (012h)	1024 x 768
		SXGA 2x24 (00Ah)	1280 x 1024
		SXGA 2x24 (018h)	1280 x 1024
		UXGA 2x24 (00Ch)	1600 x 1200
		Customized EDID 1	User-defined profile
		Customized EDID 2	User-defined profile
		Customized EDID 3	User-defined profile
Local flat panel scaling	Determines the screen content should be output according to the defined Local Flat Panel Type.	Centering	The screen content is output centered on the display.
		Expand Text	The text is stretched across the entire surface of the display.
		Expand Graphics	The graphics are stretched across the entire surface of the display.
		Expand Text & Graphics	Text and graphics are stretched across the entire surface of the display.
SDVO Port B Device	Option for selecting the video device that is connected to the SDVO Port B.	None	No video device connected.
		DVI	Video signal output is optimized for a DVI-compatible video device.
		TV	Video signal output is optimized for a TV-compatible video device.
		CRT	Video signal output is optimized for a CRT-compatible video device.
		LVDS	Video signal output is optimized for a LVDS-compatible video device.
		DVI-Analog	Video signal output is optimized for an analog DVI-compatible video device.

Table 96: 945GME - Advanced Graphics Configuration - Setting options (cont.)

BIOS setting	Meaning	Setting options	Effect
SDVO Port C Device	Option for selecting the video device that is connected to the SDVO Port A.	None	No video device connected.
		DVI	Video signal output is optimized for a DVI-compatible video device.
		TV	Video signal output is optimized for a TV-compatible video device.
		CRT	Video signal output is optimized for a CRT-compatible video device.
		LVDS	Video signal output is optimized for a LVDS-compatible video device.
		DVI-Analog	Video signal output is optimized for an analog DVI-compatible video device.
SDVO/DVI Hotplug Support	If this option is set to enabled, the Windows XP graphics driver supports "hotplug" and "configuration mode persistence" for DVI monitors connected to a DVI SDVO transmitter. "Hotplug" support means that when a DVI monitor is connected while the operating system is running, it is detected automatically and activated. "Configuration mode persistence" means that, for example, a dual DVI configuration is automatically restored when both DVI monitors are reconnected, even if only one of them was connected and activated during a previous boot.	Enabled	"Hotplug" and "Configuration mode persistence" mode enabled.
		Disabled	"Hotplug" and "Configuration mode persistence" mode disabled.
Display Mode Persistence	"Display mode persistence" means that the operating system can remember and restore the previous display configuration. For example, a dual DVI configuration is automatically restored when both DVI monitors are reconnected, even if only one of them was connected and activated during a previous boot.	Enabled	Enables this function.
		Disabled	Disables this function.

Table 96: 945GME - Advanced Graphics Configuration - Setting options (cont.)

1.4.5 CPU configuration

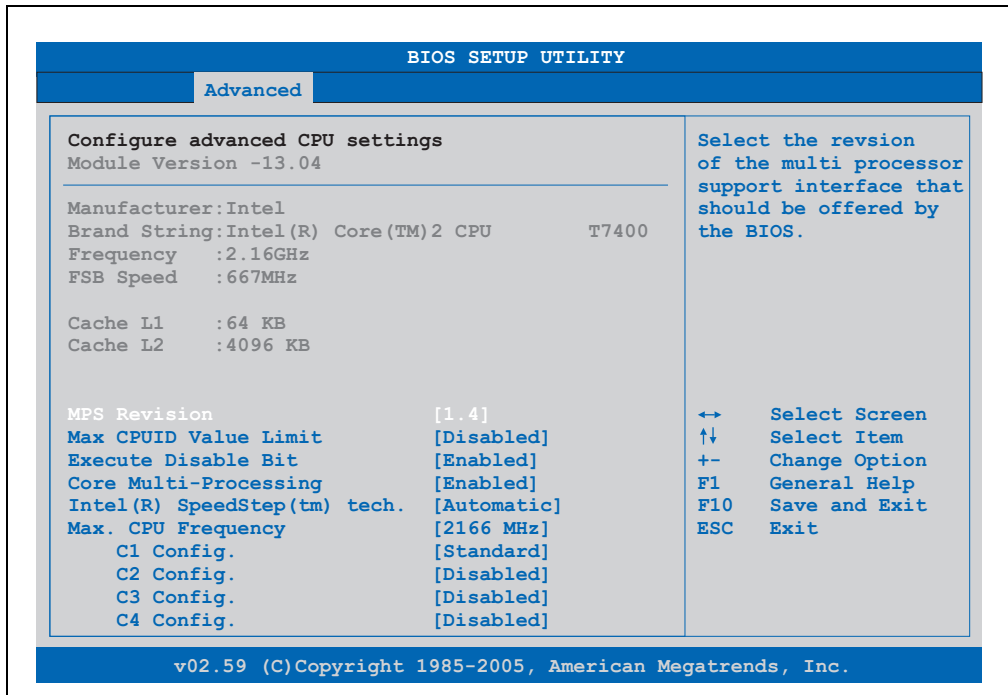


Figure 90: 945GME - Advanced CPU Configuration

BIOS setting	Meaning	Setting options	Effect
MPS Revision	This option supports the use of multiple CPUs (MPS=multi-processor system).	1.1	Sets MPS support Revision 1.1
		1.4	Sets MPS support Revision 1.4
Max CPUID value limit	Option for limiting the CPUID input value. This could be necessary for older operating systems.	Enabled	The processor limits the maximum CPUID input value to 03h if necessary when the the processor supports a higher value.
		Disabled	The processor returns the current maximum value upon request of the CPUID input value.
Execute Disable Bit	Option for enabling or disabling hardware support for prevention of data execution.	Enabled	Enables this function.
		Disabled	Disables this function.
Core Multi-Processing	When using a Dual Core processor, this option can be used to disable a core.	Enabled	Both cores are used in a Dual Core processor.
		Disabled	Only one core is used in a Dual Core processor.
Intel(R) SpeedStep(TM) tech.	Option for controlling the Intel(R) SpeedStep(TM) technology. The processor clock speed is increased or decreased according to the amount of calculations that must be made. As a result, the power consumption depends largely on the processor load.	Automatic	The processor speed is regulated by the operating system.
		Maximum speed	The processor speed is set to a maximum.
		Minimum speed	The processor speed is set to a minimum.
		Disabled	Disables SpeedStep technology.

Table 97: 945GME - Advanced CPU Configuration - Setting options

BIOS setting	Meaning	Setting options	Effect
Max. CPU frequency	Option for setting the maximum processor speed if the value "Automatic" or "Maximum Speed" is set for the option "Intel(R) SpeedStep(TM) tech.".	xxxx MHz	The processor speed is limited to the set value.
C1 Config	Power Management for Intel Core Duo processor.	Default	Standard C1 support.
		Enhanced	Enhanced C1 support.
C2 Config	Power Management for Intel Core Duo processor.	Default	Standard C2 support.
		Enhanced	Enhanced C2 support.
		Disabled	Disabled C2 support.
C3 Config	Power Management for Intel Core Duo processor.	Default	Standard C3 support.
		Enhanced	Enhanced C3 support.
		Disabled	Disabled C3 support.
C4 Config	Power Management for Intel Core Duo processor.	Default	Standard C4 support.
		Enhanced	Enhanced C4 support.
		Disabled	Disabled C4 support.

Table 97: 945GME - Advanced CPU Configuration - Setting options (cont.)

1.4.6 Chipset configuration

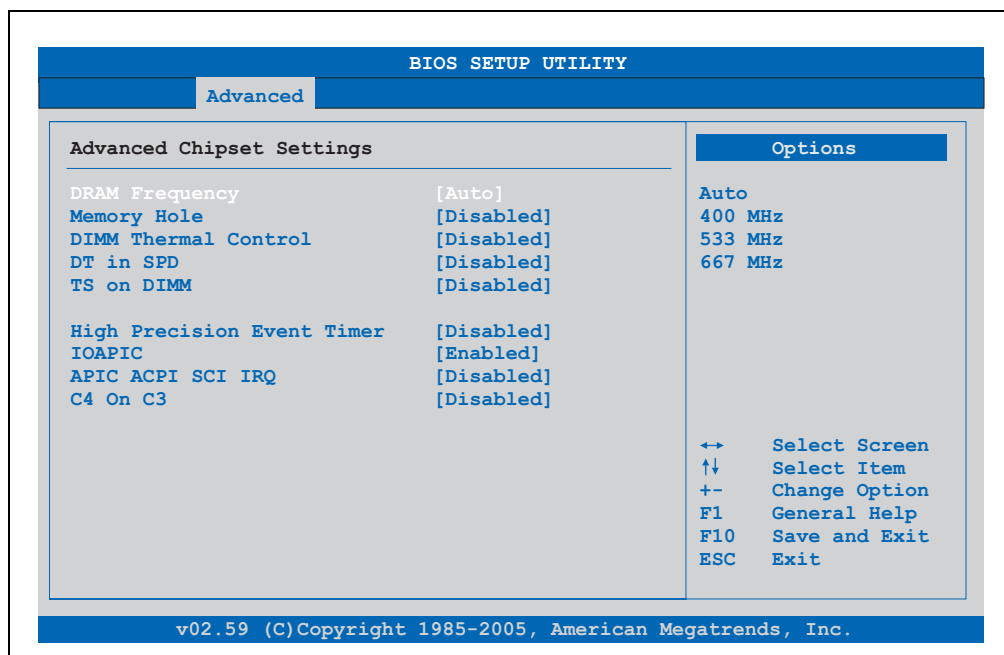


Figure 91: 945GME Advanced Chipset Configuration

BIOS setting	Meaning	Setting options	Effect
DRAM Frequency	Option for setting the RAM frequency.	Auto	Frequency set automatically by the BIOS.
		400, 533, 667 MHz	Desired clock frequency set manually.
Memory Hole	Option for ISA cards with frame buffer. Not relevant for an PPC800.	Disabled	Disables this function.
		15MB-16MB	This address area is reserved.
DIMM Thermal Control	Option for setting the maximum surface temperature of the DIMM module. The module is cooled by limiting the memory bandwidth if the defined surface temperature is reached.	Disabled	Surface temperature not limited.
		40°C, 50°C, 60°C, 70°C, 80°C, 85°C, 90°C	Temperature limit value for the limitation.
DT in SPD	Option to determine whether the GMCH (Graphics and Memory Controller Hub) supports DT (Delta Temperature) in the SPD (Serial Presence Detect) Management Algorithm of the DIMM module.	Disabled	Disables this function.
		Enabled	Enables this function.
TS on DIMM	Option to determine whether the GMCH (Graphics and Memory Controller Hub) supports TS (Thermal Sensor) in the Thermal Management Algorithm of the DIMM module.	Disabled	Disables this function.
		Enabled	Enables this function.
High Precision Event Timer	The HPET is a timer inside the PC. It is able to trigger an interrupt with a high degree of accuracy, which allows other programs to better synchronize a variety of applications.	Disabled	Disables this function.
		Enabled	Enables this function. This function is recommended for multimedia applications.
IOAPIC	This option is used to activate or deactivate the APIC (Advanced Programmable Interrupt Controller). Information: The IRQ resources available to the system are expanded when the APIC mode is enabled.	Disabled	Disables this function.
		Enabled	The IRQ resources available to the system are expanded when the APIC mode is enabled.
APIC ACPI SCI IRQ	This option is used to modify the SCI IRQ when in APIC (Advanced Programmable Interrupt Controller) mode.	Disabled	IRQ9 is used for SCI.
		Enabled	IRQ20 is used for SCI.
C4 On C3	Fine-tunes the power saving function on an ACPI operating system.	Disabled	Disables this function.
		Enabled	Processor is needed in C4 if the operating system is initiated in a C3 state.

Table 98: 945GME Advanced Chipset setting options

1.4.7 I/O interface configuration

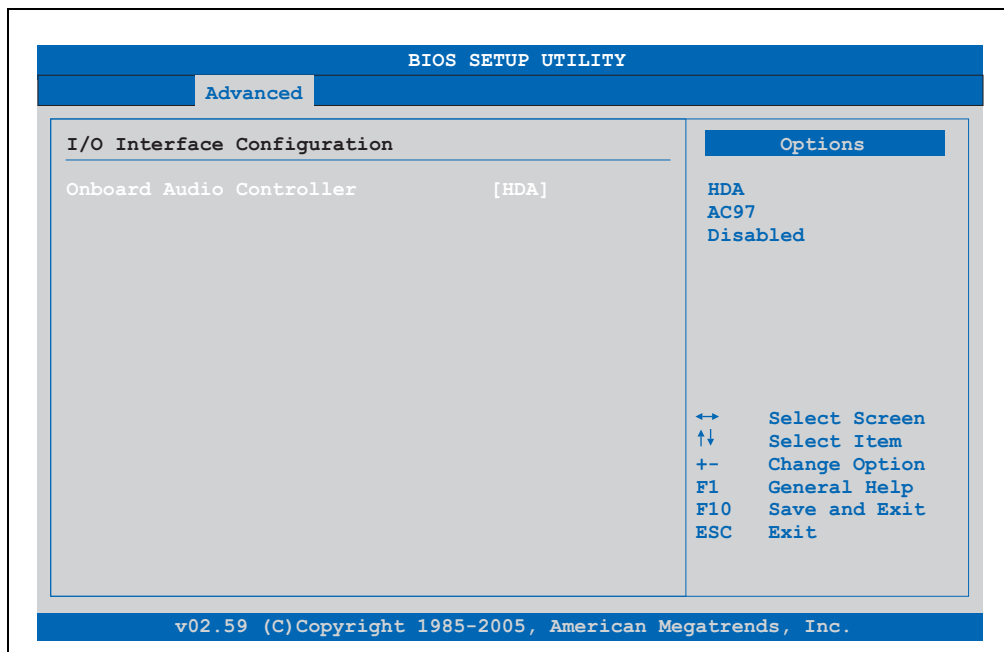


Figure 92: 945GME Advanced I/O Interface Configuration

BIOS setting	Meaning	Setting options	Effect
Onboard Audio Controller	The audio mode can be selected or switched off here.	HDA	Enables High Definition Audio sound.
		AC97	Enables AC'97 sound.
		Disabled	Disables the audio controller.

Table 99: 945GME Advanced I/O Interface Configuration setting options

1.4.8 Clock Configuration

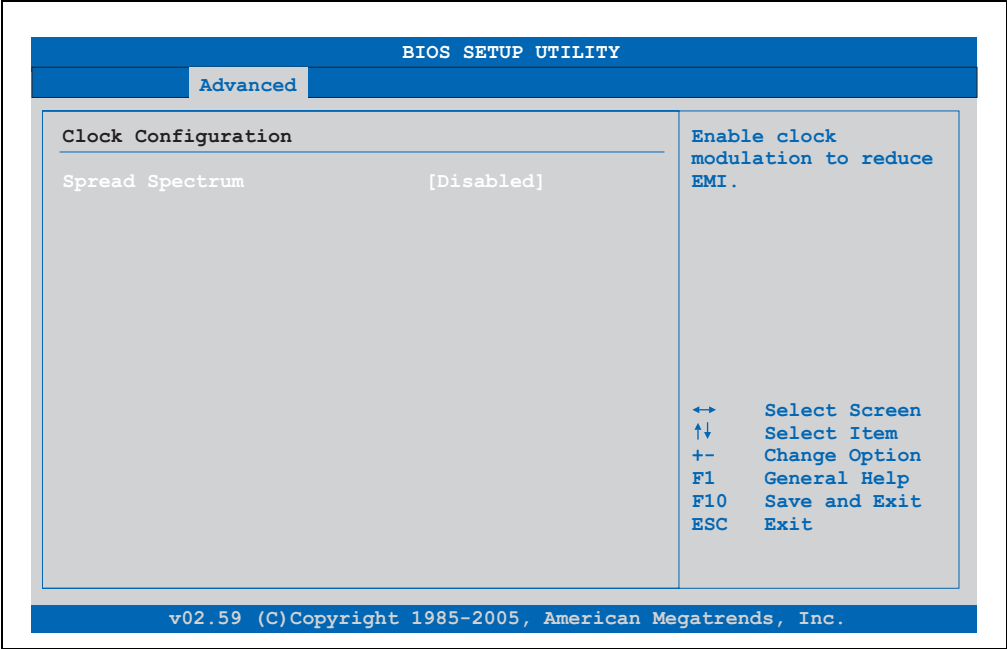


Figure 93: 945GME Advanced Clock Configuration

BIOS setting	Meaning	Setting options	Effect
Spread spectrum	With this option, the cycle frequency can be modulated by reducing electromagnetic disturbances.	Enabled	Enables this function.
		Disabled	Disables this function.

Table 100: 945GME Advanced Clock Configuration setting options

1.4.9 IDE Configuration

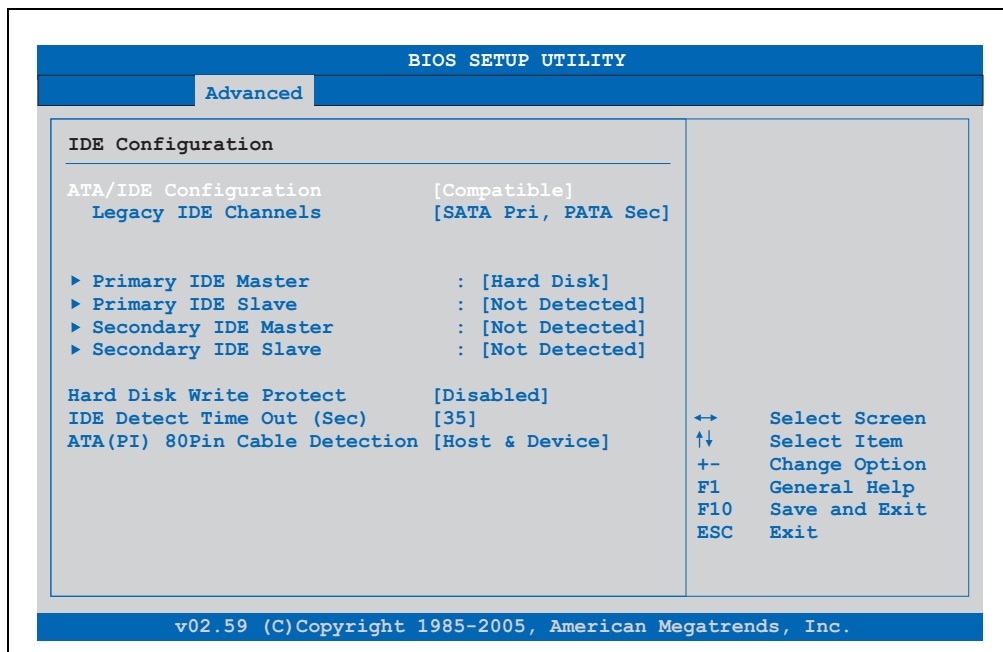


Figure 94: 945GME Advanced IDE Configuration

BIOS setting	Meaning	Setting options	Effect
ATA/IDE Configuration	Option for configuring the integrated PATA and SATA controller.	Compatible	Both controllers run in Legacy or Compatible Mode.
		Disabled	Both controllers disabled.
		Enhanced	Both controllers run in Enhanced or Native Mode.
Legacy IDE Channels ¹⁾	Option for configuring the Legacy IDE channels in Compatible Mode.	SATA Pri, PATA Sec	SATA drives are address primarily and PATA drive secondarily.
		SATA only	Only use SATA drives.
		PATA only	Only use PATA drives.
Configure SATA as ²⁾	The Serial ATA connections supported by the Southbridge can be defined here.	IDE	The serial ATA hard drive is used as a parallel ATA physical memory drive.
		RAID	RAID 0, 1, 5, 10 or the Intel® Matrix storage technology can be configured here with the serial ATA hard drive.
		AHCI	The AHCI setting enables the internal memory driver for the SATA functions, which increase the storage performance for random read-write access by allowing the drive to determine the sequence of commands.

Table 101: 945GME Advanced IDE Configuration setting options

BIOS setting	Meaning	Setting options	Effect
Configure SATA as Channels ³⁾	You can define a SATA or PATA drive as Primary or Secondary Device.	Before PATA	The SATA drives are the Primary Devices, meaning PATA are Secondary.
		Behind PATA	The PATA drives are the Primary Devices, meaning SATA are Secondary.
AHCI/RAID SATA hot plug ⁴⁾	Hot plug support for AHCI/RAID systems can be set here.	Disabled	Enables hot plug support.
		Enabled	Disables hot plug support.
Primary IDE Master	The drive in the system that is connected to the IDE primary master port is configured here.	Enter	Opens the submenu See "Primary IDE Master", on page 192
Primary IDE slave	The drive in the system that is connected to the IDE primary slave port is configured here.	Enter	Opens the submenu See "Primary IDE slave", on page 194
Secondary IDE Master	The drive in the system that is connected to the IDE secondary master port is configured here.	Enter	Opens the submenu See "Secondary IDE Master", on page 195
Secondary IDE Slave	The drive in the system that is connected to the IDE secondary slave port is configured here.	Enter	Opens the submenu See "Secondary IDE slave", on page 197
Hard disk write protect	Write protection for the hard drive can be enabled/disabled here.	Disabled	Disables this function.
		Enabled	Enables this function.
IDE Detect Time Out (Sec)	Configuring the time overrun limit value for the ATA/ATAPI device identification.	0, 5, 10, 15, 20, 25, 30, 35	Time setting in seconds.
ATA(P)I 80Pin Cable Detection	Detects whether an 80 pin cable is connected to the drive, the controller or to both. Information: This option is not available on the PPC800 CPU board. Therefore this setting is not relevant.	Host & device	Using both IDE controllers (motherboard, disk drive).
		Host	IDE controller motherboard used.
		Device	IDE disk drive controller used.

Table 101: 945GME Advanced IDE Configuration setting options

- 1) These settings are only possible if *ATA/IDE Configuration* is set to *Compatible*.
 2) These settings are only possible if *ATA/IDE Configuration* is set to *Enhanced*.
 3) These settings are only possible if *ATA/IDE Configuration* is set to *Enhanced* and *Configure SATA as* to *IDE*.
 4) These settings are only possible if *ATA/IDE Configuration* is set to *Enhanced* and *Configure SATA as* to *RAID* or *AHCI*.

Primary IDE Master

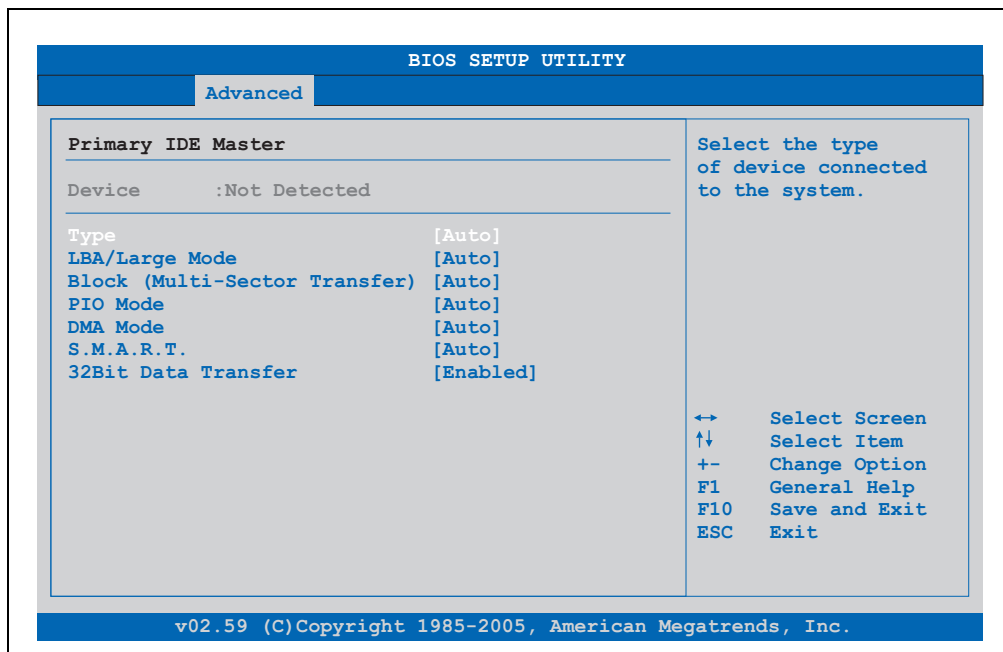


Figure 95: 945GME - Primary IDE Master

BIOS setting	Meaning	Setting options	Effect
Type	The type of drive connected to the primary master is configured here.	Not installed	No drive installed.
		Auto	Automatic recognition of the drive and setup of appropriate values.
		CD/DVD	CD -/ DVD drive.
		ARMD	ARMD - drive (zip drive)
LBA/Large Mode	This option activates the logical block addressing / large mode for IDE.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.
Block (Multi-Sector Transfer)	This option enables the block mode for IDE hard drives. When this option is enabled, the number of blocks per request from the configuration sector of the hard drive is read.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.

Table 102: 945GME - Primary IDE Master - Setting options

BIOS setting	Meaning	Setting options	Effect
PIO Mode	The PIO mode determines the data rate of the hard drive. Information: This option is not available on the PPC800. Therefore this setting is not relevant.	Auto	Automatic configuration of PIO mode.
		0, 1, 2, 3, 4	Manual configuration of PIO mode.
DMA Mode	The data transfer rate to and from the primary master drive is defined here. The DMA mode must be activated in the Windows device manager in order to guarantee maximum performance. Only possible when manually setting up the drive.	Auto	Automatic definition of the transfer rate.
		Disabled	Manual definition of the transfer rate.
S.M.A.R.T.	Monitoring function of modern hard drives (self-monitoring, analysis and reporting technology).	Auto	Automatic detection and enabling.
		Disabled	Disables this function.
		Enabled	Enables this function.
32 Bit Data Transfer	This function enables 32-bit data transfer.	Disabled	Disables this function.
		Enabled	Enables this function.

Table 102: 945GME - Primary IDE Master - Setting options (cont.)

Primary IDE slave

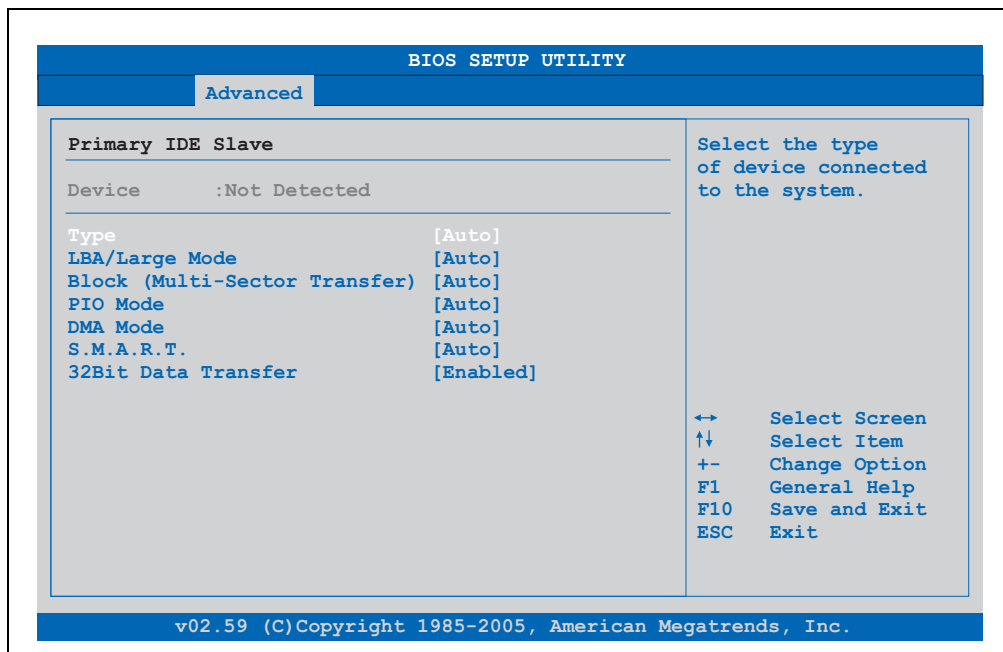


Figure 96: 945GME - Primary IDE Slave

BIOS setting	Meaning	Setting options	Effect
Type	The type of drive connected to the primary master is configured here.	Not installed	No drive installed.
		Auto	Automatic recognition of the drive and setup of appropriate values.
		CD/DVD	CD -/ DVD drive.
		ARMD	ARMD - drive (zip drive)
LBA/Large Mode	This option activates the logical block addressing / large mode for IDE.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.
Block (Multi-Sector Transfer)	This option enables the block mode for IDE hard drives. When this option is enabled, the number of blocks per request from the configuration sector of the hard drive is read.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.

Table 103: 945GME - Primary IDE Slave - Setting options

BIOS setting	Meaning	Setting options	Effect
PIO Mode	The PIO mode determines the data rate of the hard drive. Information: This option is not available on the PPC800. Therefore this setting is not relevant.	Auto	Automatic configuration of PIO mode.
		0, 1, 2, 3, 4	Manual configuration of PIO mode.
DMA Mode	The data transfer rate to and from the primary master drive is defined here. The DMA mode must be activated in the Windows device manager in order to guarantee maximum performance. Only possible when manually setting up the drive.	Auto	Automatic definition of the transfer rate.
		Disabled	Manual definition of the transfer rate.
S.M.A.R.T.	Monitoring function of modern hard drives (self-monitoring, analysis and reporting technology).	Auto	Automatic detection and enabling.
		Disabled	Disables this function.
		Enabled	Enables this function.
32 Bit Data Transfer	This function enables 32-bit data transfer.	Disabled	Disables this function.
		Enabled	Enables this function.

Table 103: 945GME - Primary IDE Slave - Setting options (cont.)

Secondary IDE Master

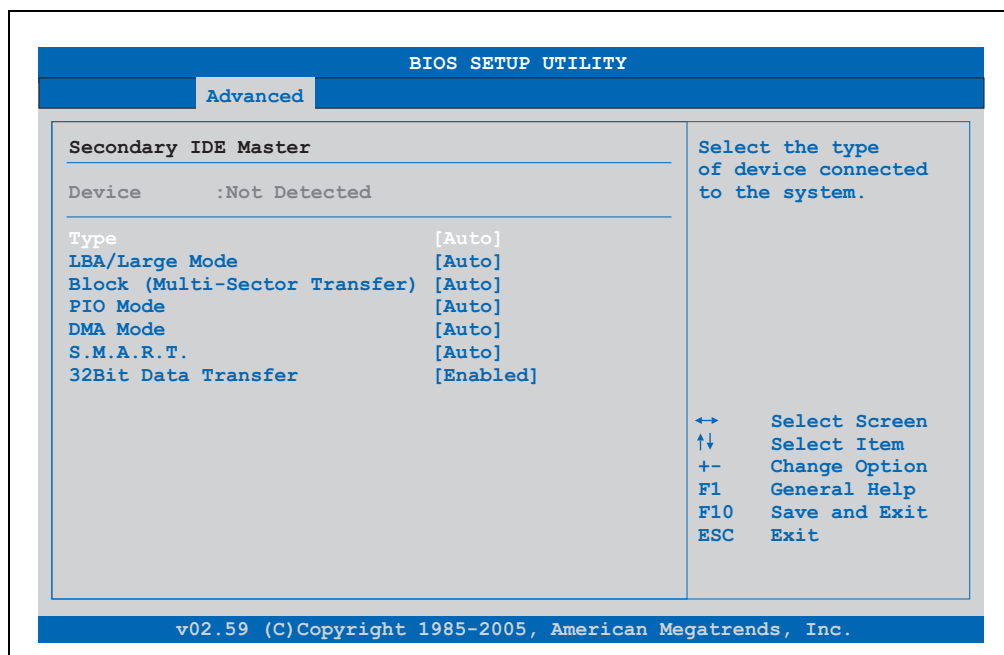


Figure 97: 945GME - Secondary IDE Master

BIOS setting	Meaning	Setting options	Effect
Type	The type of drive connected to the primary master is configured here.	Not installed	No drive installed.
		Auto	Automatic recognition of the drive and setup of appropriate values.
		CD/DVD	CD -/ DVD drive.
		ARMD	ARMD - drive (zip drive)
LBA/Large Mode	This option activates the logical block addressing / large mode for IDE.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.
Block (Multi-Sector Transfer)	This option enables the block mode for IDE hard drives. When this option is enabled, the number of blocks per request from the configuration sector of the hard drive is read.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.
PIO Mode	The PIO mode determines the data rate of the hard drive. Information: This option is not available on the PPC800. Therefore this setting is not relevant.	Auto	Automatic configuration of PIO mode.
		0, 1, 2, 3, 4	Manual configuration of PIO mode.
DMA Mode	The data transfer rate to and from the primary master drive is defined here. The DMA mode must be activated in the Windows device manager in order to guarantee maximum performance. Only possible when manually setting up the drive.	Auto	Automatic definition of the transfer rate.
		Disabled	Manual definition of the transfer rate.
S.M.A.R.T.	Monitoring function of modern hard drives (self-monitoring, analysis and reporting technology).	Auto	Automatic detection and enabling.
		Disabled	Disables this function.
		Enabled	Enables this function.
32 Bit Data Transfer	This function enables 32-bit data transfer.	Disabled	Disables this function.
		Enabled	Enables this function.

Table 104: 945GME - Secondary IDE Master - Setting options

Secondary IDE slave

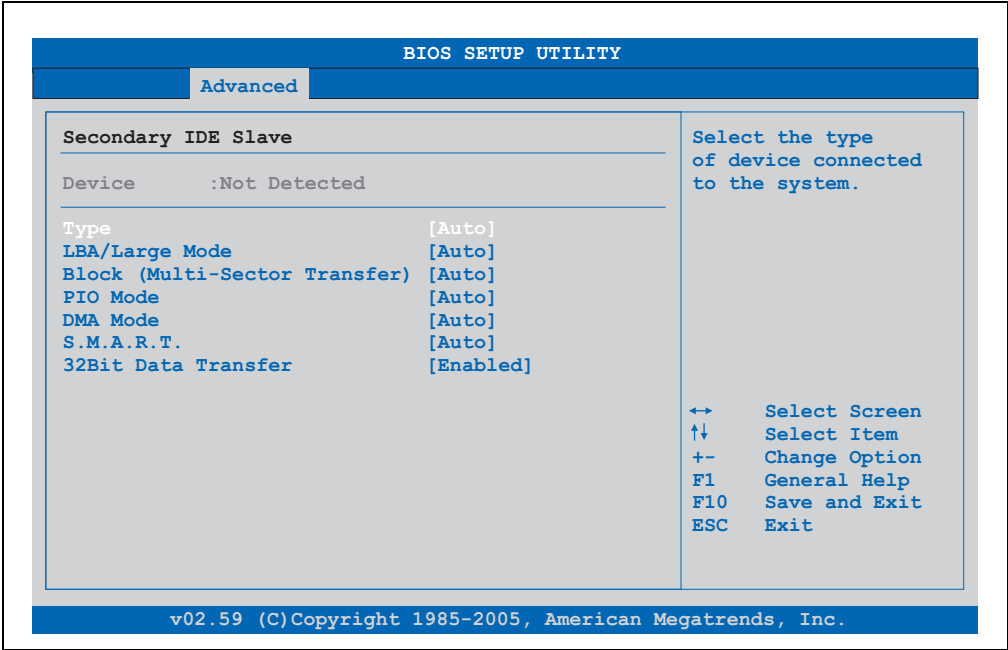


Figure 98: 945GME - Secondary IDE Slave

BIOS setting	Meaning	Setting options	Effect
Type	The type of drive connected to the primary master is configured here.	Not installed	No drive installed.
		Auto	Automatic recognition of the drive and setup of appropriate values.
		CD/DVD	CD -/ DVD drive.
		ARMD	ARMD - drive (zip drive)
LBA/Large Mode	This option activates the logical block addressing / large mode for IDE.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.
Block (Multi-Sector Transfer)	This option enables the block mode for IDE hard drives. When this option is enabled, the number of blocks per request from the configuration sector of the hard drive is read.	Disabled	Disables this function.
		Auto	Automatic enabling of this function when supported by the system.

Table 105: 945GME - Secondary IDE Slave - Setting options

BIOS setting	Meaning	Setting options	Effect
PIO Mode	The PIO mode determines the data rate of the hard drive. Information: This option is not available on the PPC800. Therefore this setting is not relevant.	Auto	Automatic configuration of PIO mode.
		0, 1, 2, 3, 4	Manual configuration of PIO mode.
DMA Mode	The data transfer rate to and from the primary master drive is defined here. The DMA mode must be activated in the Windows device manager in order to guarantee maximum performance. Only possible when manually setting up the drive.	Auto	Automatic definition of the transfer rate.
		Disabled	Manual definition of the transfer rate.
S.M.A.R.T.	Monitoring function of modern hard drives (self-monitoring, analysis and reporting technology).	Auto	Automatic detection and enabling.
		Disabled	Disables this function.
		Enabled	Enables this function.
32 Bit Data Transfer	This function enables 32-bit data transfer.	Disabled	Disables this function.
		Enabled	Enables this function.

Table 105: 945GME - Secondary IDE Slave - Setting options (cont.)

1.4.10 USB configuration

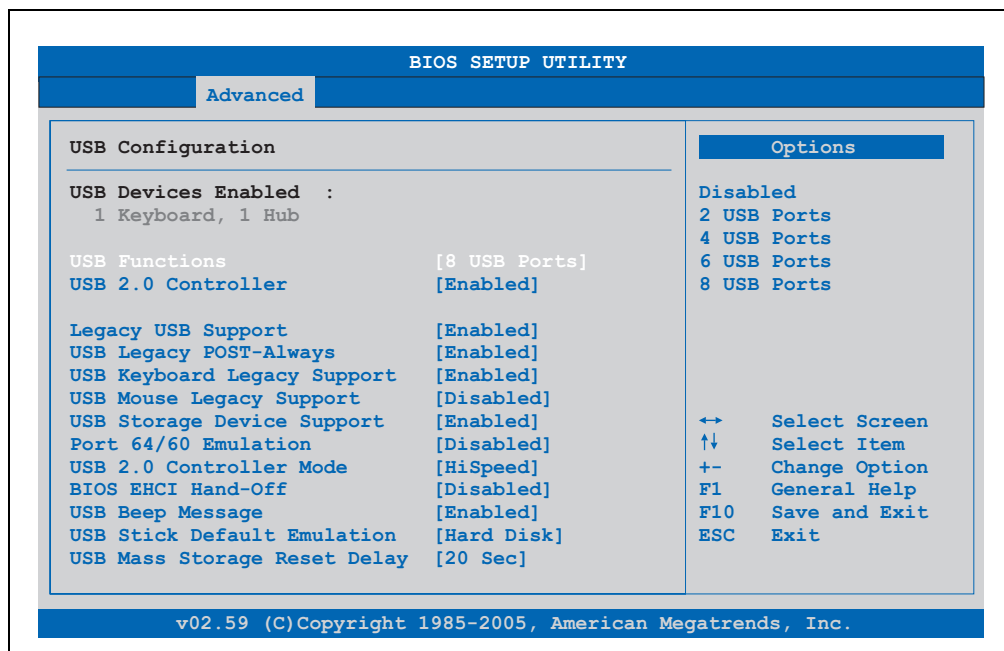


Figure 99: 945GME - Advanced USB Configuration

BIOS setting	Meaning	Setting options	Effect
USB Function	USB ports can be enabled/disabled here. The USB numbers (e.g. USB1, USB3, etc.) are printed on the PPC800 housing).	Disabled	Disables the USB port.
		2 USB Ports	USB1, USB3 are enabled.
		4 USB Ports	USB1, USB2, USB3, USB4 are enabled.
		6 USB Ports	USB1, USB2, USB3, USB4, USB5 are enabled.
		8 USB Ports	USB1, USB2, USB3, USB4, USB5, USB are enabled on an AP via SDL.
USB 2.0 Controller	Option for enabling or disabling USB 2.0 mode.	Enabled	All USB interfaces run in USB 2.0 mode.
		Disabled	All USB interfaces run in USB 1.1 mode.
Legacy USB Support	Legacy USB support can be enabled/disabled here. USB interfaces do not function during startup. USB is supported again after the operating system has started. A USB keyboard is still recognized during the POST.	Disabled	Disables this function.
		Enabled	Enables this function.
		Auto	Automatic enabling.
USB Legacy POST-Always	Option to enable Legacy USB Support during the POST (Power On Self Test) the same as the Legacy USB Support setting.	Enabled	The BIOS Setup can be called up during the POST using a USB keyboard.
		Disabled	Disables this function.
USB Keyboard Legacy Support	USB keyboard support can be enabled/disabled here.	Disabled	Disables this function.
		Enabled	Enables this function.
USB Mouse Legacy Support	USB mouse support can be enabled/disabled here.	Disabled	Disables this function.
		Enabled	Enables this function.
USB Storage Device Support	USB storage device support can be enabled/disabled here.	Disabled	Disables this function.
		Enabled	Enables this function.
Port 64/60 Emulation	Port 64/60 emulation can be enabled/disabled here.	Disabled	USB keyboard functions in all systems excluding Windows NT.
		Enabled	USB keyboard functions in Windows NT.
USB 2.0 Controller Mode	Settings can be made for the USB controller.	Full Speed	12 MBps
		Hi Speed	480 MBps
BIOS EHCI Hand-Off	The support for the operating system can be set up without the fully automatic EHCI function.	Disabled	Disables the function
		Enabled	Enables this function.
USB Beep Message	Option for outputting a tone each time a USB device is detected by the BIOS during the POST.	Disabled	Disables this function.
		Enabled	Enables this function.
USB Stick Default Emulation	You can set how the USB device is to be used.	Auto	USB devices with fewer than 530MB of memory are simulated as floppy disk drives and devices with larger capacities are simulated as hard drives.
		Hard Disk	An HDD-formatted drive can be used as an FDD (e.g. zip drive) for starting the system.

Table 106: 945GME - Advanced USB Configuration - Setting options

BIOS setting	Meaning	Setting options	Effect
USB Mass Storage Reset Delay	The waiting time that the USB device POST requires after the device start command can be set. Information: The message "No USB mass storage device detected" is displayed if no USB memory device has been installed.	10 Sec, 20 Sec, 30 Sec, 40 Sec	Value set manually.

Table 106: 945GME - Advanced USB Configuration - Setting options (cont.)

1.4.11 Keyboard/mouse configuration

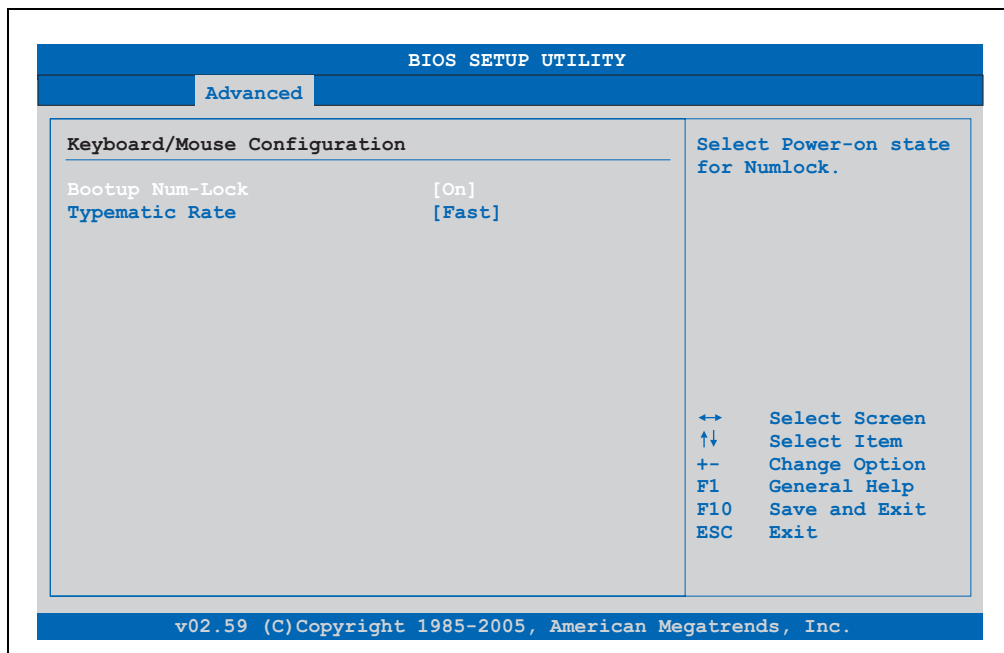


Figure 100: 945GME Advanced Keyboard/Mouse Configuration

BIOS setting	Meaning	Setting options	Effect
Boot-up Num-lock	With this field you can define the state of the NumLock key when booting.	Off	Only the cursor functions of the numerical keypad are enabled.
		On	Numeric keypad is enabled.
Typematic rate	The key repeat function is set here.	Slow	Slow key repeat.
		Fast	Fast key repeat.

Table 107: 945GME Advanced Keyboard/Mouse Configuration setting options

1.4.12 Remote access configuration

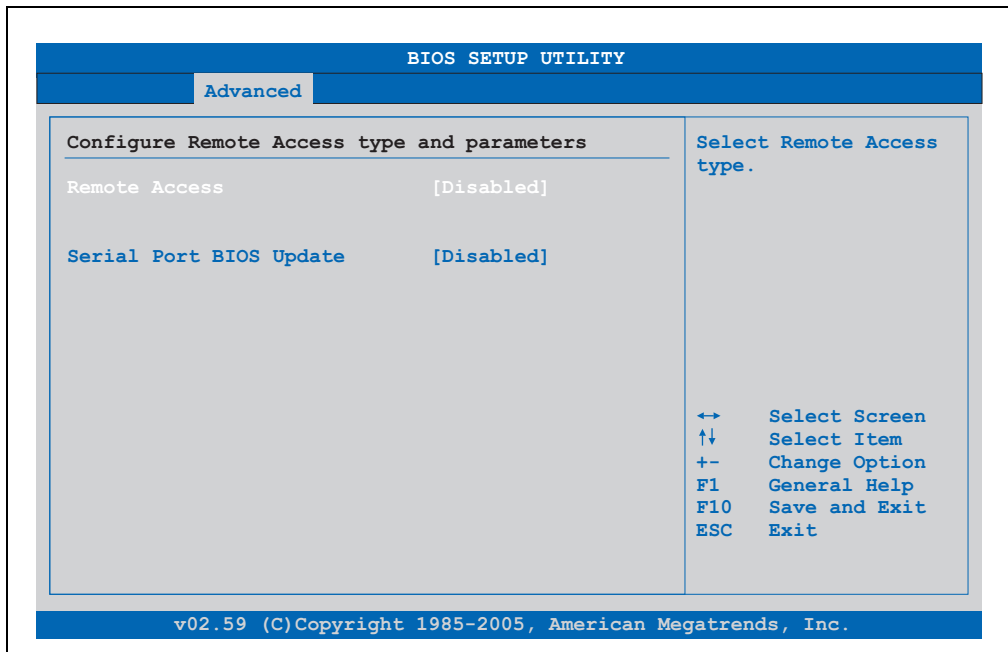


Figure 101: 945GME - Advanced Remote Access Configuration

BIOS setting	Meaning	Setting options	Effect
Remote access	The remote access function can be enabled/disabled here.	Disabled	Disables this function.
		Enabled	Enables this function.
Serial port number	The serial interface can be set using this option, as long as disabled is not entered in the <i>remote access</i> field.	COM1	Enables the COM1 interface as remote access interface.
		COM2	Enables the COM2 interface as remote access interface.
Base address, IRQ	Serial connection display for the logical address and interrupt, as long as disabled is not entered in the <i>remote access</i> field.	None	-
Serial port mode	The serial interface transfer rate is defined here, as long as disabled is not entered in the <i>remote access</i> field.	115200 8,n,1 57600 8,n,1 38400 8,n,1 19200 8,n,1 09600 8,n,1	Value set manually.
Flow control	This setting determines how the transfer is controlled via the interface. Information: The setting must be the same on the terminal and the server.	None	The interface is operated without transfer control.
		Hardware	The interface transfer control is carried out through hardware. This mode must be supported by a cable.
		Software	The interface transfer control is carried out through software.

Table 108: 945GME - Advanced Remote Access Configuration - Setting options

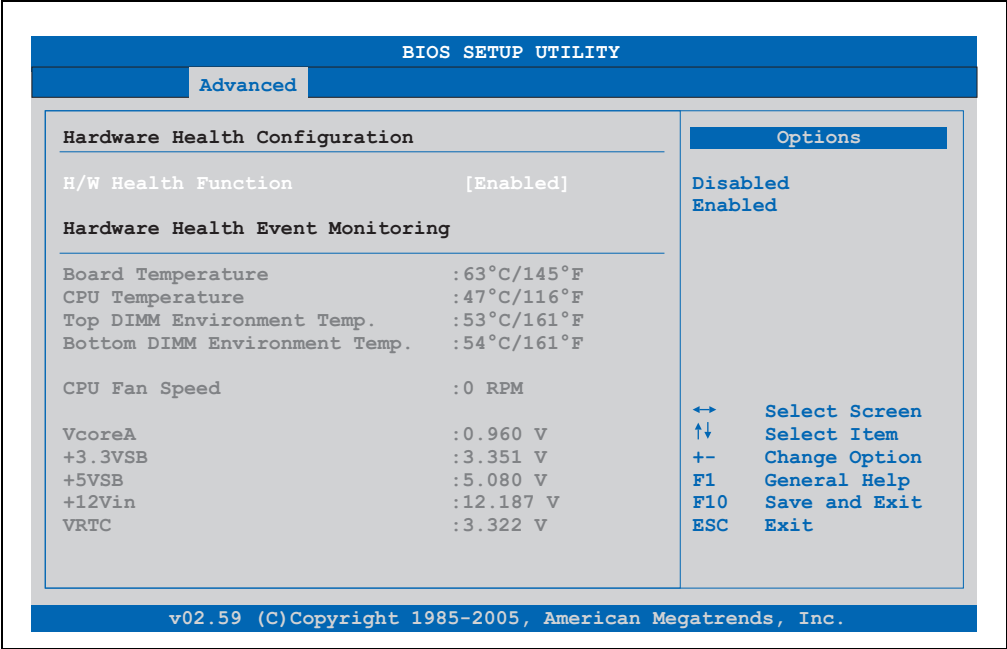
BIOS setting	Meaning	Setting options	Effect
Redirection after BIOS POST	The redirection after start up can be set here, as long as disabled is not entered in the <i>remote access</i> field.	Disabled	The redirection is switched off after start up.
		Boot loader	Redirection is enabled during system start up and charging.
		Always	Redirection is always enabled.
Terminal type	The type of connection can be chosen here, as long as disabled is not entered in the <i>remote access</i> field.	ANSI, VT100, VT-UTF8	Manual configuration of the connection type.
VT-UTF8 Combo Key Support	With this option, the VT-UTF8 Combo Key Support for the ANSI and VT100 connections can be enabled, as long as disabled is not entered in the <i>remote access</i> field.	Disabled	Disables this function.
		Enabled	Enables this function.
Sredir Memory Display Delay	The memory output delay can be set using this option, as long as disabled is not entered in the <i>remote access</i> field (Sredir -> serial redirection).	No delay	No delay.
		Delay 1 sec, Delay 2 sec, Delay 4 sec	Value set manually.
Serial port BIOS update	During system start up, the update is loaded via the serial interface in the processor. Information: If this option is disabled, the boot time is reduced.	Disabled	Disables this function.
		Enabled	Enables this function.

Table 108: 945GME - Advanced Remote Access Configuration - Setting options (cont.)

1.4.13 CPU board monitor

Information:

The displayed voltage values (e.g. core voltage, battery voltage) on this BIOS Setup page represent uncalibrated information values. These cannot be used to draw any conclusions about any hardware alarms or error conditions. The hardware components used have automatic diagnostics functions that can be applied in the event of error.



Section 4
Software

Figure 102: 945GME Advanced CPU Board Monitor

BIOS setting	Meaning	Setting options	Effect
H/W Health Function	Option for displaying all values on this page.	Enabled	Displays all values.
		Disabled	No values are shown on this page.
Board temperature	Displays the board temperature in degrees Celsius and Fahrenheit.	None	-
CPU temperature	Displays the processor's temperature (in degrees Celsius and Fahrenheit).	None	-
Top DIMM Environment Temp.	Displays the temperature of the first DRAM module.	None	-

Table 109: 945GME - Advanced Remote Access Configuration - Setting options

BIOS setting	Meaning	Setting options	Effect
Bottom DIMM Environment Temp.	Displays the temperature of the second DRAM module.	None	-
CPU Fan Speed	Displays the rotating speed of the processor fan.	None	-
VcoreA	Displays the processor's core voltage A in volts.	None	-
+3.3VSB	Displays the current voltage of the 3.3 volt supply.	None	-
+5VSB	Displays the current voltage of the 5 volt supply.	None	-
+12Vin	Displays the current voltage of the 12 volt supply.	None	-
VRTC	Displays the battery voltage (in volts).	None	-

Table 109: 945GME - Advanced Remote Access Configuration - Setting options (cont.)

1.4.14 Main Board/Panel Features

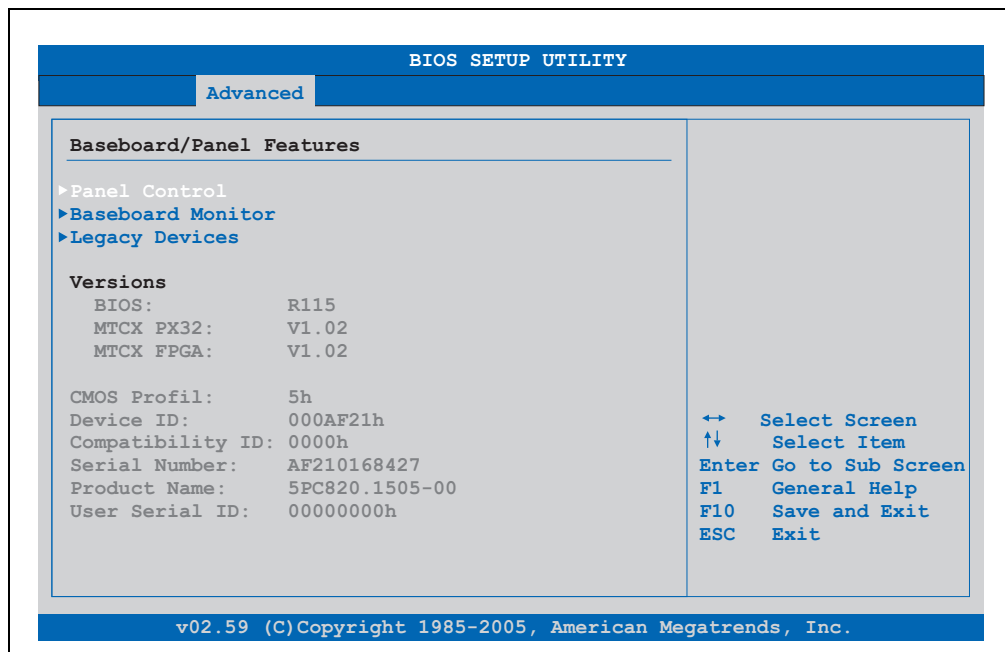


Figure 103: 945GME - Advanced Baseboard/Panel Features

BIOS setting	Meaning	Setting options	Effect
Panel control	For special setup of connected panels (display units).	Enter	Opens the submenu See "Panel control", on page 206
Main board monitor	Display of various temperatures and fan speeds.	Enter	Opens the submenu See "Main board monitor", on page 207
Legacy devices	Special settings for the interface can be changed here.	Enter	Opens the submenu See "Legacy devices", on page 208
BIOS	Displays the BIOS version.	None	-
MTCX PX32	Displays the MTCX PX32 firmware version.	None	-
MTCX FPGA	Displays the MTCX FPGA firmware version.	None	-
CMOS profile	Shows the CMOS profile number.	None	-
Device ID	Displays the hexadecimal value of the hardware device ID.	None	-
Compatibility ID	Displays the version of the device within the same B&R device code. This ID is needed for Automation Runtime.	None	-
Serial Number	Displays the B&R serial number.	None	-
Product name	Displays the B&R model number.	None	-
User serial ID	Displays the user serial ID. This 8 digit hex value can be freely assigned by the user (e.g. to give the device a unique ID) and can only be changed with using the "B&R Control Center" via the ADI driver.	None	-

Table 110: 945GME - Advanced Baseboard/Panel Features - Setting options

Panel control

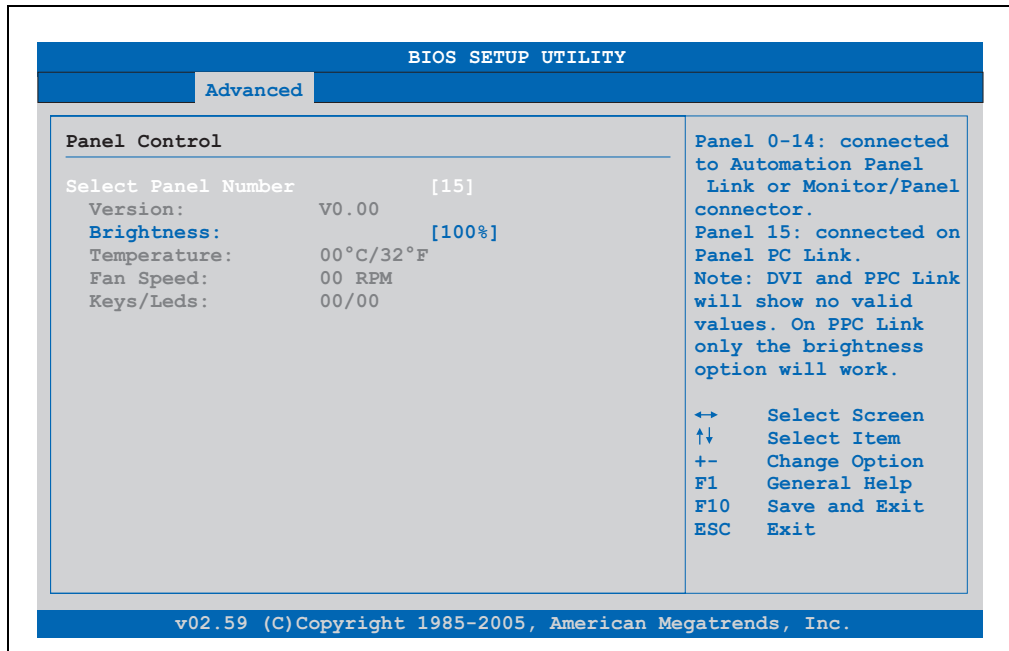


Figure 104: 945GME - Panel Control

BIOS setting	Meaning	Setting options	Effect
Select panel number	Selection of the panel number for which the values should be read out and/or changed.	0...15	Selection of panel 0 ... 15.
Version	Displays the firmware version of the SDLR controller.	None	-
Brightness	For setting the brightness of the selected panel.	0%, 10%, 20%, 30%, 40%, 50%, 60%, 70%, 80%, 90%, 100%	For setting the brightness (in %) of the selected panel. Changes take effect after saving and restarting the system (e.g. by pressing <F10>).
Temperature	Displays the selected panel's temperature (in degrees Celsius and Fahrenheit).	None	-
Fan speed	Displays fan speed for the selected panel.	None	-
Keys/LEDs	Displays the available keys and LEDs on the selected panel.	None	-

Table 111: 945GME - Panel Control - Setting options

Main board monitor

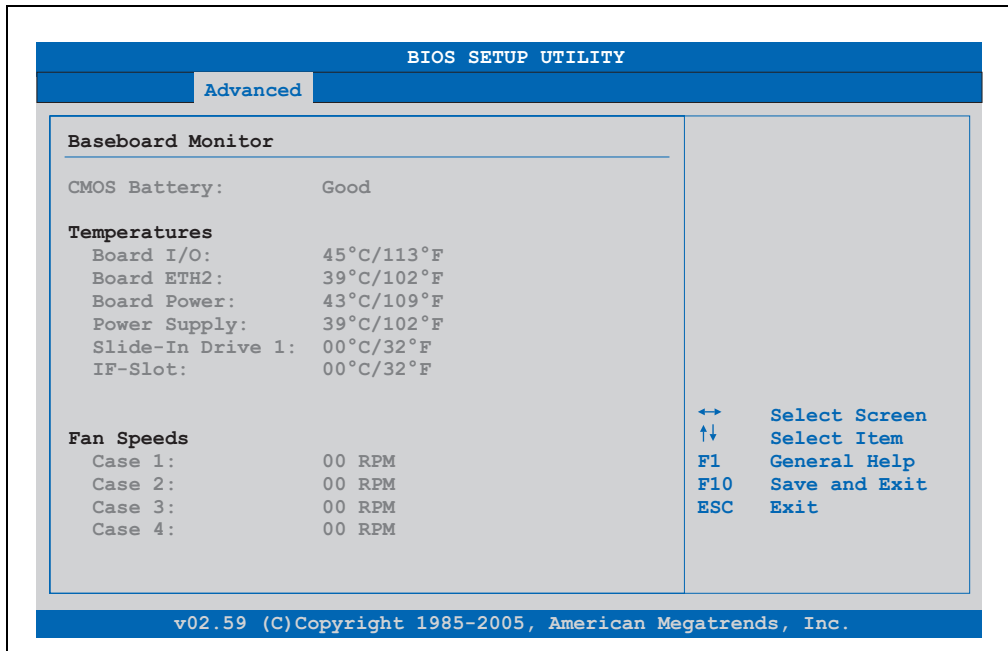


Figure 105: 945GME Baseboard Monitor

BIOS setting	Meaning	Setting options	Effect
CMOS battery	Displays the battery status. n.a. - not available Good - Battery is OK Bad - Battery is damaged.	None	-
Board I/O	Displays the temperature in the I/O area in degrees Celsius and Fahrenheit.	None	-
Board ETH2	Displays the temperature in the ETH2 controller chip area in degrees Celsius and Fahrenheit.	None	-
Board Power	Displays the power supply temperature in degrees Celsius and Fahrenheit.	None	-
Power supply	Displays the temperature in the power supply in degrees Celsius and Fahrenheit.	None	-
Slide-in drive 1	Displays the temperature of the slide-in drive 1 in degrees Celsius and Fahrenheit.	None	-
IF slot	Displays the temperature of the IF slot in degrees Celsius and Fahrenheit.	None	-
Case 1	Displays the fan speed of housing fan 1.	None	-
Case 2	Displays the fan speed of housing fan 2.	None	-

Table 112: 945GME Baseboard Monitor setting options

BIOS setting	Meaning	Setting options	Effect
Case 3	Displays the fan speed of housing fan 3.	None	-
Case 4	Displays the fan speed of housing fan 4.	None	-

Table 112: 945GME Baseboard Monitor setting options

Legacy devices

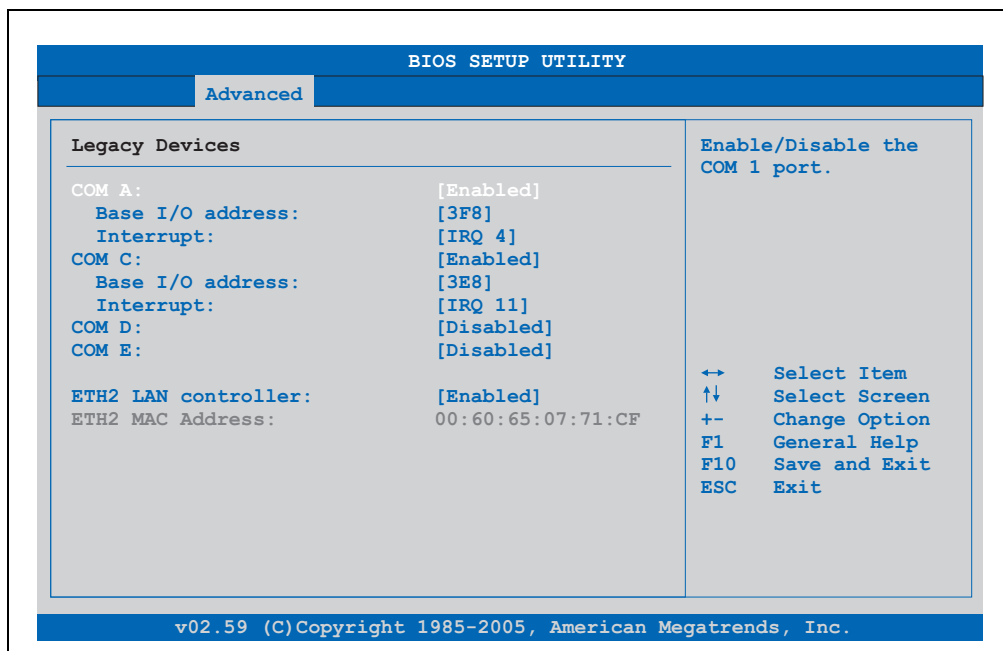


Figure 106: 945GME - Legacy Devices

BIOS setting	Meaning	Setting options	Effect
COM A	Settings for the COM1 serial interface in the system.	Disabled	Disables the interface.
		Enabled	Enables the interface.
Base I/O address	Selection of the base I/O address for the COM port.	238, 2E8, 2F8, 328, 338, 3E8, 3F8	Selected base I/O address is assigned.
Interrupt	Selection of the interrupt for the COM port.	IRQ 3, IRQ 4, IRQ 5, IRQ 6, IRQ 7, IRQ 10, IRQ 11, IRQ 12	Selected interrupt is assigned.
COM C	Setting of the COM port for the touch screen on the monitor/panel connector.	Disabled	Disables the interface.
		Enabled	Enables the interface.
Base I/O address	Selection of the base I/O address for the COM port.	238, 2E8, 2F8, 328, 338, 3E8, 3F8	Selected base I/O address is assigned.

Table 113: 945GME - Legacy Devices - Setting options

BIOS setting	Meaning	Setting options	Effect
Interrupt	Selection of the interrupt for the COM port.	IRQ 3, IRQ 4, IRQ 5, IRQ 6, IRQ 7, IRQ 10, IRQ 11, IRQ 12	Selected interrupt is assigned.
COM D	Setting of the COM port for the touch screen on the AP Link connector.	Disabled	Disables the interface.
		Enabled	Enables the interface.
Base I/O address	Selection of the base I/O address for the COM port.	238, 2E8, 2F8, 328, 338, 3E8, 3F8	Selected base I/O address is assigned.
Interrupt	Selection of the interrupt for the COM port.	IRQ 3, IRQ 4, IRQ 5, IRQ 6, IRQ 7, IRQ 10, IRQ 11, IRQ 12	Selected interrupt is assigned.
COM E	Configuration of the COM port on the B&R add-on interface.	Disabled	Disables the interface.
		Enabled	Enables the interface.
Base I/O address	Selection of the base I/O address for the COM port.	238, 2E8, 2F8, 328, 338, 3E8, 3F8	Selected base I/O address is assigned.
Interrupt	Selection of the interrupt for the COM port.	IRQ 3, IRQ 4, IRQ 5, IRQ 6, IRQ 7, IRQ 10, IRQ 11, IRQ 12	Selected interrupt is assigned.
Interrupt	Selection of the interrupt for the CAN port.	IRQ 10, NMI	Selected interrupt is assigned.
ETH2 LAN controller	For turning the onboard LAN controller (ETH2) on and off.	Disabled	Disables the controller.
		Enabled	Enables the controller.
ETH2 MAC Address	Displays the Ethernet 2 controller MAC address.	None	-

Table 113: 945GME - Legacy Devices - Setting options (cont.)

1.5 Boot

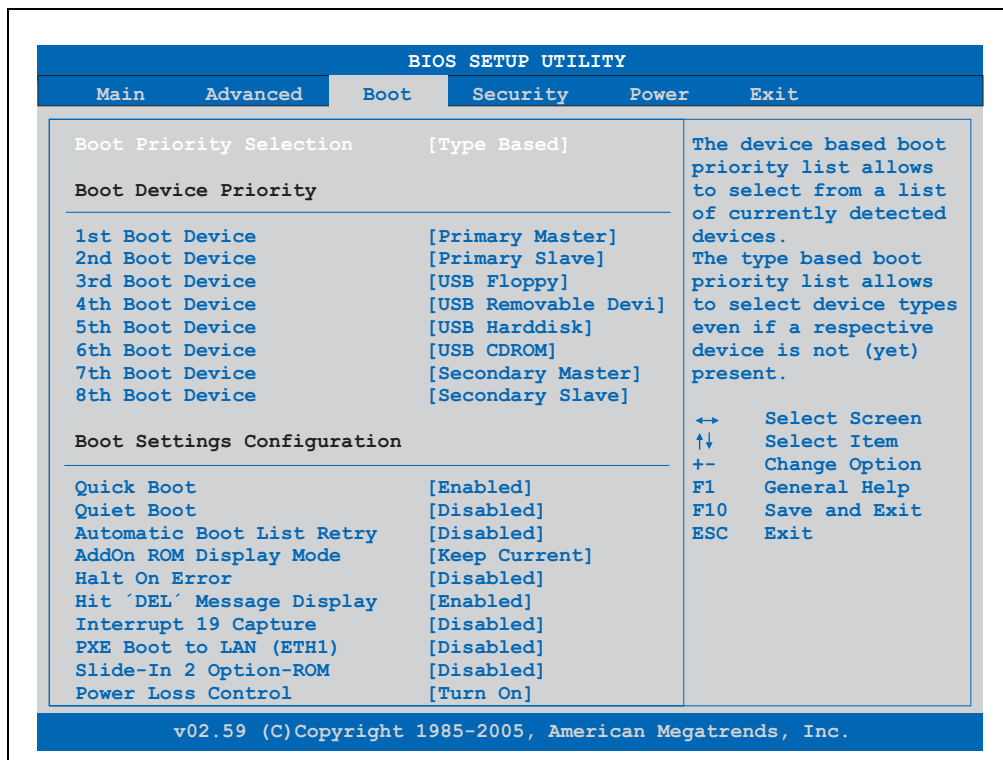


Figure 107: 945GME - Boot Menu

BIOS setting	Meaning	Setting options	Effect
Boot Priority Selection	The method for when the drives should be booted can be set here.	Device Based	Only the devices that are recognized by the system are listed. The sequence of this list can be changed.
		Type Based	The boot sequence of a device type list can be changed. Device types that are not connected can also be entered to this list.

Table 114: 945GME - Boot Menu - Setting options

BIOS setting	Meaning	Setting options	Effect
1st Boot Device	The boot drives can be set using this option.	Disabled, primary master, primary slave, secondary master, secondary slave, Legacy floppy, USB floppy, USB hard disk, USB CDROM, USB removable device, onboard LAN, external LAN, PCI mass storage PCI SCSI Card, Any PCI BEV Device, Third Master, Third Slave, PCI RAID, Local BEV ROM	Select the desired sequence.
2nd Boot Device			
3rd Boot Device			
4th Boot Device			
5th Boot Device			
6th Boot Device			
7th Boot Device			
8th Boot Device			
Quick Boot	This function reduces the boot time by skipping some POST procedures.	Disabled	Disables this function.
		Enabled	Enables this function.
Quiet Boot	Determines if POST message or OEM logo (default = black background) is displayed.	Disabled	POST message display.
		Enabled	OEM logo display instead of POST message.
Automatic Boot List Retry	With this option, the operating system attempts to automatically restart following startup failure.	Disabled	Disables this function.
		Enabled	Enables this function.
Add-On ROM Display Mode	Sets the display mode for the ROM (during the booting procedure).	Force BIOS	An additional BIOS part can be displayed.
		Keep Current	BIOS information is displayed.
Halt On Error	This option sets whether the system should pause the Power On Self Test (POST) when it encounters an error.	Disabled	The system does not pause. All errors are ignored.
		Enabled	The system pauses. The system pauses every time an error is encountered.
Hit 'DEL' Message Display	Settings can be made here for the "Hit 'DEL' Message" display. Information: When quiet boot is activated the message is not displayed.	Disabled	The message is not displayed.
		Enabled	The message is displayed.
Interrupt 19 Capture	This function can be used to incorporate the BIOS interrupt.	Disabled	Disables this function.
		Enabled	Enables this function.
PXE boot to LAN (ETH1)	Enables/disables the function to boot from LAN (ETH1).	Disabled	Disables this function.
		Enabled	Enables this function.
Slide-in 2 Optional ROM	Activation/deactivation of an optional ROM for a slide-in 2 drive.	Disabled	Disables this function.
		Enabled	Enables this function.
Power Loss Control	Determines if the system is on/off following power loss.	Remain Off	Remains off.
		Turn On	Powers on.
		Last State	Enables the previous state.

Table 114: 945GME - Boot Menu - Setting options (cont.)

1.6 Security

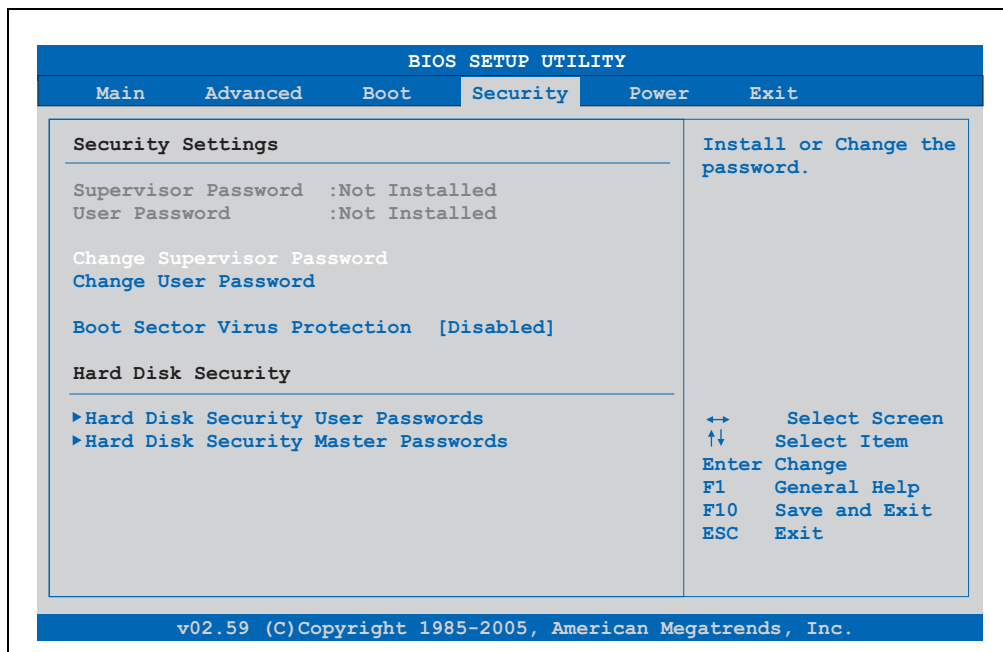


Figure 108: 945GME - Security Menu

BIOS setting	Meaning	Setting options	Effect
Supervisor Password	Displays whether or not a supervisor password has been set.	None	-
User Password	Displays whether or not a user password has been set.	None	-
Change Supervisor Password	To enter/change a supervisor password. A supervisor password is necessary to edit all BIOS settings.	Enter	Enter password.
Change User Password	To enter/change a user password. A user password allows the user to edit only certain BIOS settings.	Enter	Enter password.
Boot Sector Virus Protection	With this option, a warning is issued when the boot sector is accessed through a program or virus. Information: With this option, only the boot sector is protected, not the entire hard drive.	Disabled	Disables this function.
		Enabled	Enables this function.
Hard Disk Security User Passwords	The hard disk security user password can be created here.	Enter	Opens the submenu See "Hard disk security user password", on page 213

Table 115: 945GME - Security Menu - Setting options

BIOS setting	Meaning	Setting options	Effect
Hard Disk Security Master Passwords	The hard disk security master password can be created here.	Enter	Opens the submenu See "Hard disk security master password", on page 214

Table 115: 945GME - Security Menu - Setting options (cont.)

1.6.1 Hard disk security user password

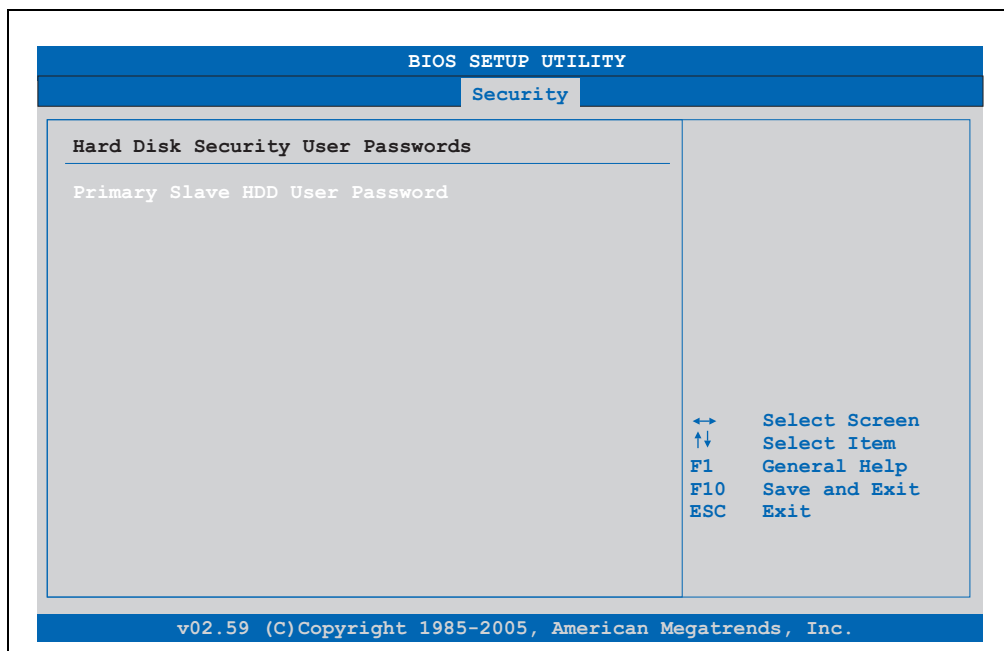


Figure 109: 945GME Hard disk security user password

BIOS setting	Meaning	Setting options	Effect
Primary slave HDD user password	This function makes it possible to use the user password to change or configure each hard drive without having to reboot the device. A user password allows the user to edit only certain BIOS settings.	Enter	Enter password.

Table 116: 945GME Hard disk security user password

1.6.2 Hard disk security master password

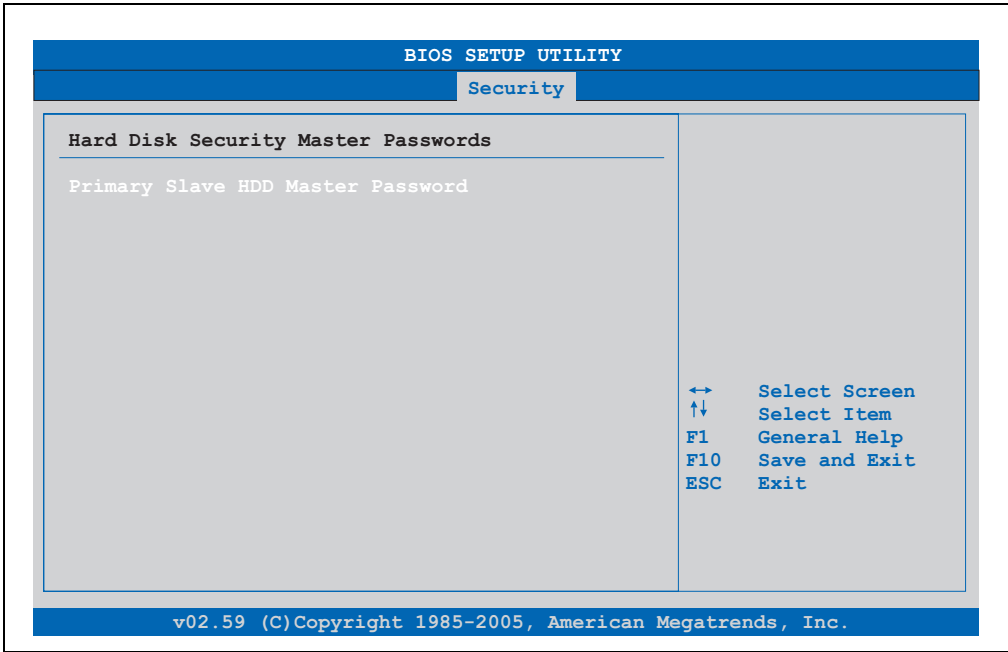


Figure 110: 945GME Hard Disk Security Master Password

BIOS setting	Meaning	Setting options	Effect
Primary Slave HDD Master Password	This function makes it possible to use the user password to change or configure each hard drive without having to reboot the device.	Enter	Enter password.

Table 117: 945GME Hard Disk Security Master Password

1.7 Power

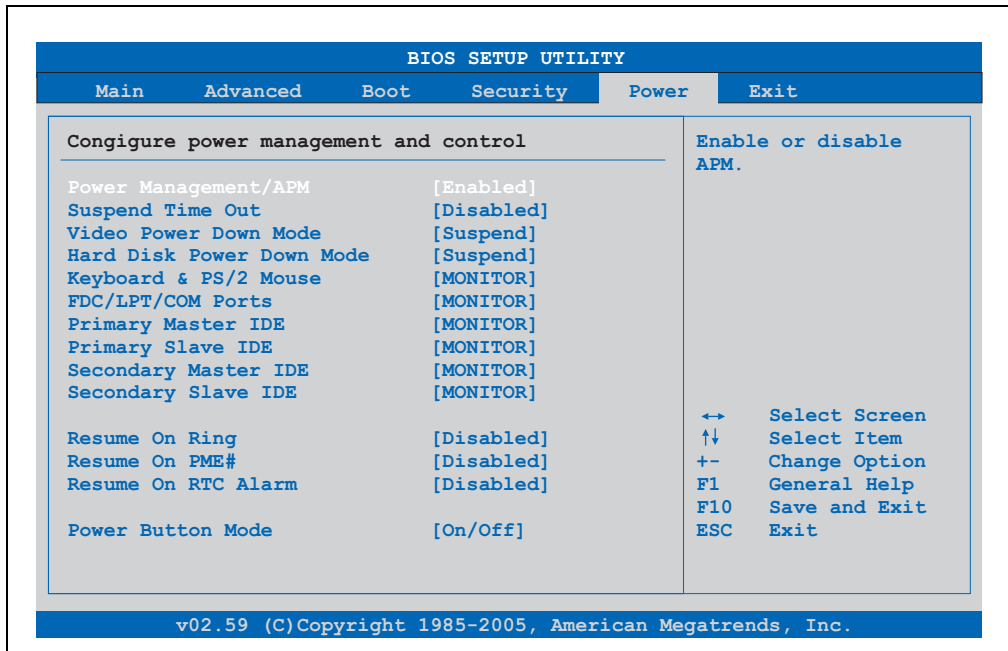


Figure 111: 945GME - Power Menu

BIOS setting	Meaning	Setting options	Effect
Power Management/APM	This option switches the APM function on or off. This is an advanced plug & play and power management functionality.	Disabled	Disables this function.
		Enabled	Enables this function.
Suspend Time Out	Using this option, you can configure how long the system stays inactive (all components but the CPU are shut off, if possible) before entering suspend mode.	Disabled	Disables this function.
		1 Min, 2 Min, 4 Min, 8 Min, 10 Min, 20 Min, 30 Min, 40 Min, 50 Min, 60 Min;	Value set manually.
Video Power Down Mode	This option allows you to set the energy saving mode for the monitor.	Disabled	Do not switch off the monitor.
		Standby	Monitor goes to standby mode.
		Suspend	Monitor goes to suspend mode.
Hard Disk Power Down Mode	This option allows you to set the energy saving mode for the hard drive.	Disabled	Do not switch off the hard drive.
		Standby	Monitor goes to standby mode.
		Suspend	Hard drive goes to suspend mode.
Keyboard & PS/2 Mouse	The monitoring of activities during power saving mode is determined here.	MONITOR	Keyboard or PS/2 mouse activities return the system to its normal state from a particular energy saving mode.
		IGNORE	Activities are ignored.

Table 118: 945GME - Power Menu - Setting options

BIOS setting	Meaning	Setting options	Effect
FDC/LPT/COM ports	The monitoring of activities during power saving mode is determined here.	MONITOR	Activity on the parallel port, the serial 1&2 port, or the floppy port returns the system to its normal state from an energy saving mode.
		IGNORE	Activities are ignored.
Primary Master IDE	The monitoring of activities during power saving mode is determined here.	MONITOR	Activities in the IRQ of specific connections or devices return the system to its normal state from power saving mode.
		IGNORE	Activities are ignored.
Primary Slave IDE	The monitoring of activities during power saving mode is determined here.	MONITOR	Activities in the IRQ of specific connections or devices return the system to its normal state from power saving mode.
		IGNORE	Activities are ignored.
Secondary Master IDE	The monitoring of activities during power saving mode is determined here.	MONITOR	Activities in the IRQ of specific connections or devices return the system to its normal state from power saving mode.
		IGNORE	Activities are ignored.
Secondary Slave IDE	The monitoring of activities during power saving mode is determined here.	MONITOR	Activities in the IRQ of specific connections or devices return the system to its normal state from power saving mode.
		IGNORE	Activities are ignored.
Resume On Ring	When the modem receives an incoming call, the PC is brought out of power saving mode.	Disabled	Disables this function.
		Enabled	Enables this function.
Resume on PME#	With this option, you can switch the PME wakeup function on or off.	Disabled	Disables this function.
		Enabled	Enables this function.
Resume On RTC Alarm	With this option, you can activate the alarm and enter the date and time for the system start.	Disabled	Disables this function.
		Enabled	Enables this function.
Power Button Mode	This function determines the function of the power button.	On/Off	Power button switches on/off.
		Suspend	Suppresses the function.

Table 118: 945GME - Power Menu - Setting options (cont.)

1.8 Exit

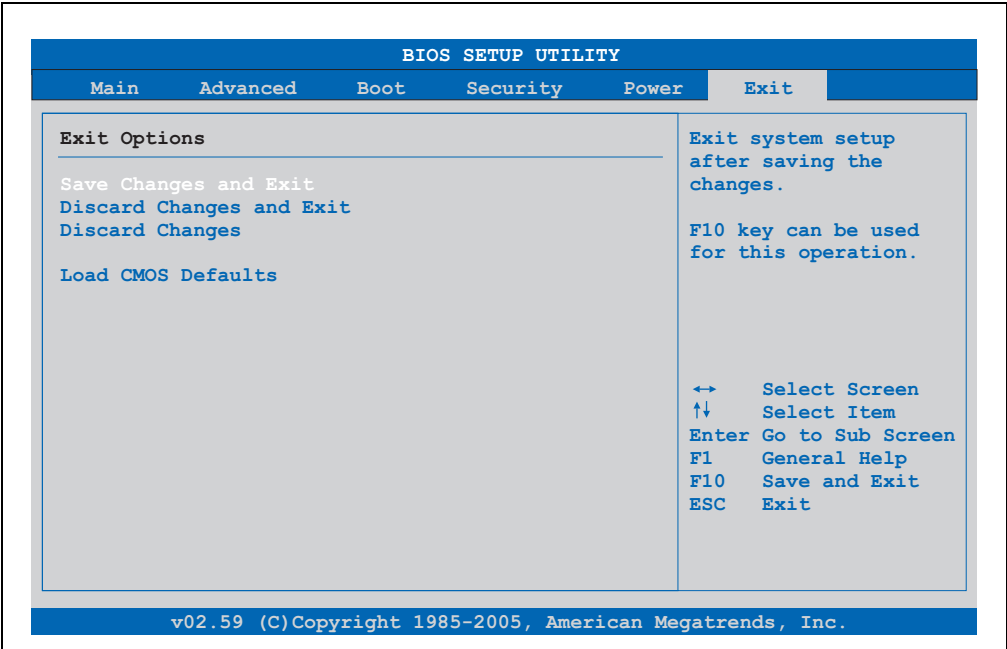


Figure 112: 945GME - Exit Menu

BIOS setting	Meaning	Setting options	Effect
Save Changes and Exit	BIOS setup is closed with this item. Changes made are saved in CMOS after confirmation, and the system is rebooted.	OK / Cancel	
Discard Changes and Exit	With this item you can close BIOS setup without saving the changes made. The system is then rebooted.	OK / Cancel	
Discard Changes	In the event that settings were made which the user can no longer remember, changes can be reset as long as they haven't been saved.	OK / Cancel	
Load CMOS Defaults	This item loads the CMOS default values, which are defined by the DIP switch settings. These settings are loaded for all BIOS configurations.	OK / Cancel	

Table 119: 855GME - (XTX) Exit menu - Setting options

1.9 BIOS default settings

The various positions of the CMOS profile hex switch (see figure "Rear view 5PC820.1505-00", on page 66) can be used to load pre-defined BIOS profile settings.



Figure 113: CMOS profile hex switch

Information:

The switch position that is set upon delivery represents the optimum BIOS default values for this system and should therefore not be changed.

If the function "load setup defaults" is chosen in the main BIOS setup menu, or if exit is selected (or <F9> is pressed) in the individual setup screens, the following BIOS settings are the optimized values that will be used.

Profile number	Optimized for	Switch position	Note
Profile 0	Reserved	0	
Profile 1	System unit 5PC810.SX01-00 / 5PC810.SX02-00	1	The default settings for this profile can be found in the APC810 user's manual. This can be downloaded for free from the B&R homepage.
Profile 2	System unit 5PC810.SX05-00	2	
Profile 3	System unit 5PC820.SX01-00/ 5PC820.SX01-01	3	The default settings for this profile can be found in the APC820 user's manual. This can be downloaded for free from the B&R homepage.
Profile 4	Reserved	4	
Profile 5	System unit 5PC820.1505-00 / 5PC820.1906-00	5	

Table 120: Profile overview

The following pages provide an overview of the BIOS default settings for the different CMOS profile switch positions. Settings highlighted in yellow are variations from the BIOS default profile (=profile 0).

1.9.1 Main

Setting / View	Profile 0	Profile 5	My setting
System Time	-	-	
System Date	-	-	
BIOS ID	-	-	
Processor	-	-	
CPU Frequency	-	-	
System Memory	-	-	
Product Revision	-	-	
Serial Number	-	-	
BC Firmware Rev.	-	-	
MAC Address (ETH1)	-	-	
Boot Counter	-	-	
Running Time	-	-	

Table 121: 945GME Main profile setting overview

1.9.2 Advanced

ACPI configuration

Setting / View	Profile 0	Profile 5	My setting
ACPI Aware O/S	Yes	Yes	
ACPI Version Features	ACPI v2.0	ACPI v2.0	
ACPI APIC support	Enabled	Enabled	
Suspend mode	S1 (POS)	S1 (POS)	
USB Device Wakeup from S3/S4	Disabled	Disabled	
Active Cooling Trip Point	Disabled	Disabled	
Passive Cooling Trip Point	Disabled	Disabled	
Critical Trip Point	105°C	105°C	

Table 122: 945GME Advanced - ACPI configuration profile setting overview

PCI Configuration

Setting / View	Profile 0	Profile 5	My setting
Plug & Play O/S	No	Yes	
PCI Latency Timer	64	64	
Allocate IRQ to PCI VGA	Yes	Yes	
Allocate IRQ to SMBUS HC	Yes	Yes	
Allocate IRQ to PCIEX2	Yes	Yes	
PCI IRQ Resource Exclusion			
IRQ3	Allocated	Available	
IRQ4	Allocated	Allocated	
IRQ5	Available	Available	
IRQ6	Available	Available	
IRQ7	Available	Available	
IRQ9	Allocated	Allocated	
IRQ10	Available	Available	
IRQ11	Allocated	Allocated	
IRQ12	Available	Available	
IRQ14	Allocated	Allocated	
IRQ15	Allocated	Allocated	
PCI Interrupt Routing			
PIRQ A (VGA,PCIEX4, ETH2,UHCI2,HDA)	Auto	Auto	
PIRQ B (PCIEX1, ETH1)	Auto	Auto	
PIRQ C (PCIEX2,IF slot)	Auto	Auto	
PIRQ D (SATA,UHCI1,SMB, PCIEX3)	Auto	Auto	
PIRQ E (INTD,UHCI3,PATA)	Auto	Auto	
PIRQ F (INTA)	Auto	Auto	
PIRQ G (INTB)	Auto	Auto	
PIRQ H (INTC,UHCI0,EHCI)	Auto	Auto	
1st Exclusive PCI	-	-	
2nd Exclusive PCI	-	-	
3rd Exclusive PCI	-	-	

Table 123: 945GME Advanced - PCI configuration profile setting overview

PCI express configuration

Setting / View	Profile 0	Profile 5	My setting
Active State Power-Management	Disabled	Disabled	
PCIe Port 0 (ETH2)	Auto	Auto	
PCIe Port 1	Auto	Auto	
PCIe Port 2 (IF slot)	Auto	Auto	
PCIe Port 3	Auto	Auto	
PCIe Port 4	Auto	Auto	
PCIe Port 5 (ETH1)	Auto	Auto	
PCIe High Priority Port	Disabled	Disabled	
Res. PCIe Hotplug Resource	No	No	
PCIe Port 0 IOxAPIC Enable	Disabled	Disabled	
PCIe Port 1 IOxAPIC Enable	Disabled	Disabled	
PCIe Port 2 IOxAPIC Enable	Disabled	Disabled	
PCIe Port 3 IOxAPIC Enable	Disabled	Disabled	

Table 124: 945GME Advanced - PCI Express configuration profile setting overview

Graphics configuration

Setting / View	Profile 0	Profile 5	My setting
Primary Video Device	Internal VGA	Internal VGA	
Internal Graphics Mode Select	Enabled, 8MB	Enabled, 8MB	
DVMT Mode Select	DVMT Mode	DVMT Mode	
DVMT/FIXED Memory	128MB	128MB	
Boot Display Device	Auto	Auto	
Boot Display Preference	SDVO-B SDVO-C LFP	LFP SDVO-B SDVO-C	
Local Flat Panel Type	Auto	Auto	
Local flat panel scaling	Centering	Expand Text & Graphics	
SDVO Port B Device	DVI	DVI	
SDVO Port C Device	DVI	None	
SDVO/DVI Hotplug Support	Enabled	Enabled	
Display Mode Persistence	Enabled	Enabled	

Table 125: 945GME Advanced - Graphics configuration profile setting overview

CPU configuration

Setting / View	Profile 0	Profile 5	My setting
MPS Revision	1.4	1.4	
Max CPUID value limit	Disabled	Disabled	
Execute Disable Bit	Enabled	Enabled	
Core Multi-Processing	Enabled	Enabled	
Intel(R) SpeedStep(tm) tech.	Automatic	Automatic	
Max. CPU frequency	xxxx MHz	xxxx MHz	
C1 Config.	Default	Default	
C2 Config.	Disabled	Disabled	
C3 Config.	Disabled	Disabled	
C4 Config.	Disabled	Disabled	

Table 126: 945GME Advanced - CPU configuration profile setting overview

Chipset configuration

Setting / View	Profile 0	Profile 5	My setting
DRAM Frequency	Auto	Auto	
Memory Hole	Disabled	Disabled	
DIMM Thermal Control	Disabled	Disabled	
DT in SPD	Disabled	Disabled	
TS on DIMM	Disabled	Disabled	
High Precision Event Timer	Disabled	Disabled	
IOAPIC	Enabled	Enabled	
APIC ACPI SCI IRQ	Disabled	Disabled	
C4 On C3	Disabled	Disabled	

Table 127: 945GME Advanced - Chipset configuration profile setting overview

I/O interface configuration

Setting / View	Profile 0	Profile 5	My setting
Onboard Audio Controller	AC97	HDA	

Table 128: 945GME Advanced - I/O Interface Configuration profile setting overview

Clock Configuration

Setting / View	Profile 0	Profile 5	My setting
Spread spectrum	Disabled	Disabled	

Table 129: 945GME Advanced - Clock configuration profile setting overview

IDE Configuration

Setting / View	Profile 0	Profile 5	My setting
ATA/IDE Configuration	Compatible	Compatible	
Legacy IDE Channels	SATA Pri, PATA Sec	SATA Pri, PATA Sec	
Configure SATA as	-	-	
Hard disk write protect	Disabled	Disabled	
IDE Detect Time Out (Sec)	35	35	
ATA(Pi) 80Pin Cable Detection	Host & device	Host & device	
Primary IDE Master			
Type	Auto	Auto	
LBA/Large Mode	Auto	Auto	
Block (Multi-Sector Transfer)	Auto	Auto	
PIO Mode	Auto	Auto	
DMA Mode	Auto	Auto	
S.M.A.R.T.	Auto	Auto	
32Bit data transfer	Enabled	Enabled	
Primary IDE slave			
Type	Auto	Auto	
LBA/Large Mode	Auto	Auto	
Block (Multi-Sector Transfer)	Auto	Auto	
PIO Mode	Auto	Auto	
DMA Mode	Auto	Auto	
S.M.A.R.T.	Auto	Auto	
32Bit data transfer	Enabled	Enabled	
Secondary IDE Master			
Type	Auto	Auto	
LBA/Large Mode	Auto	Auto	
Block (Multi-Sector Transfer)	Auto	Auto	
PIO Mode	Auto	Auto	
DMA Mode	Auto	Auto	
S.M.A.R.T.	Auto	Auto	
32Bit data transfer	Enabled	Enabled	

Table 130: 945GME Advanced - IDE configuration profile setting overview

Setting / View	Profile 0	Profile 5	My setting
Secondary IDE slave			
Type	Auto	Auto	
LBA/Large Mode	Auto	Auto	
Block (Multi-Sector Transfer)	Auto	Auto	
PIO Mode	Auto	Auto	
DMA Mode	Auto	Auto	
S.M.A.R.T.	Auto	Auto	
32Bit data transfer	Enabled	Enabled	

Table 130: 945GME Advanced - IDE configuration profile setting overview (cont.)

USB configuration

Setting / View	Profile 0	Profile 5	My setting
USB Function	8 USB Ports	8 USB Ports	
USB 2.0 Controller	Enabled	Enabled	
Legacy USB Support	Enabled	Enabled	
USB Legacy POST-Always	Enabled	Enabled	
USB Keyboard Legacy Support	Enabled	Enabled	
USB Mouse Legacy Support	Disabled	Disabled	
USB Storage Device Support	Enabled	Enabled	
Port 64/60 Emulation	Disabled	Disabled	
USB 2.0 Controller Mode	HiSpeed	HiSpeed	
BIOS EHCI Hand-Off	Disabled	Disabled	
USB Beep Message	Enabled	Enabled	
USB Stick Default Emulation	Hard Disk	Hard Disk	
USB Mass Storage Reset Delay	20 Sec	20 Sec	

Table 131: 945GME Advanced - USB configuration profile setting overview

Keyboard/mouse configuration

Setting / View	Profile 0	Profile 5	My setting
Boot-up Num-lock	On	On	
Typematic rate	Fast	Fast	

Table 132: 945GME Advanced - Keyboard/Mouse Configuration profile setting overview

Remote access configuration

Setting / View	Profile 0	Profile 5	My setting
Remote access	Disabled	Disabled	
Serial port BIOS update	Disabled	Disabled	

Table 133: 945GME Advanced - Remote Access Configuration profile setting overview

CPU board monitor

Setting / View	Profile 0	Profile 5	My setting
H/W Health Function	Enabled	Enabled	

Table 134: 945GME Advanced - CPU Board Monitor profile setting overview

Main Board/Panel Features

Setting / View	Profile 0	Profile 5	My setting
Panel control			
Select panel number	-	-	
Version	-	-	
Brightness	100%	100%	
Temperature	-	-	
Fan speed	-	-	
Keys/LEDs	-	-	
Main board monitor			
CMOS battery	-	-	
Board I/O	-	-	
Board ETH2	-	-	
Board Power	-	-	
Power supply			
Slide-in drive 1	-	-	
IF slot	-	-	
Case 1	-	-	
Case 2	-	-	
Case 3	-	-	
Case 4	-	-	
Legacy devices			
COM A	Enabled	Enabled	
Base I/O address	3F8	3F8	
Interrupt	IRQ4	IRQ4	
COM C	Enabled	Enabled	

Table 135: 945GME Advanced - Baseboard/Panel Features profile setting overview

Setting / View	Profile 0	Profile 5	My setting
Base I/O address	3E8	3E8	
Interrupt	IRQ11	IRQ11	
COM D	Disabled	Disabled	
Base I/O address	-	-	
Interrupt	-	-	
COM E	Disabled	Disabled	
Base I/O address	-	-	
Interrupt	-	-	
Base I/O address	378	378	
ETH2 LAN Controller	Enabled	Enabled	
ETH2 MAC Address	-	-	

Table 135: 945GME Advanced - Baseboard/Panel Features profile setting overview (cont.)

1.9.3 Boot

Setting / View	Profile 0	Profile 5	My setting
Boot Priority Selection	Type Based	Type Based	
1st Boot Device	Onboard LAN	Primary master	
2nd Boot Device	Primary master	Primary slave	
3rd Boot Device	Primary slave	USB floppy	
4th Boot Device	USB floppy	USB removable device	
5th Boot Device	USB removable device	USB hard disk	
6th Boot Device	USB CDROM	USB CDROM	
7th Boot Device	Secondary master	Secondary master	
8th Boot Device	Secondary slave	Secondary slave	
Quick Boot	Enabled	Enabled	
Quiet Boot	Disabled	Disabled	
Automatic Boot List Retry	Disabled	Disabled	
Add-On ROM Display Mode	Keep Current	Keep Current	
Halt On Error	Disabled	Disabled	
Hit "DEL" Message Display	Enabled	Enabled	
Interrupt 19 Capture	Disabled	Disabled	
PXE boot to LAN (ETH1)	Enabled	Disabled	
Slide-in 2 optional ROM	Enabled	Disabled	
Power Loss Control	Turn On	Turn On	

Table 136: 945GME Boot profile setting overview

1.9.4 Security

Setting / View	Profile 0	Profile 5	My setting
Supervisor Password	-	-	
User Password	-	-	
Boot Sector Virus Protection	Disabled	Disabled	
Hard disk security user password	-	-	
Hard disk security master password	-	-	

Table 137: 945GME Security profile setting overview

1.9.5 Power

Setting / View	Profile 0	Profile 5	My setting
Power Management/APM	Enabled	Enabled	
Suspend Time Out	Disabled	Disabled	
Video Power Down Mode	Suspend	Suspend	
Hard Disk Power Down Mode	Suspend	Suspend	
Keyboard & PS/2 Mouse	MONITOR	MONITOR	
FDC/LPT/COM ports	MONITOR	MONITOR	
Primary Master IDE	MONITOR	MONITOR	
Primary Slave IDE	MONITOR	MONITOR	
Secondary Master IDE	MONITOR	MONITOR	
Secondary Slave IDE	MONITOR	MONITOR	
Resume On Ring	Disabled	Disabled	
Resume on PME#	Disabled	Disabled	
Resume On RTC Alarm	Disabled	Disabled	
Power Button Mode	On/Off	On/Off	

Table 138: 945GME Power profile setting overview

1.10 BIOS Error signals (beep codes)

While the Panel PC 800 is booting, the following messages and errors can occur with BIOS. These errors are signaled by different beeping codes.

1.10.1 BIOS 945GME

Beeping code	Meaning	Necessary user action
1x short	Memory refresh failed.	Load BIOS defaults. In the event that the error persists, send industrial PC to B&R for testing.
2x short	Parity error: POST error (error in one of the hardware testing procedures)	Check the placement of the inserted card. In the event that the error persists, send industrial PC to B&R for testing.
3x short	Base 64 KB memory failure: Basic memory defect, RAM error within the initial 64 KB.	Send industrial PC to B&R for checking.
4x short	Timer not operational: System timer.	Send industrial PC to B&R for checking.
5x short	Processor error: Processor defect.	Send industrial PC to B&R for checking.
6x short	8042 gate A20 failure: Keyboard controller defect (block 8042/ A20 gate). Processor cannot switch to protected mode.	Send industrial PC to B&R for checking.
7x short	Processor exception interrupt error: Virtual mode exception error (CPU generated an interrupt error).	Send industrial PC to B&R for checking.
8x short	Display memory read/write error: Video memory not accessible; graphic card defect or not built in (no fatal error).	Check inserted graphic card position and eventually exchange. In the event that the error persists, send industrial PC to B&R for testing.
9x short	ROM-checksum error: ROM-BIOS-checksum incorrect, EPROM, EEPROM or Flash-ROM component defect, BIOS defect or incorrectly updated.	Send industrial PC to B&R for checking.
10x short	CMOS shutdown register read/write error: CMOS cannot be read/written.	Send industrial PC to B&R for checking.
11x short	Cache Error / external Cache bad: L2 - Cache on the mainboard is defected.	Send industrial PC to B&R for checking.

Table 139: BIOS post code messages BIOS 945GME

1.11 Distribution of resources

1.11.1 RAM address assignment

RAM address	Address in Hex	Resource
(TOM - 192 kB) – TOM ¹⁾	N.A.	ACPI reclaim, MPS and NVS area ²⁾
(TOM - 8 MB - 192 kB) – (TOM - 192 kB)	N.A.	VGA frame buffer ³⁾
1024 kB – (TOM - 8 MB - 192 kB)	100000h - N.A.	Extended memory
869 kB – 1024 kB	0E0000h - 0FFFFFFh	Runtime BIOS
832 kB – 869 kB	0D0000h - 0DFFFFh	Upper memory
640 kB – 832 kB	0A0000h - 0CFFFFh	Video memory and BIOS
639 kB – 640 kB	09FC00h - 09FFFFh	Extended BIOS data
0 – 639 kB	000000h - 09FC00h	Conventional memory

Table 140: RAM address assignment

1) TOM - Top of memory: max. installed DRAM

2) Only if ACPI Aware OS is set to "YES" in the setup.

3) The VGA frame buffer can be reduced to 1 MB in the setup.

1.11.2 I/O address assignment

I/O address	Resource
0000h - 00FFh	Motherboard resources
0170h - 0177h	Secondary IDE channel
01F0h - 01F7h	Primary IDE channel
0238h - 023Fh	COM5
0278h - 027Fh	Hardware Security Key (LPT2)
02E8h - 02EFh	COM4
0376h - 0376h	Secondary IDE channel command port
0377h - 0377h	Secondary IDE channel status port
0378h - 037Fh	Hardware Security Key (LPT1)
0384h - 0385h	CAN controller
03B0h - 03DFh	Video system
03E8h - 03EFh	COM3
03F6h - 03F6h	Primary IDE channel command port
03F7h - 03F7h	Primary IDE channel status port
03F8h - 03FFh	COM1
0480h - 04BFh	Motherboard resources
04D0h - 04D1h	Motherboard resources
0800h - 087Fh	Motherboard resources
0CF8h - 0CFBh	PCI config address register
0CFCh - 0CFFh	PCI config data register
0D00h - FFFFh	PCI / PCI Express bus ¹⁾
4100h - 417Fh	MTCX
FF00h - FF07h	IDE bus master register

Table 141: I/O address assignment

1) The BIOS assigns the PCI and PCI Express Bus I/O resources from FFF0h downward. Devices that are not compatible with PnP/PCI/PCI Express cannot use the I/O resources in this area.

1.11.3 Interrupt assignments in PCI mode

IRQ	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	NMI	NONE
System timer	●																	
Keyboard		●																
IRQ cascade			●															
COM1 (Serial port A)				○	●	○	○	○			○	○	○					
ACPI ¹⁾										●								
Real-time clock									●									
Coprocessor (FPU)														●				
Primary IDE channel															●			
Secondary IDE channel																●		
B&R	COM3 (COM C)			○	○	○	○	○			○	●	○					○
	COM4 (COM E)			○	○	○	○	○			○	○	○					●
	COM5 (COM D)			○	○	○	○	○			○	○	○					●
	CAN			○	○	○	○	○			○	○	○				○	●

Table 142: IRQ interrupt assignments in PCI mode

1) Advanced Configuration and Power Interface.

- ... Default setting
- ... Optional setting

1.11.4 Interrupt assignments in APIC mode

A total of 23 IRQs are available in the APIC mode (**A**dvanced **P**rogrammable Interrupt **C**ontroller). The activation of this option is only effective if it takes place before the operating system (Windows XP) is activated.

IRQ	0	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	NMI	NONE
System timer	●																									
Keyboard		●																								
IRQ cascade			●																							
COM1 (Serial port A)				○	●	○	○	○			○	○	○													
ACP ¹⁾									●																	
Real-time clock								●																		
Coprocessor (FPU)													●													
Primary IDE channel														●												
Secondary IDE channel															●											
B&R	COM3 (COM C)			○	○	○	○	○			○	●	○													○
	COM4 (COM E)			○	○	○	○	○			○	○	○													●
	COM5 (COM D)			○	○	○	○	○			○	○	○													●
	CAN			○	○	○	○	○			○	○	○												○	●
PIRQ A ²⁾																●										
PIRQ B ³⁾																	●									
PIRQ C ⁴⁾																		●								
PIRQ D ⁵⁾																			●							
PIRQ E ⁶⁾																				●						
PIRQ F ⁷⁾																					●					
PIRQ G ⁸⁾																						●				
PIRQ H ⁹⁾																							●			

Table 143: IRQ interrupt assignments in APIC mode

1) Advanced Configuration and Power Interface.

2) PIRQ A: for PCIe; UHCI Host Controller 2, VGA controller, Intel High Definition Audio Controller. PCI Express Root Port 4

3) PIRQ B: for PCIe; PCI Express root port 1, onboard Gigabit LAN controller

4) PIRQ C: for PCIe; PCI express root port 2

5) PIRQ D: for PCIe; UHCI host controller 1, SMBus controller, PCI Express root port 3, Serial ATA controller in enhanced/native mode

6) PIRQ E: PCI bus INTD, UHCI Host Controller 3, Parallel ATA controller in enhanced/native mode

7) PIRQ F: PCI bus INTA

- 8) PIRQ G: PCI bus INTB
 9) PIRQ H: PCI bus INTC, UHCI host controller 0, EHCI host controller

- ... Default setting
 ○ ... Optional setting

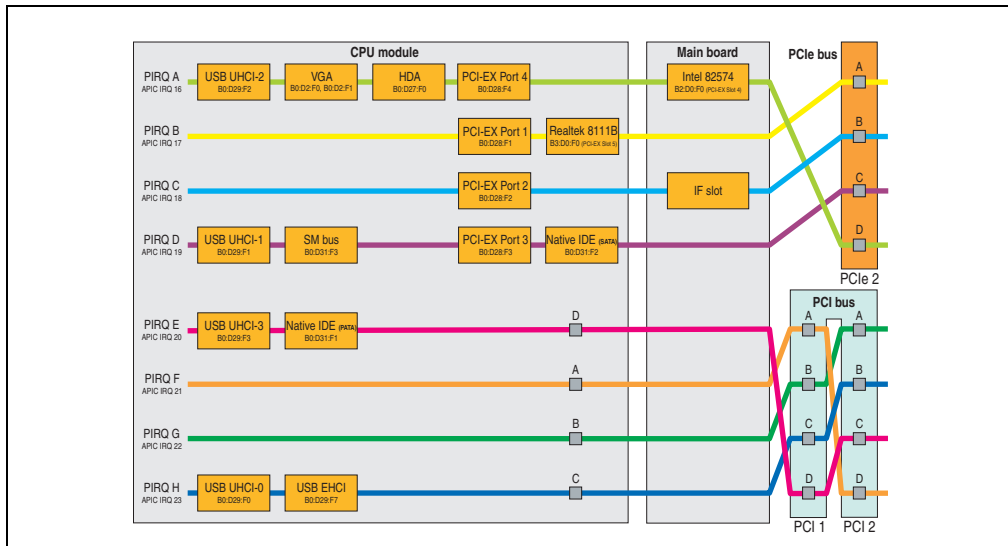


Figure 114: PCI and PCIe routing with activated APIC for CPU boards 945GME version 1.15

2. Upgrade information

Warning!

The BIOS and firmware on PPC800 systems must be kept up to date. New versions can be downloaded from the B&R homepage (www.br-automation.com).

2.1 BIOS upgrade

An upgrade might be necessary for the following reason:

- To update implemented functions or to add newly implemented functions or components to the BIOS setup (information about changes can be found in the Readme files of the BIOS upgrade).

2.1.1 What information do I need?

Information:

Individually saved BIOS settings are deleted when upgrading the BIOS.

Before you begin the upgrade, it helps to determine the various software versions.

Which BIOS version and firmware are already installed on the PPC800?

This information can be found on the following BIOS setup page:

- After switching on the PPC800, you can get to the BIOS Setup by pressing "Del".
- From the BIOS main menu "Advanced", select "Main board/panel features".

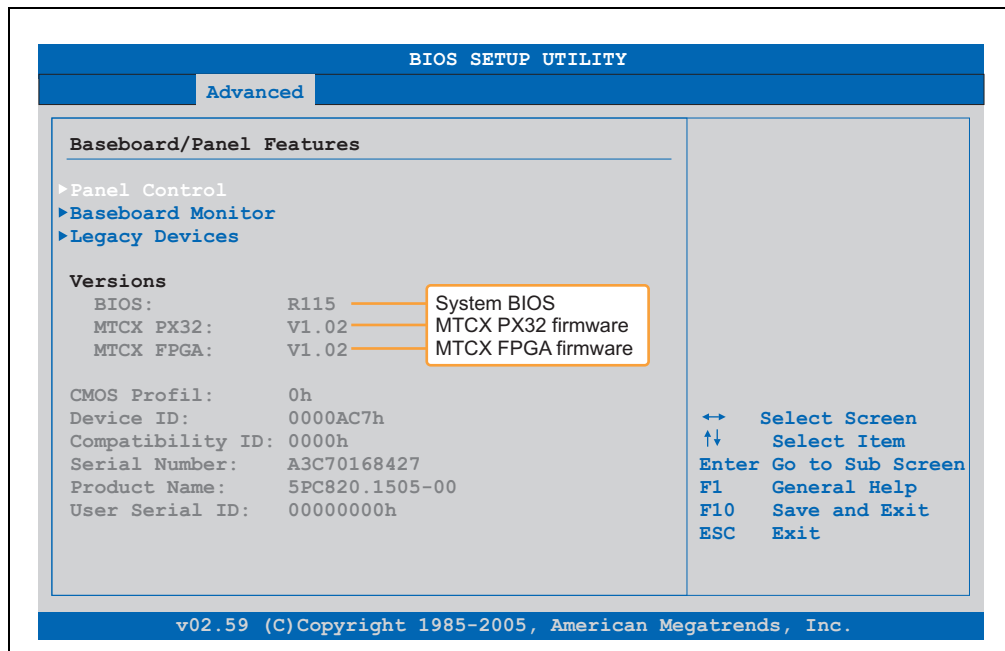


Figure 115: Software version

Which firmware is installed on the Automation Panel Link transmitter?

This information can be found on the following BIOS setup page:

- After switching on the PPC800, you can get to the BIOS Setup by pressing "Del".
- From the BIOS main menu "Advanced", select "Main board/panel features" and then "Panel control".

Information:

The version can only be displayed when an Automation Panel with an AP Link SDL transmitter (5AC801.SDL0-00) is connected.

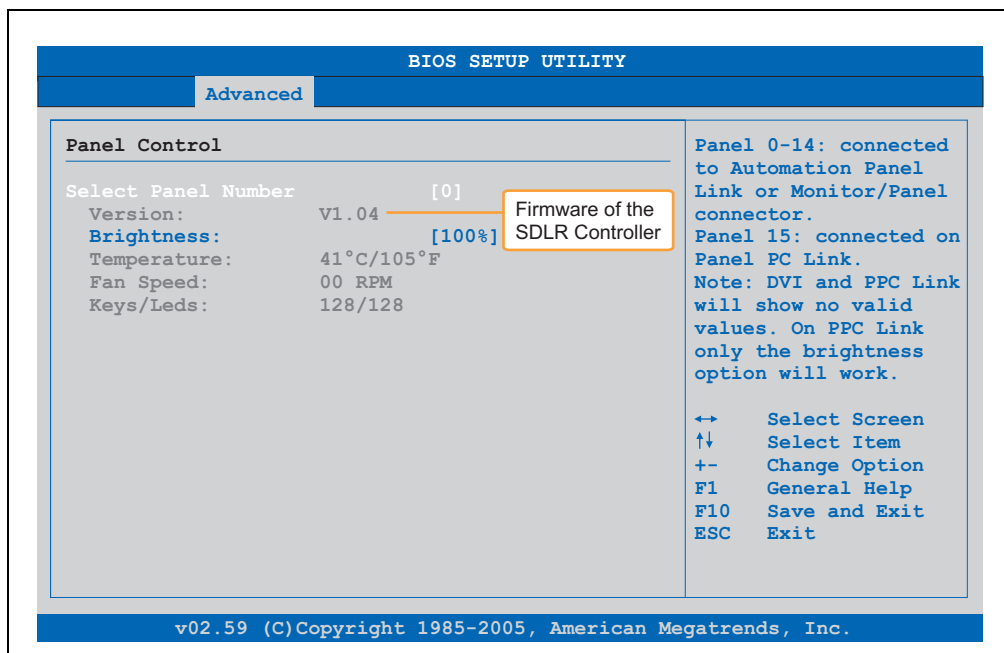


Figure 116: Firmware version of the AP Link SDL transmitter

2.1.2 BIOS upgrade for 945GME COM Express

- Download ZIP file from the B&R homepage (www.br-automation.com)
- Create bootable media.

Information:

In MS-DOS, Win95 and Win98, a blank HD disk can be made bootable using the command line command "sys a:" or "format a: /s".

Information concerning creating a bootable diskette in Windows XP can be found on page 241.

Information concerning creating a USB flash drive for a B&R upgrade can be found on page 243.

Information concerning creating a CompactFlash card for a B&R upgrade can be found on page 245.

- Copy the contents of the *.zip file to the bootable media. If the B&R upgrade was already added when the bootable media was created using the B&R Embedded OS Installer, then this step is not necessary.
- Connect the bootable media to the PPC800 and reboot the device.
- The following boot menu will be shown after startup:

1. Upgrade AMI BIOS for B945 (5PC800.B945-00,-01,-02,-03,-04)
2. Exit

Concerning point 1:

BIOS is automatically upgraded (default after 5 seconds).

Concerning point 2:

Returns to the shell (MS-DOS).

Information:

If you do not press a button within 5 seconds, then step 1 "Upgrade AMI BIOS for B945" is automatically carried out and the PPC800 is automatically updated.

- The system must be rebooted after a successful upgrade.
- Reboot and press "Del" to enter the BIOS setup menu and load the setup defaults, then select "Save Changes and Exit".

2.2 Firmware upgrade

The "PPC800 MTCX Upgrade" software makes it possible to update the firmware for multiple controllers (MTCX, SDLR, SDLT), depending on the structure of the PPC800 system.

Current "PPC800 MTCX Upgrade" software can be downloaded directly from the service portal on the B&R homepage (www.br-automation.com).

2.2.1 Procedure

To carry out a firmware upgrade, the following steps should be taken:

- Download the zip file from the B&R homepage.
- Create bootable media.

Information:

In MS-DOS, Win95 and Win98, a blank HD disk can be made bootable using the command line command "sys a:" or "format a: /s".

Information concerning creating a bootable diskette in Windows XP can be found on page 241.

Information concerning creating a USB flash drive for a B&R upgrade can be found on page 243.

Information concerning creating a CompactFlash card for a B&R upgrade can be found on page 245.

- Copy the contents of the *.zip file to the bootable media. If the B&R upgrade was already added when the bootable media was created using the B&R OS Installer, then this step is not necessary.
- Connect the bootable media to the PPC800 and reboot the device.
- The boot menu is shown after startup
- The system must be powered off and on again after a successful upgrade.

Information:

The following boot menu options including descriptions are based on Version 1.02 of the PPC800 upgrade (MTCX, SDLR, SDLT) disk. In some cases, these descriptions might not match the version you are currently using.

Boot menu options:

1. Upgrade MTCX (PPC800) PX32 and FPGA
2. Upgrade SDLR (AP800/AP900) on monitor/panel
 - 2.1. Upgrade SDLR on AP 0 (AP800/AP900)
 - 2.2. Upgrade SDLR on AP 1 (AP800/AP900)
 - 2.3. Upgrade SDLR on AP 2 (AP800/AP900)
 - 2.4. Upgrade SDLR on AP 3 (AP800/AP900)
 - 2.5. Upgrade all SDLR (AP800/AP900)
 - 2.6. Return to main menu
3. Upgrade add-on UPS (firmware and battery settings)
 - 3.1. Upgrade Add-On UPS Firmware (5AC600.UPSI-00)
 - 3.2. Upgrade Battery Settings (5AC600.UPSB-00)
 - 3.3. Return to main menu
4. Exit

Concerning point 1:

Automatically upgrade PX32 and FPGA for MTCX (default after 5 seconds).

Concerning point 2:

Submenu 1 is opened for upgrading the SDLR controller on the Monitor/Panel plug.

2.1. Upgrade SDLR on AP 0 (AP800/AP900)

The SDLR controller is automatically updated on Automation Panel 0.

2.2. Upgrade SDLR on AP 1 (AP800/AP900)

The SDLR controller is automatically updated on Automation Panel 1.

2.3. Upgrade SDLR on AP 2 (AP800/AP900)

The SDLR controller is automatically updated on Automation Panel 2.

2.4. Upgrade SDLR on AP 3 (AP800/AP900)

The SDLR controller is automatically updated on Automation Panel 3.

2.5. Upgrade all SDLR (AP800/AP900)

All SDLR controllers are automatically updated on all Automation Panels on the Monitor/Panel (default after 5 sec).

2.6. Return to main menu

Returns to the main menu.

Concerning point 3:

Submenu 3 for the add-on UPS firmware and upgrade and the battery settings upgrade is opened.

3.1. Upgrade Add-On UPS Firmware (5AC600.UPSI-00)

The firmware for the add-on UPS is updated.

3.2. Upgrade Battery Settings (5AC600.UPSB-00)

The battery settings for 5AC600.UPSB-00 are automatically updated.

3.3. Return to main menu

Returns to the main menu.

Concerning point 4:

Returns to the shell (MS-DOS).

Information:

The system must be powered off and on again after a successful upgrade.

2.2.2 Possible upgrade problems and software dependencies (for V1.02)

- The SDLR firmware can only be updated if an Automation Panel with Automation Panel Link Transceiver (5DLSDL.1000-01) and Automation Panel Link Receiver (5DLSDL.1000-00) is connected.
- Automation Panel Link transceivers (5DLSDL.1000-01) or Automation Panel Link receivers (5DLSDL.1000-00) with a Firmware version lower than or equal to V00.10 can no longer be combined with Automation Panel Link transceivers (5DLSDL.1000-01) or Automation Panel Link receivers (5DLSDL.1000-00) with a Firmware higher than or equal to V01.04. Daisy Chain mode is not possible with such a combination.
- If a UPS (e.g.: 5AC600.UPSI-00) + battery unit (e.g.: 5AC600.UPSB-00) is connected to the system and operable, then after an upgrade of the MTCX or SDLT you must either disconnect the battery or push the Power button (to put the system in Standby mode), before executing the required power off/on. If not, the firmware upgrade will not work because the UPS buffers the system.

2.3 Creating an MS-DOS boot diskette in Windows XP

- Place an empty 1.44 MB HD diskette in the disk drive
- Open Windows Explorer
- Right-click on the 3½" floppy icon and select "**Format...**".

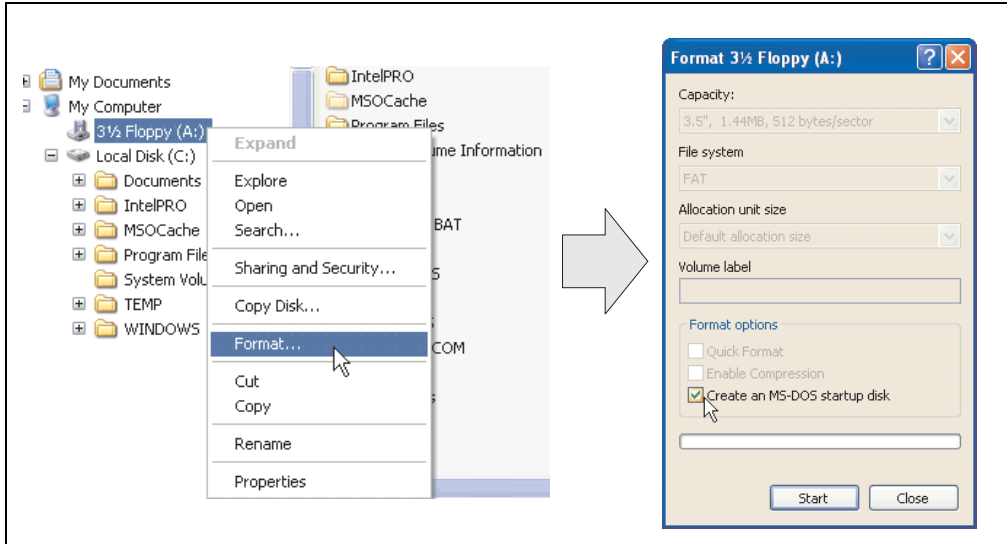


Figure 117: Creating a bootable diskette in Windows XP - step 1

- Then select the checkbox **Create an MS-DOS startup disk**, press **Start** and acknowledge the warning message with **OK**.

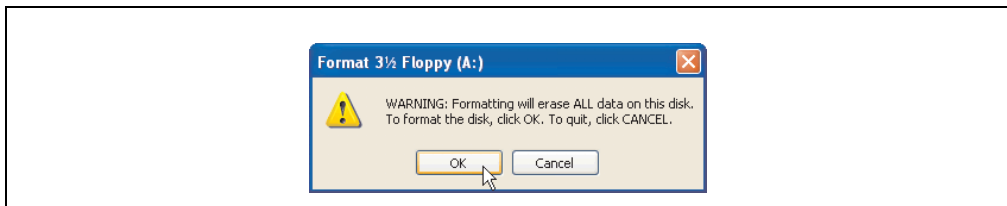


Figure 118: Creating a bootable diskette in Windows XP - step 2

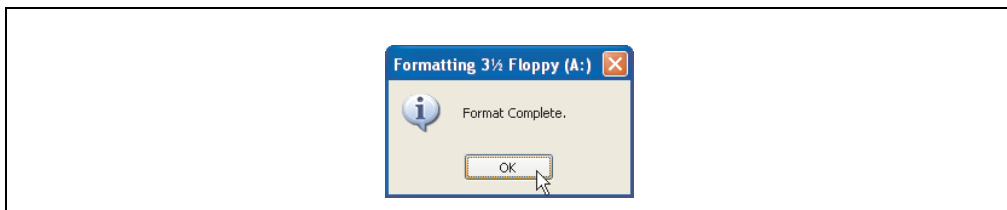


Figure 119: Creating a bootable diskette in Windows XP - step 3

Software • Upgrade information

After creating the startup disk, some of the files must be deleted because of the size of the update.

When doing this, all files (hidden, system files, etc.) must be shown on the diskette.

In the Explore, for the **Tools** menu, select **Folder Options...**, and open the **View** tab - now disable the option **Hide protected operating system files (Recommended)** (enabled by default) and enable the option **Show hidden files and folders**.

before				after			
Name	Size	Type	Date Modified	Name	Size	Type	Date Modified
DISPLAY.SYS	17 KB	System File	6/8/2000 5:00 PM	AUTOEXEC.BAT	0 KB	MS-DOS Batch File	3/22/2006 10:08 AM
EGA2.CPI	58 KB	CPI File	6/8/2000 5:00 PM	COMMAND.COM	91 KB	MS-DOS Application	6/8/2000 5:00 PM
EGA3.CPI	58 KB	CPI File	6/8/2000 5:00 PM	CONFIG.SYS	0 KB	System File	3/22/2006 10:08 AM
EGA.CPI	58 KB	CPI File	6/8/2000 5:00 PM	DISPLAY.SYS	17 KB	System File	6/8/2000 5:00 PM
KEYB.COM	22 KB	MS-DOS Application	6/8/2000 5:00 PM	EGA2.CPI	58 KB	CPI File	6/8/2000 5:00 PM
KEYBOARD.SYS	34 KB	System File	6/8/2000 5:00 PM	EGA3.CPI	58 KB	CPI File	6/8/2000 5:00 PM
KEYBRD2.SYS	32 KB	System File	6/8/2000 5:00 PM	EGA.CPI	58 KB	CPI File	6/8/2000 5:00 PM
KEYBRD3.SYS	31 KB	System File	6/8/2000 5:00 PM	IO.SYS	114 KB	System File	5/15/2001 6:57 PM
KEYBRD4.SYS	13 KB	System File	6/8/2000 5:00 PM	KEYB.COM	22 KB	MS-DOS Application	6/8/2000 5:00 PM
MODE.COM	29 KB	MS-DOS Application	6/8/2000 5:00 PM	KEYBOARD.SYS	34 KB	System File	6/8/2000 5:00 PM
				KEYBRD2.SYS	32 KB	System File	6/8/2000 5:00 PM
				KEYBRD3.SYS	31 KB	System File	6/8/2000 5:00 PM
				KEYBRD4.SYS	13 KB	System File	6/8/2000 5:00 PM
				MODE.COM	29 KB	MS-DOS Application	6/8/2000 5:00 PM
				MSDOS.SYS	1 KB	System File	4/7/2001 1:40 PM

Figure 120: Creating a bootable diskette in Windows XP - step 4

Name	Size	Type	Date Modified
AUTOEXEC.BAT	0 KB	MS-DOS Batch File	3/22/2006 10:08 AM
COMMAND.COM	91 KB	MS-DOS Application	6/8/2000 5:00 PM
CONFIG.SYS	0 KB	System File	3/22/2006 10:08 AM
DISPLAY.SYS	17 KB	System File	6/8/2000 5:00 PM
EGA2.CPI	58 KB	CPI File	6/8/2000 5:00 PM
EGA3.CPI	58 KB	CPI File	6/8/2000 5:00 PM
EGA.CPI	58 KB	CPI File	6/8/2000 5:00 PM
IO.SYS	114 KB	System File	5/15/2001 6:57 PM
KEYB.COM	22 KB	MS-DOS Application	6/8/2000 5:00 PM
KEYBOARD.SYS	34 KB	System File	6/8/2000 5:00 PM
KEYBRD2.SYS	32 KB	System File	6/8/2000 5:00 PM
KEYBRD3.SYS	31 KB	System File	6/8/2000 5:00 PM
KEYBRD4.SYS	13 KB	System File	6/8/2000 5:00 PM
MODE.COM	29 KB	MS-DOS Application	6/8/2000 5:00 PM
MSDOS.SYS	1 KB	System File	4/7/2001 1:40 PM

Figure 121: Creating a bootable diskette in Windows XP - step 5

Now all files (marked) except Command.com, IO.sys and MSDOS.sys can be deleted.

2.4 Creating a bootable USB flash drive for B&R upgrade files

When used in connection with a B&R industrial PC, it is possible to upgrade BIOS from one of the USB flash drives available from B&R. To do this, the USB flash drive must be prepared accordingly. This is done with the B&R Embedded OS Installer, which can be downloaded for free from the B&R homepage (www.br-automation.com).

2.4.1 Requirements

The following peripherals are required for creating a bootable USB flash drive:

- B&R USB flash drive
- B&R Industrial PC
- USB Media Drive
- B&R Embedded OS Installer (V3.00 or higher)

2.4.2 Procedure

- Connect the USB flash drive to the PC.
- If the drive list is not refreshed automatically, the list must be updated using the command **Drives > Refresh**.
- Mark the desired USB flash drive in the drive list.
- Change to the **Action** tab and select **Install a B&R Update to a USB flash drive** as type of action.
- Enter the path to the MS-DOS operating system files. If the files are part of a ZIP archive, then click on the button **By ZIP file....** If the files are stored in a directory on the hard drive, then click on the button **By folder....**
- In the **B&R Upgrade** text box, it's also possible to enter the path to the ZIP file for the B&R Upgrade Disk and select the file.
- Click on the **Start action** button in the toolbar.

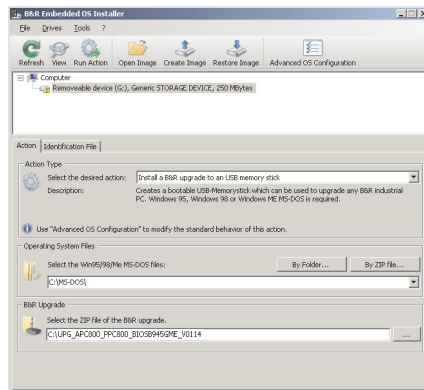


Figure 122: Creating a USB flash drive for B&R upgrade files

2.4.3 Where do I get MS-DOS?

Information concerning creating an MS-DOS boot diskette can be found in section 2.3 "Creating an MS-DOS boot diskette in Windows XP", on page 241. Then the files from the diskette are to be copied to your hard drive.

2.5 Creating a bootable CompactFlash card for B&R upgrade files

When used in connection with a B&R industrial PC, it is possible to upgrade BIOS from one of the CompactFlash cards available from B&R. To do this, the CompactFlash card must be prepared accordingly. This is done with the B&R Embedded OS Installer, which can be downloaded for free from the B&R homepage (www.br-automation.com).

2.5.1 Requirements

The following peripherals are required for creating a bootable CompactFlash card:

- CompactFlash card
- B&R Industrial PC
- B&R Embedded OS Installer (V3.10 or higher)

2.5.2 Procedure

- Insert the CompactFlash card in the CF slot on the industrial PC.
- If the drive list is not refreshed automatically, the list must be updated using the command **Drives > Refresh**.
- Select the desired CompactFlash card from the drive list.
- Change to the **Action** tab and select **Install a B&R Update to a CompactFlash card** as type of action.
- Enter the path to the MS-DOS operating system files. If the files are part of a ZIP archive, then click on the button **By ZIP file....** If the files are stored in a directory on the hard drive, then click on the button **By folder....**
- In the **B&R Upgrade** text box, it's also possible to enter the path to the ZIP file for the B&R Upgrade Disk and select the file.
- Click on the **Start action** button in the toolbar.

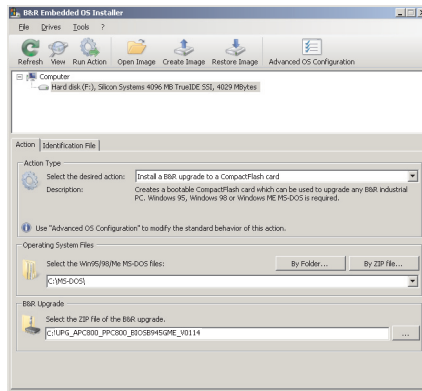


Figure 123: Creating a CompactFlash card for B&R upgrade files

2.5.3 Where do I get MS-DOS?

Information concerning creating an MS-DOS boot diskette can be found in section 2.3 "Creating an MS-DOS boot diskette in Windows XP", on page 241. Then the files from the diskette are to be copied to your hard drive.

2.6 Upgrade problems

Potential upgrade problems are listed in the Liesmich.txt or Readme.txt files on the upgrade disks.

3. Panel PC 800 with MS-DOS



Figure 124: Panel PC 800 with MS-DOS

Model number	Short description	Note
9S0000.01-010	OEM MS-DOS 6.22 German (disk) OEM MS-DOS 6.22 German disks Only delivered with a new PC.	
9S0000.01-020	OEM MS-DOS 6.22 English (disk) OEM MS-DOS 6.22 English disks Only delivered with a new PC.	

Table 144: Model numbers - MS-DOS

3.1 Known problems

Either no drivers are available for the following hardware components or only with limitations:

- HDA Sound - No support
- USB 2.0 - only USB 1.1 rates can be reached.
- "Graphics Engine 2" and therefore Extended Desktop mode also cannot be used.
- A few "ACPI control" BIOS functions cannot be used.

The following table shows the tested resolutions and color depths on the Monitor / Panel connector with 945GME CPU boards.

Resolutions for DVI	Color depth		
	8-bit	16-bit	24-bit
640 x 480	✓	✓	✓
800 x 600	✓	✓	✓
1024 x 768	✓	✓	✓
1280 x 1024	✓	✓	✓
Resolutions for RGB	Color depth		
	8-bit	16-bit	24-bit
640 x 480	✓	✓	✓
800 x 600	✓	✓	✓
1024 x 768	✓	✓	✓
1280 x 1024	✓	✓	✓
1600 x 1200	✓	✓	✓
1920 x 1440	✓	✓	

Table 145: Tested resolutions and color depths for DVI and RGB signals

4. Panel PC 800 with Windows XP Professional



Figure 125: Windows XP Professional Logo

Model number	Short description	Note
5SWWXP.0600-GER	WinXP Professional with SP3, GER Microsoft OEM Windows XP Professional Service Pack 3, CD, German. Only available with a new device.	
5SWWXP.0600-ENG	WinXP Professional with SP3, ENG Microsoft OEM Windows XP Professional Service Pack 3, CD, English. Only available with a new device.	
5SWWXP.0600-MUL	WinXP Professional with SP3, MUL Microsoft OEM Windows XP Professional Service Pack 3, CD, multi-language. Only available with a new device.	
5SWWXP.0500-GER	WinXP Professional with SP 2c, GER Microsoft OEM Windows XP Professional Service Pack 2c, CD, German. Only available with a new device.	
5SWWXP.0500-ENG	WinXP Professional with SP 2c, ENG Microsoft OEM Windows XP Professional Service Pack 2c, CD, English. Only available with a new device.	
5SWWXP.0500-MUL	WinXP Professional with SP 2c, MUL Microsoft OEM Windows XP Professional Service Pack 2c, CD, multi-language. Only available with a new device.	

Table 146: Model numbers - Windows XP Professional

4.1 Installation

Upon request, B&R can pre-install the required Windows XP Professional version on the desired mass memory (add-on hard disk, slide-in hard disk). All of the drivers required for operation (graphics, network, etc.) are also installed when doing so.

5. Panel PC 800 with Windows XP Embedded



Figure 126: Windows XP Embedded Logo

Model number	Short description	Note
5SWWXP.0427-ENG	WinXPe FP2007 PPC800 945GME Order Microsoft OEM Windows XP embedded Feature Pack 2007, English; for PPC800 with CPU boards 5PC800.B945-00, 5PC800.B945-01, 5PC800.B945-02, 5PC800.B945-03, 5PC800.B945-04; 5PC800.B945-05; CompactFlash separately (at least 512 MB).	

Table 147: Model numbers - Windows XP Embedded

5.1 General information

Windows XP Embedded is the modular version of the desktop operating system Windows XP Professional. Windows XP Embedded is based on the same binary files as Windows XP Professional and is optimally tailored to the hardware being used. In other words, only the functions and modules required by the respective device are included. Windows XP Embedded is also based on the same reliable code as Windows XP Professional. It provides industry with leading reliability, improvements in security and performance, and the latest technology for Web browsing and extensive device support.

5.2 Features with FP2007 (Feature Pack 2007)

The feature list shows the most important device functions in Windows XP Embedded with Feature Pack 2007 (FP2007).

Function	Present
Enhanced write filter (EWF)	✓
File Based Write Filter	✓
Page file	Configurable
Administrator account	✓
User account	Configurable
Explorer shell	✓
Registry filter	✓
Internet Explorer 6.0 + SP2	✓
Internet information service (IIS)	-
Terminal service	✓
Windows Firewall	✓
MSN-Explorer	-
Outlook Express	-
Administrative Tools	✓
Remote Desktop	✓
Remote Assistance	-
.NET Framework	-
ASP.NET	-
Codepages/User Locale/Keyboard	✓
Disk Management Service	✓
Windows Installer Service	✓
Class Installer	✓
CoDevice Installer	✓
Media Player	-
DirectX	-
Accessories	✓
Number of fonts	89

Table 148: Device functions in Windows XP Embedded with FP2007

5.3 Installation

Upon request, Windows XP Embedded can be preinstalled at B&R Austria on a suitable CompactFlash card (min. 512MB). The PPC800 system is then automatically configured after it has been switched on for the first time. This procedure takes approximately 30 minutes, and the device will be rebooted a number of times.

5.4 Drivers

All drivers required for operation are preinstalled on the operating system. If an older driver version is installed, the latest version can be downloaded from the B&R homepage (www.br-automation.com) and installed. A potentially activated "Enhanced Write Filter (EWF)" must be taken into consideration.

5.4.1 Touch screen driver

The touch screen driver must be manually installed in order to operate Automation Panel 800 or Automation Panel 900 touch screen devices. The driver can be downloaded from the download area on the B&R homepage (www.br-automation.com). A potentially activated "Enhanced Write Filter (EWF)" must be taken into consideration.

Information:

Required drivers can only be downloaded from the B&R homepage, not from manufacturers' pages.

6. Panel PC 800 with Windows Embedded Standard 2009



Figure 127: Windows Embedded Standard 2009 Logo

Model number	Short description	Note
5SWWXP.0727-ENG	Windows Embedded Standard 2009 PPC800 945GME Order Microsoft OEM Windows Embedded Standard 2009, English; for PPC800 with CPU boards 5PC800.B945-00, 5PC800.B945-01, 5PC800.B945-02, 5PC800.B945-03, 5PC800.B945-04, 5PC800.B945-05; CompactFlash separately (min. 1 GB).	

Table 149: Model numbers - Windows Embedded Standard 2009

6.1 General information

Windows XP Embedded Standard 2009 is the modular version of the desktop operating system Windows XP Professional with Service Pack 3. Windows XP Embedded Standard 2009 is based on the same binary files as Windows XP Professional with Service Pack 3 and is optimally tailored to the hardware being used. In other words, only the functions and modules required by the respective device are included. Windows XP Embedded Standard 2009 is also based on the same reliable code as Windows XP Professional with SP3. It provides industry with leading reliability, improvements in security and performance, and the latest technology for Web browsing and extensive device support.

6.2 Features with WES2009 (Windows Embedded Standard 2009)

The feature list shows the most important device functions in Windows Embedded Standard 2009.

Function	Present
Enhanced write filter (EWF)	✓
File Based Write Filter	✓
Page file	Configurable
Administrator account	✓
User account	Configurable
Explorer shell	✓
Registry filter	✓
Internet Explorer 7.0	✓
Internet information service (IIS)	-
Terminal service	✓
Windows Firewall	✓
MSN-Explorer	-
Outlook Express	-
Administrative Tools	✓
Remote Desktop	✓
Remote Assistance	-
.NET Framework	-
ASP.NET	-
Local Network Bridge	✓
Codepages/User Locale/Keyboard	✓
Disk Management Service	✓
Windows Installer Service	✓
Class Installer	✓
CoDevice Installer	✓
Media Player 6.4	✓
DirectX 9.0c	✓
Accessories	✓
Number of fonts	89

Table 150: Device functions in Windows Embedded Standard 2009

6.3 Installation

Upon request, Windows Embedded Standard 2009 can be preinstalled at B&R Austria on a suitable CompactFlash card (min. 1GB). The PPC800 system is then automatically configured after it has been switched on for the first time. This procedure takes approximately 30 minutes, and the device will be rebooted a number of times.

6.4 Drivers

All drivers required for operation are preinstalled on the operating system. If an older driver version is installed, the latest version can be downloaded from the B&R homepage (www.br-automation.com) and installed. A potentially activated "Enhanced Write Filter (EWF)" must be taken into consideration.

6.4.1 Touch screen driver

The touch screen driver must be manually installed in order to operate Automation Panel 800 or Automation Panel 900 touch screen devices. The driver can be downloaded from the download area on the B&R homepage (www.br-automation.com). A potentially activated "Enhanced Write Filter (EWF)" must be taken into consideration.

Information:

Required drivers can only be downloaded from the B&R homepage, not from manufacturers' pages.

7. Panel PC 800 with Automation Runtime

7.1 General information

An integral component of Automation Studio™ is Automation Runtime, the software kernel which allows applications to run on a target system. This runtime environment offers numerous important advantages:

- Guaranteed highest possible performance for the hardware being used
- Runs on all B&R target systems
- Makes the application hardware-independent
- Applications can be easily ported between B&R target systems
- Cyclic system guarantees deterministic behavior
- Configurable jitter tolerance in all task classes
- Supports all relevant programming language such as IEC 61131-3 and C
- Extensive function library conforming to IEC 61131-3 as well as the expanded B&R Automation library
- Integrated into Automation NET. Access to all networks and bus systems via function calls or the Automation Studio™ configuration

7.2 AR010

The hardware dongle 1A4300.LZ1U must be connected to use AR010 on a Panel PC 800 (see section 11 "B&R Automation Studio 3.0USBdongle", on page 323).

8. Automation Device Interface (ADI) - Control Center

The ADI (Automation Device Interface) enables access to specific functions of B&R devices. Settings for this device can be read and edited using the B&R Control Center applet in the control panel.

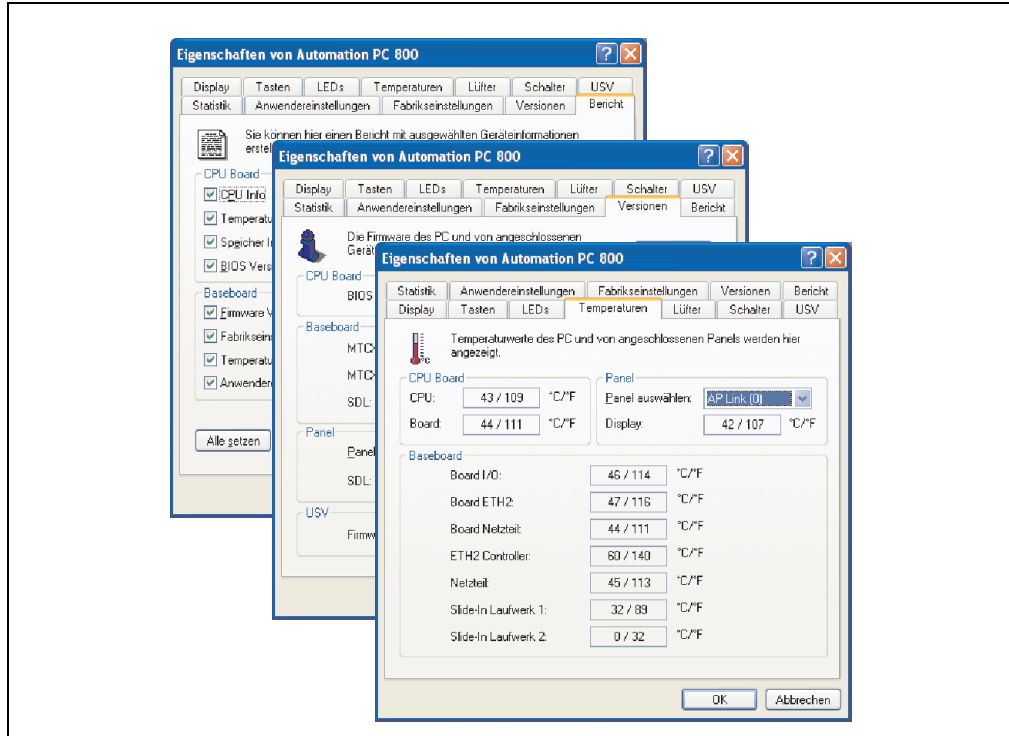


Figure 128: ADI Control Center Screenshots - Examples

Information:

The displayed temperature and voltage values (e.g. CPU temperature, core voltage, battery voltage) on the corresponding ADI page represent uncalibrated information values. These cannot be used to draw any conclusions about any hardware alarms or error conditions. The hardware components used have automatic diagnostics functions that can be applied in the event of error.

8.1 Function

- Adjusting the display-specific parameters of connected Panels
- Reading of device-specific keys

- Activation of device specific LEDs on a foil keypad
- Reading temperatures, fan speeds, statistical data, and switch settings
- Reading user settings and factory settings
- Reading software versions
- Updating and securing firmware
- Creating reports about the current system (support assistance)
- Setting the SDL equalizer value for the SDL cable adjustment
- Configuring an optional mounted UPS
- Change the user serial ID.

Supports following systems:

System	Operating system	Note
Automation PC 820	Windows XP Professional	Installation using its own setup
	Windows XP Embedded	Content of B&R Windows XP Embedded image
	Windows Embedded Standard 2009	Content of B&R Windows Embedded Standard 2009 image
Automation PC 810	Windows XP Professional	Installation using its own setup
	Windows XP Embedded	Content of B&R Windows XP Embedded image
	Windows Embedded Standard 2009	Content of B&R Windows Embedded Standard 2009 image
Automation PC 620	Windows XP Professional	Installation using its own setup
	Windows XP Embedded	Content of B&R Windows XP Embedded image
	Windows CE	Content of B&R Windows CE image
	Windows Embedded Standard 2009	Content of B&R Windows Embedded Standard 2009 image
Panel PC 700	Windows XP Professional	Installation using its own setup
	Windows XP Embedded	Content of B&R Windows XP Embedded image
	Windows Embedded Standard 2009	Content of B&R Windows Embedded Standard 2009 image
Panel PC 725	Windows XP Professional	Installation using its own setup
	Windows Embedded Standard 2009	Content of B&R Windows Embedded Standard 2009 image
Panel PC 800	Windows XP Professional	Installation using its own setup
	Windows XP Embedded	Content of B&R Windows XP Embedded image
	Windows Embedded Standard 2009	Content of B&R Windows Embedded Standard 2009 image
Power Panel BIOS devices	Windows XP Embedded	Content of B&R Windows XP Embedded image
	Windows CE	Content of B&R Windows CE image
	Windows Embedded Standard 2009	Content of B&R Windows Embedded Standard 2009 image
Mobile Panel BIOS devices	Windows XP Embedded	Content of B&R Windows XP Embedded image
	Windows CE	Content of B&R Windows CE image
Automation Panel 800	-	Together with APC620/ APC810/ APC820/ PPC700/ PPC800

Table 151: System support - ADI driver

System	Operating system	Note
Automation Panel 900	-	Together with APC620/ APC810/ APC820/ PPC700/ PPC800

Table 151: System support - ADI driver

A detailed description of the Control Center can be found in the integrated online help.

The B&R Automation Device Interface (ADI) driver (also contains Control Center) can be downloaded for free from the download area on the B&R homepage (www.br-automation.com).

8.2 Installation

The latest version of the ADI driver for the existing target system can be found in the download area (Service - Material Related Downloads - BIOS / Drivers / Updates) on the B&R homepage (www.br-automation.com).

1. Download and unzip the ZIP archive
2. Close all applications
3. Run BrSetup.exe (e.g. double-click on it in Explorer).

- or -

Right click on BrSetup.inf in explorer and select "Install".

Information:

The ADI driver and B&R control center are already included in the Windows XP Embedded and Windows Embedded Standard 2009 operating system.

If a more current ADI driver version exists (see the B&R homepage download area), it can be installed later. A potentially activated "Enhanced Write Filter (EWF)" must be taken into consideration when installing.

8.3 SDL equalizer setting

- 1) Start the **Control Center** in the **Control Panel**.
- 2) Then select the **Display** tab.
- 3) Click on **Settings**. This opens the following dialog box:

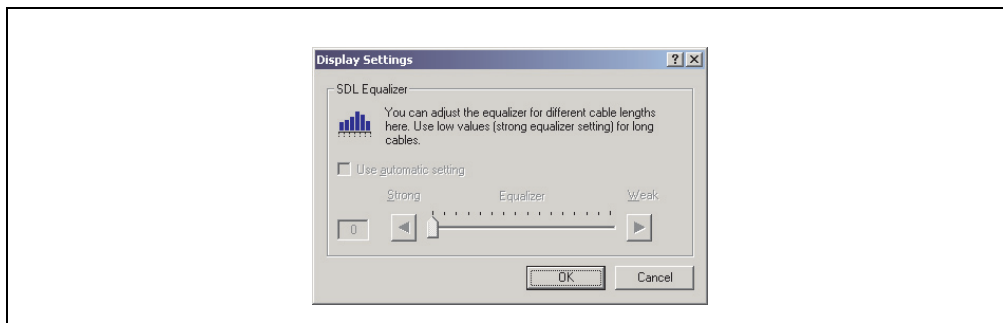


Figure 129: ADI Control Center - SDL equalizer settings

You can change the display's SDL equalizer settings in this dialog box. The equalizer is integrated in the Automation Panel and adapts the DVI signal to various cable lengths. The equalizer value is automatically calculated based on the cable length: You may set a different equalizer value in order to obtain the best possible display quality (e.g. with low-quality cables or poor DVI signal quality).

The value is optimally defined for the cable length when using the "Automatic setting".

The equalizer value can only be changed if the function is supported by Automation Panel 900 (starting with Panel Firmware version 1.04 or higher).

8.4 UPS configuration

Here you can view the status values for an optionally installed B&R APC add-on UPS as well as change, update or save the battery settings for the UPS. You can also configure the system settings for the UPS.

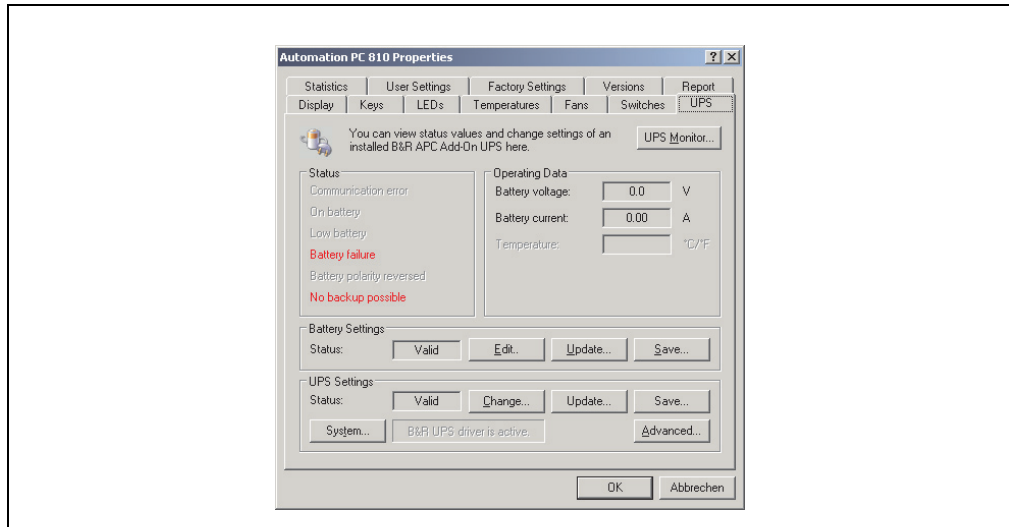


Figure 130: ADI Control Center - UPS settings

Caution!

The installed UPS must be selected and configured in the Control Panel using the energy options in order for battery operation to be supported.

Information:

The UPS service is supported starting with B&R Windows Embedded Version 2.10 or higher.

8.4.1 Installing the UPS service for the B&R APC add-on UPS

- 1) Open the **Control Center** in the **Control Panel**.
- 2) Select **UPS** tab.
- 3) Click on **System** under **UPS settings**. This opens the **Power Options** in the **Control Panel**. (The **Power Options** can also be opened directly from the **Control Panel**.)
- 4) Select the **UPS** tab and click **Select...**
- 5) Choose 'Bernecker + Rainer' as manufacturer and 'APC Add-On UPS' as model and then click **Finish**. The value for the COM connection is only required for a serially connected UPS and is ignored by the APC add-on UPS driver.
- 6) Click on **Apply** to begin UPS operation. After a few seconds the UPS status and details are displayed.
- 7) Click **OK**.

The text field beside **System** (on the **UPS** tab in the **Control Center**) also indicates whether the B&R UPS driver is active.

Information:

Administrator rights are required in order to change the energy options or display the UPS status.

8.4.2 Displaying UPS status values

- 1) Open the **Control Center** in the **Control Panel**.
- 2) Select **UPS** tab.

The displayed values are updated automatically.

Information:

The "reversed battery polarity" status is only displayed in UPS firmware Version 1.08 or higher.

In UPS firmware Version 1.07 or smaller, a change between battery operation and normal operation can lead to communication errors.

- 3) **Select UPS monitor** to display UPS status changes since the last time the system or UPS driver was started.

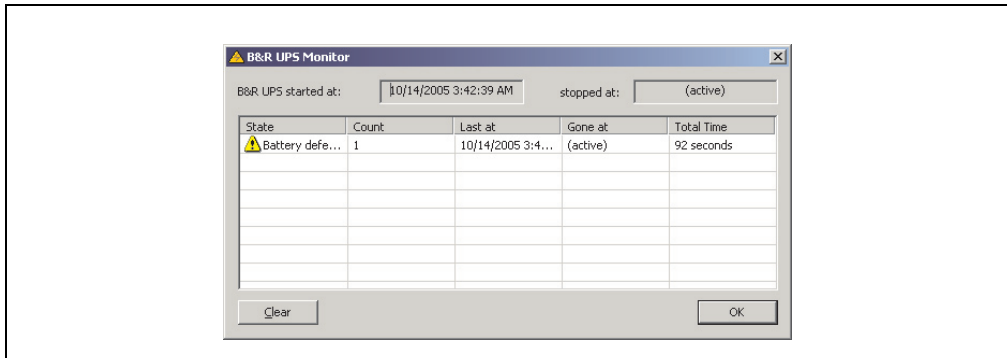


Figure 131: ADI Control Center - UPS monitor

The dialog box is updated automatically when the status changes.

To remove a status from the list, click on **delete**.

Information:

The current status of the UPS is also displayed when the UPS service is started in the Windows Control Panel on the UPS page in the energy options.

Information:

In a German version of Windows XP Professional the battery status is displayed as "low" in the energy options, even if the battery is OK (Windows error). In an English version, three battery status levels are displayed: unknown, OK, replace A low battery status is never displayed.

8.4.3 Changing UPS battery settings

- 1) Open the **Control Center** in the **Control Panel**.
- 2) Select **UPS** tab.
- 3) Under "Battery settings," click on **Edit**. Clicking on "Open" opens a dialog box.
- 4) Select and **open** the file containing the battery settings.

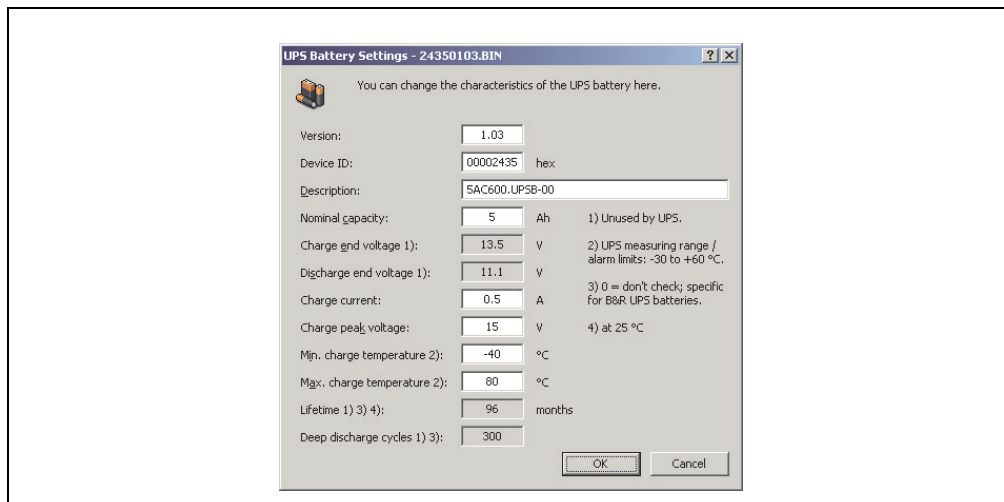


Figure 132: ADI Control Center - UPS battery settings

In this dialog box you can change the settings for the UPS battery.

The changed settings are written to the file by clicking on the **OK** button. The battery settings for the UPS can then be updated with this file.

Information:

To make settings for batteries not from B&R, it is best to make a copy of a file with battery settings from B&R under a new name and make adjust the settings in this file for the battery being used.

Current files with settings for batteries from B&R can be updated using B&R's "Upgrade PPC800 MTCX" software.

Information:

- The current UPS firmware version 1.10 does not use charge end voltage, deep discharge voltage, lifespan and deep discharge cycles.
- Lifespan is only included in version 2 (and higher) of the UPS battery settings and only valid for B&R UPS batteries at 25°C ambient temperature.
- Deep discharge cycles are only included in version 3 (and higher) of the UPS battery settings and only valid for B&R UPS batteries.

Information:

If you would like to change the current battery settings on the UPS, they must first be saved in a file.

8.4.4 Updating UPS battery settings

- 1) Open the **Control Center** in the **Control Panel**.
- 2) Select **UPS** tab.
- 3) Under **Battery settings**, click on **Update**. Clicking on "Open" opens a dialog box.
- 4) Select and **open** the file containing the battery settings. The "Download" dialog box is opened.

The transfer can be aborted by clicking on **Cancel** in the Download dialog box. **Cancel** is disabled when the flash memory is being written to.

Caution!

- The UPS cannot be operated while updating the battery settings.
- If the transfer is interrupted, then the procedure must be repeated until the battery settings have been updated successfully. Otherwise battery operation will no longer be possible.

Deleting the data in flash memory can take several seconds depending on the memory block being used. The progress indicator is not updated during this time.

Information:

The UPS is automatically restarted after a successful download. This can cause a brief failure in the UPS communication.

8.4.5 Saving UPS battery settings

- 1) Open the **Control Center** in the **Control Panel**.
- 2) Select **UPS** tab.
- 3) Under "Battery settings", click on **Save**. "Save under" dialog box opened.
- 4) Enter a file name or select an existing file and click on **Save**.

Information:

UPS settings can only be saved using UPS firmware version 1.10 and higher.

The transfer can be aborted by clicking on **Cancel** in the Download dialog box.

8.4.6 Configuring UPS system settings

- 1) Open the **Control Center** in the **Control Panel**.
- 2) Select **UPS** tab.
- 3) Click on **Change** under **UPS settings**. This opens the following dialog box:

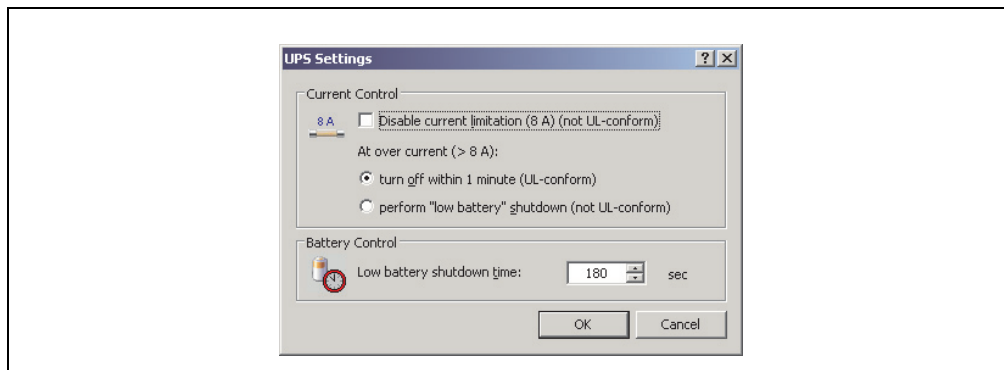


Figure 133: ADI Control Center - UPS settings

Further information regarding the UPD system settings can be found in the Windows help.

Information:

- UPS settings can only be changed using UPS firmware version 1.10 and higher. If there are no changed settings on the UPS, then the factory or default settings are used.
- The UPS is automatically restarted after UPS settings have been changed. This can cause a brief disruption in communication with the UPS.
- Administrator rights are required in order to change the energy options or display the UPS status.

Disabling 8 A current limitation

Select the checkbox **Disable current limitation (8 A)**.

If current limitation is enabled (checkbox deselected), then the UPS uses battery operation to check whether the UPS battery is discharged with 8 A for longer than 16 seconds. If so, then an overcurrent alarm is sent to the PC.

Information:

Current limitation is only supported with UPS firmware version 1.10 and higher.

Enabling one of the two following options determines how the UPS should perform when an overcurrent alarm occurs:

If **Turn-off within 1 minute** is selected, then the UPS will turn-off within one when an overcurrent alarm occurs.

Warning!

The operating system will not be properly shut down if an overcurrent alarm occurs!

If **Perform "low battery" shutdown** is selected, then the UPS will also signal a "Low battery alarm" in addition to the overcurrent alarm and will turn off after the defined **Low battery shutdown time**. This will allow the operating system to shut down properly when UPS service is enabled.

Changing the UPS shutdown time when battery is low

Enter the **"Low Battery" shutdown time** in seconds. This is the amount of time that the UPS will wait before shutting off the power supply when the battery level is low.

This prevents the UPS battery from becoming too discharged if the Windows UPS service is not enabled and the UPS is therefore not turned off by the operating system.

If the UPS service is enabled, then the UPS will be turned off by the operating system when the battery level is low, based on the Windows UPS service **Turn-off delay** (see "Changing additional UPS settings", on page 268). The **low battery shutdown time** will then be ignored.

Information:

- The low battery shutdown time must be set to at least 60 seconds, so that the operating system has enough time to send the shutdown command to the UPS when the battery level is low (normally occurs after approximately 30 seconds).
- The low battery shutdown time can only be set in UPS firmware version 1.10 and later. UPS firmware version 1.08 always uses a turn off delay time of 180 seconds. UPS firmware versions earlier than 1.08 do not shut down automatically when the battery level is low.

8.4.7 Changing additional UPS settings

- 1) Open the **Control Center** in the **Control Panel**.
- 2) Select **UPS** tab.
- 3) Click on **Advanced** under **UPS settings**. This opens the following dialog box:

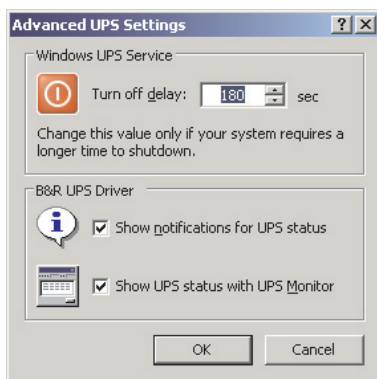


Figure 134: ADI Control Center - Advanced UPS settings

Information:

Administer rights are required in order to display this dialog box.

Change turn-off time for UPS

The **Shutdown time** can be specified in seconds under **Windows UPS service**. This is the length of time that the UPS waits before switching off the power supply. When a critical alarm occurs (e.g. at low battery level), the Windows UPS service will send a shutdown command with the turn off delay time to the UPS and will shut down the system.

Information:

This time is evaluated by the Windows UPS Service, but can not be set in the UPS system settings of the energy options. This value should only be changed if the system requires longer than the default setting of 180 seconds to shut down.

Caution!

The time entered must be longer than the time required to shut down the operating system.

Activate UPS messages

Under **B&R UPS driver**, select the checkbox **UPS status message**. Any changes to the UPS status will then trigger a message from the B&R UPS driver.

Information:

Shutting down the system is only reported by the Windows UPS Service. The UPS Service also sends other messages if they are activated in the UPS system settings energy options. These messages are only displayed when the Windows Alerter and Windows Messenger¹⁾ are active and the PC is connected to a network. Additionally, some conditions of the B&R APC add-on UPS are not detected by the Windows UPS Service, and are therefore do not trigger messages (e.g. when there are no battery settings on the UPS). The Windows services can be found by opening the Control Panel and selecting "Services" from the Administrative Tools.

¹⁾ The Windows Alerter is supported starting with B&R Windows Embedded Version 2.10 or higher.

If the checkbox **Display UPS status with UPS monitor** is also activated, a new message is not displayed for every change, but only a general message and request for you to start the B&R UPS monitor. As long as the UPS monitor is active, no new messages are displayed.

Information:

Regardless of these options, all changes to the UPS status are logged in Windows event protocol (under "Application").

Chapter 5 • Standards and certifications

1. Applicable European guidelines

- EMC directive 2004/108/EG
- Low-voltage directive 2006/95/EG

2. Overview of standards

Standard	Description
EN 55011 Class A	Electromagnetic compatibility (EMC), radio disturbance product standard, industrial, scientific, and medical high-frequency devices (ISM devices), limit values and measurement procedure; group 1 (devices that do not create HF during material processing) and group 2 (devices that create HF during material processing)
EN 55022 Class A	Electromagnetic compatibility (EMC), radio disturbance characteristics, information technology equipment (ITE devices), limits and methods of measurement
EN 60060-2	High-voltage test techniques - part 2: Measuring systems
EN 60068-2-1	Environmental testing - part 2: Tests; test A: Dry cold
EN 68068-2-2	Environmental testing - part 2: Tests; test B: Dry heat
EN 60068-2-3	Environmental testing - part 2: Tests; test and guidance: Damp heat, constant
EN 60068-2-6	Environmental testing - part 2: Tests; test: Vibration (sinusoidal)
EN 60068-2-14	Environmental testing - part 2: Tests; test N: Change of temperature
EN 60068-2-27	Environmental testing - part 2: Tests; test and guidance: Shock
EN 60068-2-30	Environmental testing - part 2: Tests; test and guidance: Damp heat, cyclic
EN 60068-2-31	Environmental testing - part 2: Tests; test: Drop and topple, primarily for equipment-type specimens
EN 60068-2-32	Environmental testing - part 2: Tests; test: Free fall
EN 60204-1	Safety of machinery, electrical equipment on machines - part 1: General requirements
EN 60529	Degrees of protection provided by enclosures (IP code)
EN 60664-1	Insulation coordination for equipment within low-voltage systems - part 1: Principles, requirements and tests
EN 60721-3-2	Classification of environmental conditions - part 3: Classification of groups of environmental parameters and their severities, section 2: Transport
EN 60721-3-3	Classification of environmental conditions - part 3: Classification of groups of environmental parameters and their severities, section 3: Stationary use at weather-protected locations
EN 61000-3-2	Electromagnetic compatibility (EMC) - part 3-2: Limits for harmonic current emissions (equipment input current ≤ 16 A per phase)

Table 152: Overview of standards

Standards and certifications • Overview of standards

Standard	Description
EN 61000-3-3	Electromagnetic compatibility (EMC) - part 3-3: Limitation of voltage changes, voltage fluctuations and flicker in public low-voltage supply systems, equipment with rated current ≤ 16 A per phase, and not subject to conditional connection.
EN 61000-4-2	Electromagnetic compatibility (EMC) - part 4-2: Testing and measuring techniques; electrostatic discharge immunity test
EN 61000-4-3	Electromagnetic compatibility (EMC) - part 4-3: Testing and measuring techniques; radiated radio-frequency electromagnetic field immunity test
EN 61000-4-4	Electromagnetic compatibility (EMC) - part 4-4: Testing and measuring techniques; electrical fast transient/burst immunity test
EN 61000-4-5	Electromagnetic compatibility (EMC) - part 4-5: Testing and measuring techniques; surge immunity test
EN 61000-4-6	Electromagnetic compatibility (EMC) - part 4-6: Testing and measuring techniques; immunity to conducted disturbances, induced by radio-frequency fields
EN 61000-4-8	Electromagnetic compatibility (EMC) - part 4-8: Testing and measuring techniques; power frequency magnetic field immunity test
EN 61000-4-11	Electromagnetic compatibility (EMC) - part 4-11: Testing and measuring techniques; voltage dips, short interruptions and voltage variations immunity tests
EN 61000-4-18	Electromagnetic compatibility (EMC) - part 4-18: Testing and measuring techniques; damped oscillatory waves immunity test
EN 61000-6-2	Electromagnetic compatibility (EMC), generic immunity standard - part 2: industrial environment
EN 61000-6-4	Electromagnetic compatibility (EMC), generic emission standard - part 2: industrial environment
EN 61131-2	Product standard, programmable logic controllers - part 2: Equipment requirements and tests
UL 508	Industrial control equipment (UL = Underwriters Laboratories)
47 CFR	Federal Communications Commission (FCC), 47 CFR Part 15 Subpart B Class A
VCCI V-3	Agreement of Voluntary Control Council for Interference by Information Technology Equipment; Class A
ICES 003	Devices that cause interference - Digital devices; Class A

Table 152: Overview of standards (cont.)

3. Emission requirements (emission)

Emissions	Test carried out according to	Limits according to
Network-related emissions	EN 55011 / EN 55022	EN 61000-6-4: Generic standard (industrial areas)
		EN 55011: Industrial, scientific, and medical (ISM) radio-frequency equipment, class A (industrial areas)
		EN 55022: Information technology equipment (ITE devices), class A (industrial areas)
		EN 61131-2: Programmable logic controllers
		EN 50091-2: Uninterruptible power systems (UPS), class A
		47 CFR Part 15 Subpart B Class A (FCC)
Emissions, Electromagnetic emissions	EN 55011 / EN 55022	EN 61000-6-4: Generic standard (industrial areas)
		EN 55011: Industrial, scientific, and medical (ISM) radio-frequency equipment, class A (industrial areas)
		EN 55022: Information technology equipment (ITE devices), class A (industrial areas)
		EN 61131-2: Programmable logic controllers
		EN 50091-2: Uninterruptible power systems (UPS), class A
		47 CFR Part 15 Subpart B Class A (FCC)
Harmonic currents for devices with an input current of ≤ 16 A per line	EN 61000-3-2	EN 61000-3-2: Limits for harmonic current emissions (equipment input current ≤ 16 A per phase)
Voltage changes, voltage fluctuations and flicker in public low-voltage supply systems, equipment with rated current ≤ 16 A per phase, and not subject to conditional connection.	EN 61000-3-3	EN 61000-3-3: Limitation of voltage changes, voltage fluctuations and flicker in public low-voltage supply systems, for equipment with rated current less than or equal to ≤ 16 A per phase and not subject to conditional connection, class A/D

Table 153: Overview of limits and testing guidelines for emissions

3.1 Network-related emissions

Test carried out according to EN 55011 / EN 55022	Limits according to EN 61000-6-4	Limits according to EN 55011 Class A	Limits according to EN 55022 Class A
Power mains connections 150 kHz - 500 kHz	-	79 dB (μV) Quasi-peak value 66 dB (μV) Average	79 dB (μV) Quasi-peak value 66 dB (μV) Average
Power mains connections 500 kHz - 30 MHz	-	73 dB (μV) Quasi-peak value 60 dB (μV) Average	73 dB (μV) Quasi-peak value 60 dB (μV) Average
AC mains connections 150 kHz - 500 kHz	79 dB (μV) Quasi-peak value 66 dB (μV) Average	-	-
AC mains connections 500 kHz - 30 MHz	73 dB (μV) Quasi-peak value 60 dB (μV) Average	-	-
Other connections 150 kHz - 500 kHz	-	-	97 - 87 dB (μV) und 53 - 43 dB (μA) Quasi-peak value 84 - 74 dB (μV) und 40 - 30 dB (μA) Average
Other connections 500 kHz - 30 MHz	-	-	87 dB (μV) and 43 dB (μA) Quasi-peak value 74 dB (μV) and 30 dB (μA) Average
Test carried out according to EN 55011 / EN 55022	Limits according to EN 61131-2	Limits according to 47 CFR Part 15 Subpart B class A	
Power mains connections ¹⁾ 150 kHz - 500 kHz	-	-	
Power mains connections 500 kHz - 30 MHz	-	-	
AC mains connections 150 kHz - 500 kHz	79 dB (μV) Quasi-peak value 66 dB (μV) Average	79 dB (μV) Quasi-peak value 66 dB (μV) Average	
AC mains connections 500 kHz - 30 MHz	73 dB (μV) Quasi-peak value 60 dB (μV) Average	73 dB (μV) Quasi-peak value 60 dB (μV) Average	
Other connections 150 kHz - 500 kHz	-	-	
Other connections 500 kHz - 30 MHz	-	-	

Table 154: Test requirements - Network-related emissions for industrial areas

1) AC network connections only with EN 61131-2

3.2 Emissions, electromagnetic emissions

Test carried out according to EN 55011 / EN 55022	Limits according to EN 61000-6-4	Limits according to EN 55011 Class A	Limits according to EN 55022 Class A
30 MHz - 230 MHz measured at a distance of 10 m	< 40 dB (μV/m) Quasi-peak value	< 40 dB (μV/m) Quasi-peak value	< 40 dB (μV/m) Quasi-peak value
230 MHz - 1 GHz measured at a distance of 10 m	< 47 dB (μV/m) Quasi-peak value	< 47 dB (μV/m) Quasi-peak value	< 47 dB (μV/m) Quasi-peak value
Test carried out according to EN 55011 / EN 55022	Limits according to EN 61131-2	Limits according to EN 50091-2 class A	
30 MHz - 230 MHz measured at a distance of 10 m	< 40 dB (μV/m) Quasi-peak value	< 40 dB (μV/m) Quasi-peak value	
230 MHz - 1 GHz measured at a distance of 10 m	< 47 dB (μV/m) Quasi-peak value	< 47 dB (μV/m) Quasi-peak value	
Test carried out	Limits according to 47 CFR Part 15 Subpart B class A		
30 MHz - 88 MHz measured at a distance of 10 m	< 90 dB (μV/m) Quasi-peak value		
88 MHz - 216 MHz measured at a distance of 10 m	< 150 dB (μV/m) Quasi-peak value		
216 MHz - 960 MHz measured at a distance of 10 m	< 210 dB (μV/m) Quasi-peak value		
> 960 MHz measured at a distance of 10 m	< 300 dB (μV/m) Quasi-peak value		

Table 155: Test requirements - Electromagnetic emissions for industrial areas

4. Requirements for immunity to disturbances (immunity)

Immunity	Test carried out according to	Limits according to
Electrostatic discharge (ESD)	EN 61000-4-2	EN 61000-6-2: Generic standard (industrial areas)
		EN 61131-2: Programmable logic controllers
Immunity to high-frequency electromagnetic fields (HF field)	EN 61000-4-3	EN 61000-6-2: Generic standard (industrial areas)
		EN 61131-2: Programmable logic controllers
Immunity to high-speed transient electrical disturbances (burst)	EN 61000-4-4	EN 61000-6-2: Generic standard (industrial areas)
		EN 61131-2: Programmable logic controllers
Immunity to surge voltages	EN 61000-4-5	EN 61000-6-2: Generic standard (industrial areas)
		EN 61131-2: Programmable logic controllers
Immunity to conducted disturbances	EN 61000-4-6	EN 61000-6-2: Generic standard (industrial areas)
		EN 61131-2: Programmable logic controllers
Immunity against magnetic fields with electrical frequencies	EN 61000-4-8	EN 61000-6-2: Generic standard (industrial areas)
		EN 61131-2: Programmable logic controllers
Immunity to voltage dips, short-term interruptions and voltage fluctuations	EN 61000-4-11	EN 61000-6-2: Generic standard (industrial areas)
		EN 61131-2: Programmable logic controllers
Immunity to damped oscillatory waves	EN 61000-4-18	EN 61131-2: Programmable logic controllers

Table 156: Overview of limits and testing guidelines for immunity

Evaluation criteria according to EN 61000-6-2

Criteria A:

The operating equipment must continue to work as intended **during** the test. There should be no interference in the operating behavior and no system failures below a minimum operating quality as defined by the manufacturer.

Criteria B:

The operating equipment must continue to work as directed **after** the test. There should be no interference in the operating behavior and no system failures below a minimum operating quality as defined by the manufacturer.

Criteria C:

A temporary function failure is permitted if the function restores itself, or the function can be restored by activating configuration and control elements.

Criteria D:

Deterioration or failure of the function, which can no longer be established (operating equipment destroyed).

4.1 Electrostatic discharge (ESD)

Test carried out according to EN 61000-4-2	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
Contact discharge to powder-coated and bare metal housing parts	±4 kV, 10 discharges, criteria B	±4 kV, 10 discharges, criteria B	
Discharge through the air to plastic housing parts	±8 kV, 10 discharges, criteria B	±8 kV, 10 discharges, criteria B	

Table 157: Test requirements - Electrostatic discharge (ESD)

4.2 High-frequency electromagnetic fields (HF field)

Test carried out according to EN 61000-4-3	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
Housing, completely wired	80 MHz - 1 GHz, 10 V/m, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	2 GHz - 2.7 GHz, 1 V/m, 1.4 GHz - 2 GHz, 3 V/m, 80 MHz - 1 GHz, 10 V/m, 80% amplitude modulation with 1 kHz, 3 sec. duration, criteria A	

Table 158: Test requirements - High-frequency electromagnetic fields (HF field)

4.3 High-speed transient electrical disturbances (burst)

Test carried out according to EN 61000-4-4	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
AC power I/O	±2 kV, criteria B	-	
AC power inputs	-	±2 kV, criteria B	
AC power outputs	-	±1 kV, criteria B	
DC power I/O >10 m	±2 kV, criteria B	-	
DC power inputs >10 m	-	±2 kV, criteria B	
DC power outputs >10 m	-	±1 kV, criteria B	
Functional ground connections, signal lines and I/Os >3 m	±1 kV, criteria B	±1 kV, criteria B	
Unshielded AC I/O >3 m	-	±2 kV, criteria B	
Analog I/O	±1 kV, criteria B	±1 kV, criteria B	

Table 159: Test requirements - High-speed transient electrical disturbances (burst)

4.4 Surges (surge)

Test carried out according to EN 61000-4-5	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
AC power I/O, L to L	±1 kV, criteria B	±1 kV, criteria B	
AC power I/O, L to PE	±2 kV, criteria B	±2 kV, criteria B	
DC power I/O, L+ to L-, >10 m	±0.5 kV, criteria B	-	
DC power I/O, L to PE, >10 m	±0.5 kV, criteria B	-	
DC power inputs, L+ to L-	-	±0.5 kV, criteria B	
DC power inputs, L to PE	-	±1 kV, criteria B	
DC power outputs, L+ to L-	-	±0.5 kV, criteria B	
DC power outputs, L to PE	-	±0.5 kV, criteria B	
Signal connections >30 m	±1 kV, criteria B	±1 kV, criteria B	
All shielded cables	-	±1 kV, criteria B	

Table 160: Test requirements - Surge voltages

4.5 Conducted disturbances

Test carried out according to EN 61000-4-6	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
AC power I/O	150 kHz - 80 MHz, 10 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	150 kHz - 80 MHz, 3 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	
DC power I/O	150 kHz - 80 MHz, 10 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	150 kHz - 80 MHz, 3 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	
Functional ground connections	150 kHz - 80 MHz, 10 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	150 kHz - 80 MHz, 3 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	
Signal connections >3 m	150 kHz - 80 MHz, 10 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	150 kHz - 80 MHz, 3 V, 80% amplitude modulation with 1 kHz, length 3 seconds, criteria A	

Table 161: Test requirements - Conducted disturbances

4.6 Magnetic fields with electrical frequencies

Test carried out according to EN 61000-4-8	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
Test direction x, test in the field of an induction coil 1 m x 1 m	30 A/m, criteria A	30 A/m, criteria A	
Test direction y, test in the field of an induction coil 1 m x 1 m	30 A/m, criteria A	30 A/m, criteria A	
Test direction z, test in the field of an induction coil 1 m x 1 m	30 A/m, criteria A	30 A/m, criteria A	

Table 162: Test requirements - Magnetic fields with electrical frequencies

4.7 Voltage dips, fluctuations and short-term interruptions

Test carried out according to EN 61000-4-11	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
AC power inputs	Voltage dip 70% (30% reduction), 0.5 periods, criteria B	-	
AC power inputs	Voltage dip 40% (60% reduction), 5 periods, criteria C	-	
AC power inputs	Voltage dip 40% (60% reduction), 50 periods, criteria C	-	
AC power inputs	Voltage interruptions < 5% (> 95% reduction), 250 periods, criteria C	-	
AC power inputs	-	20 interruptions, 0.5 periods, criteria A	

Table 163: Test requirements - Voltage dips, fluctuations, and short-term interruptions

Standards and certifications • Requirements for immunity to disturbances (immunity)

Test carried out according to EN 61000-4-11	Limits according to EN 61000-6-2	Limits according to EN 61131-2	
DC power inputs	-	20 interruptions for 10 ms < UN - 15%, criteria A	

Table 163: Test requirements - Voltage dips, fluctuations, and short-term interruptions (cont.)

4.8 Damped oscillatory waves

Test carried out according to EN 61000-4-18	Limits according to EN 61131-2		
AC power inputs	max. 2.5 kV, 1 MHz $\pm 10\%$, repeat rate 400/seconds, length 2 seconds, connection lengths 2 m, criteria B		
DC power inputs	max. 2.5 kV, 1 MHz $\pm 10\%$, repeat rate 400/seconds, length 2 seconds, connection lengths 2 m, criteria B		

Table 164: Test requirements - Damped oscillatory waves

5. Mechanical conditions

Vibration	Test carried out according to	Limits according to
Vibration operation	EN 60068-2-6	EN 61131-2: Programmable logic controllers EN 60721-3-3 class 3M4
Vibration during transport (packaged)	EN 60068-2-6	EN 60721-3-2 class 2M1 EN 60721-3-2 class 2M2 EN 60721-3-2 class 2M3
Shock during operation	EN 60068-2-27	EN 61131-2: Programmable logic controllers EN 60721-3-3 class 3M4
Shock during transport (packaged)	EN 60068-2-27	EN 60721-3-2 class 2M1 EN 60721-3-2 class 2M2 EN 60721-3-2 class 2M3
Toppling (packaged)	EN 60068-2-31	EN 60721-3-2 class 2M1 EN 60721-3-2 class 2M2 EN 60721-3-2 class 2M3
Free fall (packaged)	EN 60068-2-32	EN 61131-2: Programmable logic controllers

Table 165: Overview of limits and testing guidelines for vibration

5.1 Vibration operation

Test carried out according to EN 60068-2-6	Limits according to EN 61131-2		Limits according to EN 60721-3-3 class 3M4		
Vibration during operation: Uninterrupted duty with moveable frequency in all 3 axes (x, y, z), 1 octave per minute	10 sweeps for each axis		10 sweeps for each axis		
	Frequency	Limit value	Frequency	Limit value	
	5 - 9 Hz	Amplitude 3.5 mm	2 - 9 Hz	Amplitude 3 mm	
	9 - 150 Hz	Acceleration 1 g	9 - 200 Hz	Acceleration 1 g	

Table 166: Test requirements - Vibration during operation

5.2 Vibration during transport (packaged)

Test carried out according to EN 60068-2-6	Limits according to EN 60721-3-2 class 2M1		Limits according to EN 60721-3-2 class 2M2		Limits according to EN 60721-3-2 class 2M3	
Vibration during transport: Uninterrupted duty with moveable frequency in all 3 axes (x, y, z)	10 sweeps for each axis, packaged		10 sweeps for each axis, packaged		10 sweeps for each axis, packaged	
	Frequency	Limit value	Frequency	Limit value	Frequency	Limit value
	2 - 9 Hz	Amplitude 3.5 mm	2 - 9 Hz	Amplitude 3.5 mm	2 - 8 Hz	Amplitude 7.5 mm
	9 - 200 Hz	Acceleration 1 g	9 - 200 Hz	Acceleration 1 g	8 - 200 Hz	Acceleration 2 g
	200 - 500 Hz	Acceleration 1.5 g	200 - 500 Hz	Acceleration 1.5 g	200 - 500 Hz	Acceleration 4 g

Table 167: Test requirements - Vibration during transport (packaged)

5.3 Shock during operation

Test carried out according to EN 60068-2-27	Limits according to EN 61131-2	Limits according to EN 60721-3-3 class 3M4	
Shock during operation: Pulse (half-sine) stress in all 3 axes (x, y, z)	Acceleration 15 g, length 11 ms, 18 shocks	Acceleration 10 g, length 11 ms	

Table 168: Test requirements - Shock during operation

5.4 Shock during transport (packaged)

Test carried out according to EN 60068-2-27	Limits according to EN 60721-3-2 class 2M1	Limits according to EN 60721-3-2 class 2M2	Limits according to EN 60721-3-2 class 2M3
Pulse (half-sine) stress in all 3 axes (x, y, z)	Acceleration 10 g, Length 11 ms, each 3 shocks, packaged	Acceleration 30 g, Length 6 ms, each 3 shocks, packaged	Acceleration 100 g, Length 6 ms, each 3 shocks, packaged

Table 169: Test requirements - Shock during transport

5.5 Toppling

Test carried out according to EN 60068-2-31	Limits according to EN 60721-3-2 class 2M1		Limits according to EN 60721-3-2 class 2M2		Limits according to EN 60721-3-2 class 2M3	
Drop and topple	Devices: Drop/topple on each edge, packaged		Devices: Drop/topple on each edge, packaged		Devices: Drop/topple on each edge, packaged	
	Weight	Required	Weight	Required	Weight	Required
	< 20 kg	Yes	< 20 kg	Yes	< 20 kg	Yes
	20 - 100 kg	-	20 - 100 kg	Yes	20 - 100 kg	Yes
	> 100 kg	-	> 100 kg	-	> 100 kg	Yes

Table 170: Test requirements - Toppling

5.6 Free fall (packaged)

Test carried out according to EN 60068-2-32	Limits according to EN 61131-2		Limits according to EN 60721-3-2 class 2M1		Limits according to EN 60721-3-2 class 2M2		Limits according to EN 60721-3-2 class 2M3	
Free fall	Devices with delivery packaging each with 5 fall tests		Devices packaged		Devices packaged		Devices packaged	
	Weight	Height	Weight	Height	Weight	Height	Weight	Height
	< 10 kg	1.0 m	< 20 kg	0.25 m	< 20 kg	1.2 m	< 20 kg	1.5 m
	10 - 40 kg	0.5 m	20 - 100 kg	0.25 m	20 - 100 kg	1.0 m	20 - 100 kg	1.2 m
	> 40 kg	0.25 m	> 100 kg	0.1 m	> 100 kg	0.25 m	> 100 kg	0.5 m
	Devices with product packaging each with 5 fall tests							
	Weight	Height						
	< 10 kg	0.3 m						
	10 - 40 kg	0.3 m						
	> 40 kg	0.25 m						

Table 171: Test requirements - Free fall

6. Climate conditions

Temperature / humidity	Test carried out according to	Limits according to
Worst case operation	UL 508	UL 508: Industrial control equipment EN 61131-2: Programmable logic controllers
Dry heat	EN 60068-2-2	EN 61131-2: Programmable logic controllers
Dry cold	EN 60068-2-1	EN 61131-2: Programmable logic controllers
Large temperature fluctuations	EN 60068-2-14	EN 61131-2: Programmable logic controllers
Temperature fluctuations in operation	EN 60068-2-14	EN 61131-2: Programmable logic controllers
Humid heat, cyclic	EN 60068-2-30	EN 61131-2: Programmable logic controllers
Humid heat, constant (storage)	EN 60068-2-3	EN 61131-2: Programmable logic controllers

Table 172: Overview of limits and testing guidelines for temperature and humidity

6.1 Worst case operation

Test carried out according to UL 508	Limits according to UL 508	Limits according to EN 61131-2	
Worst case during operation. Operation of the device with the max. ambient temperature specified in the data sheet at the max. specified load	3 hours at max. ambient temperature (min. +40°C) duration approx. 5 hours	3 hours at max. ambient temperature (min. +40°C) duration approx. 5 hours	

Table 173: Test requirements - Worst case during operation

6.2 Dry heat

Test carried out according to EN 60068-2-2	Limits according to EN 61131-2		
Dry heat	16 hours at +70°C for 1 cycle, then 1 hour acclimatization and function testing, duration approximately 17 hours		

Table 174: Test requirements - Dry heat

6.3 Dry cold

Test carried out according to EN 60068-2-1	Limits according to EN 61131-2		
Dry cold	16 hours at -40°C for 1 cycle, then 1 hour acclimatization and function testing, duration approximately 17 hours		

Table 175: Test requirements - Dry cold

6.4 Large temperature fluctuations

Test carried out according to EN 60068-2-14	Limits according to EN 61131-2		
Large temperature fluctuations	3 hours at -40°C and 3 hours at +70°C, 5 cycles, then 2 hours acclimatization and function testing, duration approximately 14 hours		

Table 176: Test requirements - Large temperature fluctuations

6.5 Temperature fluctuations in operation

Test carried out according to EN 60068-2-14	Limits according to EN 61131-2		
Open devices: These can also have a housing and are installed in switching cabinets	3 hours at +5°C and 3 hours at 55°C, 5 cycles, temperature gradient 3°C / min, the unit is occasionally supplied with voltage during testing, duration approximately 30 hours		
Closed devices: These are devices whose data sheet specifies a surrounding housing (enclosure) with the corresponding safety precautions	3 hours at +5°C and 3 hours at +55°C, 5 cycles, temperature gradient 3°C / min, the unit is occasionally supplied with voltage during testing, duration approximately 30 hours		

Table 177: Test requirements - Temperature fluctuations during operation

6.6 Humid heat, cyclic

Test carried out according to EN 60068-2-30	Limits according to EN 61131-2		
Alternating climate	24 hours at +25°C / +55°C and 97% / 83% RH, 2 cycles, then 2 hours acclimatization, function testing and insulation, duration approximately 50 hours		

Table 178: Test requirements - Humid heat, cyclic

6.7 Humid heat, constant (storage)

Test carried out according to EN 60068-2-3	Limits according to EN 61131-2		
Humid heat, constant (storage)	48 hours at +40°C and 92.5% RH, then insulation test within 3 hours, duration approximately 49 hours		

Table 179: Test requirements - Humid heat, constant (storage)

7. Safety

Safety	Test carried out according to	Limits according to
Ground resistance	EN 61131-2	EN 60204-1: Electrical equipment of machines
		EN 61131-2: Programmable logic controllers
Insulation resistance		EN 60204-1: Electrical equipment of machines
High voltage	EN 60060-1	EN 61131-2: Programmable logic controllers
		UL 508: Industrial control equipment
Residual voltage	EN 61131-2	EN 60204-1: Electrical equipment of machines
		EN 61131-2: Programmable logic controllers
Leakage current		VDE 0701-1: Service, changes and testing of electrical devices
Overload	UL 508	EN 61131-2: Programmable logic controllers
		UL 508: Industrial control equipment
Simulation component defect	UL 508	EN 61131-2: Programmable logic controllers
		UL 508: Industrial control equipment
Voltage range		EN 61131-2: Programmable logic controllers

Table 180: Overview of limits and testing guidelines for safety

7.1 Ground resistance

Test carried out according to EN 61131-2	Limits according to EN 60204-1		Limits according to EN 61131-2
Ground resistance: housing (from any metal part to the ground terminal)	Smallest effective cross section of the protective ground conductor for the branch being tested	Maximum measured voltage drop at a test current of 10 A	Test current 30 A for 2 min, < 0.1 Ω
	1.0 mm ²	3.3 V	
	1.5 mm ²	2.6 V	
	2.5 mm ²	1.9 V	
	4.0 mm ²	1.4 V	
	> 6.0 mm ²	1.0 V	

Table 181: Test requirements - Ground resistance

7.2 Insulation resistance

Test carried out	Limits according to EN 60204-1		
Insulation resistance: main circuits to protective ground conductor	> 1 M Ω at 500 V DC voltage		

Table 182: Test requirements - Insulation resistance

7.3 High voltage

Test carried out according to EN 60060-1	Limits according to EN 61131-2				Limits according to UL 508		
High voltage: Primary circuit to secondary circuit and to protective ground circuit (transformers, coils, varistors, capacitors and components used to protect against over-voltage can be removed before the test)	Input voltage	Test voltage			Input voltage	Test voltage	
		1.2/50 μ s voltage surge peak	AC, 1 min	DC, 1 min		AC, 1 min	DC, 1 min
	0 - 50 VAC 0 - 60 VDC	850 V	510 V	720 V	≤ 50 V	500 V	707 V
	50 - 100 VAC 60 - 100 VDC	1360 V	740 V	1050 V	> 50 V	1000 V + 2 x U_N	(1000 V + 2 x U_N) x 1.414
	100 - 150 VAC 100 - 150 VDC	2550 V	1400 V	1950 V			
	150 - 300 VAC 150 - 300 VDC	4250 V	2300 V	3250 V			
	300 - 600 VAC 300 - 600 VDC	6800 V	3700 V	5250 V			
	600 - 1000 VAC 600 - 1000 VDC	10200 V	5550 V	7850 V			

Table 183: Test requirements - High voltage

7.4 Residual voltage

Test carried out according to EN 61131-2	Limits according to EN 60204-1	Limits according to EN 61131-2	
Residual voltage after switching off	< 60 V after 5 sec (active parts) < 60 V after 1 sec (plug pins)	< 60 V after 5 sec (active parts) < 60 V after 1 sec (plug pins)	

Table 184: Test requirements - Residual voltage

7.5 Leakage current

Test carried out	Limits according to VDE 0701-1		
Leakage current: Phase to ground	< 3.5 mA		

Table 185: Test requirements - Leakage current

7.6 Overload

Test carried out according to UL 508	Limits according to EN 61131-2	Limits according to UL 508	
Overload of transistor outputs	50 switches, 1.5 I _N , 1 sec on / 9 sec off	50 switches, 1.5 I _N , 1 sec on / 9 sec off	

Table 186: Test requirements - Overload

7.7 Defective component

Test carried out according to UL 508	Limits according to EN 61131-2	Limits according to UL 508	
Simulation of how components in power supply became defective	Non-flammable surrounding cloth No contact with conductive parts	Non-flammable surrounding cloth No contact with conductive parts	

Table 187: Test requirements - Defective component

7.8 Voltage range

Test carried out according to	Limits according to EN 61131-2			
Supply voltage	Measurement value	Tolerance min/max		
	24 VDC 48 VDC 125 VDC	-15% +20%		
	24 VAC 48 VAC 100 VAC 110 VAC 120 VAC 200 VAC 230 VAC 240 VAC 400 VAC	- 15% +10%		

Table 188: Test requirements - Voltage range

8. Other tests

Other tests	Test carried out according to	Limits according to
Protection type	-	EN 60529: Degrees of protection provided by enclosures (IP code)
Degree of pollution	-	EN 60664-1: Insulation coordination for equipment within low-voltage systems - part 1: Principles, requirements and tests

Table 189: Overview of limits and testing guidelines for other tests

8.1 Protection type

Test carried out according to	Limits according to EN 60529	Limits according to EN 60529	
Protection of the operating equipment	IP2. Protection against large solid foreign bodies 12.5 mm diameter	IP6. No penetration of dust -> dust-proof	
Protection of personnel	IP2. Protection against touching dangerous parts with fingers	IP6. Protection against touching dangerous parts with conductor	
Protection against water permeation with damaging consequences	IP.0 Not protected	IP.5 Protection against water jets	

Table 190: Test requirements - Protection

9. International certifications

B&R products and services comply with applicable standards. They are international standards from organizations such as ISO, IEC and CENELEC, as well as national standards from organizations such as UL, CSA, FCC, VDE, ÖVE, etc. We give special consideration to the reliability of our products in an industrial environment.

Certifications	
USA and Canada 	All important B&R products are tested and listed by Underwriters Laboratories and checked quarterly by a UL Inspector. This mark is valid for the USA and Canada and simplifies certification of your machines and systems in these areas.
Europe 	All harmonized EN standards for the applicable directives are met.

Table 191: International Certifications

Chapter 6 • Accessories

1. Overview

Model number	Short description	Note
0AC201.91	Lithium batteries, 4 pcs. Lithium batteries, 4 pcs., 3 V / 950 mAh, button cell	
4A0006.00-000	Lithium battery, 1 pc. Lithium battery, 1 pc., 3 V / 950 mAh, button cell	
0TB103.9	Plug 24V 5.08 3-pin screw clamps 24 VDC 3-pin connector, female. Screw clamp, 3.31 mm ² , protected against vibration by the screw flange.	
0TB103.91	Plug 24V 5.08 3-pin cage clamps 24 VDC 3-pin connector, female. Cage clamps, 3.31 mm ² , protected against vibration by the screw flange.	
5AC900.1000-00	Adapter DVI-A/m to CRT DB15HD/f Adapter DVI (plug) to CRT (socket), for connecting a standard monitor to a DVI-I interface.	
5AC900.1200-01	USB port cap IP65 M20 /2 Front-side USB port cap (attached) knurled, short, not slotted.	
5AC900.1200-02	USB port cap IP65 M20 /3 Front-side USB port cap (attached) knurled, tall, not slotted.	
5AC900.1200-03	USB port cap IP65 M20 /4 Front-side USB port cap (attached) knurled, tall, slotted.	
5AC600.UPSI-00	Add-on UPS module UPS module for APC620 / APC810 / PPC800 system units. Order cable (5CAUPS.0005-00 or 5CAUPS.0030-00) and battery unit (5AC600.UPSB-00) separately.	
5AC600.UPSB-00	Battery unit 5 Ah UPS battery unit for the add-on UPS module	
5CAUPS.0005-00	PPC800 UPS cable 0.5 m Connection cable between add-on UPS module and UPS battery unit, length 0.5 meters	
5CAUPS.0030-00	PPC800 UPS cable 3 m Connection cable between add-on UPS module and UPS battery unit, length 3 meters	
9A0100.11	UPS 24 VDC 24 VDC input, 24 VDC output, serial interface	
9A0100.14	UPS battery unit type B 24 V; 2.2 Ah; including battery cage	
9A0100.15	UPS battery unit type B (replacement part) 2 x 12 V; 2.2 Ah; for battery unit 9A0100.14	
9A0017.01	RS232 Null Modem Cable, 0.6 m To connect UPS and load system (9-pin DSUB socket - 9-pin DSUB socket)	

Table 192: Model numbers - Accessories

Model number	Short description	Note
9A0017.02	RS232 Null Modem Cable, 1.8 m To connect UPS and load system (9-pin DSUB socket - 9-pin DSUB socket)	
5CFCDR.0512-04	CompactFlash 512 MB B&R CompactFlash card with 512 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.1024-04	CompactFlash 1024 MB B&R CompactFlash card with 1024 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.2048-04	CompactFlash 2048 MB B&R CompactFlash card with 2048 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.4096-04	CompactFlash 4096 MB B&R CompactFlash card with 4096 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.8192-04	CompactFlash 8192 MB B&R CompactFlash card with 8192 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.016G-04	16 GB B&R CompactFlash card CompactFlash card with 16 GB SLC NAND flash and IDE/ATA interface	
5CFCDR.0064-03	CompactFlash 64 MB SSI CompactFlash card with 64 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.0128-03	CompactFlash 128 MB SSI CompactFlash card with 128 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.0256-03	CompactFlash 256 MB SSI CompactFlash card with 256 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.0512-03	CompactFlash 512 MB SSI CompactFlash card with 512 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.1024-03	CompactFlash 1024 MB SSI CompactFlash card with 1024 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.2048-03	CompactFlash 2048 MB SSI CompactFlash card with 2048 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.4096-03	CompactFlash 4096 MB SSI CompactFlash card with 4096 MB SLC NAND flash and IDE/ATA interface	
5CFCDR.8192-03	CompactFlash 8192 MB SSI CompactFlash card with 8192 MB SLC NAND flash and IDE/ATA interface	
5MMUSB.2048-00	USB flash drive 2 GB SanDisk USB 2.0 flash drive 2 GB	
1A4300.LZ1U	B&R Automation Studio 3.0 USB dongle Dongle for using AR010.	
5CADVI.0018-00	DVI-D cable 1.8 m Single cable, DVI-D/m:DVI-D/m; length: 1.8 m	
5CADVI.0050-00	DVI-D cable 5 m Single cable, DVI-D/m:DVI-D/m; length: 5 m	
5CADVI.0100-00	DVI-D cable 10 m Single cable, DVI-D/m:DVI-D/m; length: 10 m	
5CASDL.0018-00	SDL cable 1.8 m SDL cable for a fixed type of layout; length: 1.8 m	
5CASDL.0018-01	SDL cable 1.8 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 1.8 m	
5CASDL.0018-03	SDL flex cable 1.8 m SDL cable for fixed and flexible type of layout; length: 1.8 m	

Table 192: Model numbers - Accessories

Model number	Short description	Note
5CASDL.0050-00	SDL cable 5 m SDL cable for a fixed type of layout; length: 5 m	
5CASDL.0050-01	SDL cable 5 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 5 m	
5CASDL.0050-03	5 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 5 m	
5CASDL.0100-00	SDL cable 10 m SDL cable for a fixed type of layout; length: 10 m	
5CASDL.0100-01	SDL cable 10 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 10 m	
5CASDL.0100-03	10 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 10 m	
5CASDL.0150-00	SDL cable 15 m SDL cable for a fixed type of layout; length: 15 m	
5CASDL.0150-01	SDL cable 15 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 15 m	
5CASDL.0150-03	15 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 15 m	
5CASDL.0200-00	SDL cable 20 m SDL cable for a fixed type of layout; length: 20 m	
5CASDL.0200-03	20 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 20 m	
5CASDL.0250-00	SDL cable 25 m SDL cable for a fixed type of layout; length: 25 m	
5CASDL.0250-03	25 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 25 m	
5CASDL.0300-00	SDL cable 30 m SDL cable for a fixed type of layout; length: 30 m	
5CASDL.0300-03	30 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 30 m	
5CASDL.0300-13	30 m SDL flex cable with extender SDL cable with extender for fixed and flexible type of layout; length: 30 m	
5CASDL.0400-13	40 m SDL flex cable with extender SDL cable with extender for fixed and flexible type of layout; length: 40 m	
5CAUSB.0018-00	USB 2.0 cable, A/m:B/m 1.8 m USB 2.0 connection cable; plug type A - type B; length 1.8 m	
5CAUSB.0050-00	USB 2.0 cable, A/m:B/m 5 m USB 2.0 connection cable; plug type A - type B; length 5 m	
9A0014.02	RS232 cable DB9/f:DB9/m 1.8 m RS232 extension cable for remote operation of a display unit with touch screen; length 1.8 m.	
9A0014.05	RS232 cable DB9/f:DB9/m 5 m RS232 extension cable for remote operation of a display unit with touch screen; length 5 m.	
9A0014.10	RS232 cable DB9/f:DB9/m 10 m RS232 extension cable for remote operation of a display unit with touch screen; length 10 m.	

Table 192: Model numbers - Accessories

2. Replacement CMOS batteries

The lithium battery is needed for buffering the BIOS and real-time clock.

The battery is subject to wear and must be replaced when the battery power ("Bad" status) is insufficient.

2.1 Order data

Model number	Description	Figure
0AC201.91	Lithium batteries, 4 pcs., 3 V / 950 mAh button cell	
4A0006.00-000	Lithium battery, 1 piece, 3 V / 950 mAh button cell	

Table 193: Order data - Lithium batteries

2.2 Technical data

Warning!

Replace battery with Renata, type CR2477N only. Use of another battery may present a risk of fire or explosion.

Battery may explode if mistreated. Do not recharge, disassemble or dispose of in fire.

Information:

The following characteristics, features and limit values only apply to this accessory and can deviate those specified for the entire device. For the entire device where this accessory is installed, refer to the data provided specifically for the entire device.

Features	0AC201.91	4A0006.00-000
Capacity	950 mAh	
Voltage	3 V	
Self discharge at 23°C	< 1% per year	
Storage time	Max. 3 years at 30° C	

Table 194: Technical data - lithium batteries

Environment	0AC201.91	4A0006.00-000
Storage temperature	-20 to +60°C	
Relative humidity	0 to 95% (non-condensing)	

Table 194: Technical data - lithium batteries (cont.)

3. Supply voltage connector (TB103 3-pin)

3.1 General information

This single row 3-pin terminal block is mainly used to connect the supply voltage.

3.2 Order data

Model number	Description	Figure
0TB103.9	Plug for the 24 V supply voltage (screw clamps)	 0TB103.9  0TB103.91
0TB103.91	Plug for the 24 V supply voltage (cage clamps)	

Table 195: Order data - TB103

3.3 Technical data

Information:

The following characteristics, features and limit values only apply to this accessory and can deviate those specified for the entire device. For the entire device where this accessory is installed, refer to the data provided specifically for the entire device.

Name	0TB103.9	0TB103.91
Number of pins	3	
Type of terminal	Screw clamps	Cage clamps
Distance between contacts	5.08 mm	

Table 196: Technical data - TB103

Name	0TB103.9	0TB103.91
Resistance between contacts	$\leq 5 \text{ m}\Omega$	
Nominal voltage according to VDE / UL, CSA	250 V / 300 V	
Current load according to VDE / UL, CSA	14.5 A / 10 A per contact	
Terminal size	0.08 mm ² - 3.31 mm ²	
Cable type	Copper wires only (no aluminum wires!)	

Table 196: Technical data - TB103 (cont.)

4. DVI - monitor adapter 5AC900.1000-00

This adapter enables a standard monitor to be connected to the DVI-I interface.

4.1 Order data

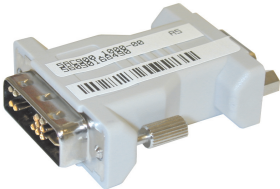
Model number	Description	Figure
5AC900.1000-00	Adapter DVI-A/m to CRT DB15HD/f Adapter DVI (plug) to CRT (socket), for connecting a standard monitor to a DVI-I interface.	

Table 197: Order data - DVI - CRT adapter

5. USB interface cover (attached)

Front side USB port cap (attached) for Automation Panel 900, Panel PC 700 and Panel PC 800 devices.

5.1 Order data

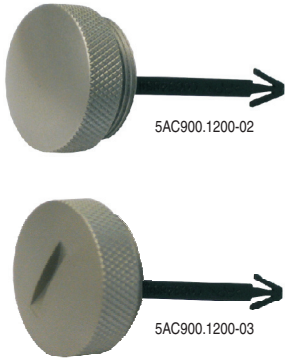
Model number	Description	Figure
5AC900.1200-01	USB port cap IP65 M20 /2 Front-side USB port cap (attached) knurled, short, not slotted.	
5AC900.1200-02	USB port cap IP65 M20 /3 Front-side USB port cap (attached) knurled, tall, not slotted.	
5AC900.1200-03	USB port cap IP65 M20 /4 Front-side USB port cap (attached) knurled, tall, slotted.	

Table 198: Order data - USB port cap (attached)

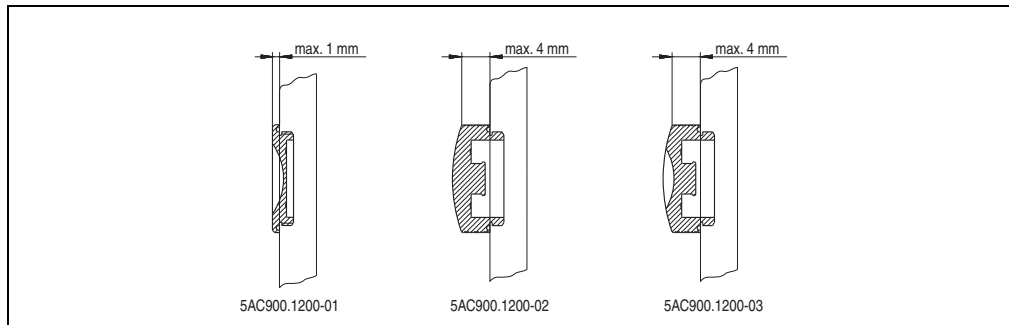


Figure 135: USB port cap (attached) - Height

6. Uninterruptible power supply

With the optionally integrated UPS, the Panel PC 800 makes sure that the PC system completes write operations even after a power failure occurs. When the UPS detects a power failure, it switches to battery operation immediately without interruption. This means that all running programs will be ended properly by the UPS software. This prevents the possibility of inconsistent data (only functions if the UPC is already configured and the driver is activated).

Information:

More detailed information about uninterruptible power supplies can be found in the UPS manual. This can be downloaded from the B&R homepage.

Information:

The monitor is not buffered by the UPS and will shut off when the power fails.

By integrating the charging circuit in the Panel PC 800 housing, the installation has been reduced to merely attaching the connection cable to the battery unit mounted next to the PC.

Special emphasis was placed on ease of maintenance when the battery unit was designed. The batteries are easily accessible from the front and can be switched in just a few moments when servicing.

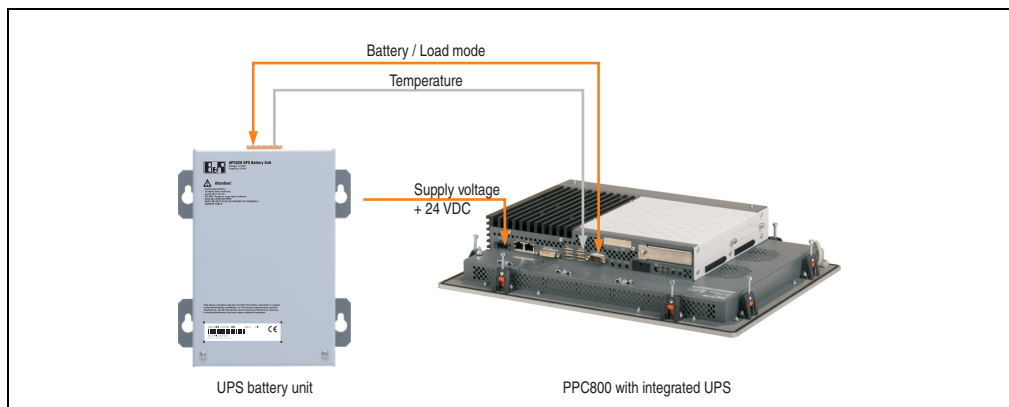


Figure 136: UPS principle

6.1 Features

- Long-lasting, maintenance-free rechargeable batteries
- Communication via integrated interfaces
- Temperature sensor
- Driver software
- Deep discharge protection

6.2 Requirements

- 1) An appropriate system unit.
- 2) Add-on UPS module 5AC600.UPSI-00
- 3) Battery unit 5AC600.UPSB-00
- 4) UPS connection cable 0.5 m (5CAUPS.0005-00) or 3 m (5CAUPS.0030-00)
- 5) For info regarding configuration of the B&R UPS using the ADI Control Center.

6.3 Individual components

6.3.1 Add-on UPS module 5AC600.UPSI-00

The add-on UPS module can easily be installed in an appropriate PPC800 system unit (List of required revisions: see section "Requirements", on page 301).

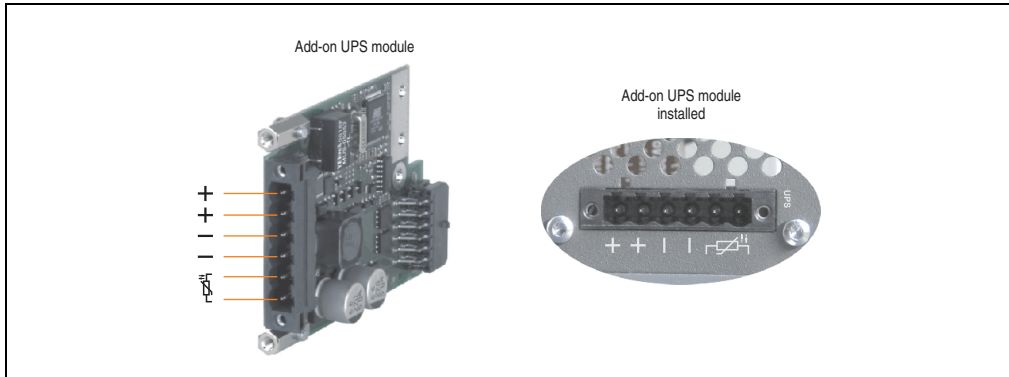


Figure 137: Add-on UPS module 5AC600.UPSI-00

Technical data

Features	5AC600.UPSI-00
Switching threshold mains / battery operation	15 / 13 V
Mains failure bridging	Max. 20 min at 150 W load
Charging current	Max. 0.5 A
Deep discharge protection	Yes, at 10 V on the battery unit
Short circuit protection	No
Power requirements	Max. 7.5 W
Status indicators	Via the ADI Control Center (see section 8 "Automation Device Interface (ADI) - Control Center")
Configuration	Via the ADI Control Center (see section 8 "Automation Device Interface (ADI) - Control Center")

Table 199: Technical data - 5AC600.UPSI-00

Installation

The module is installed using the materials included in the delivery.

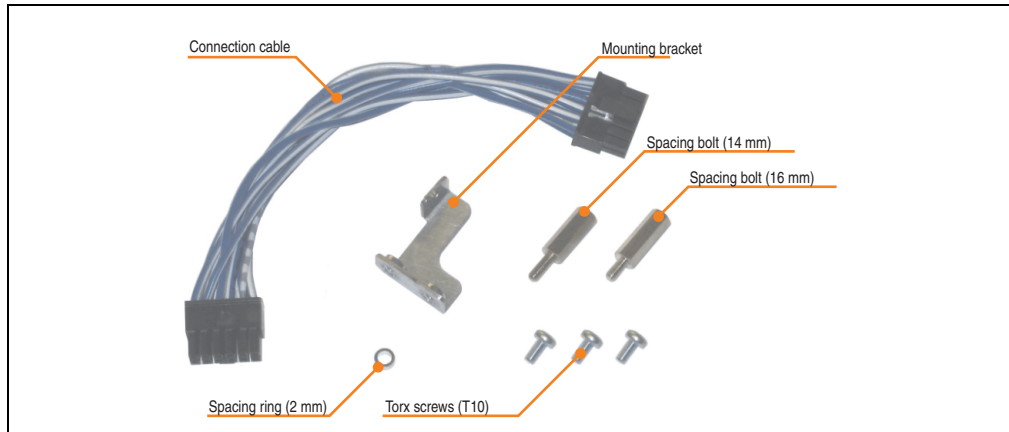


Figure 138: Add-on UPS module 5AC600.UPSI-00 - Installation materials

6.3.2 Battery unit 5AC600.UPSB-00

The battery unit is subject to wear and should be replaced regularly (at least following the specified lifespan).

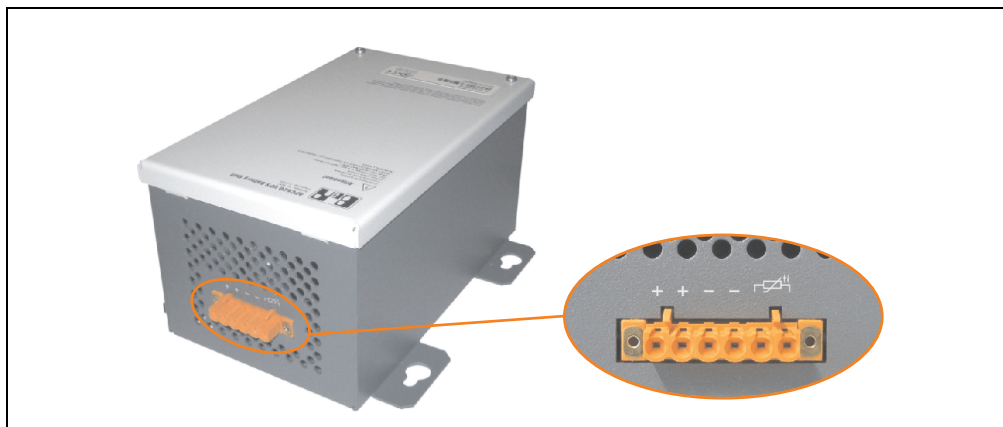


Figure 139: Battery unit 5AC600.UPSB-00

Technical data

Features	5AC600.UPSB-00
Battery Type Method	Energys Cyclon 2 V 5 Ah; (6 connected in series) Single cell (X cell)
Operating current	Max. 8 A
Deep discharge voltage	10 V
Dimensions (W x H x D)	Figure 142 "Dimensions - 5AC600.UPSB-00", on page 306
Temperature sensor	NTC resistance
Weight	Approx. 3.2 kg
Ambient temperature Operation Bearings Transport	-40 to +80°C -65 to +80°C -65 to +80°C
Relative humidity Operation Bearings Transport	5 to 95% (non-condensing) 5 to 95% (non-condensing) 5 to 95% (non-condensing)
Altitude	Max. 3000 meters
Mounting instructions	See "Mounting instructions", on page 307
Lifespan	10 years at 25°C (up to 80% battery capacity)
Maintenance interval during storage	6 month interval between charges

Table 200: Technical data - 5AC600.UPSB-00

Temperature life span diagram up to 20% battery capacity.

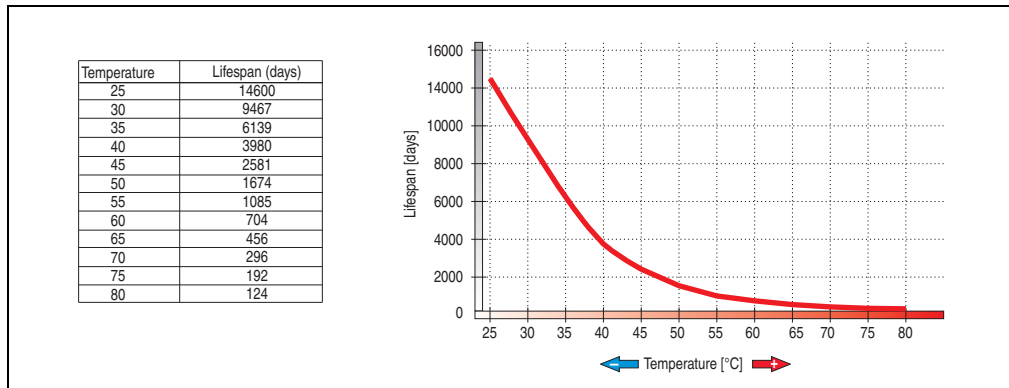


Figure 140: Temperature life span diagram

Deep discharge cycles

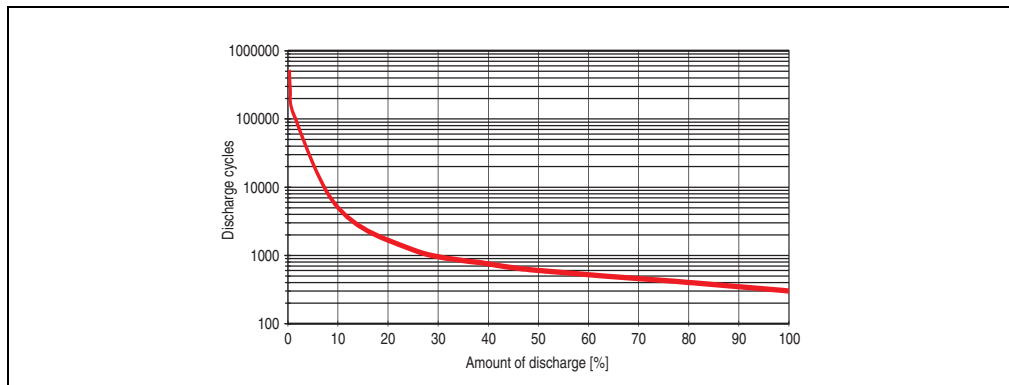


Figure 141: Deep discharge cycles

Dimensions

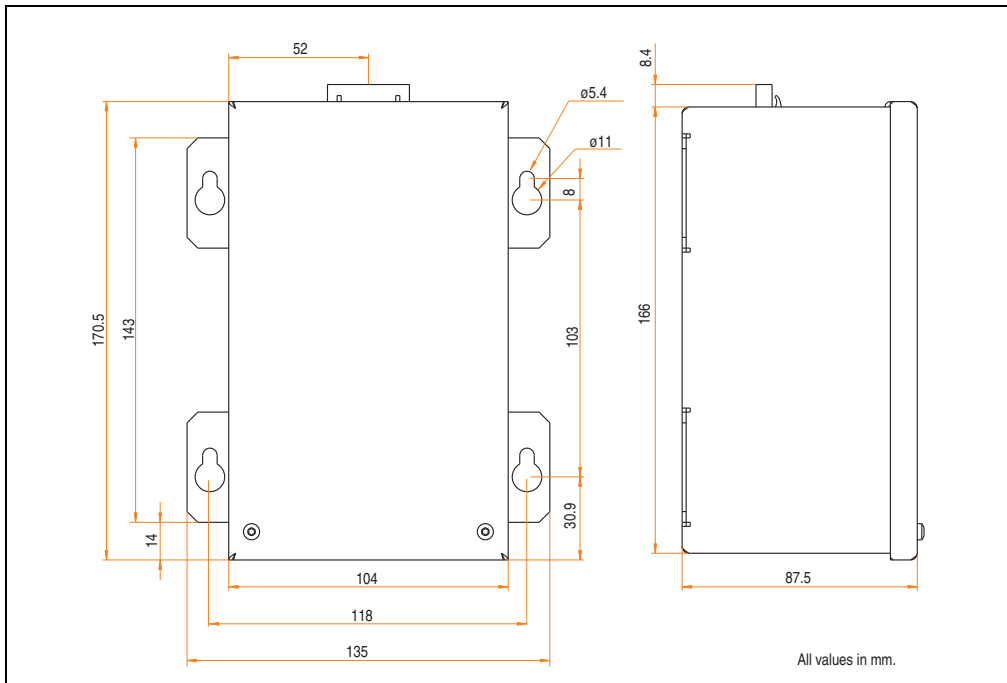


Figure 142: Dimensions - 5AC600.UPSB-00

Drilling template

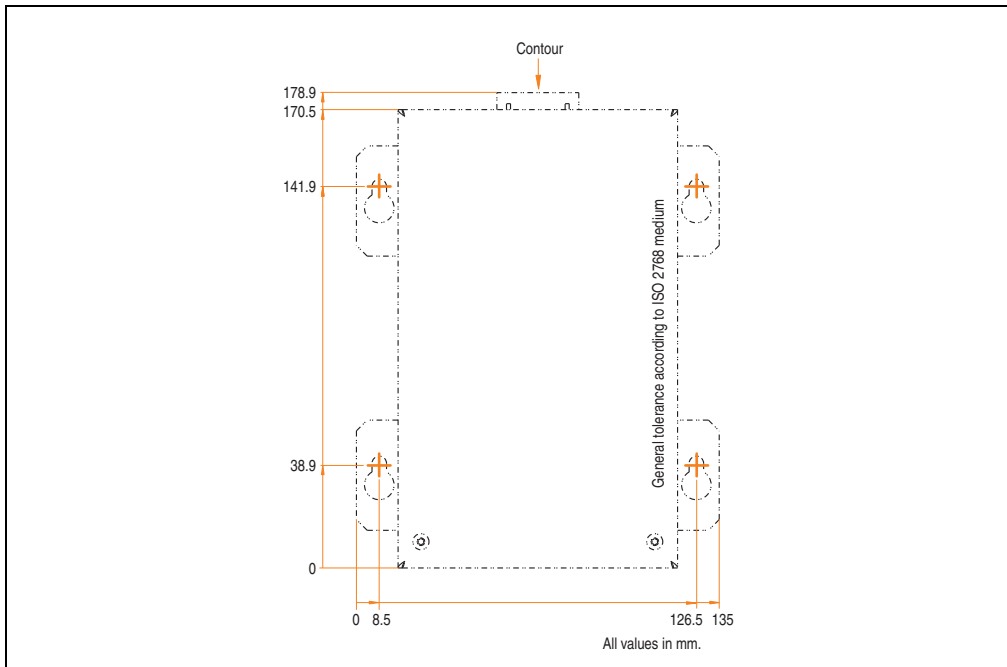


Figure 143: Drilling template for the battery unit

Mounting instructions

Due to the unique construction of these batteries, they can be stored and operated in any position.

6.3.3 UPS connection cable

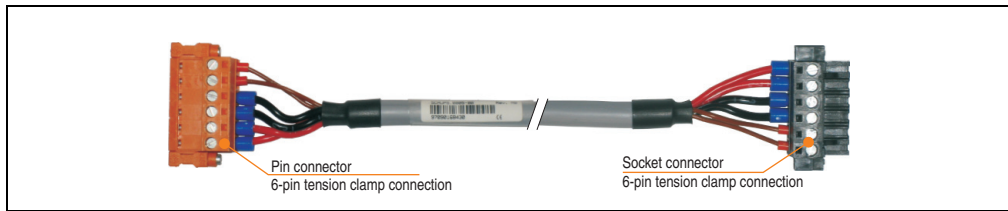


Figure 144: UPS connection cable

Technical data

Features	5CAUPS.0005-00	5CAUPS.0030-00
Length	0.5 m	3 m
Outer diameter	8.5 mm ±0.2 mm	
Connector type	6-pin plug connectors, tension clamp connection / 6-pin socket connectors, tension clamp connection	
Wire cross section Temperature sensor wire Voltage wire	2 x 0.5 mm ² (AWG 20) 4 x 2.5 mm ² (AWG 13)	
Line resistance 0.5 mm ² 2.5 mm ²	Max. 39 Ω/km Max. 7.98 Ω/km	
Flex radius Fixed installation Free-moving	5x wire cross-section 10x wire cross-section	
Temperature range Moving Non-moving	-5 to +80°C -30 to +80°C	
Weight	Approx. 143 kg/km	
Materials Cable shield Color	Thermoplastic PVC-based material Window gray (similar to RAL 7040)	
Peak operating voltage	12 V DC	
Testing AC voltage Wire / wire	1500 V	
Operating voltage	Max. 300 V	
Current load	10 A at +20°C	

Table 201: Technical data - UPS connection cable

7. External UPS

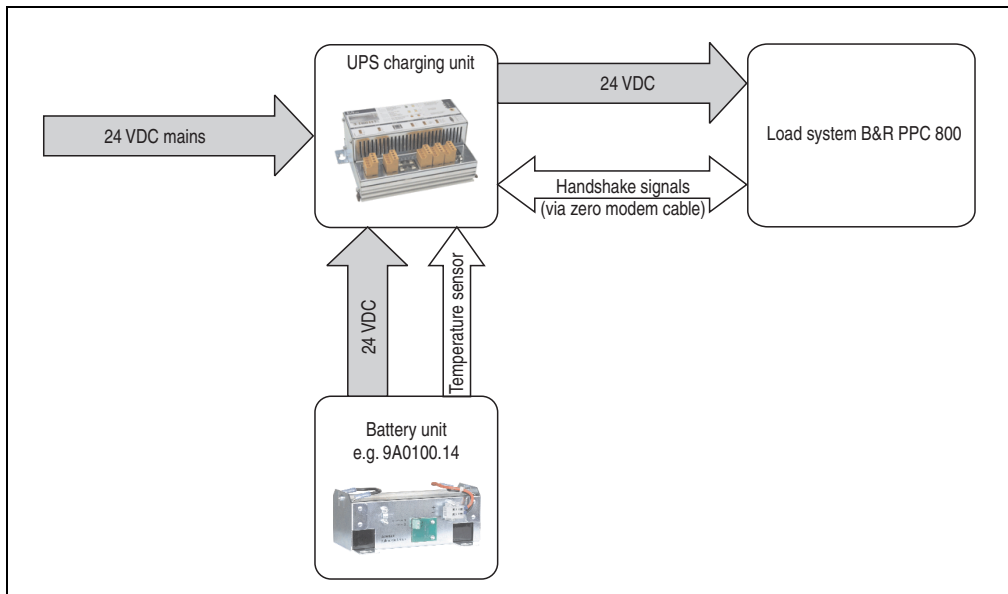


Figure 145: Block diagram of the UPS

7.1 General information

For supply with an external UPS, a UPS charging unit, a battery unit and a null modem cable are required.

In normal operation, the 24 VDC supply voltage is put straight through to the load system. If the supply voltage fails, the rechargeable UPS batteries power the PC to allow controlled shutdown without loss of data.

Data and commands are exchanged between the UPS and the load system via the handshake signals for an RS232 interface.

More information concerning an external UPS is available in the "UPS manual", which can be downloaded from the B&R homepage (www.br-automation.com).

7.2 Order data

Model number	Description	Note
9A0100.11	UPS 24 VDC 24 VDC input, 24 VDC output, serial interface	
9A0100.14	UPS battery unit type B 24 V; 2.2 Ah; including battery cage	
9A0100.15	UPS battery unit type B (replacement part) 2 x 12 V; 2.2 Ah; for battery unit 9A0100.14	
9A0017.01	RS232 Null Modem Cable, 0.6 m To connect UPS and load system (9-pin DSUB socket - 9-pin DSUB socket)	
9A0017.02	RS232 Null Modem Cable, 1.8 m To connect UPS and load system (9-pin DSUB socket - 9-pin DSUB socket)	

Table 202: UPS - Order data

8. CompactFlash cards 5CFCRD.xxxx-04

8.1 General information

Information:

B&R CompactFlash cards 5CFCRD.xxxx-04 and CompactFlash cards from a different manufacturer cannot be used in the same system at the same time. Due to differences in technology (older vs. newer technologies), problems can occur during system startup that are caused by the different boot times.

See chapter 3 "Commissioning", section 8 "Known problems / issues", on page 163.

Information:

The 5CFCRD.xxxx-04 CompactFlash cards are supported on B&R devices with WinCE Version 6.0 or higher.

8.2 Order data

Model number	Description	Figure
5CFCRD.0512-04	512 MB B&R CompactFlash card	
5CFCRD.1024-04	1024 MB B&R CompactFlash card	
5CFCRD.2048-04	2048 MB B&R CompactFlash card	
5CFCRD.4096-04	4096 MB B&R CompactFlash card	
5CFCRD.8192-04	8192 MB B&R CompactFlash card	
5CFCRD.016G-04	16 GB B&R CompactFlash card	
		CompactFlash card

Table 203: Order data - CompactFlash cards

8.3 Technical data

Caution!

A sudden loss of power can cause data to be lost! In very rare cases, the mass memory may also become damaged.

To prevent damage and loss of data, it is recommended to use a UPS device.

Information:

The following characteristics, features and limit values only apply to this accessory and can deviate those specified for the entire device. For the entire device where this accessory is installed, refer to the data provided specifically for the entire device.

Features	5CFCRD.0512-04	5CFCRD.1024-04	5CFCRD.2048-04	5CFCRD.4096-04	5CFCRD.8192-04	5CFCRD.016G-04
MTBF (at 25°C)	> 3,000,000 hours					
Maintenance	None					
Data reliability	< 1 unrecoverable error in 10 ¹⁴ bit read accesses					
Data retention	10 years					
Lifetime monitoring	Yes					
Supported operating modes	PIO Mode 0-6, Multiword DMA Mode 0-4, Ultra DMA Mode 0-4					
Continuous reading	Typically 35 MB/s (240X) ¹⁾²⁾ Max. 37 MB/s (260X) ¹⁾²⁾	Typically 35 MB/s (240X) ¹⁾ Max. 37 MB/s (260X) ¹⁾²⁾	Typically 35 MB/s (240X) ¹⁾ Max. 37 MB/s (260X) ¹⁾²⁾	Typically 33 MB/s (220X) ¹⁾ Max. 34 MB/s (226X) ¹⁾²⁾	Typically 27 MB/s (180X) ¹⁾ Max. 28 MB/s (186X) ¹⁾²⁾	Typically 36 MB/s (240X) ¹⁾ Max. 37 MB/s (247X) ¹⁾²⁾
Continuous writing	Typically 17 MB/s (110X) Max. 20 MB/s (133X)	Typically 17 MB/s (110X) Max. 20 MB/s (133X)	Typically 17 MB/s (110X) Max. 20 MB/s (133X)	Typically 16 MB/s (106X) Max. 18 MB/s (120X)	Typically 15 MB/s (100X) Max. 17 MB/s (110X)	Typically 18 MB/s (120X) Max. 19 MB/s (126X)
Endurance						
Guaranteed amount of data ³⁾ Results in 5 years ³⁾	50 TB 27.40 GB/day	100 TB 54.79 GB/day	200 TB 109.59 GB/day	400 TB 219.18 GB/day	800 TB 438.36 GB/day	1600 TB 876.72 GB/day
Clear/write cycles Guaranteed Typical ⁴⁾	100,000 2,000,000					
SLC flash	Yes					
Wear leveling	Static					
Error Correction Coding (ECC)	Yes					

Table 204: Technical data - CompactFlash cards 5CFCRD.xxxx-04

Support	5CFCRD.0512-04	5CFCRD.1024-04	5CFCRD.2048-04	5CFCRD.4096-04	5CFCRD.8192-04	5CFCRD.016G-04
Hardware	PP300/400, PPC300, PPC700, PPC725, PPC800, APC620, APC810, APC820					
Windows XP Professional	-	-	-	Yes	Yes	Yes
Windows XP Embedded	Yes	Yes	Yes	Yes	Yes	Yes
Windows Embedded Standard 2009	-	Yes	Yes	Yes	Yes	Yes
Windows CE 6.0	Yes	Yes	Yes	Yes	Yes	Yes ⁵⁾
Windows CE 5.0	-	-	-	-	-	-
PVI Transfer Tool	V3.2.3.8 (part of PVI Development Setup V2.06.00.3011)					-
B&R Embedded OS Installer	V3.10					-
Mechanical characteristics						
Dimensions						
Length	36.4 ±0.15 mm					
Width	42.8 ±0.10 mm					
Thickness	3.3 ±0.10 mm					
Weight	10 g					
Environmental characteristics						
Ambient temperature						
Operation	0 to +70°C					
Bearings	-65 to +150°C					
Transport	-65 to +150°C					
Relative humidity						
Operation/Storage/Transport	Max. 85% at 85°C					
Vibration						
Operation/Storage/Transport	20 G peak, 20- 2000 Hz, 4 in each direction (JEDEC JESD22, method B103) 5.35 G RMS, 15 min per level (IEC 68-2-6)					
Shock						
Operation/Storage/Transport	1.5k G peak, 0.5 ms 5 times (JEDEC JESD22, method B110) 30 G, 11 ms 1 time (IEC 68-2-27)					
Altitude	Max. 15,000 feet (4,572 m)					

Table 204: Technical data - CompactFlash cards 5CFCRD.xxxx-04 (cont.)

- 1) Speed specification with 1X = 150 KB/s. All specifications refer to the Samsung Flash chips, CompactFlash cards in UDMA mode 4, 30 ns cycle time in True-IDE mode with sequential write/read test.
- 2) The file is written/read sequentially in True IDE mode with the DOS program Thruput.exe.
- 3) Endurance of B&R CF cards (linear written block size with 128 kB)
- 4) Depending on the average file size.
- 5) Not supported by B&R Embedded OS installer.

8.3.1 Temperature humidity diagram - Operation and storage

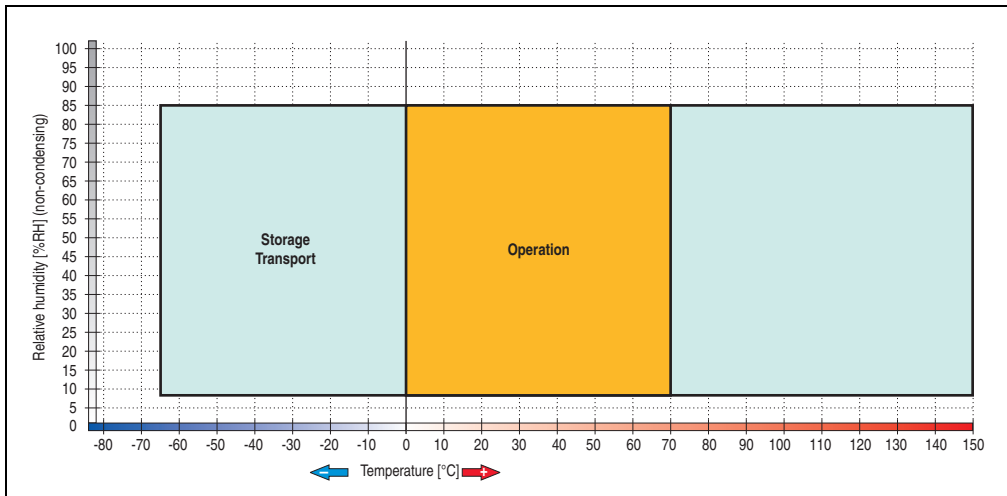


Figure 146: Temperature humidity diagram - CompactFlash cards 5CFCRD.xxxx-04

8.4 Dimensions

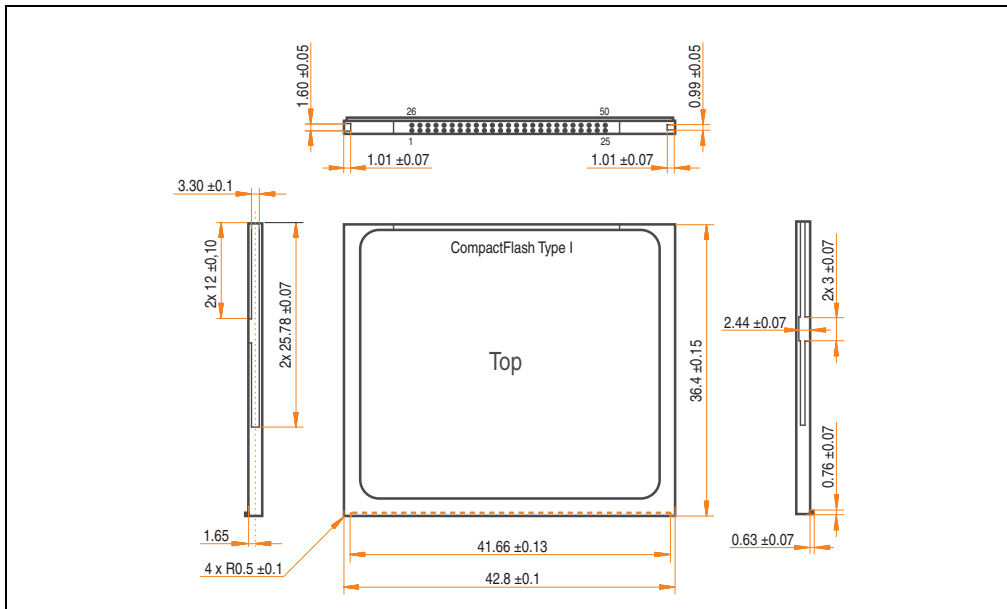


Figure 147: Dimensions - CompactFlash card Type I

8.5 Benchmark

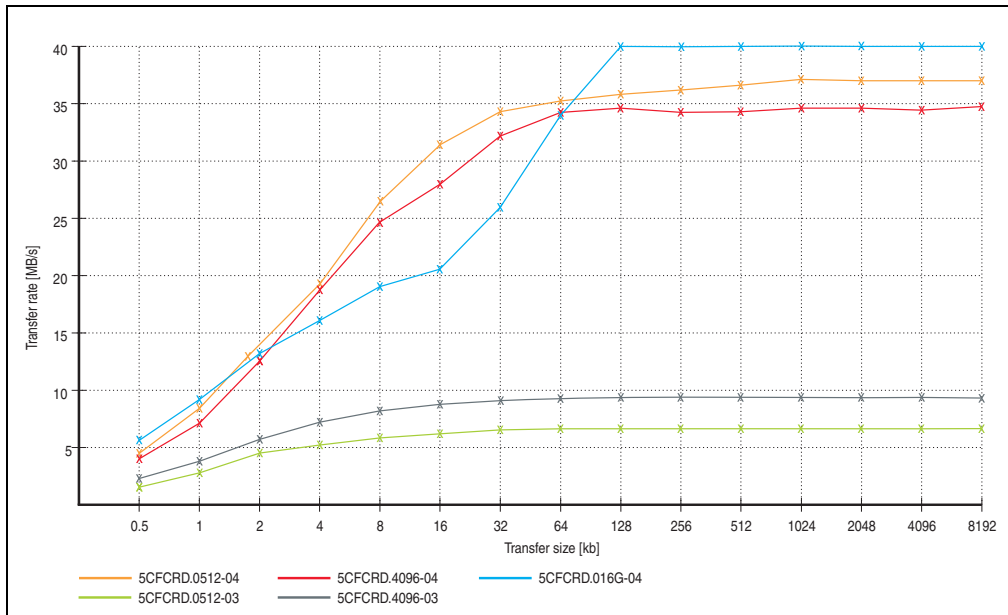


Figure 148: ATTO disk benchmark v2.34 comparison (reading)

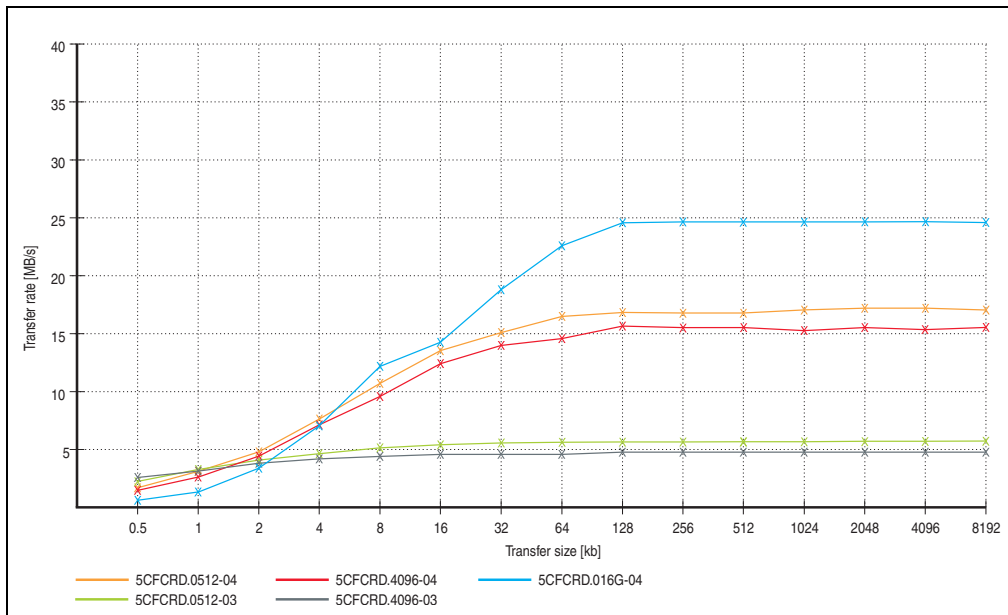


Figure 149: ATTO disk benchmark v2.34 comparison (writing)

9. CompactFlash cards - 5CFCRD.xxxx-03

9.1 General information

Information:

Silicon Systems CompactFlash cards 5CFCRD.xxxx-03 and CompactFlash cards from a different manufacturer cannot be used in the same system at the same time. Due to differences in technology (older vs. newer technologies), problems can occur during system startup that are caused by the different boot times.

See chapter 3 "Commissioning", section 8 "Known problems / issues", on page 163.

Information:

On Windows CE 5.0 devices, 5CFCRD.xxxx-03 CompactFlash cards up to 1GB are supported.

9.2 Order data

Model number	Description	Figure
5CFCRD.0064-03	CompactFlash 64 MB SSI	 CompactFlash card
5CFCRD.0128-03	CompactFlash 128 MB SSI	
5CFCRD.0256-03	CompactFlash 256 MB SSI	
5CFCRD.0512-03	CompactFlash 512 MB SSI	
5CFCRD.1024-03	CompactFlash 1024 MB SSI	
5CFCRD.2048-03	CompactFlash 2048 MB SSI	
5CFCRD.4096-03	CompactFlash 4096 MB SSI	
5CFCRD.8192-03	CompactFlash 8192 MB SSI	

Table 205: Order data - CompactFlash cards

9.3 Technical data

Caution!

A sudden loss of power can cause data to be lost! In very rare cases, the mass memory may also become damaged.

To prevent damage and loss of data, B&R recommends that you use a UPS device.

Information:

The following characteristics, features and limit values only apply to this accessory and can deviate those specified for the entire device. For the entire device where this accessory is installed, refer to the data provided specifically for the entire device.

Features	5CFCRD. 0064-03	5CFCRD. 0128-03	5CFCRD. 0256-03	5CFCRD. 0512-03	5CFCRD. 1024-03	5CFCRD. 2048-03	5CFCRD. 4096-03	5CFCRD. 8192-03
MTBF (at 25°C)	> 4,000,000 hours							
Maintenance	None							
Data reliability	< 1 unrecoverable error in 10 ¹⁴ bit read accesses							
Data retention	10 years							
Lifetime monitoring	Yes							
Supported operating modes	PIO Mode 0-4, Multiword DMA Mode 0-2							
Continuous reading	Typically 8 MB/s							
Continuous writing	Typically 6 MB/s							
Endurance								
Clear/write cycles Typical	> 2,000,000							
SLC flash	Yes							
Wear leveling	Static							
Error Correction Coding (ECC)	Yes							
Support								
Hardware	MP100/200, PP100/200, PP300/400, PPC300, PPC700, PPC725, PPC800, Provit 2000, Provit 5000, APC620, APC680, APC810, APC820							
Windows XP Professional	-	-	-	-	-	-	Yes	Yes
Windows XP Embedded	-	-	-	Yes	Yes	Yes	Yes	Yes
Windows Embedded Standard 2009	-	-	-	-	Yes	Yes	Yes	Yes
Windows CE 6.0	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes ¹⁾

Table 206: Technical data - CompactFlash cards 5CFCRD.xxxx-03

Accessories • CompactFlash cards - 5CFCRD.xxxx-03

Support	5CFCRD. 0064-03	5CFCRD. 0128-03	5CFCRD. 0256-03	5CFCRD. 0512-03	5CFCRD. 1024-03	5CFCRD. 2048-03	5CFCRD. 4096-03	5CFCRD. 8192-03
Windows CE 5.0	Yes	Yes	Yes	Yes	Yes	-	-	-
PVI Transfer Tool	V2.57 (part of PVI Development Setup V2.5.3.3005)							
B&R Embedded OS Installer	V2.21							
Mechanical characteristics								
Dimensions								
Length	36.4 ±0.15 mm							
Width	42.8 ±0.10 mm							
Thickness	3.3 ±0.10 mm							
Weight	11.4 g							
Environmental characteristics								
Ambient temperature								
Operation	0 to +70°C							
Bearings	-50 to +100°C							
Transport	-50 to +100°C							
Relative humidity								
Operation/Storage/Transport	8 to 95%, non-condensing							
Vibration								
Operation	Max. 16.3 g (159 m/s ² 0-peak)							
Storage/Transport	Max. 30 g (294 m/s ² 0-peak)							
Shock								
Operation	Max. 1000 g (9810 m/s ² 0-peak)							
Storage/Transport	Max. 3000 g (29430 m/s ² 0-peak)							
Altitude	Maximum 80,000 feet (24,383 meters)							

Table 206: Technical data - CompactFlash cards 5CFCRD.xxxx-03 (cont.)

1) Not supported by B&R Embedded OS installer.

9.3.1 Temperature humidity diagram - Operation and storage

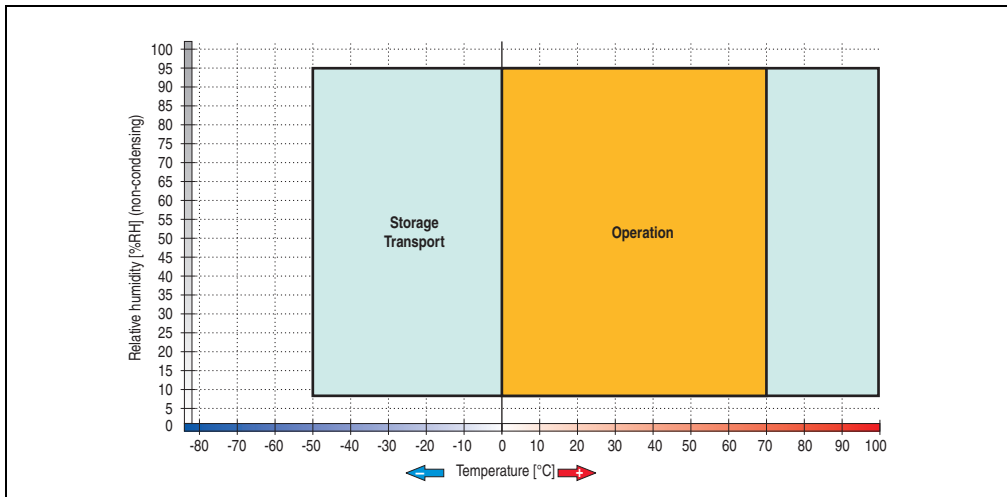


Figure 150: Temperature humidity diagram - CompactFlash cards 5CFCRD.xxxx-03

9.4 Dimensions

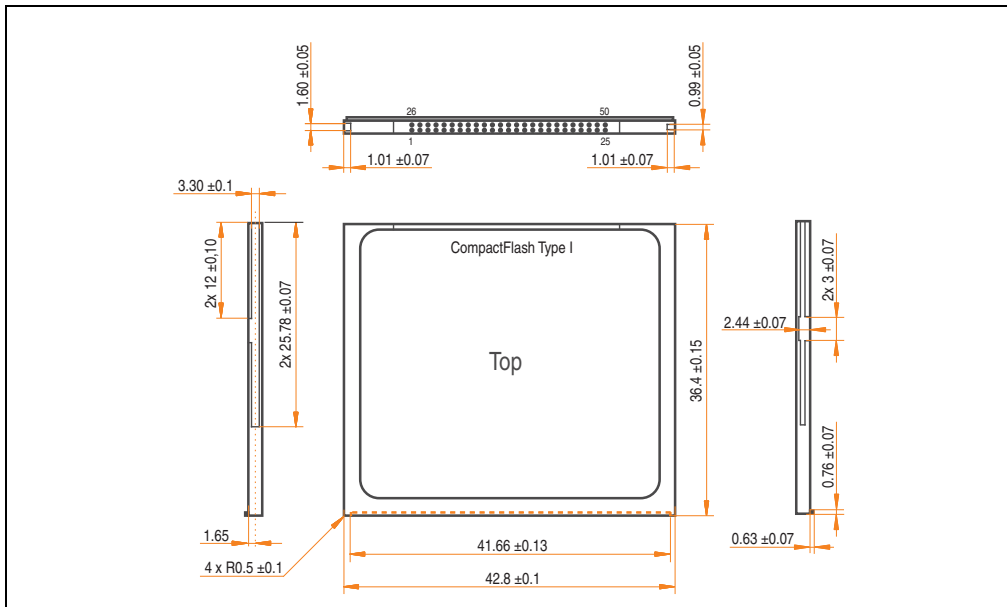


Figure 151: Dimensions - CompactFlash card Type I

10. USB flash drive

Information:

We reserve the right to supply alternative products due to the vast quantity of flash drives available on the market and their corresponding short product lifecycle. Therefore, the following measures might be necessary in order to boot from these flash drives (e.g. the SanDisk Cruzer Micro flash drive with 512 MB):

- The flash drive must be reformatted or in some cases even re-partitioned (set active partition).
- The flash drive must be at the top of the BIOS boot order, or alternatively the IDE controllers can also be deactivated in the BIOS. This can be avoided in most cases if a "`fdisk /mbr`" command is also executed on the USB flash drive.

10.1 General information

USB flash drives are easy-to-exchange storage media. Because of the fast data transfer (USB 2.0), the USB flash drives are ideal for use as a portable memory medium. Without requiring additional drivers ("Hot Plug & Play" - except with Windows 98SE), the USB flash drive can be converted immediately into an additional drive where data can be read or written. Only USB flash drives from the memory specialists [SanDisk](#) are used.

10.2 Order data

Model number	Description	Figure
5MMUSB.2048-00	USB flash drive 2 GB SanDisk Cruzer Micro	

Table 207: Order data - USB flash drives

10.3 Technical data

Information:

The following characteristics, features and limit values only apply to this accessory and can deviate those specified for the entire device. For the entire device where this accessory is installed, refer to the data provided specifically for the entire device.

Features	5MMUSB.2048-00
LED	1 LED (green), signals data transfer (send and receive)
Power supply Current requirements	Via the USB port 650 μ A in sleep mode, 150 mA read/write
Interface Type Transfer rate Sequential reading Sequential writing Connection	USB specification 2.0 high speed device, mass storage class, USB-IF and WHQL certified USB 1.1 and 2.0 compatible Up to 480 MBit (high speed) Max. 8.7 MB/second Max. 1.7 MB/second To each USB type A interface
MTBF (at 25°C)	100,000 hours
Data retention	10 years
Maintenance	None
Operating system support	Windows CE 4.2, CE 5.0, ME, 2000, XP and Mac OS 9.1.x+, OS X v10.1.2+
Mechanical characteristics	
Dimensions Length Width Thickness	52.2 mm 19 mm 7.9 mm
Environmental characteristics	
Ambient temperature Operation Bearings Transport	0 to +45°C -20 to +60°C -20 to +60°C
Relative humidity Operation Bearings Transport	10 to 90%, non-condensing 5 to 90%, non-condensing 5 to 90%, non-condensing
Vibration Operation Bearings Transport	at 10 - 500 Hz: 2 g (19.6 m/s ² 0-peak), oscillation rate 1/minute At 10 - 500 Hz: 4 g (39.2 m/s ² 0-peak), oscillation rate 1/minute At 10 - 500 Hz: 4 g (39.2 m/s ² 0-peak), oscillation rate 1/minute
Shock Operation Bearings Transport	Max. 40 g (392 m/s ² 0-peak) and 11 ms length Max. 80 g (784 m/s ² 0-peak) and 11 ms length Max. 80 g (784 m/s ² 0-peak) and 11 ms length
Altitude Operation Bearings Transport	3,048 meters 12,192 meters 12,192 meters

Table 208: Technical data - USB flash drive 5MMUSB.2048-00

10.3.1 Temperature humidity diagram - Operation and storage

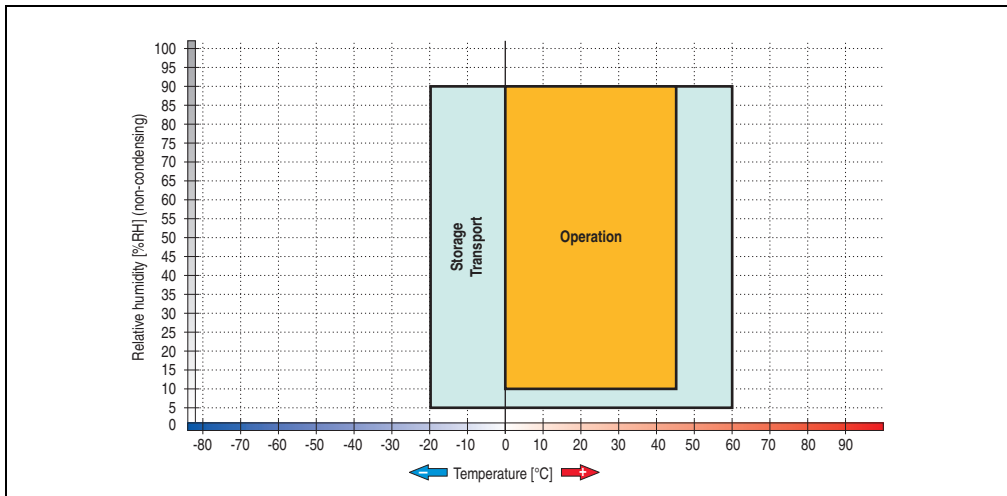


Figure 152: Temperature humidity diagram - USB flash drive - 5MMUSB.2048-00

Temperature data is for operation at 500 meters. Derating the max. ambient temperature - typically 1°C per 1000 meters (from 500 meters above sea level).

11. B&R Automation Studio 3.0USBdongle

11.1 Order data

Model number	Description	Figure
1A4300.LZ1U	B&R Automation Studio 3.0 USB dongle Dongle for using AR010.	

Table 209: Order data - B&R Automation Studio 3.0 Dongle

12. HMI Drivers & Utilities DVD 5SWHMI.0000-00



Figure 153: HMI Drivers & Utilities DVD 5SWHMI.0000-00

Model number	Short description	Note
5SWHMI.0000-00	HMI Drivers & Utilities DVD	

Table 210: Order data - HMI Drivers & Utilities DVD

This DVD contains drivers, utilities, software upgrades and user's manuals for B&R Panel system products (see B&R homepage – Industrial PCs, Visualization and Operation). Information in detail:

BIOS upgrades for the products

- Automation PC 620
- Panel PC 700
- Automation PC 680
- Provit 2000 product family - IPC2000/2001/2002
- Provit 5000 product family - IPC5000/5600/5000C/5600C
- Power Panel 100 BIOS devices
- Mobile Panel 100 BIOS devices
- Power Panel 100 / Mobile Panel 100 user boot logo
- Power Panel 100 / Mobile Panel 100 REMHOST utility

Drivers for the devices

- Automation Device Interface (ADI)
- Audio
- Chipset
- CD-ROM
- LS120
- Graphics
- Network
- PCI RAID controller
- Touch screen
- Touchpad
- Interface board

Updates

- Firmware upgrades (e.g. MTCX, SMXC)

Utilities/Tools

- Automation Device Interface (ADI)
- Miscellaneous
- MTC utilities
- Key editor
- MTC & Mkey utilities
- Mkey utilities
- UPS configuration software
- ICU ISA configuration
- Intel PCI NIC boot ROM
- Diagnostics
- CompactFlash lifespan calculation for Silicon Systems CompactFlash cards 5CFCRD.xxxx-03

Windows and embedded operating systems

- Thin client
- Windows CE
- Windows NT Embedded
- Windows XP Embedded

MCAD templates for

- Industrial PCs
- Visualization and operating devices
- Legend strip templates

Documentation for

- B&R Windows CE
- Automation PC 620
- Automation PC 680
- Automation Panel 900
- Panel PC 700
- Power Panel 15/21/35/41
- Power Panel 100/200
- Provit 2000
- Provit 3030
- Provit 4000
- Provit 5000
- Provit Benchmark
- Provit Mkey
- Windows NT Embedded application guide
- Windows XP Embedded application guide
- Uninterruptible power supply

Service tools

- Acrobat Reader 5.0.5 (freeware in German, English, and French)
- Power Archiver 6.0 (freeware in German, English, and French)
- Internet Explorer 5.0 (German and English)
- Internet Explorer 6.0 (German and English)

13. Cables

13.1 DVI cable 5CADVI.0xxx-00

The DVI cables 5CADVI.0xxx-00 are designed for fixed layout.

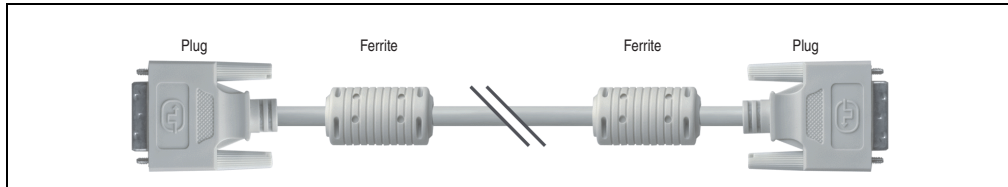


Figure 154: DVI extension cable - 5CADVI.0xxx-00 (similar)

Caution!

The DVI cable can only be plugged in and unplugged when the device is turned off.

13.1.1 Order data

Model number	Description	Note
5CADVI.0018-00	DVI-D cable 1.8 m Single cable, DVI-D/m:DVI-D/m; length: 1.8 m	
5CADVI.0050-00	DVI-D cable 5 m Single cable, DVI-D/m:DVI-D/m; length: 5 m	
5CADVI.0100-00	DVI-D cable 10 m Single cable, DVI-D/m:DVI-D/m; length: 10 m	

Table 211: Model numbers - DVI cables

13.1.2 Technical data

Features	5CADVI.0018-00	5CADVI.0050-00	5CADVI.0100-00
Length Tolerance	1.8 m ±30 mm	5 m ±50 mm	10 m ±100 mm
Cable diameter Maximum	8.5 mm		
Shielding	Individual cable pairs and entire cable		
Connector type Connection cycles	2x DVI-D (18+1), male 100		
Wire cross section	AWG 28		
Line resistance	Max. 237 Ω/km		
Insulation resistance	Min. 100 MΩ/km		
Flexibility	Limited flexibility; valid for ferrite magnet - ferrite magnet (tested 100 cycles with 5x cable diameter, 20 cycles / minute)		
Flex radius Fixed layout	See figure "Flex radius specification", on page 328 5x cable diameter (plug - ferrite magnet and ferrite magnet - ferrite magnet)		
Weight	Approx. 300 g	Approx. 590 g	Approx. 2100 g

Table 212: Technical data - DVI cable 5CADVI.0xxx-00

13.1.3 Flex radius specification

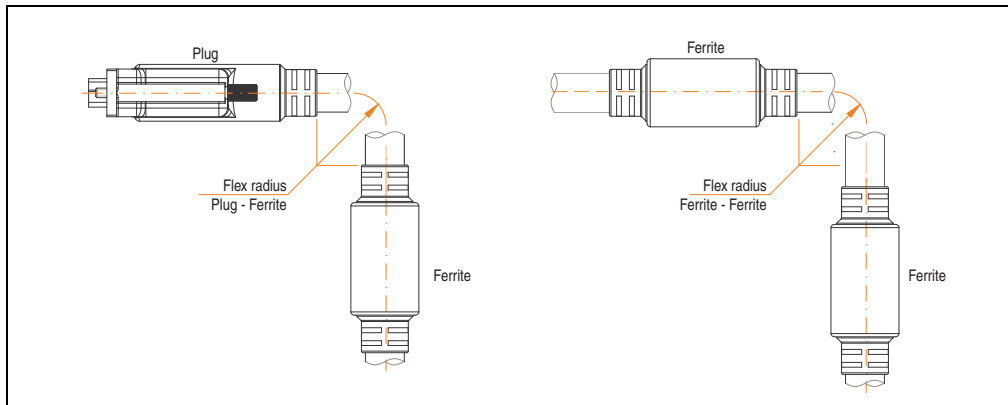


Figure 155: Flex radius specification

13.1.4 Cable specifications

The following figure shows the pin assignments for the DVI cable available at B&R. If you want to build a suitable cable yourself, it should be wired according to these specifications.

Warning!

If a self-built cable is used, B&R cannot guarantee that it will function properly. The DVI cables provided by B&R are guaranteed to function properly.

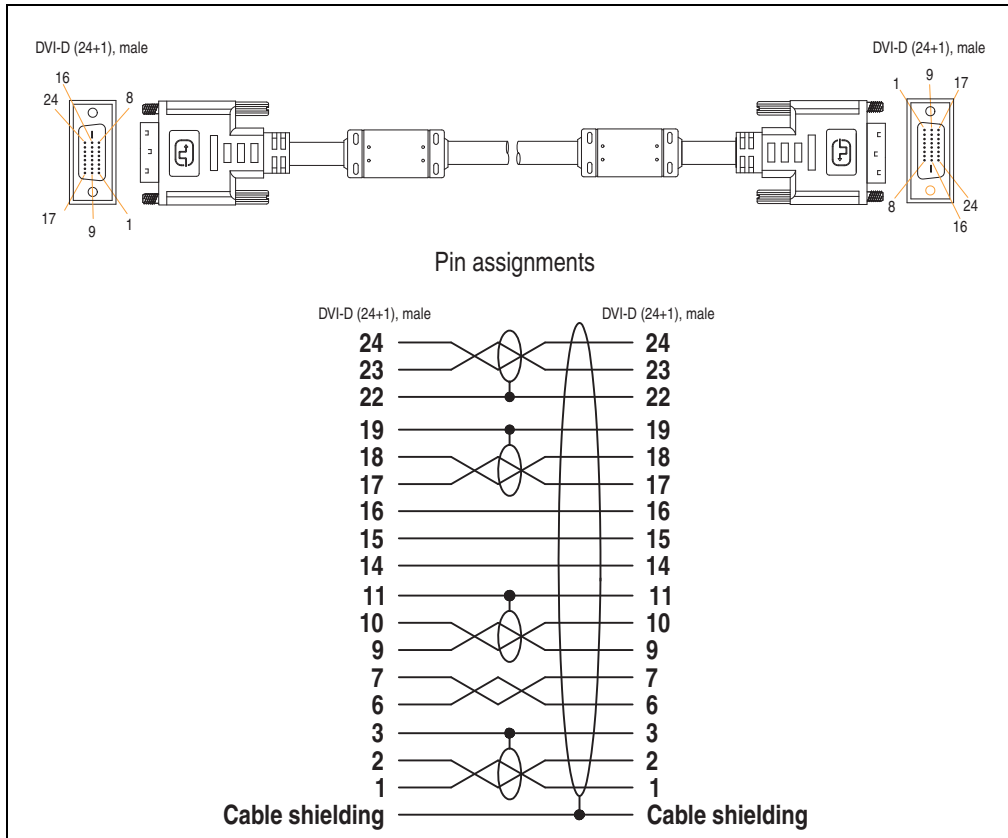


Figure 156: Pin assignments - DVI cable

13.2 SDL cable 5CASDL.0xxx-00

The SDL cables 5CASDL.0xxx-00 are designed for fixed layout. Use of the SDL flex cable 5CASDL.0xxx-03 is required for a flexible installation (e.g. in swing arm systems).

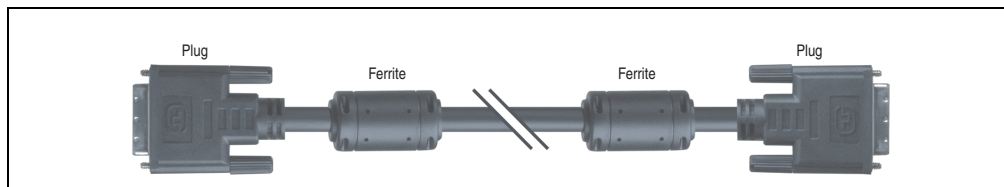


Figure 157: SDL extension cable (similar)

Caution!

The SDI cable can only be plugged in and unplugged when the device is turned off.

13.2.1 Order data

Model number	Description	Note
5CASDL.0018-00	SDL cable 1.8 m SDL cable for a fixed type of layout; length: 1.8 m	
5CASDL.0050-00	SDL cable 5 m SDL cable for a fixed type of layout; length: 5 m	
5CASDL.0100-00	SDL cable 10 m SDL cable for a fixed type of layout; length: 10 m	
5CASDL.0150-00	SDL cable 15 m SDL cable for a fixed type of layout; length: 15 m	
5CASDL.0200-00	SDL cable 20 m SDL cable for a fixed type of layout; length: 20 m	
5CASDL.0250-00	SDL cable 25 m SDL cable for a fixed type of layout; length: 25 m	
5CASDL.0300-00	SDL cable 30 m SDL cable for a fixed type of layout; length: 30 m	

Table 213: Model numbers - SDL cables

13.2.2 Technical data

Features	5CASDL.001 8-00	5CASDL.005 0-00	5CASDL.010 0-00	5CASDL.015 0-00	5CASDL.020 0-00	5CASDL.025 0-00	5CASDL.030 0-00
Length Tolerance	1.8 m ±50 mm	5 m ±80 mm	10 m ±100 mm	15 m ±120 mm	20 m ±150 mm	25 m ±200 mm	30 m ±200 mm
Cable diameter Typical Maximum	8.6 ±0.2 mm 9 mm		11 ±0.2 mm 11.5 mm				
Shielding	Individual cable pairs and entire cable						
Connector type Connection cycles	2x DVI-D (24+1), male 100						
Wire cross section	AWG 28		AWG 24				
Line resistance	Max. 237 Ω/km		Max. 93 Ω/km				
Insulation resistance	Min. 10 MΩ/km						
Flexibility	Limited flexibility; valid for ferrite magnet - ferrite magnet (tested 100 cycles with 5x cable diameter, 20 cycles / minute)						
Halogen-free	No						
Flex radius Fixed layout	See figure "Flex radius specification", on page 331 5x cable diameter (plug - ferrite magnet and ferrite magnet - ferrite magnet)						
Weight	Approx. 300 g	Approx. 590 g	Approx. 2100 g	Approx. 3000 g	Approx. 4100 g	Approx. 5100 g	Approx. 6100 g

Table 214: Technical data - SDL cables 5CASDL.0xxx-00

13.2.3 Flex radius specification

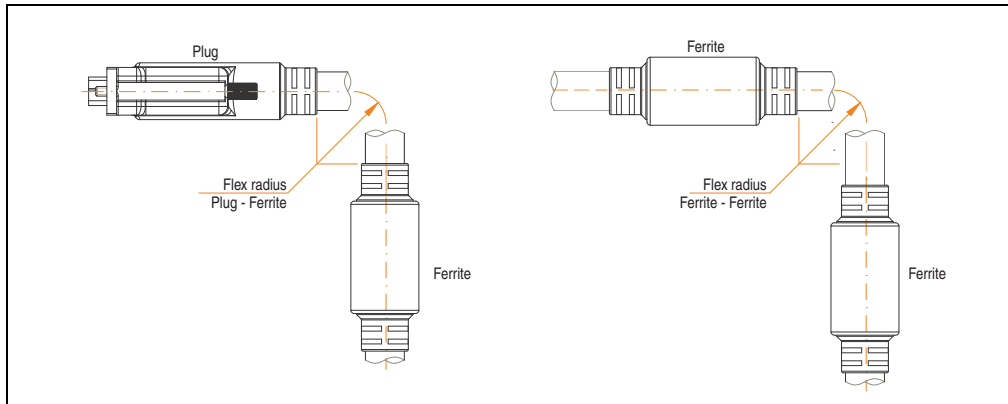


Figure 158: Flex radius specification

13.2.4 Cable specifications

The following figure shows the pin assignments for the SDL cable available at B&R. If you want to build a suitable cable yourself, it should be wired according to these specifications.

Warning!

If a self-built cable is used, B&R cannot guarantee that it will function properly. The SDL cables provided by B&R are guaranteed to function properly.

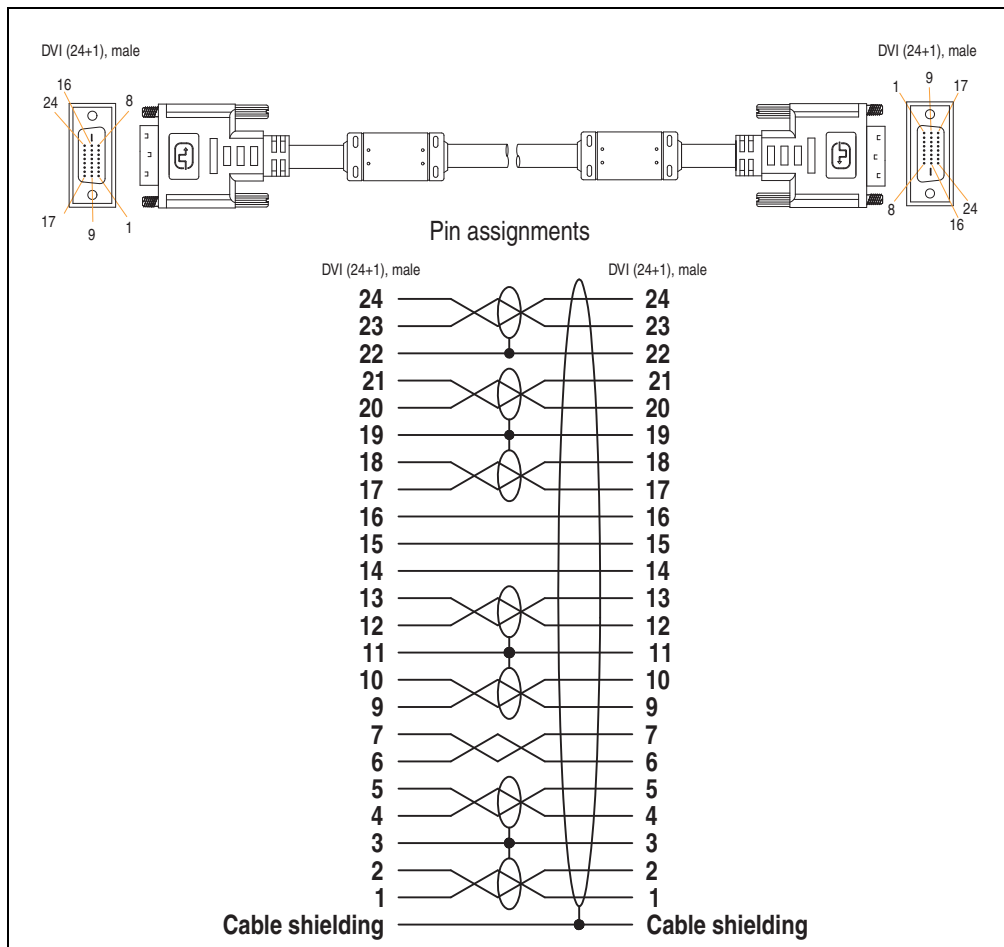


Figure 159: Pin assignments - SDL cable 5CASDL.0xxx-00

13.3 SDL cable with 45° plug 5CASDL.0xxx-01

The SDL cables 5CASDL.0xxx-01 are designed for fixed layout.

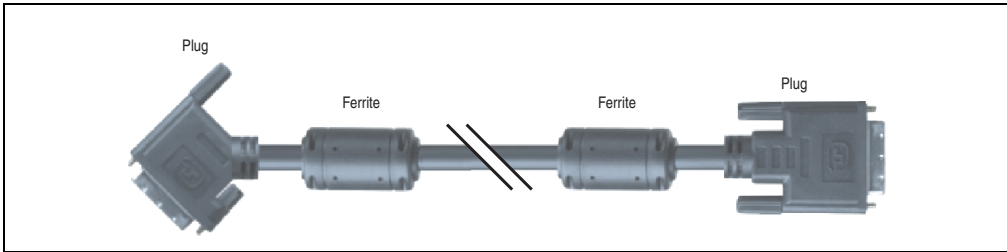


Figure 160: SDL cable with 45° plug (similar)

Caution!

The SDI cable can only be plugged in and unplugged when the device is turned off.

13.3.1 Order data

Model number	Description	Note
5CASDL.0018-01	SDL cable 1.8 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 1.8 m	
5CASDL.0050-01	SDL cable 5 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 5 m	
5CASDL.0100-01	SDL cable 10 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 10 m	
5CASDL.0150-01	SDL cable 15 m 45° SDL cable for fixed type of layout with one-sided 45° plug; length: 15 m	

Table 215: Model numbers - SDL cables with 45° plug

13.3.2 Technical data

Features	5CASDL.0018-01	5CASDL.0050-01	5CASDL.0100-01	5CASDL.0150-01
Length Tolerance	1.8 m ±50 mm	5 m ±80 mm	10 m ±100 mm	15 m ±120 mm
Cable diameter Maximum	9 mm		11.5 mm	
Shielding	Individual cable pairs and entire cable			
Connector type Connection cycles	2x DVI-D (24+1), male 100			
Wire cross section	AWG 28		AWG 24	
Line resistance	Max. 237 Ω/km		Max. 93 Ω/km	
Insulation resistance	Min. 10 MΩ/km			
Flexibility	Limited flexibility; valid for ferrite magnet - ferrite magnet (tested 100 cycles with 5x cable diameter, 20 cycles / minute)			
Halogen-free	No			
Flex radius Fixed layout	See figure "Flex radius specification", on page 334 5x cable diameter (plug - ferrite magnet and ferrite magnet - ferrite magnet)			
Weight	Approx. 300 g	Approx. 590 g	Approx. 2100 g	Approx. 3000 g

Table 216: Technical data - SDL cable with 45° plug 5CASDL.0xxx-01

13.3.3 Flex radius specification

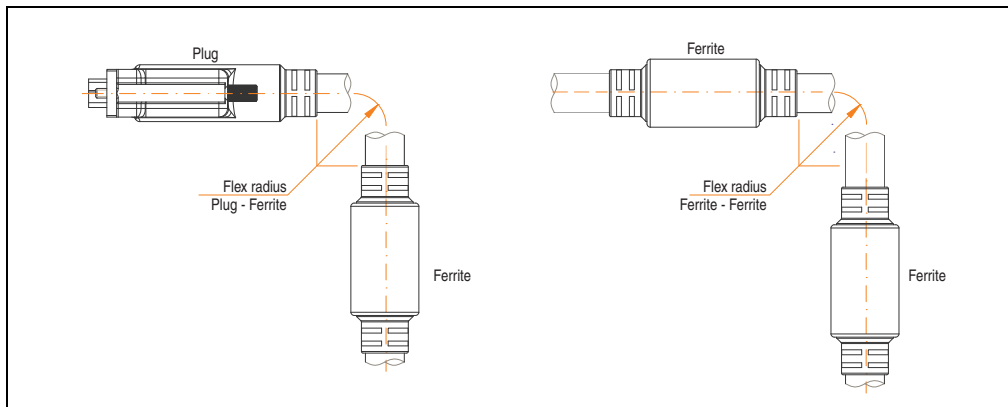


Figure 161: Flex radius specification

13.3.4 Cable specifications

The following figure shows the pin assignments for the SDL cable available at B&R. If you want to build a suitable cable yourself, it should be wired according to these specifications.

Warning!

If a self-built cable is used, B&R cannot guarantee that it will function properly. The SDL cables provided by B&R are guaranteed to function properly.

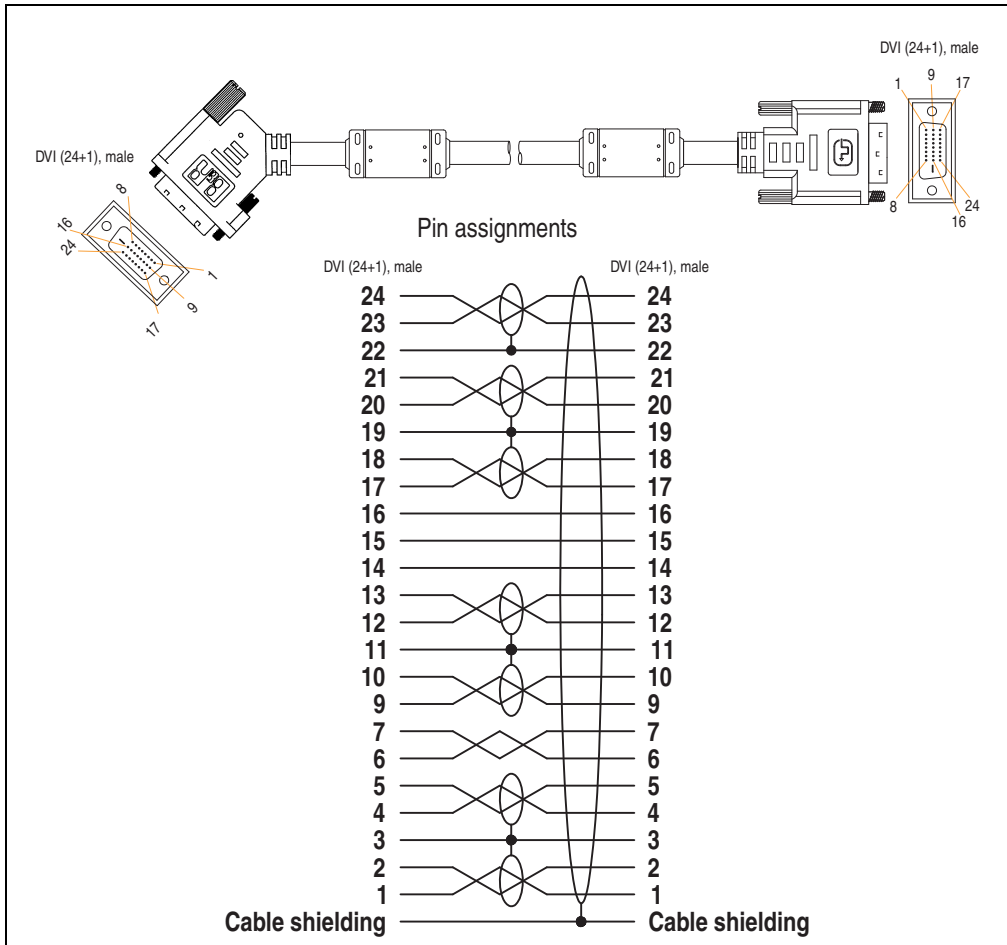


Figure 162: Pin assignments - SDL cable with 45° plug 5CASDL.0xxx-01

13.4 SDL flex cable 5CASDL.0xxx-03

The SDL flex cables 5CASDL.0xxx-03 are designed for both fixed and flexible installations (e.g. in swing arm systems).

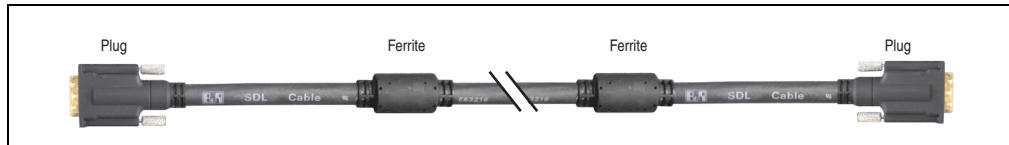


Figure 163: SDL cable 5CASDL.0xxx-03 (similar)

Caution!

The SDI cable can only be plugged in and unplugged when the device is turned off.

13.4.1 Order data

Model number	Description	Note
5CASDL.0018-03	1.8 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 1.8 m	
5CASDL.0050-03	5 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 5 m	
5CASDL.0100-03	10 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 10 m	
5CASDL.0150-03	15 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 15 m	
5CASDL.0200-03	20 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 20 m	
5CASDL.0250-03	25 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 25 m	
5CASDL.0300-03	30 m flex SDL cable SDL cable for fixed and flexible type of layout; length: 30 m	

Table 217: Model numbers - SDL cable 5CASDL.0xxx-03

13.4.2 Technical data

Mechanical characteristics	5CASDL.001 8-03	5CASDL.005 0-03	5CASDL.010 0-03	5CASDL.015 0-03	5CASDL.020 0-03	5CASDL.025 0-03	5CASDL.030 0-03
Length Tolerance	1.8 m ±20 mm	5 m ±45 mm	10 m ±90 mm	15 m ±135 mm	20 m ±180 mm	25 m ±225 mm	30 m ±270 mm
Cable diameter Maximum	12 mm						
Shielding	Individual cable pairs and entire cable						
Connector type Connection cycles Contacts Mechanical protection	2x DVI-D (24+1), male Min. 200 Gold plated Metal cover with crimped stress relief						
Max. tension During installation During operation	≤ 400 N ≤ 50 N						
Materials Cable shield Color	RoHS compliant Aluminum foil clad + tinned copper mesh Black (similar to RAL 9005)						
Flexibility	Flexible; valid for ferrite magnet - ferrite magnet (tested 300,000 cycles with 15x cable diameter, 4800 cycles / hour)						
Halogen-free	Yes						
Flex radius Fixed layout flexible installation	See figure "Flex radius specification", on page 338 6x cable diameter (of plug - ferrite magnet) 10x cable diameter (of ferrite magnet - ferrite magnet) 15x cable diameter (of ferrite magnet - ferrite magnet)						
Weight	Approx. 450 g	Approx. 1000 g	Approx. 2000 g	Approx. 3000 g	Approx. 4000 g	Approx. 5000 g	Approx. 6000 g
Electrical properties (at +20°C)							
Wire cross section	24 AWG (control wires) 26 AWG (DVI, USB, data)						
Line resistance 24 AWG 26 AWG	≤ 95 Ω/km ≤ 145 Ω/km						
Insulation resistance	> 200 MΩ/km						
Wave impedance	100 ±10 Ω						
Test voltage Wire/wire Wire / shield	1 kV _{eff} 0.5 kV _{eff}						
Operating voltage	≤ 30 V						
Environmental characteristics							
Temperature resistance Fixed installation Moving Bearings	-20 to +80°C -5 to +60°C -20 to +80°C						
Fire resistance	Fire resistant according to UL758 (cable vertical flame test)						

Table 218: Technical data - SDL cable 5CASDL.0xxx-03

Standards and certifications	5CASDL.001 8-03	5CASDL.005 0-03	5CASDL.010 0-03	5CASDL.015 0-03	5CASDL.020 0-03	5CASDL.025 0-03	5CASDL.030 0-03
Torsion load	100,000 cycles (tested angle of rotation: $\pm 85^\circ$ speed: 50 cycles / minute)						
Cable drag chain	300,000 cycles Tested flex radius: 180 mm; 15x cable diameter; hub: 460 mm; speed: 4800 cycles / hour						
Approbation	UL AWM 20236 80°C 30 V						
Oil and hydrolysis resistance	According to VDE 0282-10						

Table 218: Technical data - SDL cable 5CASDL.0xxx-03 (cont.)

13.4.3 Flex radius specification

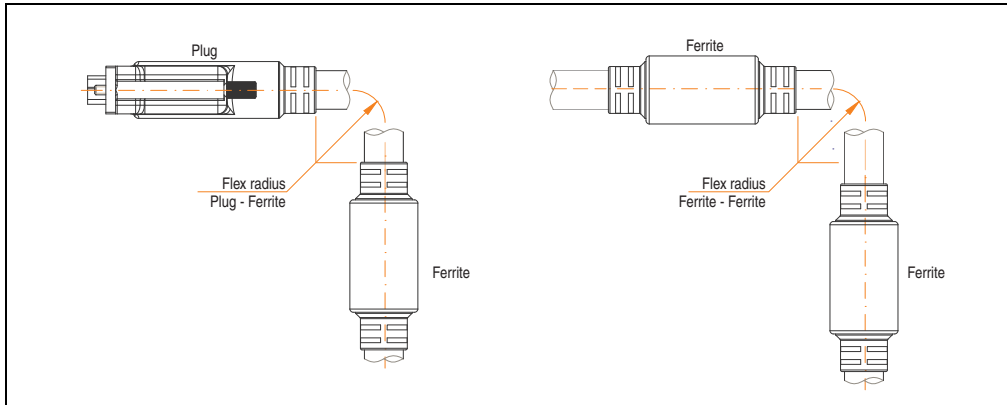


Figure 164: Flex radius specification

13.4.4 Dimensions

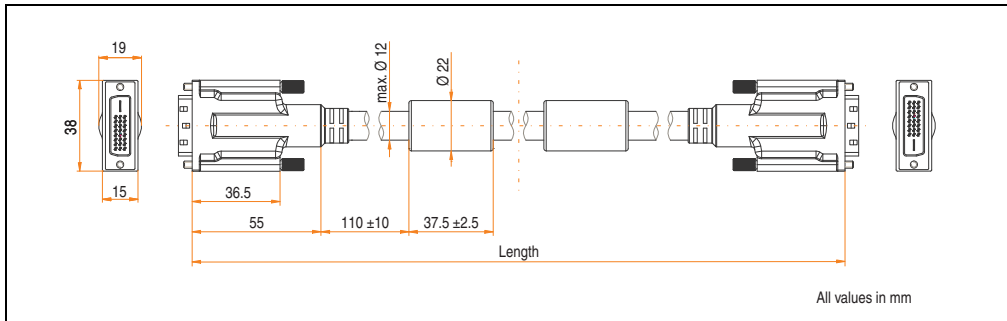


Figure 165: Dimensions - SDL cable 5CASDL.0xxx-03

13.4.5 Structure

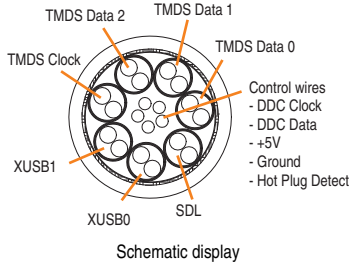
Element	Assignment	Cross section	
DVI	TMDS data 0	26 AWG	 Schematic display
	TMDS data 1	26 AWG	
	TMDS data 2	26 AWG	
	TMDS cycle	26 AWG	
USB	XUSB0	26 AWG	
	XUSB1	26 AWG	
Data	SDL	26 AWG	
Control wires	DDC cycle	24 AWG	
	DDC data	24 AWG	
	+ 5 V	24 AWG	
	mass	24 AWG	
	Hot Plug detect	24 AWG	

Table 219: Structure - SDL cable 5CASDL.0xxx-03

13.4.6 Cable specifications

The following figure shows the pin assignments for the SDL cable available at B&R. If you want to build a suitable cable yourself, it should be wired according to these specifications.

Warning!

If a self-built cable is used, B&R cannot guarantee that it will function properly.

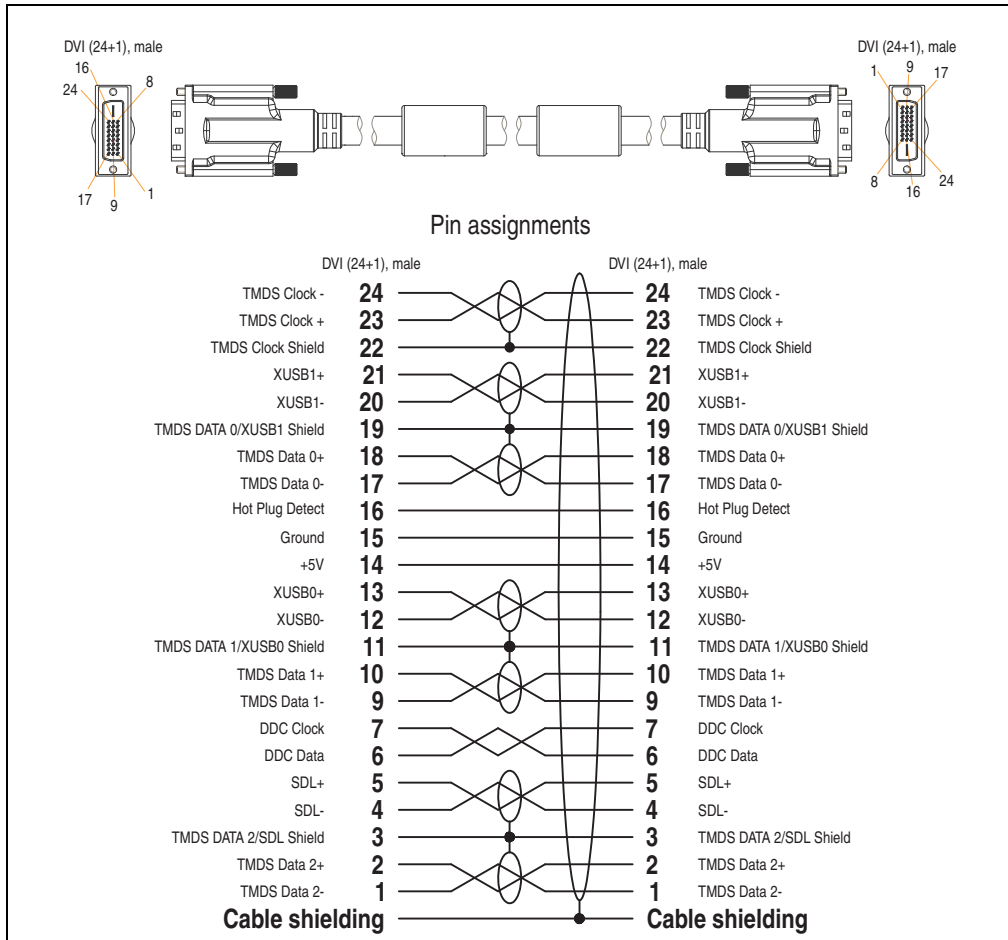


Figure 166: Pin assignments - SDL cable 5CASDL.0xxx-03

13.5 SDL flex cable with extender 5CASDL.0x00-13

The SDL flex cables (with extender) 5CASDL.0x00-13 are designed for both fixed and flexible installations (e.g. in swing arm systems).

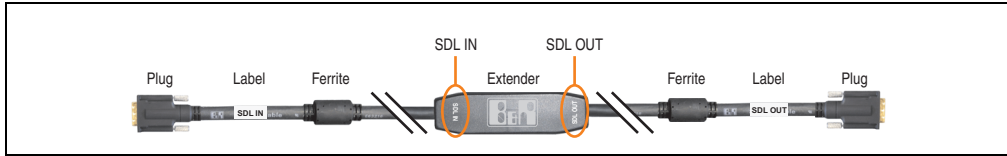


Figure 167: SDL flex cable with extender - 5CASDL.0x00-13 (similar)

Caution!

SDL cables with extender can only be plugged in and unplugged when the device is turned off. The correct direction of connection (SDL IN, SDL OUT) for the wiring is illustrated on the middle of the extender and between the ferrite magnet and plug (with a sticker).

13.5.1 Order data

Model number	Description	Note
5CASDL.0300-13	30 m SDL flex cable with extender SDL cable with extender for fixed and flexible type of layout; length: 30 m	
5CASDL.0400-13	40 m SDL flex cable with extender SDL cable with extender for fixed and flexible type of layout; length: 40 m	

Table 220: Model numbers - SDL flex cable with extender

13.5.2 Technical data

Features	5CASDL.0300-13	5CASDL.0400-13
Length Tolerance	30 m ±200 mm	40 m ±200 mm
Dimensions - Extender box	Height 18.5 mm, width 35 mm, length 125 mm	
Cable diameter Maximum	12 mm	
Shielding	Individual cable pairs and entire cable	
Connector type Connection cycles Contacts Mechanical protection	2x DVI-D (24+1), male Min. 200 Gold plated Metal cover with crimped stress relief	
Max. tension During installation During operation	≤ 400 N ≤ 50 N	

Table 221: Technical data - SDL flex cable with extender 5CASDL.0x00-13

Accessories • Cables

Features	5CASDL.0300-13	5CASDL.0400-13
Materials Cable shield Color	RoHS compliant Aluminum foil clad + tinned copper mesh Black (similar to RAL 9005)	
Flexibility	Flexible; valid for ferrite magnet - ferrite magnet (tested 300,000 cycles with 15x cable diameter, 4800 cycles / hour)	
Halogen-free	Yes	
Flex radius Fixed layout flexible installation	See figure "Flex radius specification", on page 343 6x cable diameter (of plug - ferrite magnet) 10x cable diameter (of ferrite magnet - extender) 15x cable diameter (of ferrite magnet - ferrite magnet)	
Weight	Approx. 6200 g	Approx. 8000 g
Electrical properties (at +20°C)		
Wire cross section	24 AWG (control wires) 26 AWG (DVI, USB, data)	
Line resistance 24 AWG 26 AWG	≤ 95 Ω/km ≤ 145 Ω/km	
Insulation resistance	> 200 MΩ/km	
Wave impedance	100 ±10 Ω	
Test voltage Wire/wire Wire / shield	1 kV _{eff} 0.5 kV _{eff}	
Operating voltage	≤ 30 V	
Environmental characteristics		
Temperature resistance Fixed installation Moving Bearings	-20 to +60°C -5 to +60°C -20 to +60°C	
Fire resistance	Fire resistant according to UL758 (cable vertical flame test)	
Standards and certifications		
Torsion load	100,000 cycles (tested angle of rotation: ±85° speed: 50 cycles / minute)	
Cable drag chain	300,000 cycles Tested flex radius: 180 mm; 15x cable diameter; hub: 460 mm; speed: 4800 cycles / hour	
Approbation	UL AWM 20236 80°C 30 V	
Oil and hydrolysis resistance	According to VDE 0282-10	

Table 221: Technical data - SDL flex cable with extender 5CASDL.0x00-13 (cont.)

13.5.3 Flex radius specification

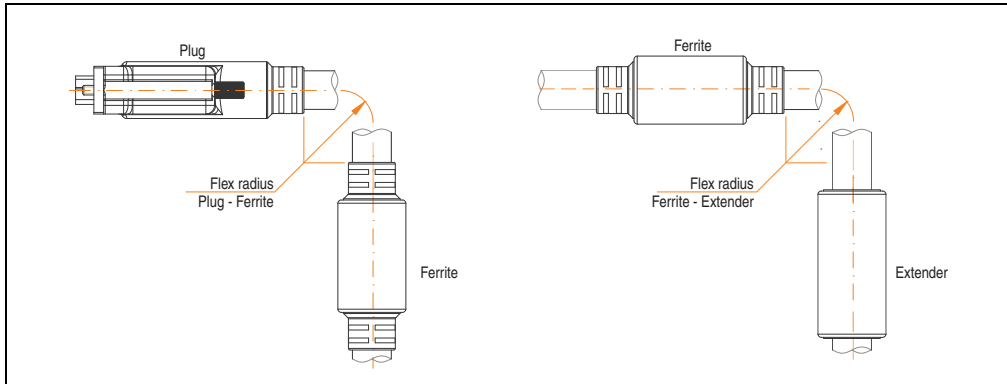


Figure 168: Flex radius specification

13.5.4 Dimensions

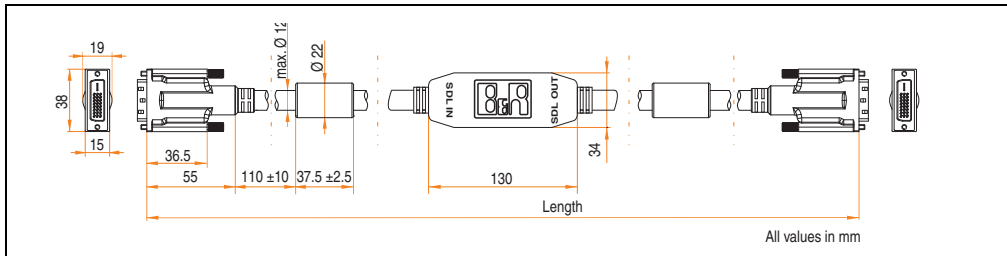


Figure 169: Dimensions - SDL flex cable with extender 5CASDL.0x00-13

13.5.5 Cable connection

The SDL flex cable with extender must be connected correctly between the Industrial PC and Automation Panel 900 display unit. The signal direction is indicated on the extender unit for this purpose:

- Connect the end labeled "SDL IN" with the video output of the Automation PC 620 or Panel PC 800 (monitor/panel output) or Panel OUT of an AP900 AP Link card.
- The "SDL OUT" end should be connected to the display unit (e.g. Automation Panel 900) via the Automation Panel Link insert card (Panel IN).

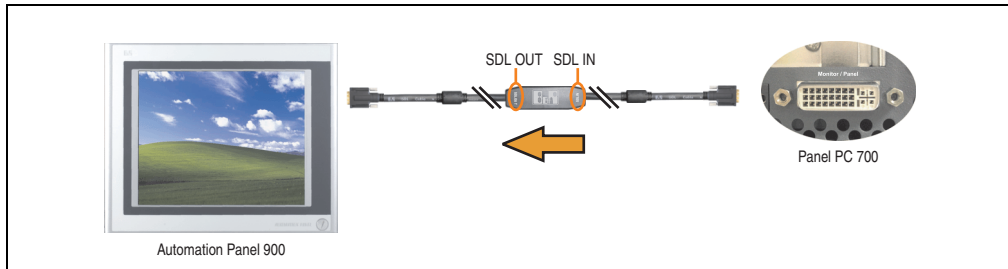


Figure 170: Example of signal direction for the SDL flex cable with extender - PPC800

13.5.6 Cable specifications

The following figure shows the pin assignments for the SDL flex cable with extender available at B&R.

Information:

Only B&R SDL flex cables with extender can be used.

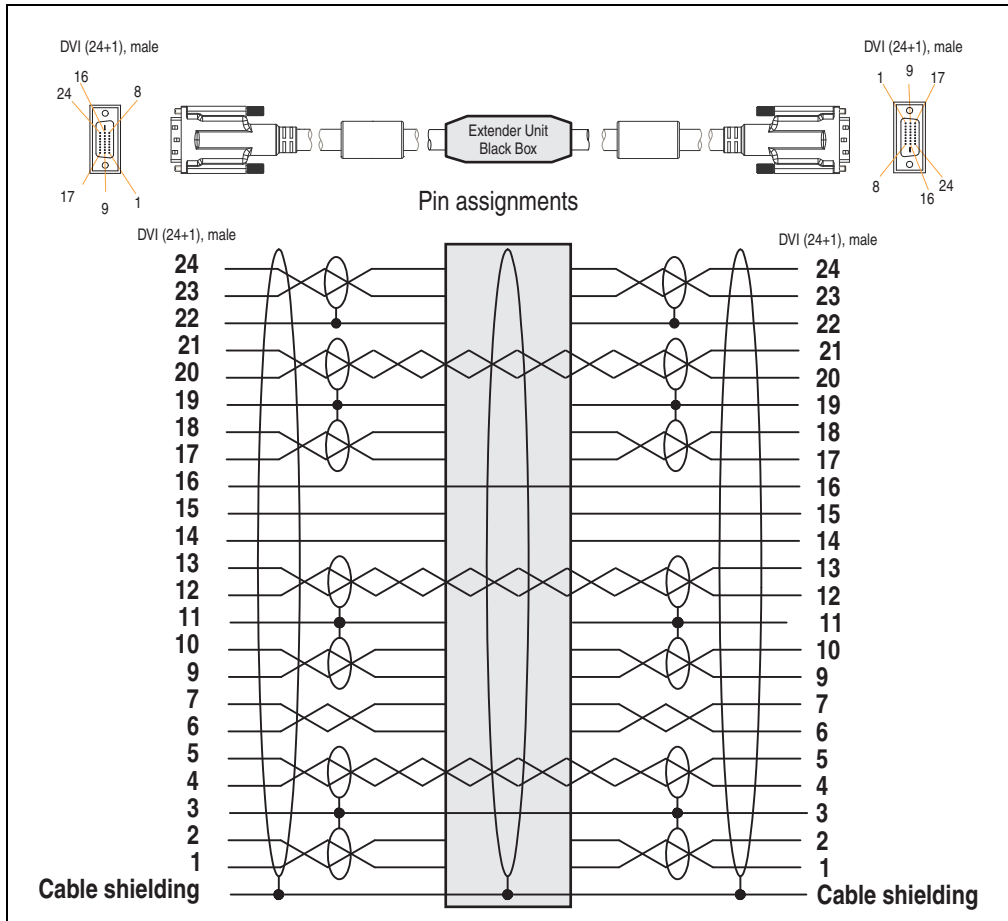


Figure 171: Pin assignments - SDL flex cable with extender 5CASDL.0x00-13

13.6 RS232 cable

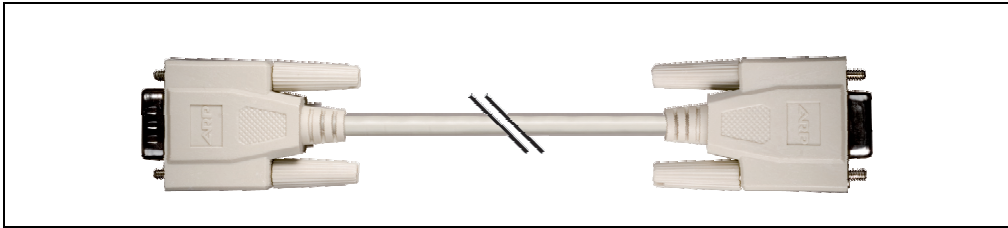


Figure 172: RS232 extension cable (similar)

13.6.1 Order data

Model number	Description	Note
9A0014.02	RS232 cable DB9/f:DB9/m 1.8 m RS232 extension cable for remote operation of a display unit with touch screen, length 1.8 m.	
9A0014.05	RS232 cable DB9/f:DB9/m 5 m RS232 extension cable for remote operation of a display unit with touch screen, length 5 m.	
9A0014.10	RS232 cable DB9/f:DB9/m 10 m RS232 extension cable for remote operation of a display unit with touch screen, length 10 m.	

Table 222: Model numbers - RS232 cables

13.6.2 Technical data

Features	9A0014.02	9A0014.05	9A0014.10
Length Tolerance	1.8 m ±50 mm	5 m ±80 mm	10 m ±100 mm
Outer diameter	Max. 5 mm		
Shielding	Entire cable		
Connector type	DSUB (9-pin), male / female		
Wire cross section	AWG 26		
Flexibility	Flexible		
Flex radius	Min. 70 mm		

Table 223: Technical data - RS232 cables

13.6.3 Cable specifications

The following figure shows the pin assignments for the RS232 cable available at B&R. If you want to build a suitable cable yourself, it should be wired according to these specifications.

Warning!

If a self-built cable is used, B&R cannot guarantee that it will function properly. The RS232 cables provided by B&R are guaranteed to function properly.

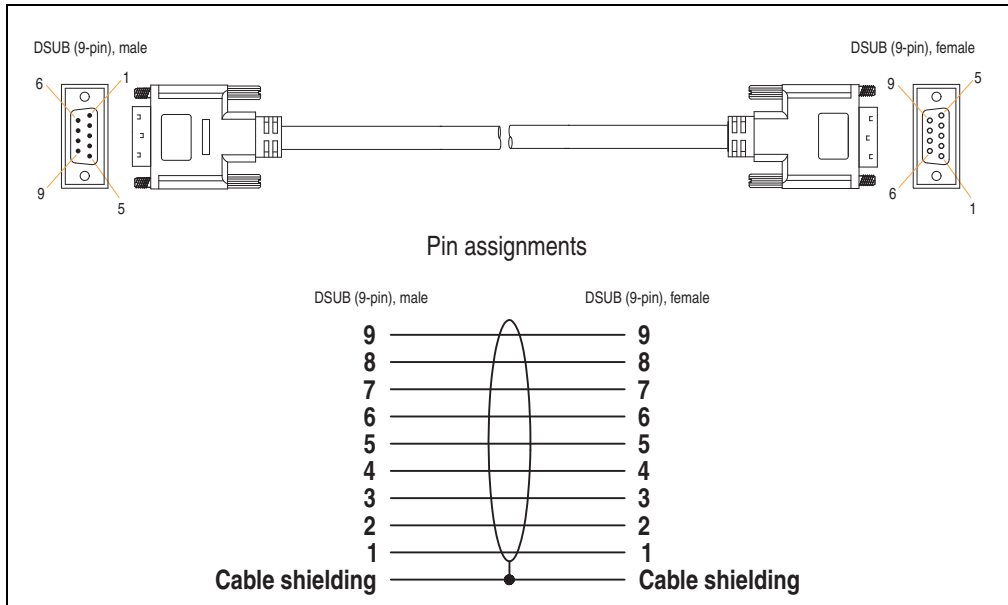


Figure 173: Pin assignments - RS232 cable

13.7 USB cable

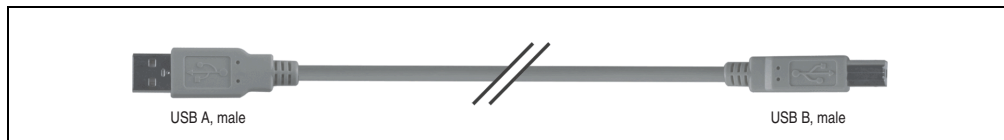


Figure 174: USB extension cable (similar)

13.7.1 Order data

Model number	Description	Note
5CAUSB.0018-00	USB 2.0 cable, A/m:B/m 1.8 m USB 2.0 connection cable; plug type A - type B; length 1.8 m	
5CAUSB.0050-00	USB 2.0 cable, A/m:B/m 5 m USB 2.0 connection cable; plug type A - type B; length 5 m	

Table 224: Model numbers - USB cables

13.7.2 Technical data

Features	5CAUSB.0018-00	5CAUSB.0050-00
Length Tolerance	1.8 m ±30 mm	5 m ±50 mm
Outer diameter	Max. 5 mm	
Shielding	Entire cable	
Connector type	USB type A male and USB type B male	
Wire cross section	AWG 24, 28	
Flexibility	Flexible	
Flex radius	Min. 100 mm	

Table 225: Technical data - USB cables

13.7.3 Cable specifications

The following figure shows the pin assignments for the USB cable available at B&R. If you want to build a suitable cable yourself, it should be wired according to these specifications.

Warning!

If a self-built cable is used, B&R cannot guarantee that it will function properly. The USB cables provided by B&R are guaranteed to function properly.

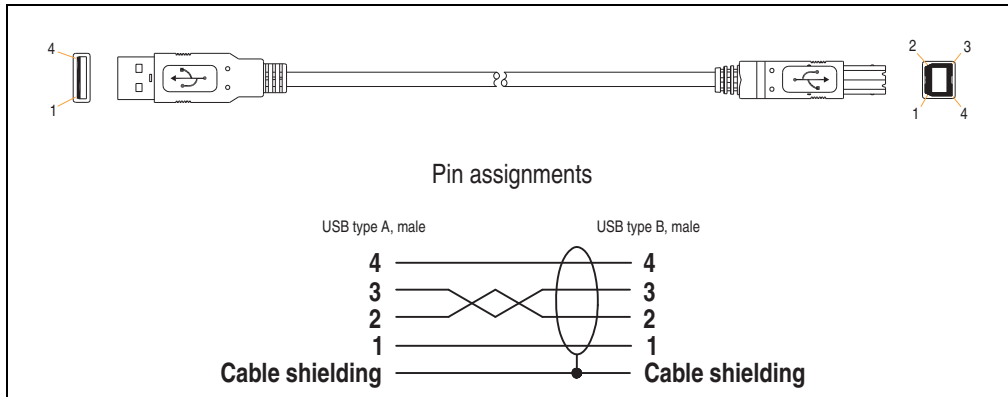


Figure 175: Pin assignments - USB cable

Chapter 7 • Maintenance / Servicing

The following chapter describes service/maintenance work which can be carried out by a trained, qualified user.

1. Changing the battery

Information:

- The product design allows the battery to be changed with the PPC800 switched either on or off. In some countries, safety regulations do not allow batteries to be changed while the module is switched on.
- Any BIOS settings that have been made will remain when the battery is changed with the power turned off (stored in non-volatile EEPROM). The date and time must be reset later because this data is lost when the battery is changed.
- The battery should only be changed by qualified personnel.

Warning!

Replace battery with Renata, type CR2477N only. Use of another battery may present a risk of fire or explosion.

Battery may explode if mistreated. Do not recharge, disassemble or dispose of in fire.

1.1 Battery test

The battery status (good or bad) is checked every time the device is turned on, as well as every 24 hours. The check involves applying a load to the battery for a short time (approx. 1 second), followed by an evaluation. The evaluated battery status is displayed in the BIOS Setup pages and in the B&R Control Center (ADI driver), but can also be read in a customer application via the ADI Library.

Battery status	Meaning
OK	Data buffering is guaranteed
Bad	Data buffering is guaranteed for approx. another 500 hours from the point in time that the battery capacity is determined to be BAD (insufficient).

Table 226: Meaning of battery status OK - Bad

From the point when battery capacity is recognized as insufficient, data buffering is guaranteed for approximately another 500 hours. When changing the battery, data is buffered for approximately another 10 minutes by a gold leaf capacitor.

The following replacement lithium batteries are available: 4A0006.00-000 (1 pc.) and 0AC201.91 (4 pcs.).

1.2 Procedure

- Disconnect the power supply to the Panel PC 800.
- Touch the housing or ground connection (not the power supply!) in order to discharge any electrostatic charge from your body.
- Remove the black plastic cover from the battery compartment and carefully pull out the battery using removal strips.
- The battery should not be held by its edges. Insulated tweezers may also be used for inserting the battery.

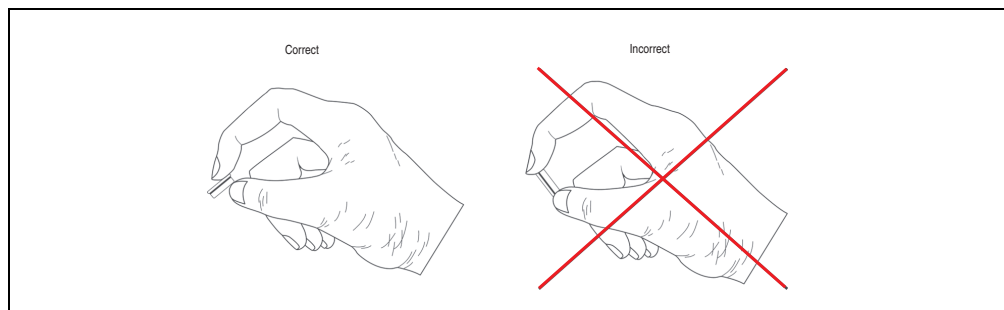


Figure 176: Battery handling

- Insert the new battery with correct polarity.
- To make the next battery change easier, be sure the removal strip is in place when inserting battery.
- Reconnect power supply to Panel PC 800 (plug in power cable and press power button).
- Date and time might need to be reset in BIOS.

Warning!

Lithium batteries are considered hazardous waste. Used batteries should be disposed of according to local requirements.

Appendix A

1. Temperature sensor locations

Sensors monitor temperature values in many different areas in the PPC800. The temperatures¹⁾ can be read in BIOS (menu item "Advanced" - Baseboard/panel features - Baseboard monitor) or in Microsoft Windows XP/Embedded or Windows Embedded Standard 2009, using the B&R Control Center²⁾.

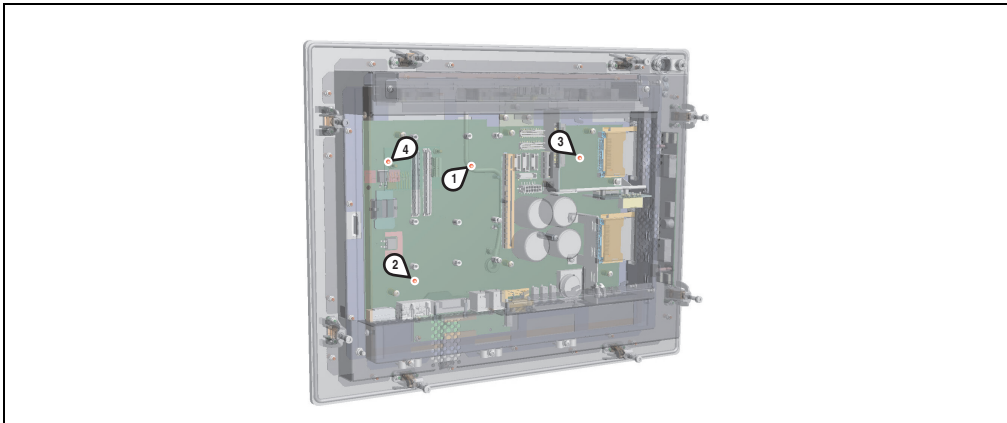


Figure 177: Temperature sensor locations

Position	Measurement point for	Measurement	Max. specified
1	Board I/O	Board I/O area temperature (sensor on the baseboard).	80°C
2	Board ETH2	Baseboard temperature near the ETH2 controller (sensor on the baseboard).	80°C
3	Board Power	Board power supply temperature (sensor on the baseboard).	80°C
4	Power supply	Power supply temperature.	80°C
-	Slide-in drive 1	Temperature of a slide-in drive (the sensor is integrated on the slide-in drive).	Depending on the slide-in drive being used
-	IF slot	Temperature of the PCIe slot; the sensor is located directly on the plug-in card.	Depending on the plug-in cards used

Table 227: Temperature sensor locations

1) The measured temperature is a guideline for the immediate ambient temperature, but can be influenced by neighboring components.

2) The B&R Control Center - ADI driver - can be downloaded for free from the download area on the B&R homepage (www.br-automation.com).

2. Maintenance Controller Extended (MTCX)

The MTCX controller (FPGA processor) is located on the main board (part of every system unit).

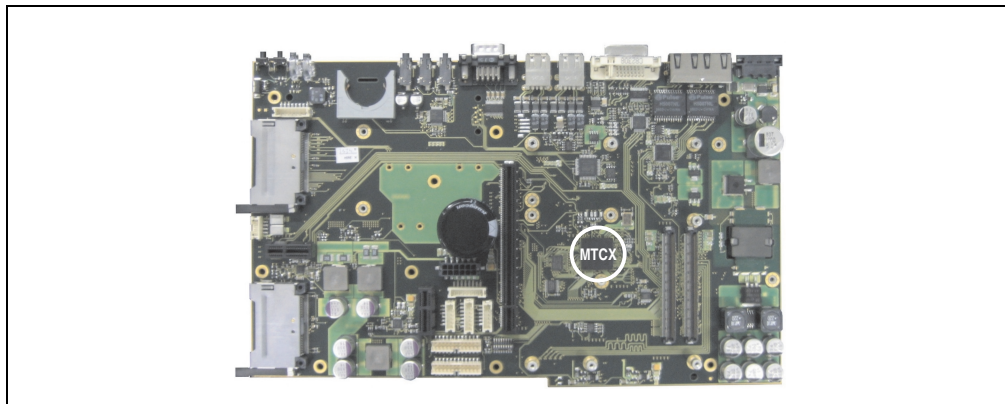


Figure 178: MTCX controller location

The MTCX is responsible for the following monitoring and control functions:

- Power on (power OK sequencing) and power fail logic
- Watchdog handling (NMI and reset handling)
- Temperature monitoring
- Fan control
- Key handling / coordination (matrix keyboard on Automation Panel 900 devices configurable using B&R Key Editor, PS/2 keyboard)
- LED handling (matrix keyboard with LEDs on Automation Panel 900 devices configurable using B&R Key Editor)
- Advanced desktop operation (USB forwarding)
- Daisy chain display operation (touch screen, USB forwarding)
- Panel locking mechanism (configurable using B&R Control Center - ADI driver)
- Backlight control for a connected B&R display
- Statistical data recording (power cycles - each power on, power on and fan hours are recorded - every full hour is counted e.g. 50 minutes no increase)
- SDL data transfer (display, matrix keyboard, touch screen, service data, USB)
- Status LEDs (HDD, Link, Run)

The functions of the MTCX can be expanded via Firmware upgrade¹⁾. The version can be read in BIOS (menu item "advanced" - baseboard/panel features) or in Microsoft Windows XP/embedded, using B&R Control Center.

¹⁾ Can be downloaded from the download area on the B&R homepage (www.br-automation.com).

2.1 Temperature monitoring - Fan control

The MTCX constantly monitors the temperature using temperature sensors (see section 2.1 "Temperature monitoring - Fan control", on page 355), which directly determine how the fan is controlled. The RPM depends on the temperature measured. The limit values depend on the MTCX firmware version being used.

Sensor range	Start-up temperature	Max fan speed at:
Board I/O	+ 60°C	+ 76°C
Board ETH2	+ 60°C	+ 76°C
Board Power	+ 60°C	+ 76°C
Power supply	+ 60°C	+ 76°C
Slide-in drive 1	+ 44°C	+ 60°C
IF slot	+ 65°C	+ 81°C

Table 228: Temperature limits of the fan (MTCX PX32 V1.01).

Once the start-up temperature is reached, the device is started at the minimum fan speed. The maximum fan speed is reached at a start-up temperature of 16°C. The fan speed in this area is controlled depending on the temperature.

For example, slide-in 1: $44^{\circ}\text{C} + 16^{\circ}\text{C} = 60^{\circ}\text{C}$ --> maximum fan speed

The fans are first switched off again if the evaluated temperature remains 6°C lower than the start-up temperature for a time span of 30 minutes (=lag-time).

3. B&R Key Editor

On display units, it is often necessary to adjust the function keys and LEDs for the application software being used. The B&R Key Editor makes it quick and easy to adapt the application to a unique configuration.

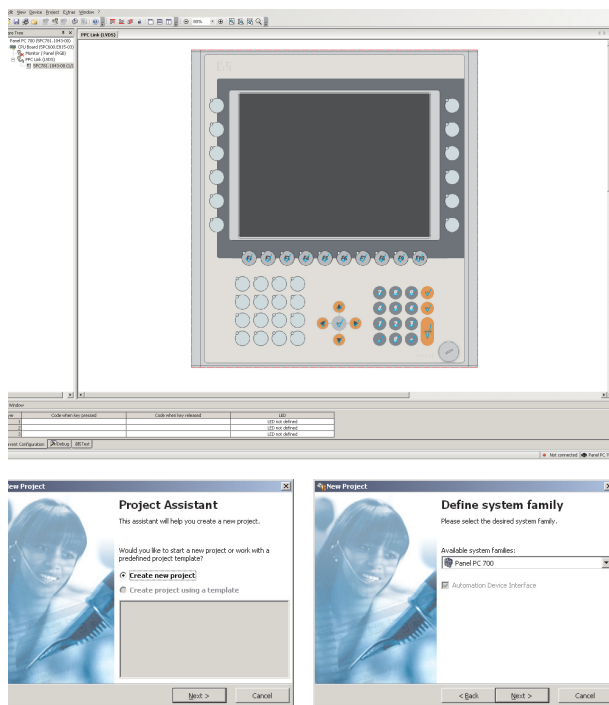


Figure 179: B&R Key Editor screenshots (Version 3.00)

Features:

- Configuration of normal keys like on a keyboard (A, B, C, etc.)
- Keyboard shortcuts (CTRL+C, SHIFT+DEL, etc.) on one key
- Special key functions (change brightness, etc.)
- Assign functions to LEDs (HDD access, power, etc.)
- 4 assignments per key possible (using layer function)
- Configuration of panel locking time when multiple Automation Panel 900 devices are connected to Automation PC 620, Panel PC 700 and Panel PC 800 devices

Supports following systems (Version 3.00):

- Automation PC 620 (ETX, XTX, Embedded)
- Automation PC 800
- Automation PC 820
- Panel PC 300
- Panel PC 700 (ETX, XTX)
- Panel PC 800
- Power Panel 65
- Power Panel 100.200
- Power Panel 300/400
- Mobile Panel 100, 200
- Mobile Panel 40/50
- IPC2000, IPC2001, IPC2002
- IPC5000, IPC5600
- IPC5000C, IPC5600C

A detailed guide for configuring keys and LEDs can be found in the B&R Key Editor's online help.

The B&R Key Editor can be downloaded for free from the download area on the B&R homepage (www.br-automation.com). Additionally, it can also be found on the B&R HMI Drivers & Utilities DVD (model number 5SWHMI.0000-00).

4. B&R Automation Device Interface (ADI) development kit

The ADI development kit is used to access the functions of the ADI driver. The programming languages C (with import libraries for Microsoft Visual C++ 6.0 and Microsoft eMbedded Visual C++ 4.0) and Visual Basic (for Microsoft Visual Basic 6.0) are supported.

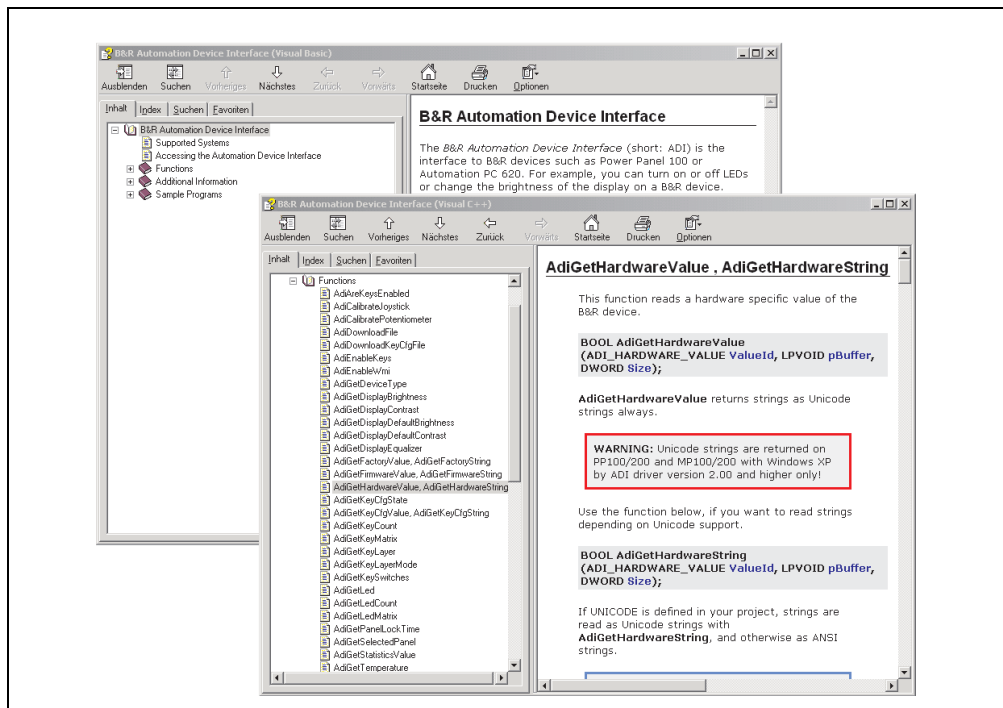


Figure 180: ADI development kit screenshots (Version 2.40)

Features:

- Extensive library of API functions
- Supported programming languages: Visual Basic, Visual C++
- Online documentation (German, English)
- Installation using its own setup

Supports following systems:

- Automation PC 620
- Automation PC 810
- Automation PC 820
- Panel PC 300

- Panel PC 700
- Panel PC 800
- Power Panel 100/200
- Power Panel 300/400
- Mobile Panel 40/50
- Mobile Panel 100/200

A detailed description of using the ADI functions can be found in the integrated online help.

The B&R Automation Device Interface (ADI) development kit can be downloaded for free from the download area on the B&R homepage (www.br-automation.com).

4.1 Installation

The latest version of the B&R Automation Device Interface (ADI) Development Kit can be found in the download area (Service - Material Related Downloads - BIOS / Drivers / Updates) on the B&R homepage (www.br-automation.com).

Run Setup.exe to install (e.g. by double-clicking in Explorer).

5. Membrane

The décor foil conforms to DIN 42115 (section 2). This means it is resistant to exposure to the following chemicals for a 24-hour period with no visible signs of damage:

Information:

The following characteristics, features, and limit values only apply to this individual component and can deviate from those specified for the entire device.

Ethanol Cyclohexanol Diacetone alcohol Glycol Isopropanol Glycerine Methanol Triacetin Dowandol DRM/PM	Formaldehyde 37 - 42% Acetaldehyde Aliphatic hydrocarbons Toluene Xylene White spirits	Trichloroethane Ethyl acetate Diethyl ether N-Butyl acetate Amyl acetate Butylcellosolve Ether
Acetone Methyl ethyl ketone Dioxan Cyclohexanone MIBK Isophorone	Formic acid <50% Acetic acid <50% Phosphoric acid <30% Hydrochloric acid <36% Nitric acid <10% Trichloroacetic acid <50% Sulphuric acid <10%	Sodium hypochlorite <20% Hydrogen peroxide <25% Potassium carbonate Washing agents Fabric conditioner Ferric chloride Ferrous chloride (FeCl ₂) Ferrous chloride (FeCl ₃) Dibutyl phthalate Diocetyl phthalate Sodium carbonate
Ammonia <40% Caustic soda <40% Potassium hydroxide Alkali carbonate Bichromate Potassium Acetonitrile Sodium bisulphate	Cutting oil Diesel oil Linseed oil Paraffin oil Blown castor oil Silicon oil Turpentine oil substitute Universal brake fluid Aviation fuel Gasoline Water Sea water Decon	

Table 229: Chemical resistance of the décor foil

The décor foil conforms to DIN 42115 section 2 for exposure to glacial acetic acid for less than one hour without visible damage.

6. Viewing angles

The viewing angle information of the display types (R, L, U, D) can be seen in the technical data for the individual components.

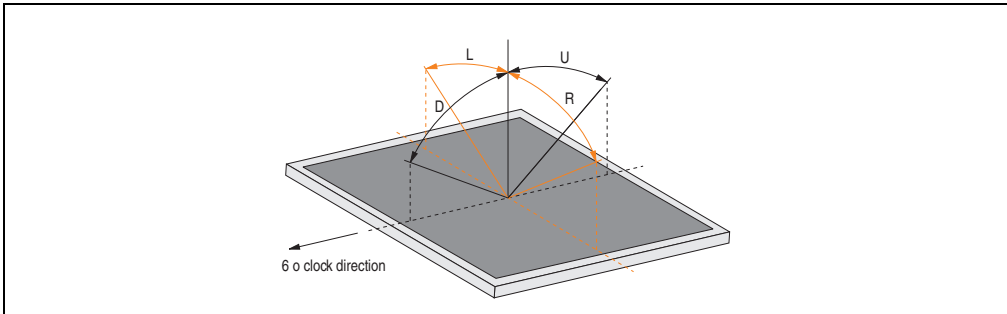


Figure 181: Viewing angle definition

7. Glossary

A

ACPI

Abbreviation for "**A**dvanced **C**onfiguration and **P**ower **I**nterface". Configuration interface that enables the operating system to control the power supply for each device connected to the PC. With ACPI, the computer's BIOS is only responsible for the details of communication with the hardware.

ADI

Abbreviation for "Automation Device Interface" The ADI interface allows access to specific functions (e.g. brightness control, firmware updates, static value read) of B&R devices. The settings can be read or changed in the Control Panel with the B&R Control Center Applet (already included in the B&R embedded operating system).

APC

An abbreviation for "**A**utomation **P**C".

API

Abbreviation for "**A**pplication **P**rogram **I**nterface" The interface, which allows applications to communicate with other applications or with the operating system.

Automation Runtime

A uniform runtime system for all B&R automation components.

B

Baud rate

Measurement unit for data transfer speed. It indicates the number of states for a transferred signal per second and is measured using the baud unit of measurement. 1 baud = 1 bit/sec or 1 bps.

BIOS

An abbreviation for "**B**asic **I**nterface/**O**utput **S**ystem". Core software for computer systems with essential routines for controlling input and output processes on hardware components, for performing tests after system start and for loading the operating system. Although BIOS is used to configure a system's performance, the user does not usually come into contact with it.

Bit

Binary digit > binary position, binary character, smallest discrete unit of information. A bit can have the value 0 or 1.

Bit rate

The number of bits that can be transferred within a specified time unit. 1 bit/sec = 1 baud.

Bootstrap loader

A program that automatically runs when the computer is switched on or restarted. After some basic hardware tests have been carried out, the bootstrap loader starts a larger loader and hands over control to it, which in turn boots the operating system. The bootstrap loader is typically found in ROM on the computer.

Byte

Data format [1 byte = 8 bits] and a unit for characterizing information amounts and memory capacity. The following units are the commonly used units of progression: KB, MB, GB.

B&R Automation Runtime

Windows-based program for creating installation disks to install B&R Automation Runtime™ on the target system.

C**Cache**

Background memory, also known as non-addressable memory or fast buffer memory. It is used to relieve the fast main memory of a computer. For example, data that should be output to slower components by the working memory (e.g. disk storage, printers) is stored temporarily in cache memory and output from there at an appropriate speed for the target devices.

CAN

An abbreviation for "**C**ontroller **A**rea **N**etwork" (serial bus system). Structure according to ISO 11898; Bus medium: twisted pair. Good transfer properties in short distances less than 40 m with a 1 MBit/sec data transfer rate. Maximum number of stations: Theoretically unlimited, but practically limited up to 64. Real-time capable (i.e. defined maximum latency times for messages with high priority). High reliability using error detection, error handling, troubleshooting. Hamming distance.

CD-ROM

Abbreviation for "**C**ompact **D**isc **R**ead-**O**nly **M**emory". A removable data medium with a capacity of ~700 MB. CD-ROMs are optically scanned.

CE mark

A CE mark for a product. It consists of the letters "CE" and indicates conformity to all EU guidelines for the labeled product. It indicates that the individual or corporate body who has performed or attached the label assures that the product conforms to all EU guidelines for complete harmonization. It also indicates that all mandatory conformity evaluation procedures have taken place.

CMOS

"CMOS" is a battery powered memory area where fundamental parameters of an IBM (or compatible) personal computer are stored. Information such as the type of hard drive, size of the working memory and the current date and time are required when booting the computer. As the name suggests, the memory is based on CMOS technology standards.

COM

A device name used to access serial ports in MS-DOS. The first serial port can be accessed under COM1, the second under COM2, etc. A modem, mouse, or serial printer is typically connected to a serial port.

COM1

Device name for the first serial port in a PC system. The input/output area for COM1 is usually found at address 03F8H. Generally, the COM1 port is assigned to IRQ 4. In many systems, an RS232 serial mouse is connected to COM1.

COM2

Device name for the second serial port in a PC system. The input/output area for COM2 is usually found at address 02F8H. Generally, the COM2 port is assigned to IRQ 3. In many systems, a modem is connected to COM2.

COM3

Device name for a serial port in a PC system. The input/output area for COM3 is usually found at address 03E8H. Generally, the COM3 port is assigned to IRQ 4. In many systems, COM3 is used as an alternative for COM1 or COM2 if peripheral devices are already connected to COM1 and COM2.

CompactFlash®

CompactFlash memory cards [CF cards] are exchangeable nonvolatile mass memory systems with very small dimensions [43 x 36 x 3.3 mm, approximately half the size of a credit card]. In addition to the flash memory chips, the controller is also present on the cards. CF cards provide complete PC card / ATA functionality and compatibility. A 50-pin CF card can be simply inserted in a passive 68-pin type II adapter card. It conforms to all electrical and mechanical PC card interface specifications. CF cards were launched by SanDisk back in 1994. Currently, memory capacities reach up to 64 GB per unit. Since 1995, CompactFlash Association [CFA] has been looking after standardization and the worldwide distribution of CF technology

CPU

An abbreviation for "**C**entral **P**rocessing **U**nit". Interprets and executes commands. It is also known as a "microprocessor" or "processor" for short. A processor is able to receive, decode and execute commands, as well as transfer information to and from other resources via the computer bus.

CTS

An abbreviation for "**C**lear **T**o **S**end". A signal used when transferring serial data from modem to computer, indicating its readiness to send the data. CTS is a hardware signal which is transferred via line number 5 in compliance with the RS-232-C standard.

D**DCD**

An abbreviation for "**D**ata **C**arrier **D**etected". A signal used in serial communication that is sent by the modem to the computer it is connected to, indicating that it is ready for transfer.

Dial-up

Data is transferred over the telephone network using a modem or an ISDN adapter.

DIMM

"Double In-line Memory Module" consisting of one or more RAM chips on a small circuit board that is connected with the motherboard of a computer.

DMA

Direct **M**emory **A**ccess > Accelerated direct access to a computer's RAM by bypassing the CPU.

DRAM

An abbreviation for "**D**ynamic **R**andom **A**ccess **M**emory". Dynamic RAM consists of an integrated semiconductor circuit that stores information based on the capacitor principle. Capacitors lose their charge in a relatively short time. Therefore, dynamic RAM circuit boards must contain a logic that allows continual recharging of RAM chips. Since the processor cannot access dynamic RAM while it is being recharged, one or more waiting states can occur when reading or writing data. Although it is slower, dynamic RAM is used more often than static RAM since the simple design of the circuits means that it can store four times more data than static RAM.

DSR

An abbreviation for "**Data Set Ready**". A signal used in serial data transfer, which is sent by the modem to the computer it is connected to, indicating its readiness for processing. DSR is a hardware signal which is sent via line number 6 in compliance with the RS-232-C standard.

DTR

An abbreviation for "**Data Terminal Ready**". A signal used in serial data transfer that is sent by the computer to the modem it is connected to, indicating the computer's readiness to accept incoming signals.

DVD

An abbreviation for "**Digital Versatile Disc**". The next generation of optical data carrier technology. Using this technology it is possible to encode video, audio and computer data on CD. DVDs can store a higher volume of data than conventional CDs. Standard DVDs, which have a single layer, can hold 4.7 GB. Dual-layer DVDs can hold 8.5 GB. Double-sided DVDs can therefore hold up to 17 GB. A special drive is needed for DVDs. Conventional CDs can also be played on DVD drives.

DVI

Abbreviation for "**Digital Visual Interface**". An interface for the digital transfer of video data.

DVI-A

Analog only

DVI-D

Digital only

DVI-I

Integrated, i.e. analog and digital

E

EDID data

Abbreviation for "**Extended Display Identification Data**". EDID data contains the characteristics of monitors / TFT displays transferred as 128 KB data blocks to the graphics card via the Display Data Channel (DDC). This EDID data can be used to set the graphics card to the monitor properties.

EIDE

An abbreviation for "**Enhanced Integrated Drive Electronics**". An expansion of the IDE standard. Enhanced IDE is considered the standard for hardware interfaces. This interface is designed for drives with an integrated drive controller.

EMC

"Electromagnetic Compatibility" The ability of a device or a system to function satisfactorily in its electromagnetic environment without introducing intolerable electromagnetic disturbances to anything in that environment [IEV 161-01-07].

EPROM

Erasable PROM > (completely with ultraviolet light).

Ethernet

An IEEE 802.3 standard for networks. Ethernet uses bus or star topology and controls the traffic on communication lines using the access procedure CSMA/CD (Carrier Sense Multiple Access with Collision Detection). Network nodes are connected using coaxial cables, fiber optic cables or twisted pair cabling. Data transfer on an Ethernet network takes place in frames of variable lengths that consist of supply and controller information as well as 1500 bytes of data. The Ethernet standard provides base band transfers at 10 megabit and 100 megabit per second.

Ethernet POWERLINK

An enhancement of standard Ethernet. It enables data exchange under strict real-time conditions with cycle times down to 200 µs and jitter under 1 µs. This makes Ethernet power available on all communication levels of automation technology – from control levels to I/O. Ethernet POWERLINK was initiated by the company B&R Industrie-Elektronik and is now managed by the open end user and vendor association, EPSG - Ethernet POWERLINK Standardization Group (www.ethernet-powerlink.org).

F

FDD

Abbreviation for **"Floppy Disk Drive"**. Reading device for removable magnetic memory from the early days of PC technology. Due to their sensitivity and moving components, FDDs have been almost completely replaced by CompactFlash memory in modern automation solutions.

Fiber optics

Fiber optic cable

FIFO

An abbreviation for **"First In First Out"**. A queuing organization method whereby elements are removed in the same order as they were inserted. The first element inserted is the first one removed. Such an organization method is typical for a list of documents that are waiting to be printed.

Firmware

Programs stored permanently in read-only memory. Firmware is software used to operate computer-controlled devices that generally stays in the device throughout its lifespan or over a long period of time. Such software includes operating systems for CPUs and application

programs for industrial PCs as well as programmable logic controllers (e.g. the software in a washing machine controller). This software is written in read-only memory (ROM, PROM, EPROM) and cannot be easily replaced.

Floppy

Also known as a diskette. A round plastic disk with an iron oxide coating that can store a magnetic field. When the floppy disk is inserted in a disk drive, it rotates so that the different areas (or sectors) of the disk's surface are moved under the read/write head. This allows the magnetic orientation of the particle to be modified and recorded. Orientation in one direction represents binary 1, while the reverse orientation represents binary 0.

FPC

An abbreviation for "**F**lat **P**anel **C**ontroller".

FPD

An abbreviation for "**F**lat **P**anel **D**isplay".

FTP

"**F**ile **T**ransfer **P**rotocol" Rules for transferring data over a network from one computer to another computer. This protocol is based on TCP/IP, which has established itself as the standard for transferring data over Ethernet networks. FTP is one of the most used protocols on the Internet. It is defined in RFC 959 in the official regulations for Internet communication.

G

GB

Gigabyte (1 GB = 230 or 1,073,741,824 Bytes)

H

Handshake

Method of synchronization for data transfer when data is sent at irregular intervals. The sender signals that data can be sent, and the receiver signals when new data can be received.

HDD

An abbreviation for "**H**ard **D**isk **D**rive". Fixed magnetic mass memory with high capacities, e.g. 120 GB.

I

IDE

An abbreviation for "**I**ntegrated **D**rive **E**lectronics". A drive interface where the controller electronics are integrated in the drive.

Interface

From the hardware point of view, an interface is the connection point between two modules/devices/systems. The units on both sides of the interface are connected by the interface lines so that data, addresses, and control signals can be exchanged. The term interface includes all functional, electrical and constructive conditions [encoding, signal level, pin assignments] that characterize the connection point between the modules, devices, or systems. Depending on the type of data transfer, a differentiation is made between parallel [e.g. Centronics, IEEE 488] and serial interfaces [e.g. V.24, TTY, RS232, RS422, RS485], which are set up for different transfer speeds and transfer distances. From the point of view of software, the term "interface" describes the transfer point between program modules using specified rules for transferring the program data.

ISA

An abbreviation for "**I**ndustry **S**tandard **A**rchitecture". A term given for the bus design which allows expansion of the system with plug-in cards that can be inserted in PC expansion slots.

ISO

International Organization for Standardization > Worldwide federation of national standardization institutions from over 130 countries. ISO is not an acronym for the name of the organization; it is derived from the Greek word "isos", meaning "equal" (www.iso.ch).

J

Jitter

Jitter is a term that describes time deviations of cyclic events. If, for example, an event should take place every 200µs and it actually occurs every 198 to 203µs, then the jitter is 5µs. Jitter has many causes. It originates in the components and transfer media of networks because of noise, crosstalk, electromagnetic interference and many other random occurrences. In automation technology, jitter is a measure of the quality of synchronization and timing.

Jumper

A small plug or wire link for adapting the hardware configuration used to connect the different points of an electronic circuit.

L

LCD

An abbreviation for "**L**iquid **C**rystal **D**isplay". A display type, based on liquid crystals that have a polarized molecular structure and are enclosed between two transparent electrodes as a thin layer. If an electrical field is applied to the electrodes, the molecules align themselves with the field and form crystalline arrangements that polarize the light passing through. A polarization filter, which is arranged using lamellar electrodes, blocks the polarized light. In this way, a cell

(pixel) containing liquid crystals can be switched on using electrode gates, thus coloring this pixel black. Some LCD displays have an electroluminescent plate behind the LCD screen for lighting. Other types of LCD displays can use color.

LED

An abbreviation for "**L**ight **E**mitting **D**iode". A semiconductor diode which converts electrical energy into light. LEDs work on the principle of electroluminescence. They are highly efficient because they do not produce much heat in spite of the amount of light they emit. For example, "operational status indicators" on floppy disk drives are LEDs.

LPT

Logical device name for line printers. In MS-DOS, names are reserved for up to three parallel printer ports with the names LPT1, LPT2 and LPT3. The first parallel port (LPT1) is usually identical to the primary parallel output device PRN (in MS-DOS the logical device name for the printer). The abbreviation LPT stands for "Line Printer Terminal".

M

MB

Megabyte (1 MB = 220 or 1,048,576 bytes).

Microprocessor

Highly integrated circuit with the functionality of a CPU, normally housed on a single chip. It comprises a control unit, arithmetic and logic unit, several registers and a link system for connecting memory and peripheral components. The main performance features are the internal and external data bus and address bus widths, the command set and the clock frequency. Additionally, a choice can be made between CISC and RISC processors. The first commercially available worldwide microprocessor was the Intel 4004. It came on the market in 1971.

MIPS

Million instructions per second > Measurement for the computing speed of computers.

Motherboard

A circuit board that houses the main components of a computer such as the CPU switching circuit, co-processors, RAM, ROM for firmware, interface circuits, and expansion slots for hardware expansions.

MTBF

An abbreviation for "**M**ean **t**ime **b**etween **f**ailure". The average time which passes before a hardware component fails and repair is needed. This time is usually expressed in thousands or ten thousands of hours, sometimes known as power-on hours (POH).

MTC

An abbreviation for "**M**aintenance **C**ontroller". The MTC is an independent processor system that provides additional functions for a B&R industrial PC that are not available with a normal PC. The MTC communicates with the B&R industrial PC via the ISA bus (using a couple register).

MTCX

An abbreviation for "**M**aintenance **C**ontroller **EX**tended". The MTCX is an independent processor system that provides additional functions for a B&R industrial PC that are not available with a normal PC. The MTC communicates with the B&R industrial PC via the ISA bus (using a couple register).

Multitasking

Multitasking is an operating mode in an operating system that allows several computer tasks to be executed virtually simultaneously.

O

OEM

Abbreviation for "**O**riginal **E**quipment **M**anufacturer"; A company that integrates third-party and in-house manufactured components into their own product range and then distributes these products under its own name.

OPC

OLE for Process Control > A communication standard for components in the area of automation. The goal of OPC development is to provide an open interface that builds on Windows-based technologies such as OLE, COM and DCOM. It allows problem-free standardized data transfer between controllers, operating and monitoring systems, field devices and office applications from different manufacturers. This development is promoted by the OPC Foundation, which is made up of over 200 companies from around the world, including Microsoft and other leading companies. Nowadays, OPC is also interpreted as a synonym for Openness, Productivity and Connectivity, symbolizing the new possibilities that this standard opens up.

OPC server

The missing link between connection modules for the Interbus and the visualization application. It communicates serially with the connection modules via the ISA or PCI bus or Ethernet.

P

Panel

A common term for B&R display units (with or without keys).

PCI Bus

Abbreviation for "**P**eripheral **C**omponent **I**nterconnect bus". Developed by Intel as an intermediary/local bus for the latest PC generations. It is basically a synchronous bus. The main clock of the CPU is used for synchronization. The PCI bus is microprocessor-independent, 32-bit and 64-bit compatible, and supports both 3.3 V and 5 V cards and devices.

PCMCIA

An abbreviation for "**P**ersonal **C**omputer **M**emory **C**ard **I**nternational **A**ssociation". An association of manufacturers and dealers who are dedicated to the cultivation and further development of common standards for peripheral devices based on PC cards with a slot for such cards. PC cards are mainly used for laptops, palmtops (and other portable computers), and intelligent electronic devices. Version 1 of the PCMCIA standard was introduced in 1990.

PLC

Programmable Logic Controller; Computer-based control device that functions using an application program. The application program is relatively easy to create using standardized programming languages [IL, FBD, LAD, AS, ST]. Because of its serial functionality, reaction times are slower compared to connection-oriented control. Today, PLCs are available in device families with matched modular components for all levels of an automation hierarchy.

PnP

An abbreviation for "**P**lug and **P**lay". Specifications developed by Intel. Using Plug and Play allows a PC to automatically configure itself so that it can communicate with peripheral devices (e.g. monitors, modems, and printers). Users can connect a peripheral device (plug) and it immediately runs (play) without having to manually configure the system. A Plug and Play PC requires a BIOS that supports Plug and Play and a respective expansion card.

POH

An abbreviation for "**P**ower **O**n **H**ours". See MTBF.

POST

An abbreviation for "**P**ower-**O**n **S**elf **T**est". A set of routines that are stored in ROM on the computer and that test different system components, e.g. RAM, disk drive and the keyboard in order to determine that the connection is operating correctly and ready for operation. POST routines notify the user of problems that occur. This is done using several signal tones or by displaying a message that frequently accompanies a diagnosis value on the standard output or standard error devices (generally the monitor). If the POST runs successfully, control is transferred over to the system's bootstrap loader.

POWERLINK

See "Ethernet POWERLINK".

PROFIBUS-DP

PROFIBUS for "decentralized peripherals". PROFIBUS DP can be used to allow simple digital and analog I/O modules as well as intelligent signal and data processing units to be installed in the machine room, which among other things can significantly reduce cabling costs. Often used for time-critical factory automation applications.

Q

QVGA

Abbreviation for "**Q**uarter **V**ideo **G**raphics **A**rray". Usually a screen resolution of 320 × 240 pixels.

QUXGA

Abbreviation for "**Q**uad **U**ltra **E**xtended **G**raphics **A**rray". Generally a screen resolution of 3200 × 2400 pixels (4:3). Quad implies the 4x greater pixel resolution compared to the UXGA.

QWUXGA

Abbreviation for "**Q**uad **W**UXGA"; Generally a screen resolution of 3840 × 2400 pixels (8:5, 16:10).

R

RAM

An abbreviation for "**R**andom **A**ccess **M**emory". Semiconductor memory which can be read or written to by the microprocessor or other hardware components. Memory locations can be accessed in any order. The various ROM memory types do allow random access, but they cannot be written to. The term RAM refers to a more temporary memory that can be written to as well as read.

Real time

A system is operating in real time or has real-time capability if the input sizes (e.g. signals, data) are received and processed in a defined time period, and the results are made available in real time for a partner system or the system environment. See also "real-time demands" and "real-time system".

ROM

An abbreviation for "**R**ead-**O**nly **M**emory". Semiconductor memory where programs or data were permanently stored during the production process.

RS232

Recommended Standard Number 232. Oldest and most widespread interface standard, also called a V.24 interface. All signals are referenced to ground making this an unbalanced interface. High level: -3 to -30 V, low level: +3 to +30 V; cable lengths up to 15 m, transfer rates up to 20 kbit/s; for point-to-point connections between 2 stations.

RS422

Recommended Standard Number 422. Interface standard, balanced operation, increased immunity to disturbances. High level: 2 to -6 V, low level: +2 to +6 V; four-line connection [inverted/non-inverted], permissible cable length up to 1200 m, transfer rates up to 10 MBit/s, 1 sender can transfer simplex with up to 10 receivers.

RS485

Recommended Standard Number 485. Interface standard upgraded from RS422. High level: 1.5 to -6 V, low level: +1.5 to +6 V; 2-wire connection [half duplex operation] or 4-wire connection [full duplex operation]. Cable lengths up to 1200 m, transfer rates up to 10 Mbit/s. Up to 32 participants can be connected to an RS485 bus [sender/receiver].

RTS

An abbreviation for "**R**esult **T**o **S**end". A signal used in serial data transfer for requesting send permission. For example, it is sent from a computer to the modem connected to it. The RTS signal is assigned to pin 4 according to the hardware specifications of the RS-232-C standard.

RXD

An abbreviation for "**R**ecieve (**R**X) **D**ata". A line for transferring serial data received from one device to another, e.g. from a modem to a computer. For connections complying with the RS-232-C standard, the RXD is connected to pin 3 of the plug.

S

SDRAM

An abbreviation for "**S**ynchronous **D**ynamic **R**andom **A**ccess **M**emory". A construction of dynamic semiconductor components (DRAM) that can operate with higher clock rates than conventional DRAM switching circuits. This is made possible using block access. For each access, the DRAM determines the next memory addresses to be accessed.

SFC

Sequential function chart > Graphic input language for PLCs used to represent sequential control.

Slot PLC

PC insert card that has full PLC functionality. On the PC, it is coupled via a DPR with the process using a fieldbus connection. It is programmed externally or using the host PC.

SoftPLC

Synonym for SoftPLC.

SUXGA

Abbreviation for **Super Ultra Extended Graphics Array**; Generally a screen resolution of 2048 × 1536 pixels (4:3). An alternative name is QXGA (**Quad Extended Graphics Array**), which is 4x the pixel resolution of XGA.

SVGA

Abbreviation for **"Super Video Graphics Array"**; Graphics standard with a resolution of at least 800×600 pixels and at least 256 colors.

Switch

Device, similar to a hub, that takes data packets received in a network and, unlike a hub, does not pass them on to all network nodes, instead only to the respective addressee. Unlike a hub, a switch provides targeted communication within a network that only takes place between sender and receiver. Other network nodes are not involved.

SXGA

Abbreviation for Super Extended Graphics Array. Graphics standard with a screen resolution of 1280 × 1024 pixels (aspect ratio 5:4).

SXGA+

Abbreviation for SXGA Plus; Generally 1400 × 1050 pixels.

System units

Provit system units consist of a mainboard (without processor), slots for RAM modules, VGA controller, serial and parallel interfaces, and connections for the FPD, monitor, PS/2 AT keyboard, PS/2 mouse, USB, Ethernet (for system units with Intel Celeron and Pentium III processors), Panelware keypad modules and external FDD.

T**Task**

Program unit that is assigned a specific priority by the real-time operating system. It contains a complete process and can consist of several modules.

TCP/IP

Transmission Control Protocol/Internet Suit of Protocols. Network protocol that has become the generally accepted standard for data exchange in heterogeneous networks. TCP/IP is used both in local networks for communication between various computer and also for LAN to WAN access.

TFT display

LCD (Liquid Crystal Display) technology where the display consists of a large grid of LCD cells. Each pixel is represented by a cell, whereby electrical fields produced in the cells are supported by thin film transistors (TFT) that result in an active matrix. In its simplest form, there is exactly one thin film transistor per cell. Displays with an active matrix are generally used in laptops and notebooks because they are thin, offer high-quality color displays and can be viewed from all angles.

Touch screen

Screen with touch sensors for selecting options in a displayed menu using the tip of the finger.

TXD

An abbreviation for "Transmit (**TX**) Data". A line for the transfer of serial data sent from one device to another, e.g. from a computer to a modem. For connections complying with the RS-232-C standard, the TXD is connected to pin 2 of the plug.

U

UART

An abbreviation for "**U**niversal **A**synchronous **R**eceiver-**T**ransmitter". A module generally consisting of a single integrated circuit that combines the circuits required for asynchronous serial communication for both sending and receiving. UART represents the most common type of circuit in modems for connecting to a personal computer.

UDMA

An abbreviation for "**U**ltra **D**irect **M**emory **A**ccess". A special IDE data transfer mode that allows high data transfer rates for drives. There have been many variations in recent times.

UDMA33 mode transfers 33 megabytes per second.

UDMA66 mode transfers 66 megabytes per second.

UDMA100 mode transfers 100 megabytes per second.

Both the mainboard and the hard drive must support the specification to implement modifications.

UPS

Abbreviation for "**U**ninterruptible **P**ower **S**upply". See "UPS".

USB

An abbreviation for "**U**niversal **S**erial **B**us" A serial bus with a bandwidth of up to 12 megabits per second (Mbit/s) for connecting a peripheral device to a microcomputer. Up to 127 devices can be connected to the system using a single multipurpose connection, the USB bus (e.g. external CD drives, printers, modems as well as the mouse and keyboard). This is done by connecting the devices in a row. USB allows devices to be changed when the power supply is switched on (hot plugging) and multi-layered data flow.

UPS

An abbreviation for "**U**ninterruptible **P**ower **S**upply". The UPS supplies power to systems that cannot be connected directly to the power mains for safety reasons because a power failure could lead to loss of data. The UPS allows the PC to be shut down securely without losing data if a power failure occurs.

UXGA

Abbreviation for "**U**ltra **E**xtended **G**raphics **A**rray" Generally a screen resolution of 1600 × 1200 pixels (aspect ratio 4:3, 12:9).

V

VGA

An abbreviation for "**V**ideo **G**raphics **A**dapter". A video adapter which can handle all EGA (Enhanced Graphics Adapter) video modes and adds several new modes.

W

Windows CE

Compact 32-bit operating system with multitasking and multithreading that Microsoft developed especially for the OEM market. It can be ported for various processor types and has a high degree of real-time capability. The development environment uses proven, well-established development tools. It is an open and scalable Windows operating system platform for many different devices. Examples of such devices are handheld PCs, digital wireless receivers, intelligent mobile phones, multimedia consoles, etc. In embedded systems, Windows CE is also an excellent choice for automation technology.

WSXGA

Wide SXGA, generally 1600 × 900 pixels (16:9).

WUXGA

Wide UXGA, generally 1920 × 1200 pixels (16:10).

WXGA

Wide XGA, generally 1280 × 768 pixels.

X

XGA

An abbreviation for "**E**Xtended **G**raphics **A**rray". An expanded standard for graphics controllers and monitors that was introduced by IBM in 1990. This standard supports 640x480 resolution with 65,536 colors or 1024x768 resolution with 256 colors. This standard is generally used in workstation systems.

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